



Bipolar LSI Data Book

Bipolar LSI Data Book



Second Edition

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PAL™ is a trademark of Monolithic Memories

Monolithic Memories 



Introduction

This book has been prepared to give the user a concise list of all Bipolar LSI Products offered by Monolithic Memories. It is divided by products into sections on HI REL, PROMs, ROMs, Character Generators, PAL, FIFO, Arithmetic Elements and Interface. Each section has been designed to allow the user the most useable format for the products described. The PROM, ROM, and Character Generator sections give data in the "generic" form allowing a quick review of the trade-off between devices. Cross references and selection guides are given where applicable. Programming and available programmers are given in detail. FIFO, PAL™, Arithmetic Elements and Interface data sheets are shown in detail for each product. This LSI data book was formatted with you, the user, in mind. For more information, contact the local Monolithic Memories sales representative or franchised distributor.

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Monolithic Memories—Company Profile

Monolithic Memories, Inc. is a company whose entire energies and resources are devoted to the development and production of Bipolar Large Scale Integrated (LSI) Memory and Logic circuits.

Since the company started its operation in 1970 the objective has been to establish its leadership in high-technology bipolar devices. Starting in 1971 MMI introduced the 1K PROM. This was followed with the first 2K PROM in 1972, the first 4K PROM in 1975 and the first 8K PROM in 1976.

In 1974 MMI started its expansion into the bipolar logic market with the introduction of the world's first 4-bit Slice, FIFO's Multipliers and most recently the Programmable Array Logic — PAL™.



Monolithic Memories is the world's leader in shipments of bipolar memory devices. The design fabrication and testing of all of our products is accomplished in a modern facility in Sunnyvale, California. Assembly of all devices is performed in a company owned facility in Penang, Malaysia. Both facilities are in the process of expansion to provide the bipolar LSI devices in great demand by the electronics industry.

PAL™ is a trademark of Monolithic Memories

Fast FIFOs from inventory.

For years, MMI has made the world's fastest FIFOs. Now they're even faster, and come in four-bit and five-bit versions.

MMI's FIFOs are designed to meet the needs of high-speed data processing applications. They are available in 4-bit and 5-bit versions, and are designed to operate at speeds up to 100 MHz. They are also available in a variety of package types, including DIP, PLCC, and Quad Flat Pack.

MMI's FIFOs are designed to meet the needs of high-speed data processing applications. They are available in 4-bit and 5-bit versions, and are designed to operate at speeds up to 100 MHz. They are also available in a variety of package types, including DIP, PLCC, and Quad Flat Pack.

Monolithic Memories

The company's products are used in a wide variety of products that range from electronic games to highly complex computer applications. There is a special emphasis placed on the manufacture of quality high-reliability devices for use in applications which include undersea and space programs.

Pick the interface that really fits.

Why compromise? MMI's broad line of LSI and S octal interface lets you pick the exact part you need every time.

MMI's LSI and S octal interface products are designed to meet the needs of high-speed data processing applications. They are available in a variety of package types, including DIP, PLCC, and Quad Flat Pack.

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Monolithic Memories

Monolithic Memories sells its products through a worldwide organization of sales representatives and distributors in the United States, Europe and Japan.

Monolithic Memories announces: a revolution in logic design!

PAL will save you money, space and sweat.

Use PAL to enhance your manufacturing and design capabilities.

Programmable Array Logic (PAL) is a type of LSI device that can be programmed to perform a wide variety of logic functions. It is a more flexible and cost-effective alternative to discrete logic and other LSI devices.

Monolithic Memories

Hire a veteran.

Employ Monolithic Memories' industry standard LSI to your advantage in your military system.

MMI's LSI and S octal interface products are designed to meet the needs of high-speed data processing applications. They are available in a variety of package types, including DIP, PLCC, and Quad Flat Pack.

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Quality System

The quality system at Monolithic Memories is based on MIL-Q-9858, "Quality Program Requirements," MIL-I-45208, "Inspection System Requirements," and MIL-M-38510, Appendix A, "Product Assurance Program." MIL-M-38510 plays a significant role in structuring MMI's quality program.

MMI's facilities in Sunnyvale were certified in June of 1977 by DESC, Defense Electronics Supply Center, to manufacture and qualify to class B and class C Schottky Bipolar PROMs, ROMs and RAMs in accordance with the requirements of MIL-M-38510. This certification included a successful audit of our quality system to the stringent requirements of Appendix A of MIL-M-38510 which defines a Product Assurance Program tailored for integrated circuit manufacturers by DESC. This same quality system has also met the strict requirements of both "controlled" and "captive" line programs connected with our special Hi-Rel programs.

The quality accent at MMI is on process control as reflected in the use of many monitors and audits rather than gate inspections. This philosophy is consistent with building in quality and reliability rather than attempting to screen for it.

Process Control

MMI's advanced low-power Schottky TTL process uses such techniques as redundant masking to reduce random defects and self-aligning masking to reduce active chip area. Although more costly than the standard SSI or MSI Schottky TTL processes, these approaches yield better quality, increased reliability and lower overall cost due to higher net die per wafer. During the initial production stages of new designs and periodically thereafter, engineering characterizes the design-process compatibility by careful sample selection of lots reflecting process variable extremes.

Screening

Much of the assembly (packaging only) is performed offshore at our Penang, Malaysia facility. This facility has been qualified and is routinely monitored for conformance to MIL-STD-883 by MMI's military customers as well as by MMI's Quality Control Department. All standard military hermetic MMI products are 100% screened to MIL-STD-883 Class C. This includes:

- Pre-cap inspection.*
- High-temperature storage at 150°C.
- Temperature cycling. -65°C to +150°C.
- Constant acceleration.
- Fine and gross leak.
- Final electrical test.
- Q.A. sample acceptance testing.

*Modified for LSI.

Standard commercial hermetic product receives the following screens and monitors to insure the highest possible product quality.

- Pre-cap inspection*
 - High temperature storage
 - Temperature cycle
 - Constant acceleration
 - Fine and gross leak
 - Final electrical test
- } Daily monitors in lieu of 100% screening which insure the AQL levels before are met or exceeded.

*Modified MIL-STD-883 Pre cap.

The product assurance levels which MMI guarantees are listed in the table on this page.

Reliability Engineering maintains product surveillance through routine sampling and submission to MIL-STD-883, method 5005, qualification testing. Additional step-stress and extended (limit) testing conditions are used when warranted. In general, failure rates have been found to be two orders of magnitude better than MIL-HDBK-217 estimates.

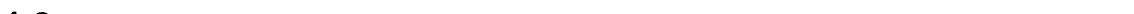
The quality organization is defined into three departments:

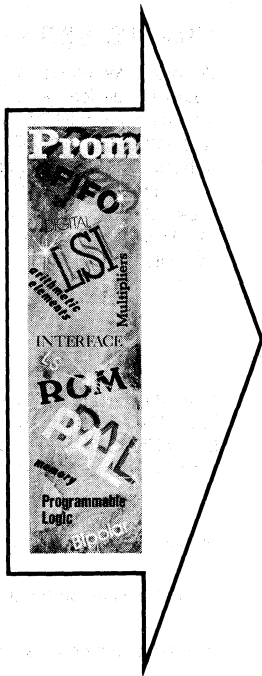
- Quality control
- Quality assurance
- Reliability assurance

Quality Assurance (AQL) Levels

TEST	LEVEL I COMMERCIAL (%)	LEVEL II MILITARY (%)
Hermeticity (includes fine and gross)	0.65	0.4
Electrical		
DC at 25°C	.40	.25
Functional at 25°C	.40	.25
AC at 25°C	.65	.40
DC at Temperature Extremes	.65	.65
Functional at Temperature Extremes	.65	.65
AC at Temperature Extremes	1.5	1.5







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Hi-Rel Products

Hi-Rel Products

MMI's Hi-Reliability Program offers a broad line of industry standard Bipolar LSI components processed and tested to Military standards. All Hi-Reliability products can be purchased screened to Classes B or C of MIL-STD-883B, Method 5004, each with two options or in full compliance with MIL-M-38510 where slash sheets exist as delineated herein.

The inherent quality and reliability of MMI's products have been successfully demonstrated in such aircraft programs as F14, F15, F16, F18, MRCA and Mirage to name the most significant. We have supplied bipolar LSI devices for the Block V and Pioneer Venus Satellite programs.

Screening Options

The following process options are available:

MIL-M-38510 Class B

MIL-STD-883 Class B

MMI "B" Program (Includes Group A tests at 125°C; Group B requirements deleted)

MIL-M-38510 Class C

MIL-STD-883 Class C

MMI "C" Program (Includes Group A tests at 125°C, Group B requirements deleted)

Package Options

The package options available are:

J: Cerdip 16, 18, 20, 24 and 40 lead varieties standard.

D: Ceramic Sidebrazed 16, 18, 24 and 40 lead upon request.

W: Ceramic Flatpack 16, 18 and 24 lead variety upon request.

F: Glass-metal Flatpack 16, 18 and 24 lead variety upon special request.

MIL-STD-883 Processed Parts

Monolithic Memories offers a complete line of high reliability bipolar LSI devices. All of our products are designed to operate over the entire military performance specification of $\pm 10\%$ VCC tolerance and -55°C to $+125^{\circ}\text{C}$ operating temperature ambient. As such, all standard military temperature range devices can be processed either to full compliance of Classes B and C of MIL-STD-883 or to only the 100% screening criteria of MIL-STD-883 (Method 5004) for both Classes B and C (MMI equivalent) as delineated in Table 1.

Many devices are available from stock. In addition to standard MIL-STD-883 high reliability devices, "Monolithic Memories has the ability to process parts to customers unique screening specifications. Some examples are:

- Selected electrical parameters
- 100% instant on (cold start) testing at -55°C
- Read and record data with Δ drift parameters
- Complete data reduction including mean, average, and three sigma analysis of each parameter
- Extended burn-in screening
- 100% AC, DC and functional testing at temperature extremes -55°C and $+125^{\circ}\text{C}$
- DPA (Destructive Physical Analysis)
- SEM (Scanning Electron Microscope) evaluation on a wafer lot basis.
- Special lot traceability to critical wafer fabrication processes, i.e., metalization
- Residual gas analysis on hermetic packages
- Custom lot qualification tests
- Special customer source inspection at pre-cap, SEM, process control monitoring points or at lot qualification testing

Monolithic Memories 

Table 1 Hi Rel Screening
MMI Available Standard Hi-Rel Screening Levels^c

FLOW	METHOD	883C METHOD 5004 ^a				MMI "C"b				883C METHOD 5004 ^a				MMI "B"b			
		PROM/PAL		LSI*	PROM/PAL		LSI*	PROM/PAL		LSI*	PROM/PAL		LSI*	PROM/PAL		LSI*	
		Unpro-grammed	Pro-grammed		ROM/ HAL	Pro-grammed		Unpro-grammed	ROM/ HAL		Pro-grammed	Unpro-grammed		ROM/ HAL	Pro-grammed		Unpro-grammed
Pre-cap visual (prior to seal)	2010 Cond B	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
Seal		Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
High Temp storage 24 Hr. @ 150°C (after seal)	1008 Cond. C	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
Temp. cycling 10 cycles. -65°C to +150°C	1010 Cond. C	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
Constant acceleration: Y1 30 KG	2001 Cond. E	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
Leak: Fine-5 x 10 ⁻⁸ cc/sec Gross—	1014 Cond. A or B 1014 Cond. C	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
Interim electrical test. DC & functional 25°C (correlated)	MMI Data Sheet	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
Test fuse/verify (DC)	MMI Std.	Yes	Yes	—	Yes	Yes	—	Yes	—	Yes	—	Yes	—	Yes	—	Yes	—
Program/verify		—	Yes	—	—	Yes	—	—	—	Yes	—	—	—	Yes	—	—	—
Burn-in 160 hr. @ 125°C	1015 Cond. D (Dynamic)	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
Final Electrical Test Static Tests at 25°C -55°C, +125°C	MMI Data Sheet	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
—Dynamic & switching tests @ 25°C		—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
—Functional Tests at 25°C		Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
Lot Acceptance: Group A Subgroup 2		—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—
Sub 1, 2, 3, 7, 8, 9 except Sub 9 for unprogrammed devices		Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
Group B tests		Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes

a Tested in full accordance with MIL-STD-883 requirements

b Tested only to 100% screening requirements of MIL-STD-883 Method 5004. Reduced Group A testing and Group B testing not performed.

c MMI will screen and test to the latest issue in effect or as dictated by the contract.

d Dynamic Testing at 25°C, +125°C, -55°C; Switching tests at 25°C only.

* LSI Logic Products (include 54SXXX and 54LSXXX interface circuits)



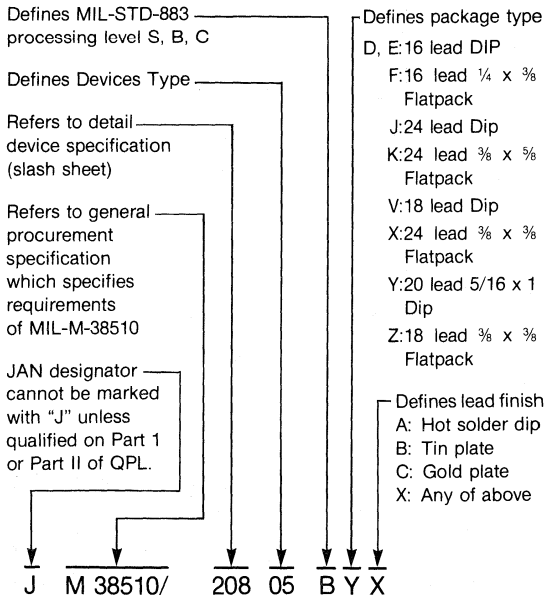
MIL-M-38510

The MIL-M-38510 Program is designed to standardize the Hi Reliability portion of the microcircuit industry much the same as MIL-S-19500 standardized the transistor industry. Its purpose is to provide the customer the highest possible quality level for the required application along with reasonable prices and fastest delivery.

The device electrical and package requirements of MIL-M-38510 are detailed by a device specification referred to as a slash sheet. Each slash sheet defines the microcircuit electrical performances and mechanical requirements. Each device listed on a slash sheet is referred to as a dash number and the group of microcircuits contained on a slash sheet is defined as a family of devices.

A unique MIL-M-38510 part number completely defines the microcircuit being procured: Device type, electrical specification, mechanical outline, 100% screening requirement/quality level, and lead finish in the following format (Table 2).

Table 2: MIL-M-38510 Part Numbering Format



In addition, all MIL-M-38510 microcircuits must be completely manufactured and assembled in a domestic USA facility.

We have a strong commitment to the MIL-M-38510 program and participate in slash sheet development with DESC, RADC and our customers. We have or will qualify all of our products for which there is a released MIL-M-38510 detailed specification (slash sheet). If one requires a product for which a slash sheet does not exist—then we can provide "883 processed" product. "883 processed" parts are screened to the full requirements of MIL-STD-883 Methods 5004 and 5005 with full electrical tests (DC, switching, and functional) over the military temperature range per MMI data sheet limits in our DESC certified facility. Each lot of 883 processed devices shipped includes a Certificate of Conformance and Group A Summary Report.

Currently released "slash sheets" for MMI supplied product are as follows:

- MIL-M38510/203 1K Schottky NiCR PROMS (256x4) 01 5300-1
02 5301-1
- MIL-M-38510/204 2K Schottky NiCR PROMS (512x4) 01 5305-1
02 5306-1
- MIL-M-38510/206 4K Schottky NiCR PROMS (1Kx4) 01 5352-1
02 5353-1
- MIL-M-38510/207 1/4K Schottky NiCR PROMS (32x8) 01 5330-1
02 5331-1
- MIL-M-38510/208 4K Schottky NiCR PROMS (512x8) 01 5340-1
02 5341-1
04 5348-1
05 5349-1
- MIL-M-38510/209 8K Schottky NiCR PROMS (1Kx8) 03 5380-1
04 5381-1

For an up-to-date status on our QPL program, call your factory representative.

Advanced Programs

MMI has participated in the Trident Missile program since 1975. This participation has involved two manufacturing concepts for the production of Extreme Reliability Components.

1. **Controlled Line**—This concept places MMI manufacturing documentation and equipment under customer control and concurrence with any change.
2. **Captive Line**—This concept defines the equipment to be used, controls and supplies wire and packages. MMI documents the systems and provides the semiconductor expertise.

The Military Programs Department is involved in TRIDENT, DISCUSS, MX, F-18, MK500 and various NASA/SPACE PROGRAMS. Our products have the capability of meeting full radiation requirements of neutron, gamma dot and ionizing environments.

Our facility has DOD clearance and we have the capability to participate in customer analysis of our designs. These analyses may lead to design changes which enhance the product capability in hostile environments. Products which have been qualified for these advanced programs are:

- 5301—1K NiCR PROM
- 5300—1K Gold PROM
- 5341—4K NiCR PROM
- 5206—2K ROM (5306 NiCR PROM Equivalent)

Contact us for further details should you require this facet of our Hi-Reliability capability.

Flat/Pack Chip Carriers and Die

Most products are available in flat packs (see individual selection guides and the package appendix for details), and our manufacturing line can accommodate your chip carrier packaging requirements as well. If your needs are for the ultimate in density, we can also supply LSI chips for your hybrid applications. These can be furnished with special 100% testing and optical inspection screens geared for hybrid packaging.

Ordering Information

Each of the screening options which MMI offers can be identified by a unique indicator for a given product. This part/screening identification system must be used when placing an order to ensure that the desired screening level is ordered. The product delivered is also marked with this indicator to verify compliance with purchase order requirements. Table 3 below provides the details of the screening identification system and includes an example.

In-House Reliability Programs

In addition to the execution of specific customer requested Hi-Rel testing, the Reliability Assurance Group conducts the following activities to establish and maintain our complete line of Hi-Reliability Bipolar LSI devices.

- Device design qualification (new/revise)
- Package qualification
- Process qualification
- On-going device/package/process qualification program.
- Extended and accelerated life testing (step/stress).
- Periodic reliability reports for in-house/field consumption.
- Process monitors (SEM).

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Table 3 Screening Level Identification/Part Marking

SCREENING LEVEL	PRODUCT IDENTIFICATION	EXAMPLE USING 512x8 NiCR PROM WITH TRI STATE OUTPUTS AND ENCASED IN 20 PIN CERDIP
MIL-M-38510 Class B	MIL-M-38510/XXXXX BXX or JM38510/XXXXX BXX	JM38510/20805 BYX
MIL-STD-883 Class B	5XXX-1X883B*	5349-1J883B
MMI "B" Program	5XXX-1XB	5349-1JB
MIL-M-38510 Class C	MIL-M-38510/XXXXX CXX or JM 38510/XXXXX CXX	JM38510/20805 CYX
MIL-STD-883 Class C	5XXX-1X 883C	5349-1J883C
MMI "C" Program	5XXX-1XC	5349-1JC

*-1 identification for Schottky NiCR PROMS only.

Hi-Rel Products

Table 4 Group A Electrical Tests

SUBGROUPS	LTPD		INITIAL SAMPLE SIZE*	
	B	C	B	C
Subgroup 1—Static Tests at +25°C	5	5	45	45
Subgroup 2—Static Tests at Maximum Rated Operating Temperature	7	10	32	22
Subgroup 3—Static Tests at Minimum Operating Temperature	7	10	32	22
Subgroup 4—Dynamic Tests at +25°C†	5	5	45	45
Subgroup 5—Dynamic Tests at Maximum Rated Operating Temperature†	7	10	32	22
Subgroup 6—Dynamic Tests at Minimum Rated Operating Temperature†	7	10	32	22
Subgroup 7—Functional Tests at +25°C	5	5	45	45
Subgroup 8—Functional Tests at Maximum and Minimum Operating Temperatures	0	15	22	15
Subgroup 9—Switching Tests at +25°C Except Unprogrammed PROM	7	10	32	22

*Groups A, B, C, and D sampling plans are based on standard LTPD tables of MIL-M-38510 Appendix B. The smallest sample size based on zero rejects allowed, has been chosen unless otherwise indicated. If necessary, the sample size will be increased once to the quantity corresponding to the next acceptance number.

† Dynamic tests are not applicable to digital memory devices; switching subgroup tests are performed to a specified functional pattern and dynamically exercised.

Table 5 Group B Tests

TEST	METHOD	CONDITIONS	LTPD	INITIAL † SAMPLE SIZE
Subgroup 1 Physical Dimensions	2016	MMI Data Sheet	No failures	2
Subgroup 2 Resistance to Solvents	2015		No failures	4
Subgroup 3 Solderability	2003	Soldering temperature of +260°C ±10°C. 90% coverage, void concentration not to exceed 10% of area	15	15 Leads from 3 devices minimum
Subgroup 4 Internal Visual and Mechanical	2014	Failure criteria from design and construction	No failures	1
Subgroup 5 Bond strength	2011	Condition D: 3 gram force minimum for aluminum wire, ultrasonic bonding	15	15 wires from 4 devices minimum
Subgroup 6 Internal Water-Vapor Content* D-1-B	1018	100 ppm max. at +100°C	No failures 1 failure	3 5

* For packages with desiccant only. MMI packages do not contain a desiccant. Thus subgroup 6 does not apply.

† All samples are devices unless otherwise stated.

Hi-Rel Products

Table 6 Group C Tests (Die Related Tests)

TEST	METHOD	CONDITIONS	LTPD	INITIAL SAMPLE SIZE
Subgroup 1* Operating Life Test	1005	Steady state life: 1,000 Hr., +125°C, condition D, Dynamic	5	77 ACC = 1*
Subgroup 2* A. Temperature Cycling	1010	Test condition C: air to air, -65°C to +150°C, 10 cycles	15	15
B. Constant Acceleration (Centrifuge)	2001	Test condition E: 30kG centri- fugal acceleration -Y1 axis only		
C. Seal (Fine and Gross)	1014	Test Conditions A or B and C		
D. Visual Examination	1010			

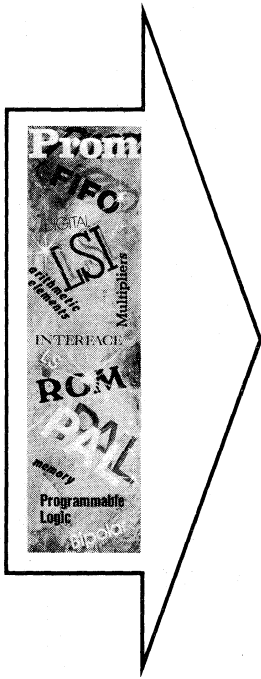
Table 7 Group D Test (Packages Related Tests)

TEST	METHOD	CONDITIONS	LTPD	INITIAL SAMPLE SIZE
Subgroup 1 A. Physical Dimensions	2016	MMI Data Sheet	15	15
B. Internal Water Vapor Content	1018	5000 PPM max. @ 100°C	No failures 1 failure	3 5
Subgroup 2 A. Lead Fatigue	2004	Test condition: B2: 3 oz. for ribbon leads: 8 oz. for all others	15	15
B. Seal (Fine and Gross)	1014	Test conditions A or B and C		
Subgroup 3* A. Thermal Shock	1011	Test method B: liquid to liquid, -55°C to +125°C, 15 cycles	15	15
B. Temperature Cycling	1010	Test condition C: air to air, -65°C to +150°C, 100 cycles		
C. Moisture Resistance	1004	Omit initial conditioning and vibration		
D. Seal (Fine and Gross)	1014	Test conditions A or B and C		
E. Visual examination	1004			
Subgroup 4* A. Mechanical Shock	2002	Test condition B: 5 shock pulses, 6 directions: 1500 g	15	15
B. Vibration Variable Frequency	2007	Test condition A: 20 g		
C. Constant Acceleration (Centrifuge)	2001	Test condition E: 30 kg centri- fugal acceleration. Y1 axis only		
D. Seal (Fine and Gross)	1014	Test conditions A or B and C		
E. Visual Examination	1010			
Subgroup 5 A. Salt Atmosphere (Corrosion)	1009	Test condition A: 24 Hr.	15	15
B. Seal (Fine and Gross)	1014	Test conditions A or B and C		
C. Visual Examination	1010			

* Electrical end points required for all subgroups (except in Group B and Subgroups 1, 2 and 5 of Group D), are room temperature. Subgroups 1, 2 and 3 of Group A DC tests, per MMI data sheet. Check factory for additional requirements.

2

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Introduction	1
HI REL	2
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Bipolar PROM Cross-Reference Guide

Bipolar PROM Cross-Reference Guide

SIZE	MEMORY DESCRIPTION		MMI	AMD	FAIR-CHILD	HARRIS	INTEL	INTER-SIL	MOTOROLA	NATIONAL	RAYTHEON	SIGNETICS	TI
	ORGANIZATION	PINS											
256	32x8	16	6330-1	27S08/29750		7602		5600				N82S23	TBP18SA030 SN74S188
			6331-1	27S09/29751		7603		5610					N82S123
1024	256x4	16	6300-1	29S10/29760		7610	3601	5603			29660	N82S27/82S126	TBP14SA10 SN74S387
			6301-1	27S11/29761		7611	3621	5623				29661	N82S129
2048	256x8	20	6308-1										
			6309-1							DM74S470		29600	
2048	512x4	24	6335-1										
			6336-1							DM74S471		29601	
2048	512x4	16	6305-1	27S12/29770		7620	3602A	5604	MCM 7620	DM74S570	29610	N82S130	
			6306-1	27S13/29771		7621	3602A	5624		MCM 7621	DM74S571	29611	N82S131
4096	512x8	20	6348-1			7648				DM74S473	29620		TBP18SA42 SN74S473
			6349-1			7649					DM74S472	29621	
4096	512x8	24	6340-1			7640	3604A	5605	MCM 7640	DM87S295	29624	N82S140	TBP18SA46 SN74S475
			6341-1			7641	3624A	5625		MCM 7641	DM87S296	29625	N82S141
4096	1024x4	18	6352-1		93452	7642	3605	5606	MCM 7642	DM74S572		N82S136	
			6353-1			93453	7643	3625	5626	MCM 7643	DM74S573		N82S137
8192	1024x8	24	6380-1		93450	7680	3608	5608	MCM 7680	DM87S229	29630	N82S180	TBP28SA86 SN74S479
			6381-1			93451	7681	3628	5618	MCM 7681	DM87S228	29631	N82S181

Note: Only commercial specification part numbers are listed.

Bipolar PROM Cross Reference Guide

AMD **MMI**
 27S08/29750 6330-1
 27S09/29751 6331-1
 27S10/29760 6300-1
 27S11/29761 6301-1
 27S12/29770 6305-1
 27S13/29771 6306-1

FAIRCHILD **MMI**
 93450 6389-1
 93451 6381-1
 93452 6352-1
 93453 6353-1

HARRIS **MMI**
 7602 6331-1
 7603 6331-1
 7610 6300-1
 7611 6301-1
 7620 6305-1
 7621 6306-1
 7648 6348-1
 7649 6349-1
 7640 6340-1
 7641 6341-1
 7642 6352-1
 7643 6353-1
 7680 6380-1
 7681 6381-1

INTEL **MMI**
 3601 6300-1
 3602A 6305-1
 3602A 6306-1
 3604A 6340-1
 3605 6352-1
 3608 6380-1
 3621 6301-1
 3624A 6341-1
 3625 6353-1
 3628 6381-1

INTERSIL **MMI**
 5600 6330-1
 5603 6300-1
 5604 6305-1
 5605 6340-1
 5606 6352-1
 5608 6380-1
 5610 6331-1
 5618 6381-1
 5623 6301-1
 5624 6306-1
 5625 6341-1
 5626 6353-1

MOTOROLA **MMI**
 MCM 7620 6305-1
 MCM 7621 6306-1
 MCM 7640 6340-1
 MCM 7641 6341-1
 MCM 7642 6352-1
 MCM 7643 6353-1
 MCM 7680 6380-1
 MCM 7681 6381-1

NATIONAL **MMI**
 DM74S470 6308-1
 DM74S471 6309-1
 DM74S472 6349-1
 DM74S473 6348-1
 DM74S580 6305-1
 DM74S571 6306-1
 DM74S572 6352-1
 DM74S573 6353-1
 DM87S228 6381-1
 DM87S229 6380-1
 DM87S295 6340-1
 DM87S296 6341-1

RAYTHEON **MMI**
 29600 6308-1
 29601 6309-1
 29610 6305-1
 29611 6306-1
 29620 6348-1
 29621 6349-1
 29624 6340-1
 29625 6341-1
 29630 6380-1
 29631 6381-1
 29660 6300-1
 29661 6301-1

SIGNETICS **MMI**
 N82S23 6330-1
 N82S27/82S127 6300-1
 N82S123 6331-1
 N82S129 6301-1
 N82S130 6305-1
 N82S131 6306-1
 N82S136 6352-1
 N82S137 6353-1
 N82S140 6340-1
 N82S141 6341-1
 N82S180 6380-1
 N28S181 6381-1

TI **MMI**
 OLD NUMBERS
 SN74S188 6330-1
 SN74S287 6301-1
 SN74S288 6331-1
 SN74S387 6300-1
 SN74S470 6308-1
 SN74S471 6309-1
 SN74S472 6349-1
 SN74S473 6348-1
 SN74S474 6341-1
 SN74S475 6340-1
 SN74S478 6381-1
 SN74S479 6380-1

TI **MMI**
 NEW NUMBERS
 TBP18SA030 6330-1
 TBP14S10 6301-1
 TBP18S030 6331-1
 TBP14SA10 6300-1
 TBP18SA22 6308-1
 TBP18S22 6309-1
 TBP18S42 6349-1
 TBP18SA42 6348-1
 TBP18S46 6341-1
 TBP18SA42 6340-1
 TBP28S86 6381-1
 TBP28SA86 6380-1

Generic PROM Family

53/63XX-1

Features/Benefits

- Standard Schottky processing
- Reliability proven nichrome fusible links (qualified for MIL-M-38510)
- PNP inputs for low input current
- Compatible pin configurations for upward expansion
- 4-bit-wide and 8-bit-wide for byte oriented applications

Application

- Microprogram store
- Microprocessor program store
- Look up table
- Character generator
- Random logic
- Code converter

Description

The 53/63XX-1-series generic PROM family offers the widest selection of sizes and organizations available in the industry. The 4-bit wide PROMs range from 256x4 to 1024x4 and feature upward/downward pin out compatibility in the space saving 16 and 18 pin packages. The 8-bit-wide PROMs range from 32x8 to 1024x8 in a wide selection of package sizes. All PROMs have the same programming specifications allowing a single generic programmer.

The family features low input current PNP inputs, full Schottky clamping, three-state and open collector outputs. The nichrome fuses store a logical high and are programmed to the low state. Special on chip circuitry and extra fuses provide preprogramming tests which assure high programming yields and high reliability.

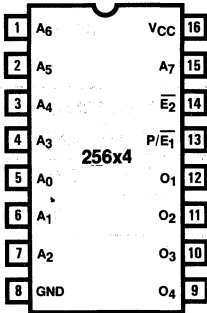
The 63 series is specified for operation over the commercial temperature and voltage range. The 53 series is specified for the military ranges.

Generic PROM Selection Guide

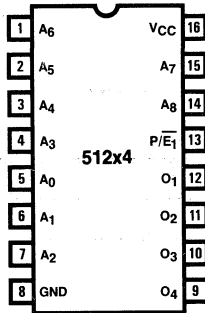
MEMORY			PACKAGE	DEVICE TYPE		
SIZE	ORGANIZATION			COMMERCIAL	MILITARY	
1K	256x4	OC	J16	6300-1	5300-1	4-bit-wide
		TS		6301-1	5301-1	
2K	512x4	OC	J16	6305-1	5305-1	
		TS		6306-1	5306-1	
4K	1024x4	OC	J18	6350-1	5350-1	
		TS		6351-1	5351-1	
		OC		6352-1	5352-1	
		TS		6353-1	5353-1	
1/4K	32x8	OC	J16	6330-1	5330-1	8-bit-wide
		TS		6331-1	5331-1	
2K	256x8	OC	J20	6308-1	5308-1	
		TS		6309-1	5309-1	
		OC	J24	6335-1		
		TS		6336-1		
4K	512x8	OC	J24	6340-1	5340-1	
		TS		6341-1	5341-1	
		OC	J20	6348-1	5348-1	
		TS		6349-1	5349-1	
8K	1024x8	OC	J24	6380-1	5380-1	
		TS		6381-1	5381-1	

Pin Configurations

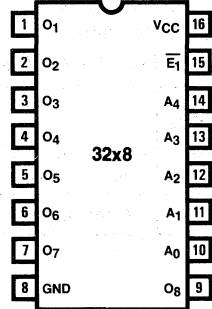
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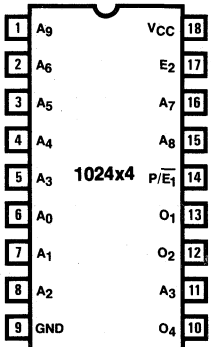
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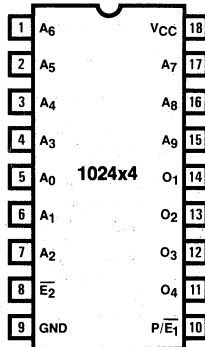
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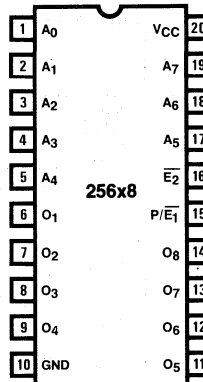
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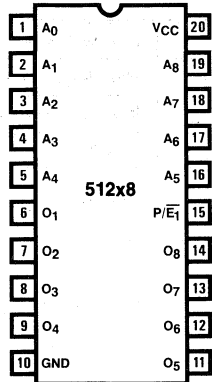
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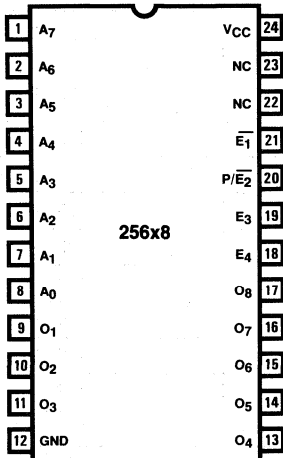
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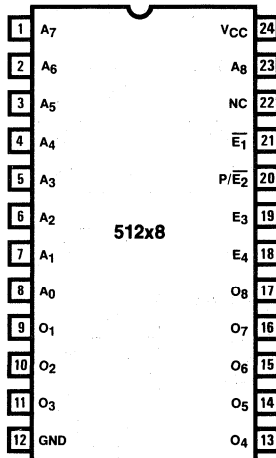
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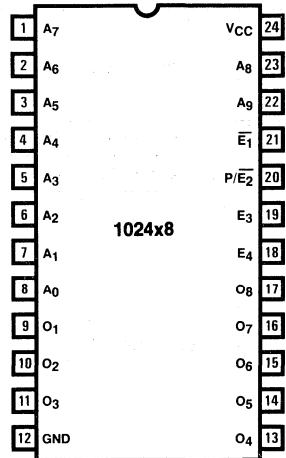
6335-1
6336-1



53/6340-1
53/6341-1



53/6380-1
53/6381-1



3

Absolute Maximum Ratings

Supply Voltage, V_{CC}	7V
Input Voltage	7V
Off-state output voltage	5.5V
Storage temperature	-65° to +150°C

Operating Conditions

SYMBOL	PARAMETER	MILITARY			COMMERCIAL			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
T_A	Operating free-air temperature	-55		125	0		75	°C

Electrical Characteristics Over Operating Conditions

SYMBOL	PARAMETER	TEST CONDITIONS	MIN TYP MAX			UNIT
			MIN	TYP	MAX	
V_{IL}	Low-level input voltage			0.8		V
V_{IH}	High-level input voltage		2			V
V_{IC}	Input clamp voltage	$V_{CC} = \text{MIN}$ $I_I = -18\text{mA}$		-1.5		V
I_{IL}	Low-level input current	$V_{CC} = \text{MAX}$ $V_I = 0.45\text{V}$		-0.25		mA
I_{IH}	High-level input current	$V_{CC} = \text{MAX}$ $V_I = 4.5\text{V}$ (Program Pin) $V_I = V_{CC} \text{MAX}$ (Other inputs)		40		μA
V_{OL}	Low-level output voltage	$V_{CC} = \text{MIN}$ $V_{IL} = 0.8\text{V}$ $V_{IH} = 2\text{V}$	MIL $I_{OL} = 12\text{mA}$	All PROMs except '30, '31, '80, '81	0.5	V
			COM $I_{OL} = 16\text{mA}$			
			MIL $I_{OL} = 8\text{mA}$			
			COM $I_{OL} = 12\text{mA}$			
V_{OH}	High-level output voltage	$V_{CC} = \text{MIN}$ $V_{IL} = 0.8\text{V}$ $V_{IH} = 2\text{V}$	MIL $I_{OH} = -2\text{mA}$	2.4		V
			COM $I_{OH} = -3.2\text{mA}$			
I_{OZL}	Off-state output current	$V_{CC} = \text{MAX}$	$V_O = 0.5\text{V}$	-100		μA
I_{OZH}			$V_O = 2.4\text{V}$	100		μA
I_{CEX}	Open collector output current	$V_{CC} = \text{MAX}$	$V_O = 2.4\text{V}$	100		μA
I_{OS}	Output short-circuit current *	$V_{CC} = 5\text{V}$	$V_O = 0\text{V}$	-20	-90	mA
I_{CC}	Supply current	$V_{CC} = \text{MAX}$ All inputs grounded All outputs open	'30, '31	125		mA
			'00, '01, '05, '06	130		
			'08, '09, 6348/9	170		
			5348/9	155		
			'35, '36, '40, '41	170		
			'50, '51, '52, '53	175		
			6380/1	190		
5380/1	180					

* Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

Switching Characteristics
Over Commercial Operating Conditions

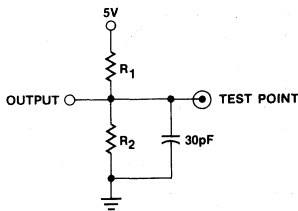
DEVICE TYPE	t _{AA} (ns) ADDRESS ACCESS TIME	t _{EA} & t _{ER} (ns) ENABLE ACCESS & RECOVERY TIME	CONDITIONS (See standard test load)	
	MAX	MAX	R1(Ω)	R2(Ω)
6300-1, 6301-1	55	30	300	600
6305-1, 6306-1	60	30		
6308-1, 6309-1	70	30		
6335-1, 6336-1	70	30		
6340-1, 6341-1	70	30		
6348-1, 6349-1	70	30		
6350-1, 6351-1	60	30		
6352-1, 6353-1	60	30		
6330-1, 6331-1	50	30	375	750
6380-1, 6381-1	90	40		

Over Military Operating Conditions

DEVICE TYPE	t _{AA} (ns) ADDRESS ACCESS TIME	t _{EA} & t _{ER} (ns) ENABLE ACCESS & RECOVERY TIME	CONDITIONS (See standard test load)	
	MAX	MAX	R1(Ω)	R2(Ω)
5300-1, 5301-1	75	40	300	600
5305-1, 5306-1	75	40		
5308-1, 5309-1	80	40		
5335-1, 5336-1	80	40		
5340-1, 5341-1	80	40		
5348-1, 5349-1	80	40		
5350-1, 5351-1	75	40		
5352-1, 5353-1	75	40		
5330-1, 5331-1	60	40	375	750
5380-1, 5381-1	125	40		

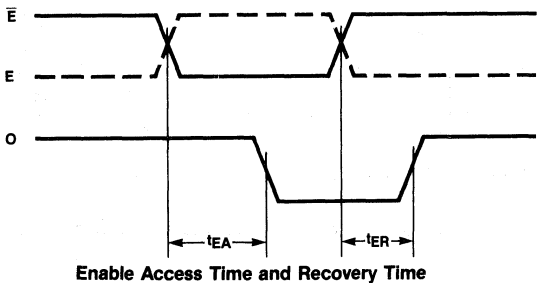
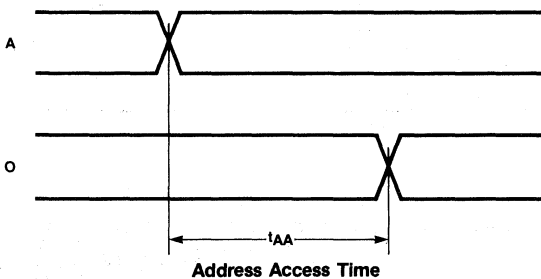
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Standard Test Load



Input Pulse: 0V to 3V
Input Rise and Fall Times: 5ns from 1V to 2V
Measurements Made at 1.5V

Definition of Waveforms



PROM Programming Instructions

53/63XX-1

Description

The 53/63XX-1 Generic PROM Family is manufactured with outputs high in all storage locations. To make an output low at

a particular word, a nichrome fusible link must be opened. This procedure is called programming.

Programming Procedure (See Figure 1)

1. Apply the desired address to the inputs.
2. Enable Inputs may be left at any state.*
3. Apply 5.5V to V_{CC} .
4. Apply V_{PP} to the program pin. (This step is not used on the 32x8 PROM)*.
5. Apply V_{OUT} to the output to be programmed. (Program only one output at a time).
6. Remove V_{OUT} .
7. Remove V_{PP} .
8. Verification may be performed after each bit or word or after completing the programming of all memory locations.

Verification Procedure (See Figure 2)

1. Enable the device.
2. To verify low-state:
 - 2A. Apply an address where the output should be low.
 - 2B. Apply 4.2V to V_{CC} .
 - 2C. Load the output with $I_{OL} = 12$ mA.
 - 2D. Check that the output is less than 0.8V.
3. To verify High-state:
 - 3A. Apply an address where the output should be high.
 - 3B. Apply 6V to V_{CC} .
 - 3C. Load the output with $I_{OH} = 0.3$ mA.
 - 3D. Check that the output is higher than 4.5V.

*The 5330/1 and 6330/1 do not have a program pin. For these devices the output only is used in programming a particular selected bit and the device must be in the disabled state.

Programming Parameters Do not test these parameters or you will program the device.

SYMBOL	PARAMETER	CONDITIONS $T_A = +25^\circ\text{C}$	FIGURE	LIMITS			UNIT
				MIN	TYP	MAX	
t_R	Slew rate of Programming Pulses †			0.3		0.5	V/ μ s
V_{CCP}	VCC During Programming			5.4	5.5	5.6	V
	Maximum Duty Cycle					25	%
V_{PP}	Programming Voltage on Program Pin *		1	27		33	V
V_{OUT}	Programming Voltage on Output Pin *		1	20		26	V
t_{D1}	Delay between V_{PP} and V_{OUT}		1	0	10	20	μ s
t_{D2}				0	0.5	1	
t_p	Pulse width of V_{OUT}		1	10		25	μ s
V_{OLV}	VOL during verification	Chip enabled $I_{OL} = 12$ mA $V_{CC} = 4.2$ V	2			0.8	V
V_{OHV}	VOH during verification	Chip enabled $I_{OH} = 0.3$ mA $V_{CC} = 6$ V	2	4.5			V

*Voltage supply must be capable of supplying at least 240 mA.

† Leading edge of V_{PP} and V_{OUT}

PROM Programming Instructions 53/63XX

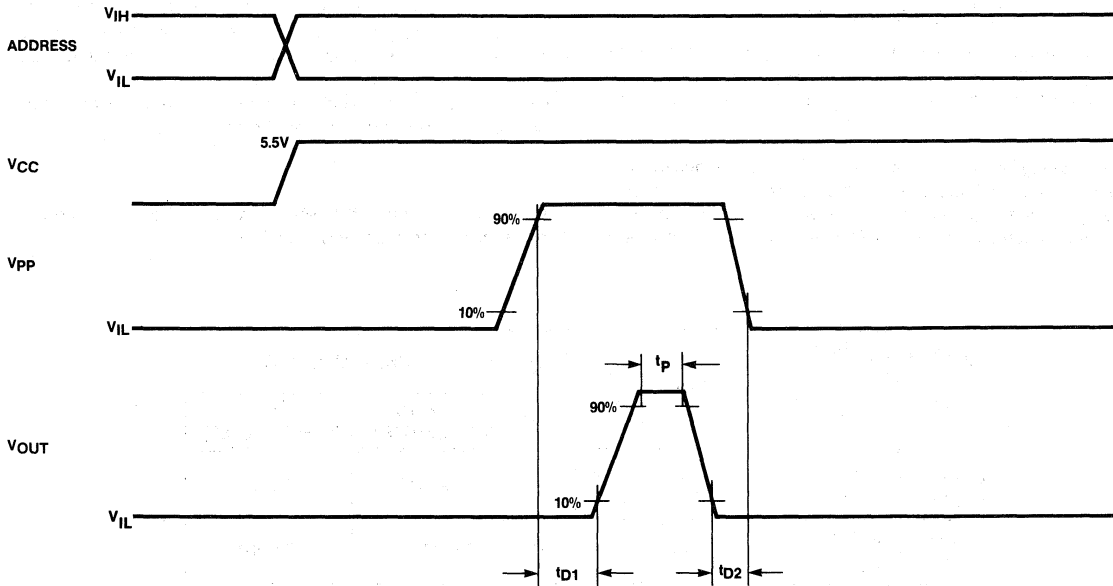


Figure 1. Programming Timing Diagram

3

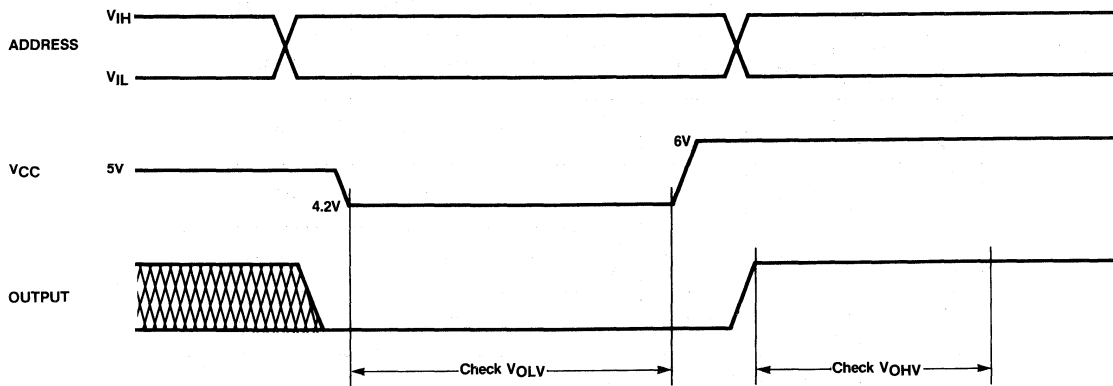


Figure 2. Verification Timing Diagram

Optimized Programming Algorithm

1. Pulse all fuses to be programmed with single, minimum voltage programming pulses (line 1 in the table).
2. Verify all fuses at low VCC (4.2V). During this step, unprogrammed fuses are pulsed up to eight more times (see table).
3. Re-verify at low VCC (4.2V) and high VCC (6V).

PULSE NUMBER	PROGRAM PIN VOLTAGE	OUTPUT VOLTAGE
1 to 3	27V	20V
4 to 6	30V	23V
7 to 9	33V	26V

PROM Programming Instructions 53/63XX

Commercial Programmers

MMI PROMs are designed and tested to give a programming yield greater than 95%. If your programming yield is lower, check your programmer. It may not be properly calibrated. (See figures 1 and 2).

Programming is final manufacturing—it must be quality-controlled. Equipment must be calibrated as a regular routine, ideally under the actual conditions of use. The best method involves a storage scope, with DC current probes clamped over

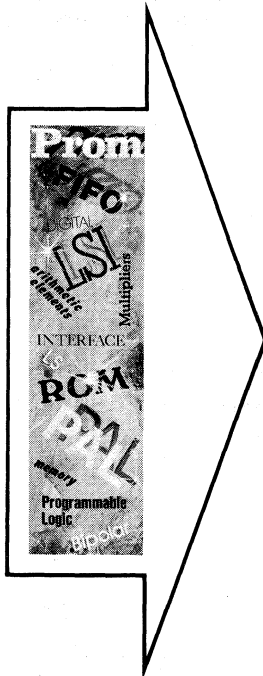
the external wires to the program pin and the output pin. The current should not be limited at a value less than 240mA. This can be checked by using a 50-ohm resistor as a load. Each time a new board or a new programming module is inserted, the whole system should be checked. Both timing and voltages must meet published specifications for the device.

Remember—The best PROMs available can be made unreliable by improper programming techniques.

PART NUMBER		SIZE	CONFIG.	OUT PUT	NO. OF PINS	SOCKET ADAPTER	
M	C					DATA I/O (ALL SERIES) *	PRO-LOG (SERIES 90, 92) †
5330-1	6330-1	1/4K	32x8	OC	16	715-1046	PA16-2
5331-1	6331-1			TS			
5300-1	6300-1	1K	256x4	OC	16	715-1035-1	PA16-1
5301-1	6301-1			TS			
5305-1	6305-1	2K	512x4	OC	16	715-1035-2	PA16-1
5306-1	6306-1			TS			
5308-1	6308-1	2K	256x8	OC	20	715-1028-1	PA20-2
5309-1	6309-1			TS			
5335-1	6335-1	2K	256x8	OC	24	715-1033-1	PA24-1
5336-1	6336-1			TS			
5340-1	6340-1	4K	512x8	OC	24	715-1033-2	PA24-1
5341-1	6341-1			TS			
5348-1	6348-1	4K	512x8	OC	20	715-1064	PA20-2
5349-1	6349-1			TS			
5350-1	6350-1	4K	1024x4	OC	18	715-1036	PA18-1
5351-1	6351-1			TS			
5352-1	6352-1	4K	1024x4	OC	18	715-1039-3	PA18-2
5353-1	6353-1			TS			
5380-1	6380-1	8K	1024x8	OC	24	715-1033-3	PA24-1
5381-1	6381-1			TS			

* Program card set is 909-1226-1 for all series DATA I/O

† Personality module is PM 9037 for all PRO-LOG (series 90, 92)



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Generic ROM Family

52/62XX-1 52/62XX-2

Features/Benefits

- High bit density up to 16K
- PNP inputs for low input current
- High speed Schottky technology
- Open collector or three state outputs

Applications

- Character generator
- Look up table
- Microprocessor program store
- Microprogram store
- Random logic
- Code converter

Description

The 52/6200 series generic ROM family is available in sizes from 8K through 16K bits. The 8-bit-wide ROMs are available as 1Kx8 and 2Kx8 organization. Additional 9-bit and 10-bit-wide output configurations are available for custom logic or character generator applications.

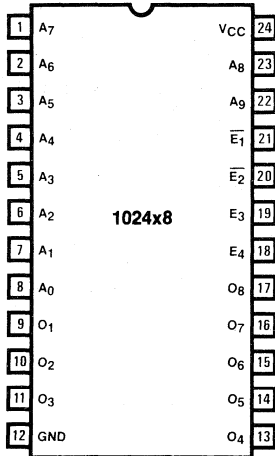
Generic ROM Selection Guide

MEMORY		PACKAGE	DEVICE TYPE	
SIZE	ORGANIZATION		COMMERCIAL	MILITARY
8192	1024x8	OC	6280-1	5280-1
		TS	6281-1	5281-1
		OC	6280-2	5280-2
		TS	6281-2	5281-2
		OC	6282-1	5282-1
		TS	6283-1	5283-1
9216	1024x9	OC	6260-1	5260-1
		TS	6261-1	5261-1
10240	1024x10	OC	6255-1	5255-1
		TS	6256-1	5256-1
10368	1152x9	OC	6290 *	5290 *
		TS	6291 *	5291 *
16384	2048x8	OC	6275-1	5275-1
		TS	6276-1	5276-1

* Detailed information in section 5 (character generators)

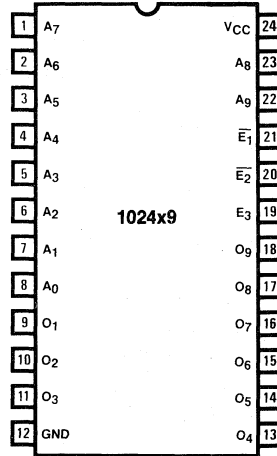
Pin Configurations

52/6280-1 52/6280-2 *52/6282-1
 52/6281-1 52/6281-2 *52/6283-1



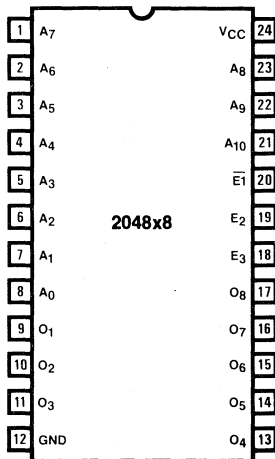
*"OR" ENABLE = $\bar{E}1 \bar{E}2 + E3 E4$

52/6260-1
 52/6261-1

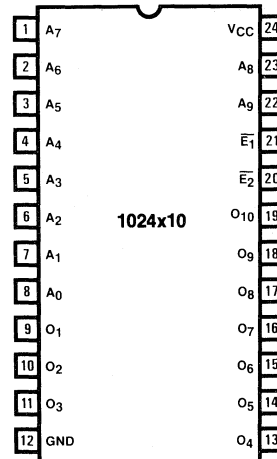


4

52/6275-1
 52/6276-1



52/6255-1
 52/6256-1



Absolute Maximum Ratings

Supply Voltage, V_{CC}	7V
Input Voltage	7V
Off-state output voltage	5.5V
Storage temperature	-65° to +150°C

Operating Conditions

SYMBOL	PARAMETER	MILITARY			COMMERCIAL			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
T_A	Operating free-air temperature	-55		125	0		75	°C

Electrical Characteristics Over Operating Conditions

SYMBOL	PARAMETER	TEST CONDITIONS	MIN TYP MAX			UNIT	
			MIN	TYP	MAX		
V_{IL}	Low-level input voltage				0.8	V	
V_{IH}	High-level input voltage		2			V	
V_{IC}	Input clamp voltage	$V_{CC} = \text{MIN}$ $I_I = -18\text{mA}$			-1.5	V	
I_{IL}	Low-level input current	$V_{CC} = \text{MAX}$ $V_I = 0.45\text{V}$			-0.25	mA	
I_{IH}	High-level input current	$V_{CC} = \text{MAX}$ $V_I = 2.4\text{V}$			40	μA	
I_I	Maximum input current	$V_{CC} = \text{MAX}$ $V_I = 5.5\text{V}$			1.0	mA	
V_{OL}	Low-level output voltage	$V_{CC} = \text{MIN}$ $V_{IL} = 0.8\text{V}$ $V_{IH} = 2\text{V}$	MIL	$I_{OL} = 8\text{mA}$	'75, '76, '80, '81, '82, '83	0.5	V
			COM	$I_{OL} = 10\text{mA}$			
			MIL	$I_{OL} = 6\text{mA}$	'55, '56, '60, '61		
			COM				
V_{OH}	High-level output voltage	$V_{CC} = \text{MIN}$ $V_{IL} = 0.8\text{V}$ $V_{IH} = 2\text{V}$	MIL	$I_{OH} = -1\text{mA}$	2.4	V	
			COM	$I_{OH} = -2\text{mA}$			
I_{OZL}	Off-state output current	$V_{CC} = \text{MAX}$ $V_O = 0.5\text{V}$	'80, '81, '82, '83, '55, '56, '60, '61			-50	μA
			'75, '76			-100	
I_{OZH}	Off-state output current	$V_{CC} = \text{MAX}$ $V_O = 2.4\text{V}$	'80, '81, '82, '83, '55, '56, '60, '61			50	μA
			'75, '76			100	
I_{CEX}	Open collector output current	$V_{CC} = \text{MAX}$ $V_O = 2.4\text{V}$			100	μA	
I_{OS}	Output short-circuit current	$V_{CC} = 5.0\text{V}$ $V_O = 0\text{V}$			-20	-90	mA
I_{CC}	Supply current	$V_{CC} = \text{MAX}$, All inputs grounded All outputs open	'55, '60			165	mA
			'56, '61			175	
			'80, '82			170	
			'81, '83			180	
			'75, '76			190	

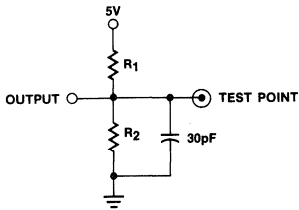
Switching Characteristics

Over operating conditions

DEVICE TYPE	$t_{AA}(ns)$ ADDRESS ACCESS TIME	$t_{EA}(ns)$ ENABLE ACCESS TIME	$t_{ER}(ns)$ ENABLE RECOVERY TIME	CONDITIONS (See standard test load)	
	MAX	MAX	MAX	$R_1 \Omega$	$R_2 \Omega$
6255-1, 6256-1	100	70	40	750	1500
5255-1, 5256-1	150	80	45		
6260-1, 6261-1	100	70	40		
5260-1, 5261-1	150	80	45		
6275-1, 6276-1	110	40	40	560	1100
5275-1, 5276-1	120	50	50		
6280-1, 6281-1	100	70	45		
5280-1, 5281-1	175	90	50		
6280-2, 6281-2	55	30	30		
5280-2, 5281-2	75	35	35		
6282-1, 6283-1	100	70	45		
5282-1, 5283-1	175	90	50		

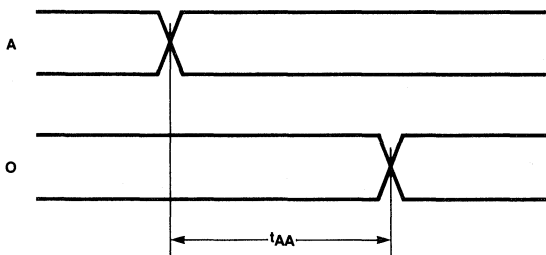
4

Standard Test Load

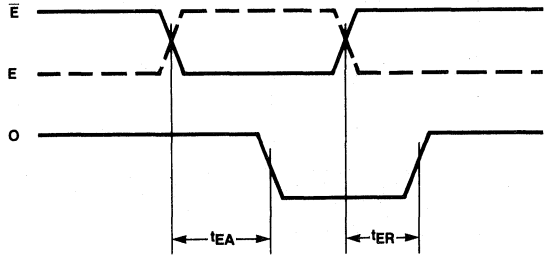


Input Pulse Amplitude 3.0V
 Input Rise and Fall Times 5ns from 1.0V to 2.0V
 Measurements Made at 1.5V

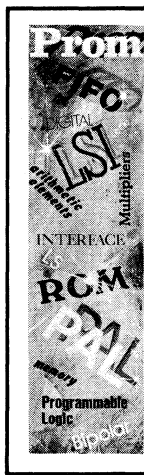
Definition of Waveforms



Address Access Time



Enable Access Time and Recovery Time



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High Speed Character Generators

Features/Benefits

- 100 ns max. access time
- Low power dissipation—500 mW
- Standard packaging—18 pin dip/24 pin dip
- Single 5 volt supply
- 64/128 characters in one package
- Open collector or three-state

Applications

- CRT displays
- Printing calculators
- LED arrays
- Typesetting

Description

The intended application for these devices is the generation of 64 or 128 ASCII alpha-numeric characters utilizing a read out system which generates the characters either horizontally or vertically, one word line at a time.

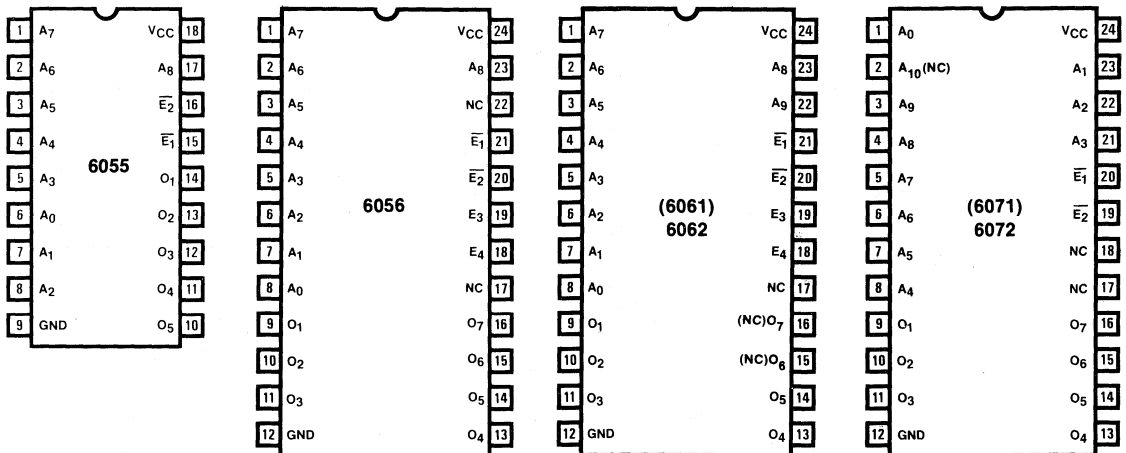
Character Generator Selection Guide

GENERIC PART NO.	CHARACTERS		MATRIX	SCAN	COMMERCIAL		MILITARY		PKG
	NO.	TYPE			OC	TS	OC	TS	
6055	64	ASCII	5 x 7	Row	6055	6155	5055	5155	J18
6056 †			5 x 7	Column	6056	6156	*	*	J24
6071			7 x 9	Row	6071	6171	*	*	J24
6061 †	128	ASCII	5 x 7	Row	6061	6161	*	*	J24
6062 †			5 x 7	Column	6062	6162	*	*	
6072			7 x 9	Row	6072	6172	*	*	
6290	128	Custom	7 x 9	Row	6290	6291	5290	5291	J24
6292			9 x 9	Row/Column	6292	6293	5292	5293	

* For military versions of these Character Generators contact the factory.

† "OR" enable = $\bar{E}1 \bar{E}2 + E3 E4$

Pin Configurations



High Speed Character Generators

Absolute Maximum Ratings

Supply Voltage, V_{CC}	7V
Input Voltage	7V
Off-state output voltage	5.5V
Storage temperature	-65° to +150°C

Operating Conditions

SYMBOL	PARAMETER	MILITARY			COMMERCIAL			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
T_A	Operating free-air temperature	-55		125	0		75	°C

Electrical Characteristics Over Operating Conditions

SYMBOL	PARAMETER	TEST CONDITIONS	MIN TYP MAX			UNIT	
			MIN	TYP	MAX		
V_{IL}	Low-level input voltage				0.8	V	
V_{IH}	High-level input voltage		2				
V_{IC}	Input clamp voltage	$V_{CC} = \text{MIN}$ $I_I = -18\text{mA}$			-1.5	V	
I_{IL}	Low-level input current	$V_{CC} = \text{MAX}$ $V_I = 0.45\text{V}$			-0.25	mA	
I_{IH}	High-level input current	$V_{CC} = \text{MAX}$ $V_I = 2.4\text{V}$			40	μA	
I_I	Maximum input current	$V_{CC} = \text{MAX}$ $V_I = 5.5\text{V}$			1	mA	
V_{OL}	Low-level output voltage	$V_{CC} = \text{MIN}$ $V_{IL} = 0.8\text{V}$ $V_{IH} = 2\text{V}$	MIL $I_{OL} = 8\text{mA}$	'55, '56, '61, '62	0.5	V	
			COM $I_{OL} = 10\text{mA}$				
			$I_{OL} = 6\text{mA}$	'71, '72			
V_{OH}	High-level output voltage	$V_{CC} = \text{MIN}$ $V_{IL} = 0.8\text{V}$ $V_{IH} = 2\text{V}$	MIL $I_{OH} = -1\text{mA}$	2.4		V	
			COM $I_{OH} = -2\text{mA}$				
I_{OZL}	Off-state output current	$V_{CC} = \text{MAX}$ $V_O = 0.5\text{V}$	'55, '56, '61, '62			μA	
			'71, '72				
I_{OZH}	Off-state output current	$V_{CC} = \text{MAX}$ $V_O = 2.4\text{V}$	'55, '56, '61, '62			μA	
			'71, '72				
I_{CEX}	Open collector output current	$V_{CC} = \text{MAX}$ $V_O = 2.4\text{V}$			100	μA	
I_{OS}	Output short-circuit current	$V_{CC} = 5\text{V}$ $V_O = 0\text{V}$			-20	-90	mA
I_{CC}	Supply current	$V_{CC} = \text{MAX}$ All inputs grounded All outputs open	Open collector		170	mA	
			Three state		180		

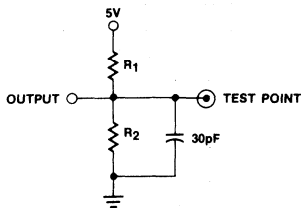
High Speed Character Generators

Switching Characteristics

Over Operating Conditions

DEVICE TYPE	tAA(ns) ADDRESS ACCESS TIME	tEA(ns) ENABLE ACCESS TIME	tER(ns) ENABLE RECOVERY TIME	CONDITIONS (See standard test load)	
	MAX	MAX	MAX	R1Ω	R2Ω
6X55, 6X56, 6X61, 6X62	100	70	45	560	1100
5055, 5155	175	90	50		
6X71, 6X72	125	75	40	750	1500

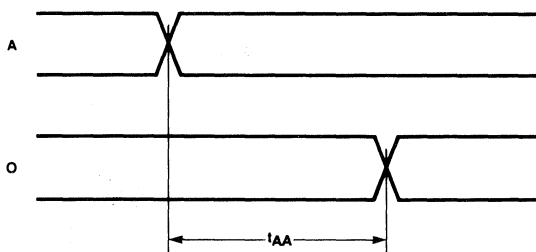
Standard Test Load



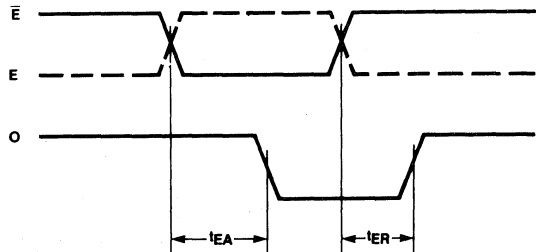
Input Pulse Amplitude 3.0V
 Input Rise and Fall Times 5ns from 1.0V to 2.0V
 Measurements Made at 1.5V

5

Definition of Waveforms



Address Access Time



Enable Access Time and Recovery Time

Character Generators

Tabulation by Octal Select-Code

64 ASCII Characters

Row Scan 6055, 6071

Column Scan 6056

	0	1	2	3	4	5	6	7
0	@	A	B	C	D	E	F	G
10	H	I	J	K	L	M	N	O
20	P	Q	R	S	T	U	V	W
30	X	Y	Z	[\]	↑	←
40		!	"	#	\$	%	&	'
50		()	*	+	,	-	.
60	0	1	2	3	4	5	6	7
70	8	9	:	;	<	=	>	?

Example:

The Character \$ is addressed by the octal code 44

128 ASCII Characters

Row Scan 6061, 6072

Column Scan 6062

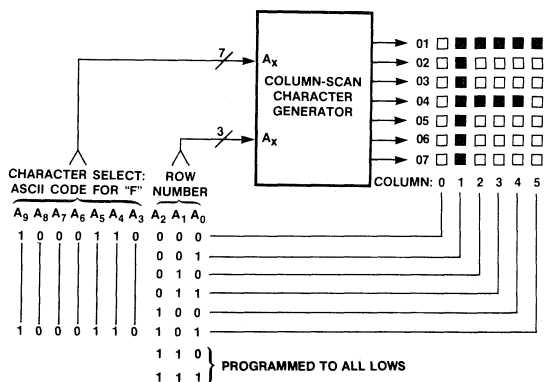
	0	1	2	3	4	5	6	7
0	△	△	△	△	△	△	△	△
10	△	△	△	△	△	△	△	△
20	△	△	△	△	△	△	△	△
30	△	△	△	△	△	△	△	△
40		!	"	#	\$	%	&	'
50		()	*	+	,	-	.
60	0	1	2	3	4	5	6	7
70	8	9	:	;	<	=	>	?
100	@	A	B	C	D	E	F	G
110	H	I	J	K	L	M	N	O
120	P	Q	R	S	T	U	V	W
130	X	Y	Z	[\]	↑	←
140	'	a	b	c	d	e	f	g
150	h	i	j	k	l	m	n	o
160	p	q	r	s	t	u	v	w
170	x	y	z	{		}	~	△

△ This ASCII code represents a control character.

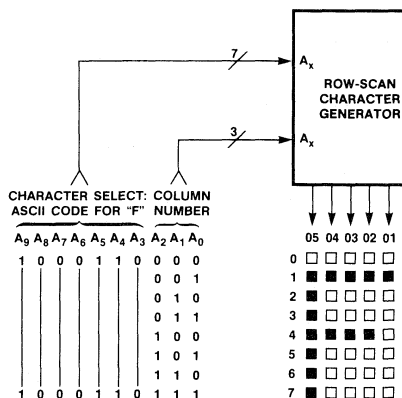
For the corresponding display character see the detailed data sheet.

Generation of the Letter "F"

Using Column Scan



Using Row Scan



5 x 7 Character Font 6061 6161

A "Filled In" Square Represents a Low Memory Output

ASCII INPUT ADDRESS	A ₅ A ₄ A ₃ 0 0 0	0 0 1	0 1 0	0 1 1	1 0 0	1 0 1	1 1 0	1 1 1	
A ₉ A ₈ A ₇ A ₆ 0 0 0 0	O ₅ O ₄ O ₃ O ₂ O ₁ 	O ₅ O ₄ O ₃ O ₂ O ₁ 	O ₅ O ₄ O ₃ O ₂ O ₁ 	O ₅ O ₄ O ₃ O ₂ O ₁ 	O ₅ O ₄ O ₃ O ₂ O ₁ 	O ₅ O ₄ O ₃ O ₂ O ₁ 	O ₅ O ₄ O ₃ O ₂ O ₁ 	O ₅ O ₄ O ₃ O ₂ O ₁ 	O ₅ O ₄ O ₃ O ₂ O ₁
	(NUL)*	(SOH)*		(ETX)*	(EOT)*	(ENQ)*	(ACK)*	(BEL)*	
0 0 0 1									
	(BS)*	(HT)*	(LF)*	(VT)*	(FF)*	(CR)*	(SO)*	(SI)*	
0 0 1 0									
	(DLE)*	(DC1)*	(DC2)*	(DC3)*	(DC4)*	(NAK)*	(SYN)*	(ETB)*	
0 0 1 1									
	(CAN)*	(EM)*	(SUB)*	(ESC)*	(FS)*	(GS)*	(RS)*	(US)*	
0 1 0 0									
0 1 0 1									
0 1 1 0									
0 1 1 1									

* The letters in parenthesis identify the control code corresponding to the appropriate pictorial representation. These representations were obtained from the USASI X 3.2 Code Practice Manual.

A "Filled In" Square Represents a Low Memory Output

ASCII INPUT ADDRESS	A ₆ A ₅ A ₄ 0 0 0	0 0 1	0 1 0	0 1 1	1 0 0	1 0 1	1 1 0	1 1 1
A ₁₀ A ₉ A ₈ A ₇ 0 0 0 0	07060504030201 [Grid with (NUL)*]	07060504030201 [Grid with (SOH)*]	07060504030201 [Grid with (ETX)*]	07060504030201 [Grid with (EOT)*]	07060504030201 [Grid with (ENQ)*]	07060504030201 [Grid with (ACK)*]	07060504030201 [Grid with (BEL)*]	
0 0 0 1	[Grid with (BS)*]	[Grid with (HT)*]	[Grid with (LF)*]	[Grid with (VT)*]	[Grid with (FF)*]	[Grid with (CR)*]	[Grid with (SO)*]	[Grid with (SI)*]
0 0 1 0	[Grid with (DLE)*]	[Grid with (DC1)*]	[Grid with (DC2)*]	[Grid with (DC3)*]	[Grid with (DC4)*]	[Grid with (NAK)*]	[Grid with (SYN)*]	[Grid with (ETB)*]
0 0 1 1	[Grid with (CAN)*]	[Grid with (EM)*]	[Grid with (SUB)*]	[Grid with (ESC)*]	[Grid with (FS)*]	[Grid with (GS)*]	[Grid with (SX)*]	[Grid with (US)*]
0 1 0 0	[Grid]	[Grid]	[Grid]	[Grid]	[Grid]	[Grid]	[Grid]	[Grid]
0 1 0 1	[Grid]	[Grid]	[Grid]	[Grid]	[Grid]	[Grid]	[Grid]	[Grid]
0 1 1 0	[Grid]	[Grid]	[Grid]	[Grid]	[Grid]	[Grid]	[Grid]	[Grid]
0 1 1 1	[Grid]	[Grid]	[Grid]	[Grid]	[Grid]	[Grid]	[Grid]	[Grid]

*The letters in parenthesis identify the control code corresponding to the appropriate pictorial representation. These representations were obtained from the USASI X 3.2 Code Practice Manual.

7 x 9 Character Font 6072 6172

A "Filled In" Square Represents a Low Memory Output

ASCII INPUT ADDRESS	A ₆ A ₅ A ₄ 0 0 0	0 0 1	0 1 0	0 1 1	1 0 0	1 0 1	1 1 0	1 1 1
A ₁₀ A ₉ A ₈ A ₇ 1 0 0 0	07060504030201	07060504030201	07060504030201	07060504030201	07060504030201	07060504030201	07060504030201	07060504030201
1 0 0 1								
1 0 1 0								
1 0 1 1								
1 1 0 0								
1 1 0 1								
1 1 1 0								
1 1 1 1								(DEL)*

High Speed Custom Character Generators

52/6290 52/6291 52/6292 52/6293

Features/Benefits

- Schottky—high speed 10MHz
- Specifically designed for custom 7 x 9 row scan and 9 x 9 font character generators
- Up to 128 characters in one package
- Low power dissipation—500mW
- Standard packaging—24 pin dip
- Single 5 volt supply
- 125 ns max. access time

Applications

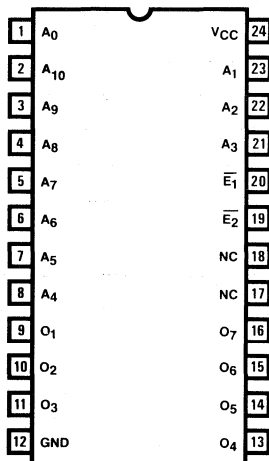
- A single package high speed bipolar replacement for slow multiple package MOS character generators
- CRT displays
- Printing calculators
- LED arrays
- Typesetting
- Navigation systems

Description

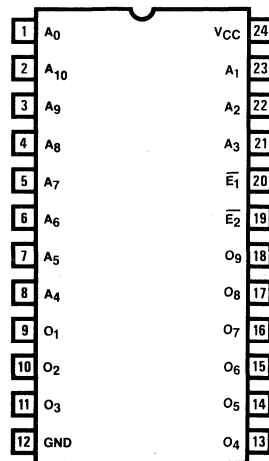
A 7 x 9 font row scan character has 7 outputs and 9 rows per character. The character is formed one row at a time. 9 words of a ROM with 7 outputs per word are required for each character. 128 characters required on 1152 x 7 ROM which is the size of the 5290/1, 6290/1. For custom column scan 7 x 9 characters consult the standard bipolar 7 x 9 character generator data sheet.

Pin Configuration

5290/1, 6290/1 (7 x 9 Row Scan)



5292/3, 6292/3 (9 x 9 Row or Column Scan)



Note 1): A₀, A₁, A₂, A₃ are used for the character scan.
2): Both enables must be low to advance the device.

A 9 x 9 font character has 9 outputs and 9 rows of columns per character depending upon whether we are forming a row or column scan. 9 words of a ROM with 9 outputs per row are required for each character. 128 characters require an 1152 x 9 ROM which is the 5292/3, 6292/3.

A₃, A₂, A₁, and A₀ pins are used to scan through the 9 ROM words per character. This is usually implemented by "short counting" a 4-bit binary counter so that it counts from 0000 to 1000 (9 counts) continuously (See applications section). A₄ thru A₁₀ are used to pick one of the 128 characters. A₄ is the least significant binary digit and A₁₀ is the most significant binary digit.

The enable E₁, and E₂ must both be low to activate the part. A disabled part (E₁ or E₂ high) has high memory outputs permitting wire ORing or blanking.

Unused scan locations generate low outputs.

Custom Font

It's easy to go from custom font to the punched card or tape format preferred by Monolithic Memories Inc. Several examples are shown. We have arbitrarily assumed that a character is formed by a series of low memory outputs in a background of high memory outputs. The assumption, of course can be reversed.

5

Absolute Maximum Ratings

Supply Voltage, V_{CC}	7V
Input Voltage	7V
Off-state output voltage	5.5V
Storage temperature	-65° to +150°C

Operating Conditions

SYMBOL	PARAMETER	MILITARY			COMMERCIAL			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
T_A	Operating free-air temperature	-55		125	0		75	°C

Electrical Characteristics Over Operating Conditions

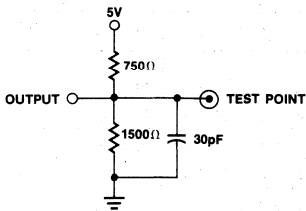
SYMBOL	PARAMETER	TEST CONDITIONS	MIN TYP MAX			UNIT	
			MIN	TYP	MAX		
V_{IL}	Low-level input voltage				0.8	V	
V_{IH}	High-level input voltage				2		
V_{IC}	Input clamp voltage	$V_{CC} = \text{MIN}$ $I_I = -18\text{mA}$			-1.5	V	
I_{IL}	Low-level input current	$V_{CC} = \text{MAX}$ $V_I = 0.45\text{V}$			-0.25	mA	
I_{IH}	High-level input current	$V_{CC} = \text{MAX}$ $V_I = 2.4\text{V}$			40	μA	
I_I	Maximum input current	$V_{CC} = \text{MAX}$ $V_I = 5.5\text{V}$			1	mA	
V_{OL}	Low-level output voltage	$V_{CC} = \text{MIN}$ $V_{IL} = 0.8\text{V}$ $V_{IH} = 2\text{V}$ $I_{OL} = 6\text{mA}$			0.5	V	
V_{OH}	High-level output voltage	$V_{CC} = \text{MIN}$ $V_{IL} = 0.8\text{V}$ $V_{IH} = 2\text{V}$ MIL $I_{OH} = -1\text{mA}$ COM $I_{OH} = -2\text{mA}$			2.4	V	
I_{OZL}	Off-state output current	$V_{CC} = \text{MAX}$ $V_O = 0.5\text{V}$			-100	μA	
I_{OZH}		$V_{CC} = \text{MAX}$ $V_O = 2.4\text{V}$			100	μA	
I_{CEX}	Open collector output current	$V_{CC} = \text{MAX}$ $V_O = 2.4\text{V}$			100	μA	
I_{OS}	Output short-circuit current	$V_{CC} = 5\text{V}$ $V_O = 0\text{V}$			-20	-90	mA
I_{CC}	Supply current	$V_{CC} = \text{MAX}$ All inputs grounded All outputs open	Open collector			170	mA
			Three state			180	

Switching Characteristics

Over Operating Conditions

DEVICE TYPE	tAA(ns) ADDRESS ACCESS TIME	tEA(ns) ENABLE ACCESS TIME	tER(ns) ENABLE RECOVERY TIME
	MAX	MAX	MAX
6290/1, 6292/3	125	75	40
5290/1, 5292/3	150	85	50

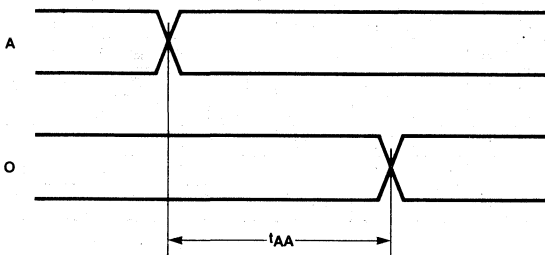
Standard Test Load



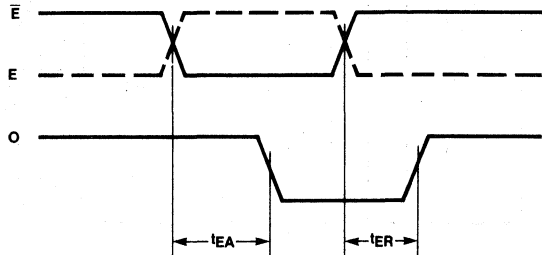
Input Pulse Amplitude 3.0V
 Input Rise and Fall Times 5ns from 1.0V to 2.0V
 Measurements Made at 1.5V

5

Definition of Waveforms



Address Access Time



Enable Access Time and Recovery Time

Custom Truth Table Coding—5290/1, 6290/1

7 x 9 ROW SCAN

The characters \$, &, *, are shown below along with the ROM coding. A "filled in" dot is arbitrarily coded with a low (L)

CHARACTER SELECT							ROM WORD (DECIMAL)	OUTPUTS							FONT											
A ₁₀	A ₉	A ₈	A ₇	A ₆	A ₅	A ₄		A ₃	A ₂	A ₁	A ₀	O ₇	O ₆	O ₅	O ₄	O ₃	O ₂	O ₁	F ₇	F ₆	F ₅	F ₄	F ₃	F ₂	F ₁	
L	L	L	L	L	L	L	CHARACTER #1	0	0	0	0	0	H	H	L	H	L	H	H	□	□	■	□	■	□	□
L	L	L	L	L	L	L		0	0	0	1	1	H	L	L	L	L	L	L	□	■	■	■	■	■	■
L	L	L	L	L	L	L		0	0	1	0	2	L	H	L	H	L	H	H	■	□	■	□	■	□	□
L	L	L	L	L	L	L		0	0	1	1	3	L	H	L	H	L	H	H	■	□	■	□	■	□	□
L	L	L	L	L	L	L		0	1	0	0	4	H	L	L	L	L	L	H	□	■	■	■	■	■	□
L	L	L	L	L	L	L		0	1	0	1	5	H	H	L	H	L	H	L	□	□	■	□	■	□	■
L	L	L	L	L	L	L		0	1	1	0	6	H	H	L	H	L	H	L	□	□	■	□	■	□	■
L	L	L	L	L	L	L		0	1	1	1	7	L	L	L	L	L	L	H	■	■	■	■	■	■	□
L	L	L	L	L	L	L	1	0	0	0	8	H	H	L	H	L	H	H	□	□	■	□	■	□	□	
L	L	L	L	L	L	H	CHARACTER #2	9	H	L	L	H	H	H	H	□	■	■	□	□	□	□				
L	L	L	L	L	L	H		10	L	H	H	L	H	H	H	■	□	□	■	□	□	□				
L	L	L	L	L	L	H		11	L	H	H	L	H	H	H	■	□	□	■	□	□	□				
L	L	L	L	L	L	H		12	H	L	L	H	H	H	H	□	■	■	□	□	□	□				
L	L	L	L	L	L	H		13	H	L	L	H	H	H	H	□	■	■	□	□	□	□				
L	L	L	L	L	L	H		14	L	H	H	L	H	L	H	■	□	□	■	□	■	□				
L	L	L	L	L	L	H		15	L	H	H	H	L	L	H	■	□	□	□	■	■	□				
L	L	L	L	L	L	H		16	L	H	H	H	H	L	H	■	□	□	□	□	■	□				
L	L	L	L	L	L	H	17	H	L	L	L	L	H	L	□	■	■	■	■	□	■					
H	H	H	H	H	H	H	CHARACTER #128	1143	H	H	H	L	H	H	H	□	□	□	■	□	□	□				
H	H	H	H	H	H	H		1144	L	H	H	L	H	H	L	■	□	□	■	□	□	■				
H	H	H	H	H	H	H		1145	H	L	H	L	H	L	H	□	■	□	■	□	■	□				
H	H	H	H	H	H	H		1146	H	H	L	L	L	H	H	□	□	■	■	■	□	□				
H	H	H	H	H	H	H		1147	H	H	H	L	H	H	H	□	□	□	■	□	□	□				
H	H	H	H	H	H	H		1148	H	H	L	L	L	H	H	□	□	■	■	■	□	□				
H	H	H	H	H	H	H		1149	H	L	H	L	H	L	H	□	■	□	■	□	■	□				
H	H	H	H	H	H	H		1150	L	H	H	L	H	H	L	■	□	□	■	□	□	■				
H	H	H	H	H	H	H		1151	H	H	H	L	H	H	H	□	□	□	■	□	□	□				

Use of Custom Truth Table Form—5290/1, 6290/1

Truth table forms are available from Monolithic Memories upon request. For customers desiring to make their own forms an example is shown below coded to the 7 x 9 Row Scan example:

WORD NUMBER	OUTPUTS							
	PIN 16 O ₇	15 O ₆	14 O ₅	13 O ₄	11 O ₃	10 O ₂	9 O ₁	
0	H	H	L	H	L	H	H	
1	H	L	L	L	L	L	L	
•	•	•	•	•	•	•	•	
•	•	•	•	•	•	•	•	
•	•	•	•	•	•	•	•	
1151	H	H	H	L	H	H	H	

NOTE:

A high voltage on the data out lines is signified by an "H". A low voltage on the data out lines is signified by an "L". The word number assumes positive logic on the address pin so for example word 511 = HHHHHHHH.

Custom Truth Table Coding—5292/3, 6292/3

9 x 9 COLUMN SCAN

The characters \$, &, *, can be seen in the font if this page is rotated 90° clockwise. A "filled in" dot is arbitrarily coded with a low (L).

9 x 9 ROW SCAN

The 9 x 9 row scan translation would be similar to the 7 x 9 row scan previously shown except that there would be a 9 x 9 font for each character and outputs 8 and 9 in the ROM would be used and coded.

CHARACTER SELECT								ROM WORD (DECIMAL)	OUTPUTS									FONT									
A ₁₀	A ₉	A ₈	A ₇	A ₆	A ₅	A ₄			O ₉	O ₈	O ₇	O ₆	O ₅	O ₄	O ₃	O ₂	O ₁	O ₉	O ₈	O ₇	O ₆	O ₅	O ₄	O ₃	O ₂	O ₁	
L	L	L	L	L	L	L	L	CHARACTER #1	8	H	L	H	H	H	L	L	H	H	□	■	□	□	□	■	■	□	□
L	L	L	L	L	L	L	L		7	H	L	H	H	L	H	H	L	H	□	■	□	□	■	□	□	■	□
L	L	L	L	L	L	L	L		6	H	L	H	H	L	H	H	L	H	□	■	□	□	■	□	□	■	□
L	L	L	L	L	L	L	L		5	L	L	L	L	L	L	L	L	L	■	■	■	■	■	■	■	■	■
L	L	L	L	L	L	L	L		4	H	L	H	H	L	H	H	L	H	□	■	□	□	■	□	□	■	□
L	L	L	L	L	L	L	L		3	L	L	L	L	L	L	L	L	L	□	□	□	□	□	□	□	□	□
L	L	L	L	L	L	L	L		2	H	L	H	H	L	H	H	L	H	□	■	□	□	■	□	□	■	□
L	L	L	L	L	L	L	L		1	H	L	H	H	L	H	H	L	H	□	■	□	□	■	□	□	■	□
L	L	L	L	L	L	L	L		0	H	H	L	L	H	H	H	L	H	□	□	■	■	□	□	□	■	□
L	L	L	L	L	L	L	H	CHARACTER #2	17	H	H	H	H	H	H	H	H	□	□	□	□	□	□	□	□	□	
L	L	L	L	L	L	L	H		16	H	H	H	H	H	L	H	L	□	□	□	□	□	□	■	□	■	
L	L	L	L	L	L	L	H		15	H	H	H	H	H	L	L	H	□	□	□	□	□	□	■	■	□	
L	L	L	L	L	L	L	H		14	H	H	H	H	H	L	H	L	□	□	□	□	□	□	■	□	■	
L	L	L	L	L	L	L	H		13	H	L	L	L	L	H	H	L	□	■	■	■	■	■	■	□	□	
L	L	L	L	L	L	L	H		12	L	H	H	L	L	H	H	L	■	□	□	■	■	□	□	□	■	
L	L	L	L	L	L	L	H		11	L	H	H	L	L	H	H	L	■	□	□	■	■	□	□	□	■	
L	L	L	L	L	L	L	H		10	L	H	H	L	L	H	H	L	H	■	□	□	■	■	□	□	□	■
L	L	L	L	L	L	L	H		9	H	L	L	H	H	L	L	H	H	□	■	■	□	□	■	■	□	□
H	H	H	H	H	H	H	H	CHARACTER #128	1151	H	H	H	H	H	H	H	H	□	□	□	□	□	□	□	□	□	
H	H	H	H	H	H	H	H		1150	H	L	H	H	H	H	L	H	□	■	□	□	□	□	□	■	□	
H	H	H	H	H	H	H	H		1149	H	H	L	H	H	L	H	H	□	□	■	□	□	□	■	□	□	
H	H	H	H	H	H	H	H		1148	H	H	H	L	H	L	H	H	H	□	□	□	■	□	■	□	□	□
H	H	H	H	H	H	H	H		1147	L	L	L	L	L	L	L	L	■	■	■	■	■	■	■	■	■	
H	H	H	H	H	H	H	H		1146	H	H	H	L	H	L	H	H	H	□	□	□	■	□	■	□	□	□
H	H	H	H	H	H	H	H		1145	H	H	L	H	H	L	H	H	□	□	■	□	□	□	■	□	□	
H	H	H	H	H	H	H	H		1144	H	L	H	H	H	H	L	H	□	■	□	□	□	□	□	□	■	
H	H	H	H	H	H	H	H		1143	H	H	H	H	H	H	H	H	□	□	□	□	□	□	□	□	□	

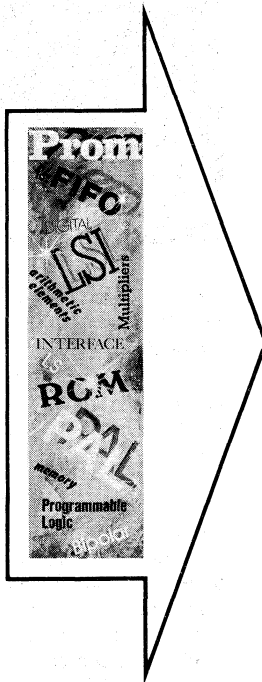
5

Use of Custom Truth Table Form—5292/3, 6292/3

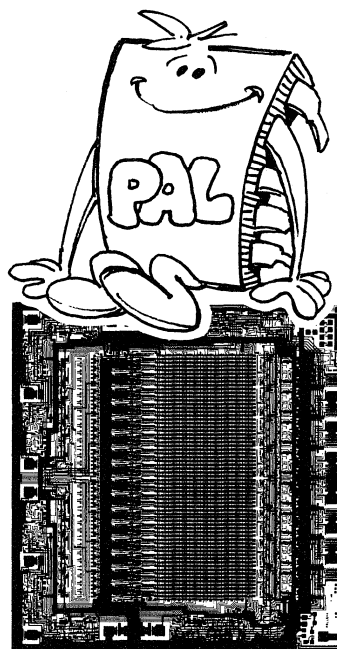
Truth table forms are available from Monolithic Memories upon request. For customers desiring to make their own forms an example is shown below coded to the 9 x 9 column scan example:

WORD NUMBER	PIN	OUTPUTS								
		18 O ₉	17 O ₈	16 O ₇	15 O ₆	14 O ₅	13 O ₄	11 O ₃	10 O ₂	9 O ₁
0	H	H	L	L	L	H	H	L	H	
1	H	L	H	H	L	H	H	L	H	
•	•	•	•	•	•	•	•	•	•	
•	•	•	•	•	•	•	•	•	•	
•	•	•	•	•	•	•	•	•	•	
1151	H	H	H	H	H	H	H	H	H	

NOTE:
A high voltage on the data out lines is signified by an "H". A low voltage on the data out lines is signified by an "L". The word number assumes positive logic on the address pin so for example word 511 = HHHHHHHH.



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The PAL™ Concept

Monolithic Memories' family of PAL devices gives designers a powerful tool with unique capabilities for use in new and existing logic designs. The PAL saves time and money by solving many of the system partitioning and interface problems brought about by increases in semiconductor device technology.

Rapid advances in large scale integration technology have led to larger and larger standard logic functions; single I.C.s now perform functions that formerly required complete circuit cards. While LSI offers many advantages, advances have been made at the expense of device flexibility. Most LSI devices still require large numbers of SSI/MSI devices for interfacing with user systems. Designers are still forced to turn to random logic for many applications.

The "complexity gap" between TTL and LSI devices has led to ineffective use of both. The TTL provides the speed and flexibility, but it is ineffective in terms of package count, power consumption, and P.C. board space. LSI offers high functional density and low power consumption, but it is slow and rigidly partitioned. Even the microprocessor, widely acclaimed for its flexibility, is slow and expensive when the costs of programming and support interfaces are considered.

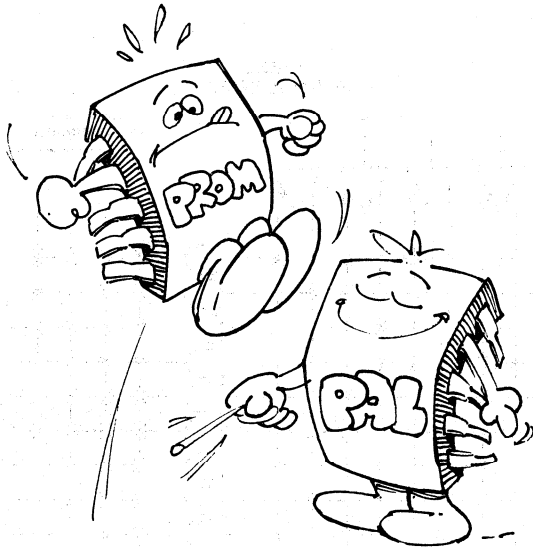
The designer is confronted with another problem when a low to medium complexity product is designed. Often the

function is well defined and could derive significant benefits from fabrication as an integrated circuit. However, the design cycle for a custom circuit is long and the costs can be very high. This makes the risk significant enough to deter most users. The technology to support maximum flexibility combined with fast turn around on custom logic has simply not been available.

Attempts to solve these problems have led to increasing interest in fuse programmable logic devices. These devices can all be user configured to provide custom functions. PROMs, FPLAs, FPGAs, and PMUXs have all been used in this way. These approaches have met with some success, but all are deficient in one or more areas. PROMs require careful design to avoid undesirable data transitions; FPLAs are expensive, difficult to program and complex to understand; FPGAs and PMUXs are not widely available and lack flexibility. All of these devices still require extensive interface logic for use in systems.

The PAL family offers a fresh approach to using fuse programmable logic. PALs are a conceptually unified group of devices which combine programmable flexibility with high speed and an extensive selection of interface options. PALs can lower inventory, cut design cycles and provide high complexity with maximum flexibility. These features, combined with lower package count and high reliability, truly make the PAL a circuit designer's best friend.

The PAL—Teaching Old PROMs New Tricks



MMI developed the modern PROM and introduced many of the architectures and techniques now regarded as industry standards. As the world's largest PROM manufacturer, MMI has the proven technology and high volume production capability required to manufacture and support the PAL.

The PAL is an extension of the fusible link technology pioneered by Monolithic Memories for use in bi-polar PROMs. The fusible link PROM first gave the digital systems designer the power to "write on silicon." In a few seconds he was able to transform a blank PROM from a general purpose device into one containing a custom algorithm, microprogram, or Boolean transfer function. This opened up new horizons for the use of PROMs in computer control stores, character generators, data storage tables and many other applications. The wide acceptance of this technology is clearly demonstrated by today's multi-million dollar PROM market.

The key to the PROM's success is that it allows the designer to quickly and easily customize the chip to fit his unique requirements. The PAL extends this programmable flexibility by utilizing proven fusible link technology to implement logic functions. Using PALs the designer can quickly and effectively implement custom logic varying in complexity from random gates to complex arithmetic functions.

ANDs and ORs

The PAL implements the familiar sum of products logic by using a programmable AND array whose output terms feed a fixed OR

array. Since the sum of products form can express any Boolean transfer function, the PAL's uses are only limited by the number of terms available in the AND - OR arrays. PAL's come in different sizes to allow for effective logic optimization.

Figure 1 shows the basic PAL structure for a two input, one output logic segment. The general logic equation for this segment is

$$\text{Output} = (I_1 + \bar{f}_1)(\bar{I}_1 + \bar{f}_2)(I_2 + \bar{f}_3)(\bar{I}_2 + \bar{f}_4) + (I_1 + \bar{f}_5)(\bar{I}_1 + \bar{f}_6)(I_2 + \bar{f}_7)(\bar{I}_2 + \bar{f}_8)$$

where the "f" terms represent the state of the fusible links in the PAL's AND array. An unblown link represents a logic 1. Thus,

fuse blown, $f = 0$

fuse intact, $f = 1$

An unprogrammed PAL has all fuses intact.

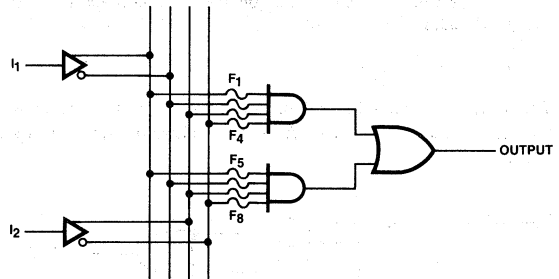


Figure 1

New Device, New Notation

Logic equations, while convenient for small functions, rapidly become cumbersome in large systems. To reduce possible confusion, complex logic networks are generally defined by logic diagrams and truth tables. Figure 2 shows the logic convention adopted to keep PAL logic easy to understand and use. In the figure, an "x" represents an intact fuse used to perform the logic AND function. (Note: the input terms on the common line with the x's are not connected together.) The logic symbology shown in Figure 2 has been informally adopted by integrated circuit manufacturers because it clearly establishes a one-to-one correspondence between the chip layout and the logic diagram. It also allows the logic diagram and truth table to be combined into a compact and easy to read form, thereby serving as a convenient shorthand for PALs. The two input - one output example from Figure 1 redrawn using the new logic convention is shown in Figure 3.

PAL Introduction

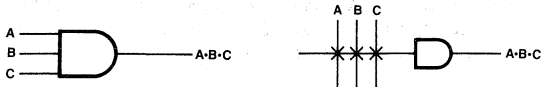


Figure 2

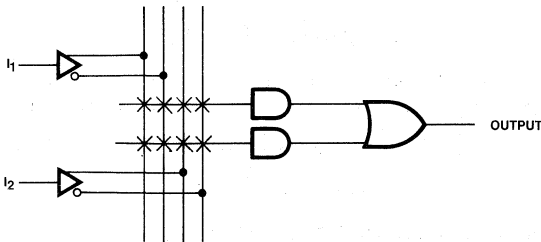


Figure 3

As a simple PAL example, consider the implementation of the transfer function:

$$\text{Output} = I_1\bar{I}_2 + \bar{I}_1I_2$$

The normal combinatorial logic diagram for this function is shown in figure 4, with the PAL logic equivalent shown in figure 5.

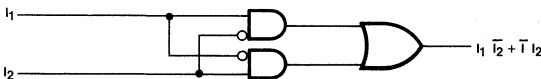


Figure 4

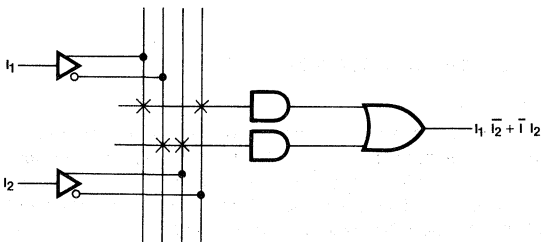


Figure 5

Using this logic convention it is now possible to compare the PAL structure to the structure of the more familiar PROM and PLA. The basic logic structure of a PROM consists of a fixed AND array whose outputs feed a programmable OR array (figure 6). PROMs are low-cost, easy to program, and available in a variety of sizes and organizations. They are most commonly

used to store computer programs and data. In these applications the fixed input is a computer memory address; the output is the contents of that memory location.

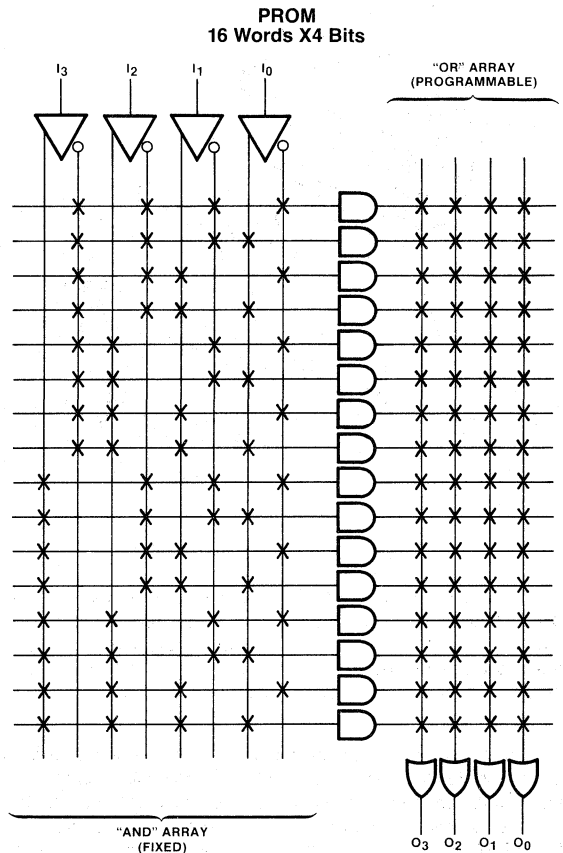


Figure 6

The basic logic structure of the PLA consists of a programmable AND array whose outputs feed a programmable OR array (Figure 7). Since the designer has complete control over all inputs and outputs, the PLA provides the ultimate flexibility for implementing logic functions. They are used in a wide variety of applications. However, this generality makes PLA's expensive, quite formidable to understand, and are costly to program (they require special programmers).

The basic logic structure of the PAL, as mentioned earlier, consists of a programmable AND array whose outputs feed a fixed OR array (Figure 8). The PAL combines much of the flexibility of the PLA with the low cost and easy programmability of the PROM. Table 1 summarizes the characteristics of the PROM, PLA, and PAL logic families.

PAL Introduction

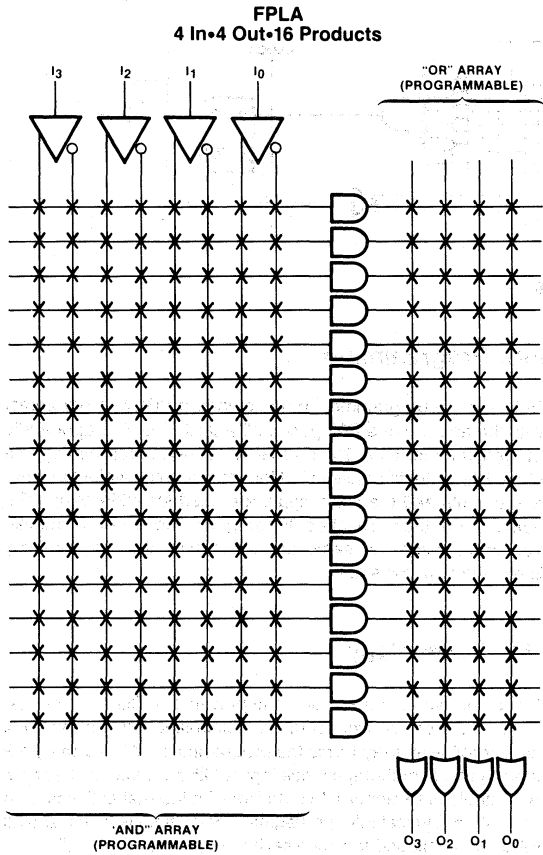


Figure 7

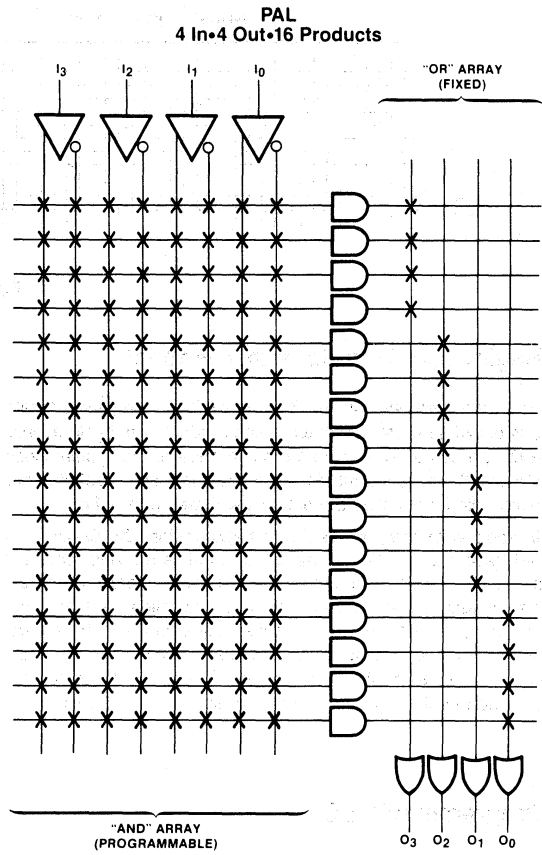


Figure 8

6

	AND	OR	OUTPUT OPTIONS
PROM	Fixed	Prog	TS, OC
FPLA	Prog	Prog	TS, OC, Fusible Polarity
FPGA	Prog	None	TS, OC, Fusible Polarity
PMUX	Fix/Prog	Fixed	TS
PAL	Prog	Fixed	TS, Registered, Feedback, I/O

Table 1

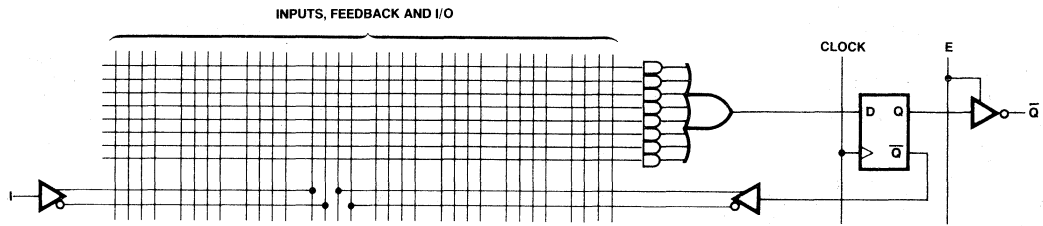


Figure 9

Registered Outputs with Feedback

High end members of the PAL family feature registered data outputs with register feedback. Each product term is stored into a D-type output flip-flop on the rising edge of the system clock (Figure 9). The Q output of the flip-flop can then be gated to the output pin by enabling the active low three-state buffer.

In addition to being available for transmission, the Q output is fed back into the PAL array as an input term. This feedback allows the PAL to "remember" the previous state, and it can alter its function based upon that state. This allows the designer to configure the PAL as a state sequencer which can be programmed to execute such elementary functions as count up, count down, skip, shift, and branch. These functions can be executed by the registered PAL at rates of up to 20 MHz.

Programmable I/O

Another feature of the high-end members of the PAL family is programmable input/output. This allows the product terms to directly control the outputs of the PAL (Figure 10). One product term is used to enable the three-state buffer, which in turn gates the summation term to the output pin. The output is also fed back into the PAL array as an input. Thus the PAL drives the I/O pin when the three-state gate is enabled; the I/O pin is an input to the PAL array when the three-state gate is disabled. This feature can be used to allocate available pins for I/O functions or to provide bi-directional output pins for operations such as shifting and rotating serial data.

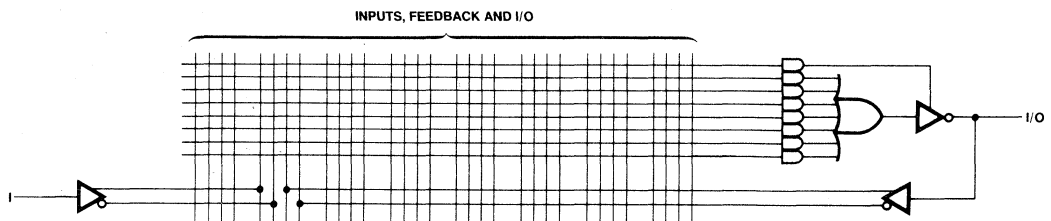


Figure 10

PAL Programming

PALs can be programmed in any standard PROM programmer with the addition of a PAL personality card. The PAL appears to the programmer as a 512 x 4 PROM. During programming four of the PAL outputs are selected for programming while the other four outputs and the eight inputs are used for addressing. The outputs are then switched to program the other locations. Verification uses the same procedure with the programming lines held in a low state.

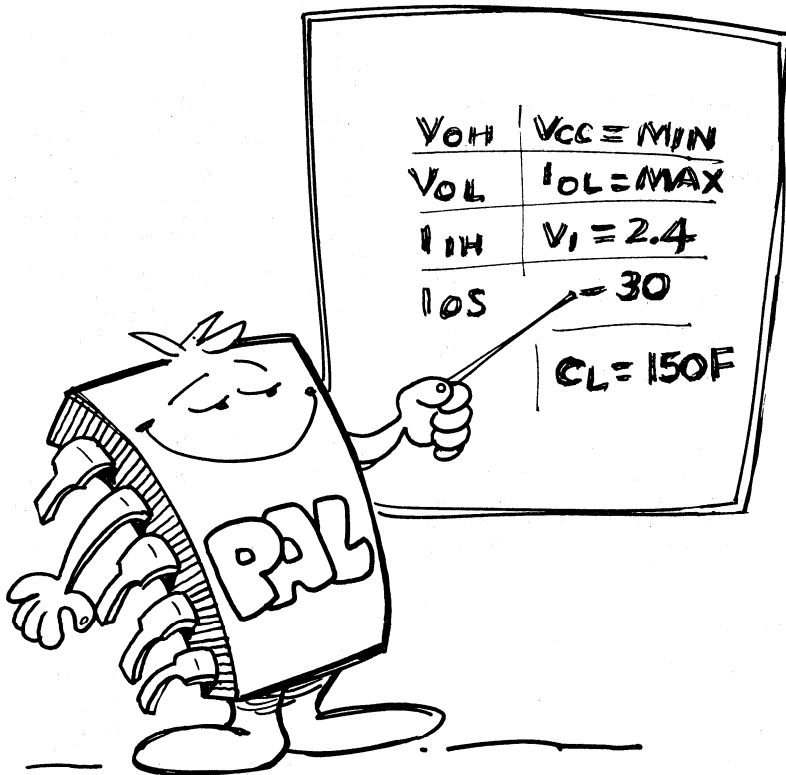
PAL Technology

PALs are manufactured using the proven TTL Schottky bipolar Ti-W fuse process used to make fusible-link PROMs. An NPN emitter follower array forms the programmable AND array. PNP inputs provide high-impedance inputs (.25 mA max.) to the array. All outputs are standard TTL drivers with internal active pull-up transistors. Typical PAL propagation delay time is 25 ns, and all PALs are packaged in space saving 20-pin "skinny-dips".

PAL Data Security

The circuitry used for programming and logic verification can be used at any time to determine the logic pattern stored in the PAL array. For security, the PAL has a "last fuse" which can be blown to disable the verification logic. This provides a significant deterrent to potential copiers, and it can be used to effectively protect proprietary designs.

PAL Series 20 Data Sheet



6

Programmable Array Logic Family

PAL™ Series 20 Data Sheet

U.S. Patent 4124899

Features/Benefits

- Programmable replacement for conventional TTL logic.
- Reduces IC inventories substantially and simplifies their control.
- Reduces chip count by 4 to 1.
- Expedites and simplifies prototyping and board layout.
- Saves space with 20-pin Skinny DIP packages.
- High speed: 25ns typical propagation delay.
- Programmed on standard PROM programmers.
- Programmable three-state outputs.
- Special feature reduces possibility of copying by competitors.

Description

The PAL family utilizes an advanced Schottky TTL process and the Bipolar PROM fusible link technology to provide user programmable logic for replacing conventional SSI/MSI gates and flip-flops at reduced chip count.

The family lets the systems engineer "design his own chip" by blowing fusible links to configure AND and OR gates to perform his desired logic function. Complex interconnections which previously required time-consuming layout are thus "lifted" from PC board etch and placed on silicon where they can be easily modified during prototype check-out or production.

The PAL transfer function is the familiar sum of products. Like the PROM, the PAL has a single array of fusible links. Unlike the PROM, the PAL is a programmable AND array driving a fixed OR array (the PROM is a fixed AND array driving a programmable OR array). In addition the PAL provides these options:

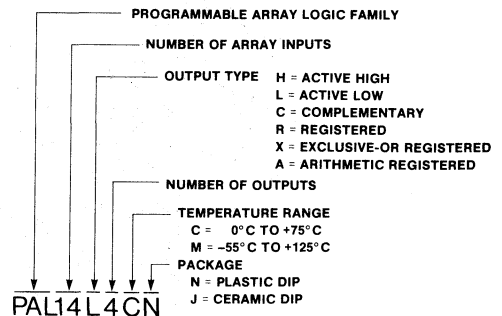
- Variable input/output pin ratio
- Programmable three-state outputs
- Registers with feedback
- Arithmetic capability

Unused inputs are tied directly to V_{CC} or GND. Product terms with all fuses blown assume the logical high state, and product terms connected to both true and complement of any single input assume the logical low state. Registers consist of D type flip-flops which are loaded on the low to high transition of the clock. PAL Logic Diagrams are shown with all fuses blown, enabling the designer use of the diagrams as coding sheets.

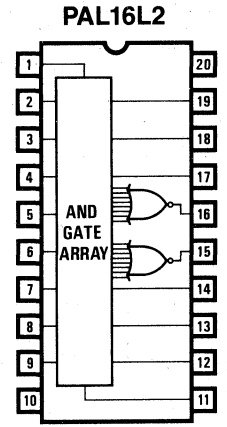
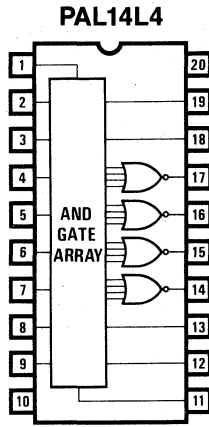
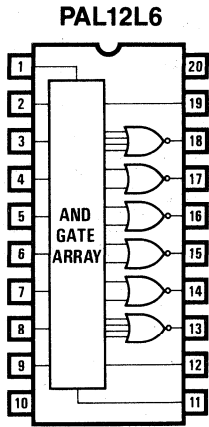
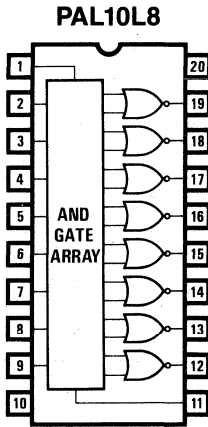
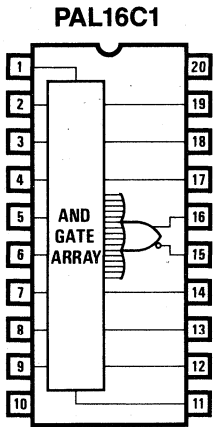
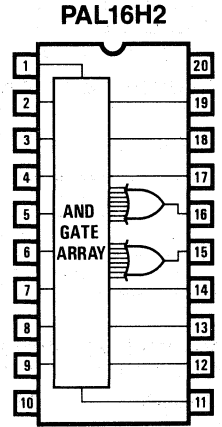
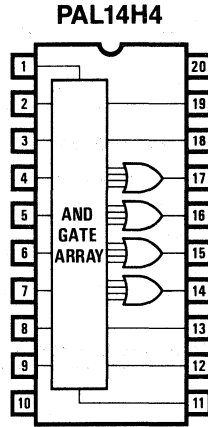
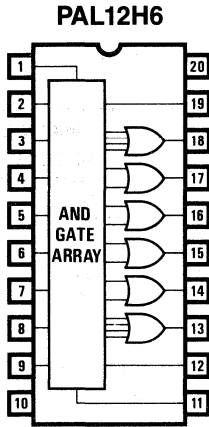
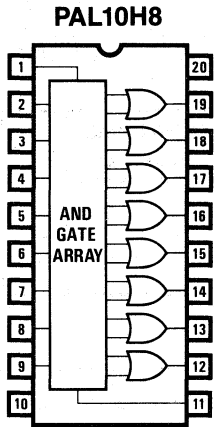
The entire PAL family is programmed on inexpensive conventional PROM programmers with appropriate personality and socket adapter cards. Once the PAL is programmed and verified, two additional fuses may be blown to defeat verification. This feature gives the user a proprietary circuit which is very difficult to copy.

PART NUMBER	DESCRIPTION
PAL10H8	OCTAL 10 INPUT AND-OR GATE ARRAY
PAL12H6	HEX 12 INPUT AND-OR GATE ARRAY
PAL14H4	QUAD 14 INPUT AND-OR GATE ARRAY
PAL16H2	DUAL 16 INPUT AND-OR GATE ARRAY
PAL16C1	16 INPUT AND-OR/AND-OR-INVERT GATE ARRAY
PAL10L8	OCTAL 10 INPUT AND-OR-INVERT GATE ARRAY
PAL12L6	HEX 12 INPUT AND-OR-INVERT GATE ARRAY
PAL14L4	QUAD 14 INPUT AND-OR-INVERT GATE ARRAY
PAL16L2	DUAL 16 INPUT AND-OR-INVERT GATE ARRAY
PAL16L8	OCTAL 16 INPUT AND-OR-INVERT GATE ARRAY
PAL16R8	OCTAL 16 INPUT REGISTERED AND-OR GATE ARRAY
PAL16R6	HEX 16 INPUT REGISTERED AND-OR GATE ARRAY
PAL16R4	QUAD 16 INPUT REGISTERED AND-OR GATE ARRAY

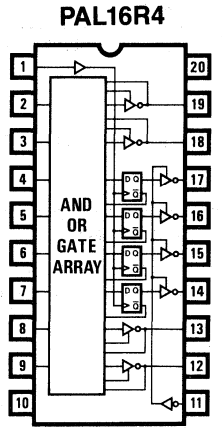
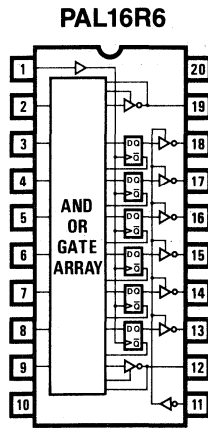
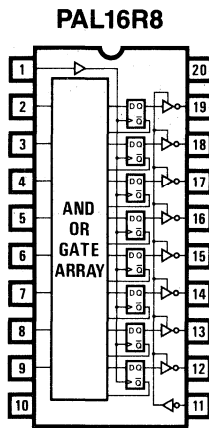
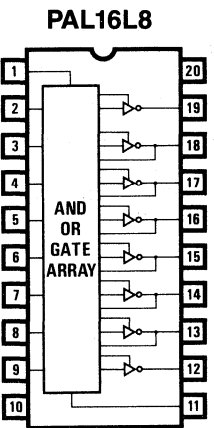
Ordering Information



PAL Logic Symbols



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PAL Series 20

Absolute Maximum Ratings

	Operating	Programming
Supply Voltage, VCC	7	12V
Input Voltage	5.5V	12V*
Off-state output Voltage	5.5V	12V
Storage temperature	-65° to +150°C	

Operating Conditions

SYMBOL	PARAMETER	MILITARY			COMMERCIAL			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
T _A	Operating free-air temperature				0		75	°C
T _C	Operating case temperature	-55		125				°C

Electrical Characteristics Over Operating Conditions

SYMBOL	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
V _{IL}	Low-level input voltage				0.8	V	
V _{IH}	High-level input voltage		2			V	
V _{IC}	Input clamp voltage	V _{CC} = MIN I _I = -18mA			-1.5	V	
I _{IL}	Low-level input current †	V _{CC} = MAX V _I = 0.4V			-0.25	mA	
I _{IH}	High-level input current †	V _{CC} = MAX V _I = 2.4V			25	μA	
I _I	Maximum input current	V _{CC} = MAX V _I = 5.5V			1	mA	
V _{OL}	Low-level output voltage	V _{CC} = MIN V _{IL} = 0.8V V _{IH} = 2V	10H8, 12H6, 14H4	MIL	I _{OL} = 8mA	0.5	V
			16H2, 16C1, 10L8 12L6, 14L4, 16L2				
			16L8 16R4	MIL	I _{OL} = 12mA		
			16R6 16R8	COM	I _{OL} = 24mA		
V _{OH}	High-level output voltage	V _{CC} = MIN V _{IL} = 0.8V V _{IH} = 2V	MIL		I _{OH} = -2mA	2.4	V
			COM		I _{OH} = -3.2mA		
I _{OZL}	Off-state output current †	V _{CC} = MAX V _{IL} = 0.8V V _{IH} = 2V	Three-state only	V _O = 0.4V		-100	μA
I _{OZH}				V _O = 2.4V		100	μA
I _{OS}	Output short-circuit current **	V _{CC} = 5V	V _O = 0V		-30	-130	mA
I _{CC}	Supply current	V _{CC} = MAX	10H8, 12H6, 14H4, 16H2, 16C1 10L8, 12L6, 14L4, 16L2		55	90	mA
			16L8		140	210	
			16R4, 16R6, 16R8		150	225	

† I/O pin leakage is the worst case of I_{OZX} or I_{Ix} e.g., I_{IL} and I_{OZH}

* Pins 1 and 11 may be raised to 22V max.

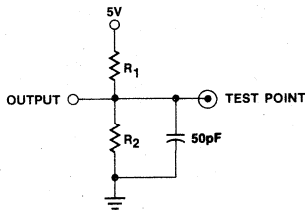
** Only one output shorted at a time.

Switching Characteristics

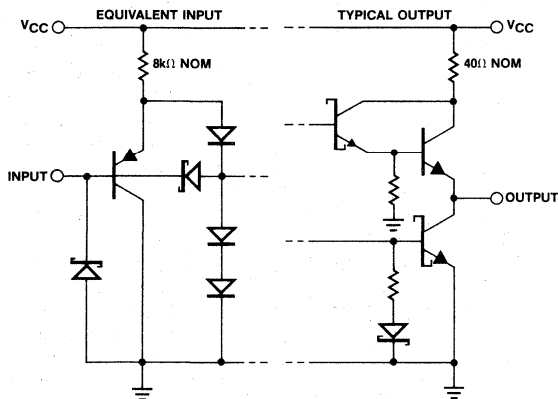
Over Operating Conditions

SYMBOL	PARAMETER	TEST CONDITIONS	MILITARY			COMMERCIAL			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
t _{PD}	Input to output	10H8 12H6 14H4 16H2 16C1 10L8 12L6 14L4 16L2 R ₁ = 560Ω R ₂ = 1.1kΩ	25	45		25	40	ns	
		16R8 16R6 16R4 16L8 R ₁ = 200Ω R ₂ = 390Ω	25	45		25	40	ns	
t _{PD}	Input or feedback to output		15	25		15	25	ns	
t _{CLK}	Clock to output or feedback		15	25		15	25	ns	
t _{PZX}	Pin 11 to output enable		15	25		15	25	ns	
t _{PXZ}	Pin 11 to output disable		15	25		15	25	ns	
t _{PZX}	Input to output enable		25	45		25	40	ns	
t _{PXZ}	Input to output disable		25	45		25	40	ns	
t _W	Width of clock	Low	25			25		ns	
		High	25			25			
t _{SU}	Setup time from input or feedback	16R8 16R6 16R4	45			40		ns	
t _H	Hold time		0	-15		0	-15	ns	
f _{MAX}	Maximum frequency	16R8 16R6 16R4	14			16		MHz	

Test Load



Schematic of Inputs and Outputs



Approved Programmers

MANUFACTURER	PERSONALITY CARD SET	SOCKET ADAPTER CONFIGURATION
Cybernetic Programming Systems, Inc.	CYMPC-1	
Data I/O Corporation	909-1427	715 1428-1 715 1428-2 715 1428-3
Pro-Log Corporation	PM9068	
Stag Systems	PM202	AM10H8 AM10L8 AM12H6 AM12L6 AM14H4 AM14L4 AM16H2 AM16L2 AM16C1
Structured Design	SD-20	

Programming

PAL fuses are programmed using a low-voltage linear-select procedure which is common to all 15 PAL types. The array is divided into two groups, products 0 thru 31 and products 32 thru 63, for which pin identifications are shown in Pin Configurations below. To program a particular fuse, both an input line and a product line are selected according to the following procedure:

- Step 1 Raise Output Disable, OD, to V_{IH}
- Step 2 Select an input line by specifying $I_0, I_1, I_2, I_3, I_4, I_5, I_6, I_7$ and L/R as shown in Table 1.
- Step 3 Select a product line by specifying A_0, A_1 and A_2 one-of-eight select as shown in Table 2.
- Step 4 Raise V_{CC} (pin 20) to V_{IH}

Step 5 Program the fuse by pulsing the output pins, O, of the selected product group to V_{IH} as shown in Programming Waveform.

- Step 6 Lower V_{CC} (pin 20) to 6.0 V
- Step 7 Pulse the CLOCK pin and verify the output pin, O, to be Low for active Low PAL types or High for active High PAL types.
- Step 8 Lower V_{CC} (pin 20) to 4.5 V and repeat step 7.
- Step 9 Should the output not verify, repeat steps 1 thru 8 up to five (5) times.

This procedure is repeated for all fuses to be blown (see Programming Waveforms).

To prevent further verification, two last fuses may be blown by raising pin 1 and pin 11 to V_P . V_{CC} is not required during this operation.

Voltage Legend

L = Low-level input voltage, V_{IL} HH = High-level program voltage, V_{IH}
 H = High-level input voltage, V_{IH} Z = High impedance (e.g., 10k Ω to 5.0V)

INPUT LINE NUMBER	PIN IDENTIFICATION								L/R
	I7	I6	I5	I4	I3	I2	I1	I0	
0	HH	HH	HH	HH	HH	HH	HH	L	Z
1	HH	HH	HH	HH	HH	HH	HH	H	Z
2	HH	HH	HH	HH	HH	HH	HH	L	HH
3	HH	HH	HH	HH	HH	HH	HH	H	HH
4	HH	HH	HH	HH	HH	HH	L	HH	Z
5	HH	HH	HH	HH	HH	HH	H	HH	Z
6	HH	HH	HH	HH	HH	HH	L	HH	HH
7	HH	HH	HH	HH	HH	HH	H	HH	HH
8	HH	HH	HH	HH	HH	L	HH	HH	Z
9	HH	HH	HH	HH	HH	H	HH	HH	Z
10	HH	HH	HH	HH	HH	L	HH	HH	HH
11	HH	HH	HH	HH	HH	H	HH	HH	HH
12	HH	HH	HH	HH	L	HH	HH	HH	Z
13	HH	HH	HH	HH	H	HH	HH	HH	Z
14	HH	HH	HH	HH	L	HH	HH	HH	HH
15	HH	HH	HH	HH	H	HH	HH	HH	HH
16	HH	HH	HH	L	HH	HH	HH	HH	Z
17	HH	HH	HH	H	HH	HH	HH	HH	Z
18	HH	HH	HH	L	HH	HH	HH	HH	HH
19	HH	HH	HH	H	HH	HH	HH	HH	HH
20	HH	HH	L	HH	HH	HH	HH	HH	Z
21	HH	HH	H	HH	HH	HH	HH	HH	Z
22	HH	HH	L	HH	HH	HH	HH	HH	HH
23	HH	HH	H	HH	HH	HH	HH	HH	HH
24	HH	L	HH	HH	HH	HH	HH	HH	Z
25	HH	H	HH	HH	HH	HH	HH	HH	Z
26	HH	L	HH	HH	HH	HH	HH	HH	HH
27	HH	H	HH	HH	HH	HH	HH	HH	HH
28	L	HH	HH	HH	HH	HH	HH	HH	Z
29	H	HH	HH	HH	HH	HH	HH	HH	Z
30	L	HH	HH	HH	HH	HH	HH	HH	HH
31	H	HH	HH	HH	HH	HH	HH	HH	HH

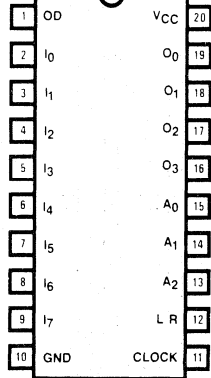
Table 1 Input Line Select

PRODUCT LINE NUMBER	PIN IDENTIFICATION						
	O3	O2	O1	O0	A2	A1	A0
0, 32	Z	Z	Z	HH	Z	Z	Z
1, 33	Z	Z	Z	HH	Z	Z	HH
2, 34	Z	Z	Z	HH	Z	HH	Z
3, 35	Z	Z	Z	HH	Z	HH	HH
4, 36	Z	Z	Z	HH	HH	Z	Z
5, 37	Z	Z	Z	HH	HH	Z	HH
6, 38	Z	Z	Z	HH	HH	HH	Z
7, 39	Z	Z	Z	HH	HH	HH	HH
8, 40	Z	Z	HH	Z	Z	Z	Z
9, 41	Z	Z	HH	Z	Z	Z	HH
10, 42	Z	Z	HH	Z	Z	HH	Z
11, 43	Z	Z	HH	Z	Z	HH	HH
12, 44	Z	Z	HH	Z	HH	Z	Z
13, 45	Z	Z	HH	Z	HH	Z	HH
14, 46	Z	Z	HH	Z	HH	HH	Z
15, 47	Z	Z	HH	Z	HH	HH	HH
16, 48	Z	HH	Z	Z	Z	Z	Z
17, 49	Z	HH	Z	Z	Z	Z	HH
18, 50	Z	HH	Z	Z	Z	HH	Z
19, 51	Z	HH	Z	Z	Z	HH	HH
20, 52	Z	HH	Z	Z	HH	Z	Z
21, 53	Z	HH	Z	Z	HH	Z	HH
22, 54	Z	HH	Z	Z	HH	HH	Z
23, 55	Z	HH	Z	Z	HH	HH	HH
24, 56	HH	Z	Z	Z	Z	Z	Z
25, 57	HH	Z	Z	Z	Z	Z	HH
26, 58	HH	Z	Z	Z	Z	HH	Z
27, 59	HH	Z	Z	Z	Z	HH	HH
28, 60	HH	Z	Z	Z	HH	Z	Z
29, 61	HH	Z	Z	Z	HH	Z	HH
30, 62	HH	Z	Z	Z	HH	HH	Z
31, 63	HH	Z	Z	Z	HH	HH	HH

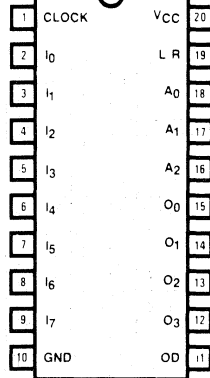
Table 2 Product Line Select

Pin Configurations

PRODUCTS 0 THRU 31



PRODUCTS 32 THRU 63

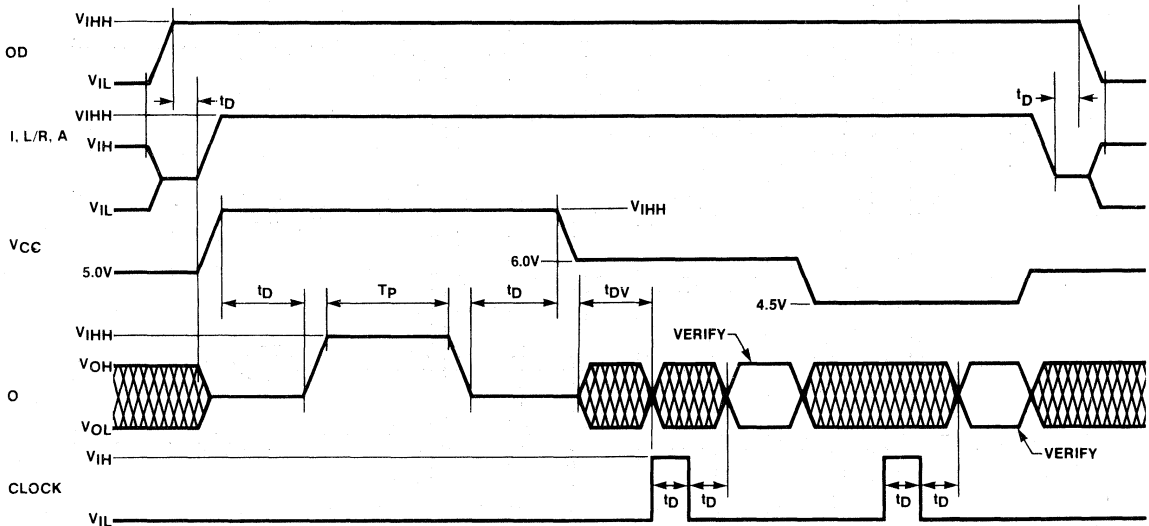


Programming Parameters $T_A = 25^\circ C$

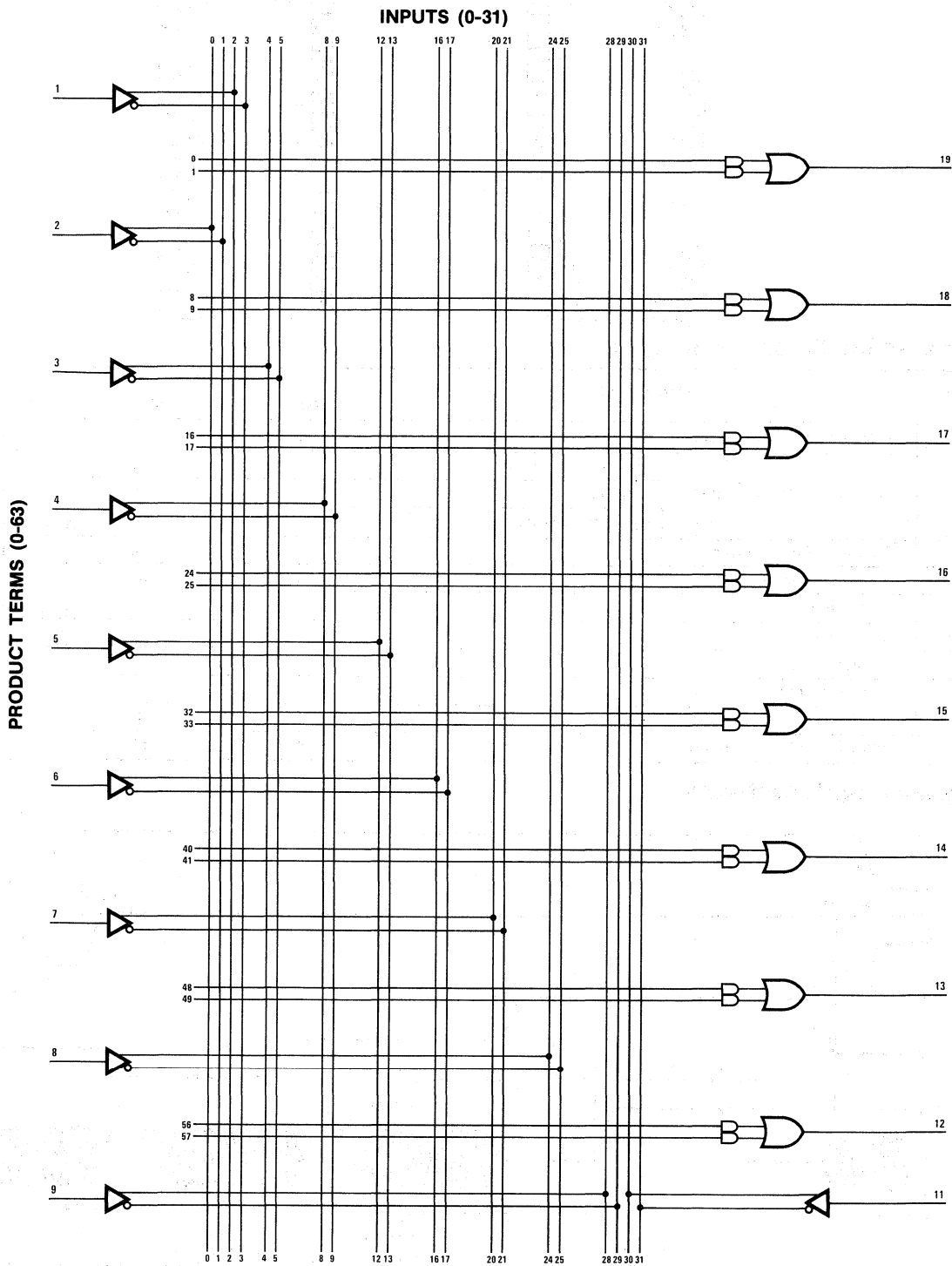
SYMBOL	PARAMETER	LIMITS			UNIT
		MIN	TYP	MAX	
V_{IH}	Program-level input voltage	11	11.5	12	V
I_{IH}	Program-level input current	Output Program Pulse			mA
		OD, L/R			
		All Other Inputs			
I_{CCH}	Program Supply Current			400	mA
T_P	Program Pulse Width	10		50	μs
t_D	Delay time	100			ns
t_{DV}	Delay Time to Verify	100			μs
	Program Pulse duty cycle			25	%
V_P	Verify-Protect-input voltage	20	21	22	V
I_P	Verify-Protect-input current			400	mA
T_{PP}	Verify-Protect Pulse Width	20		50	msec

6

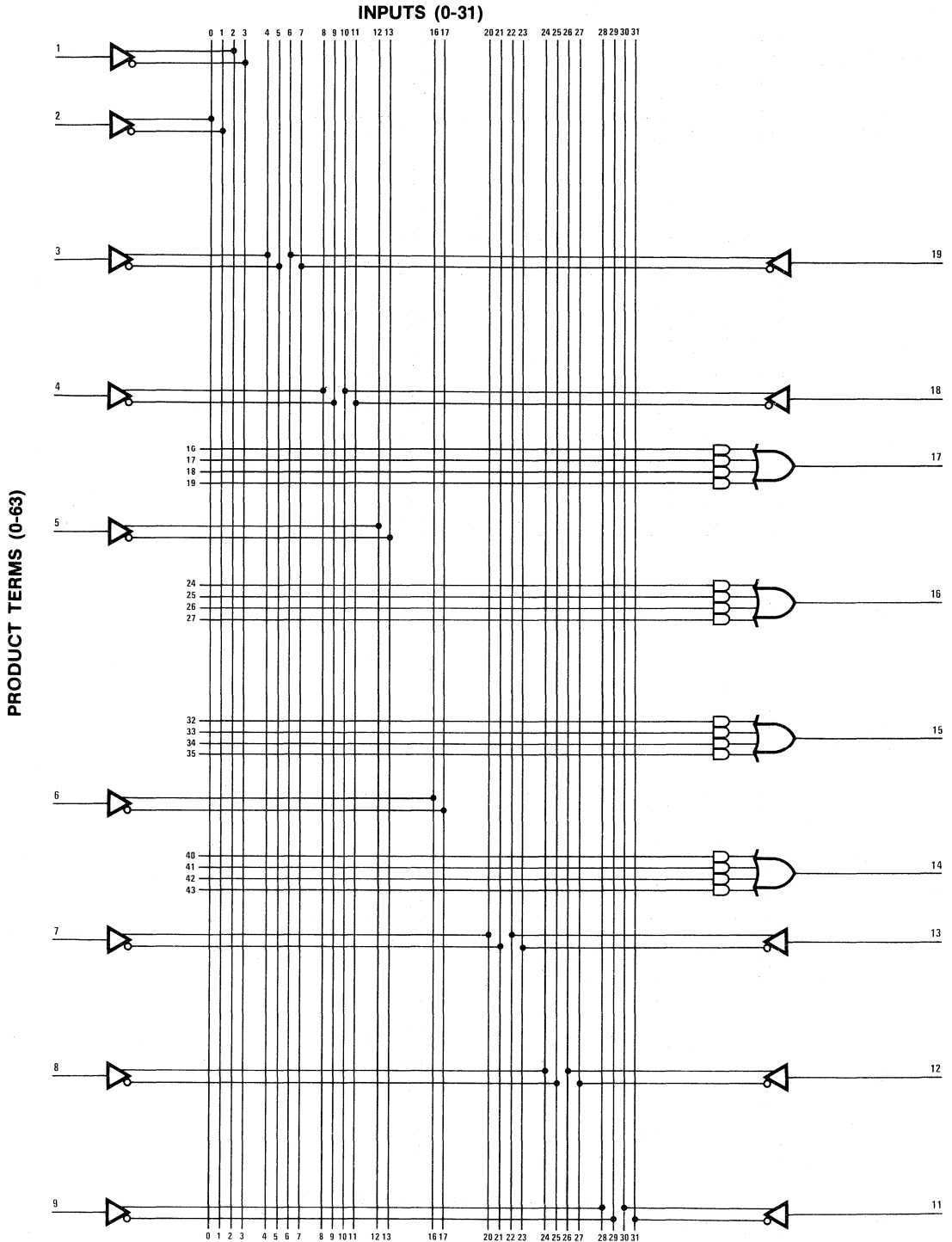
Programming Waveforms

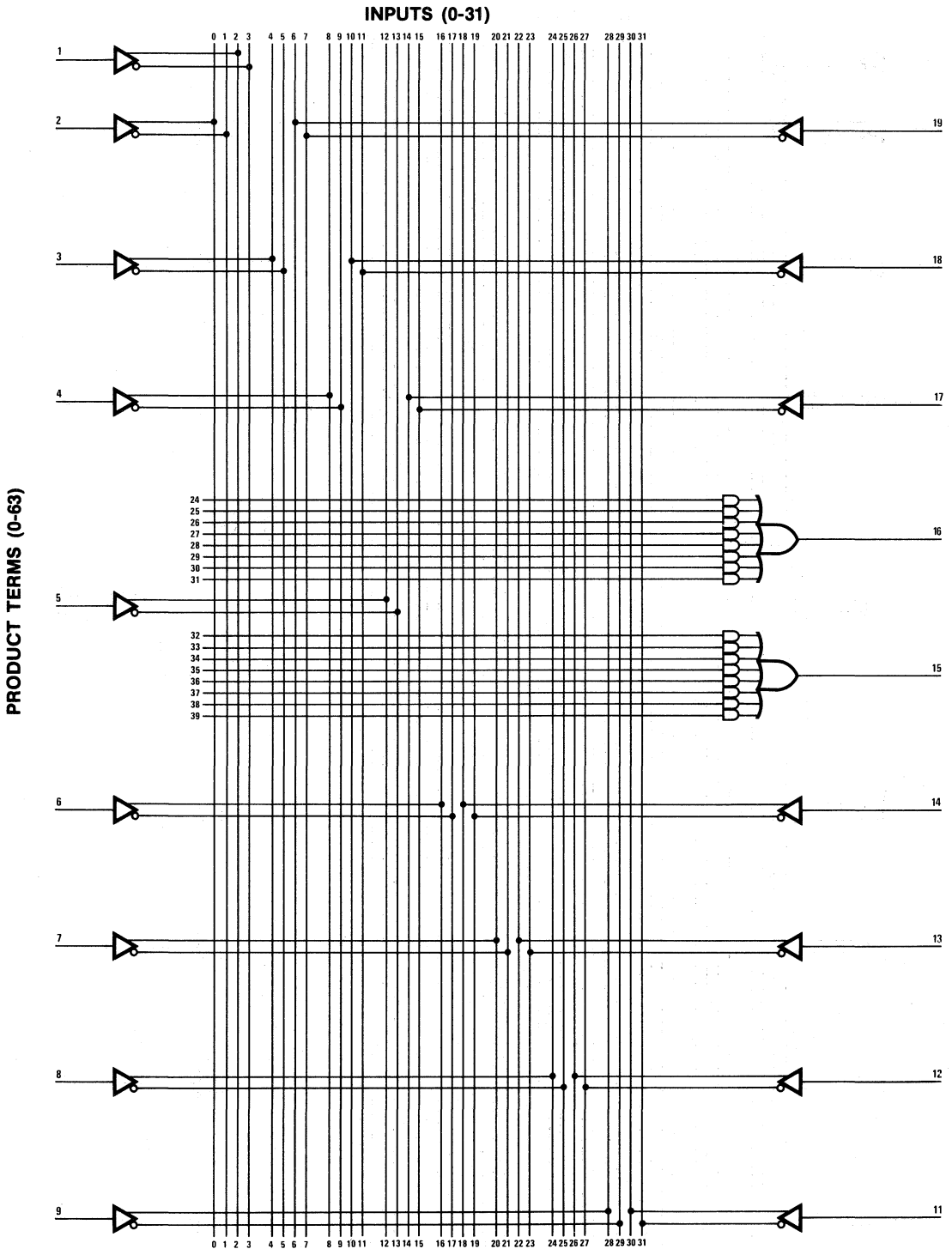


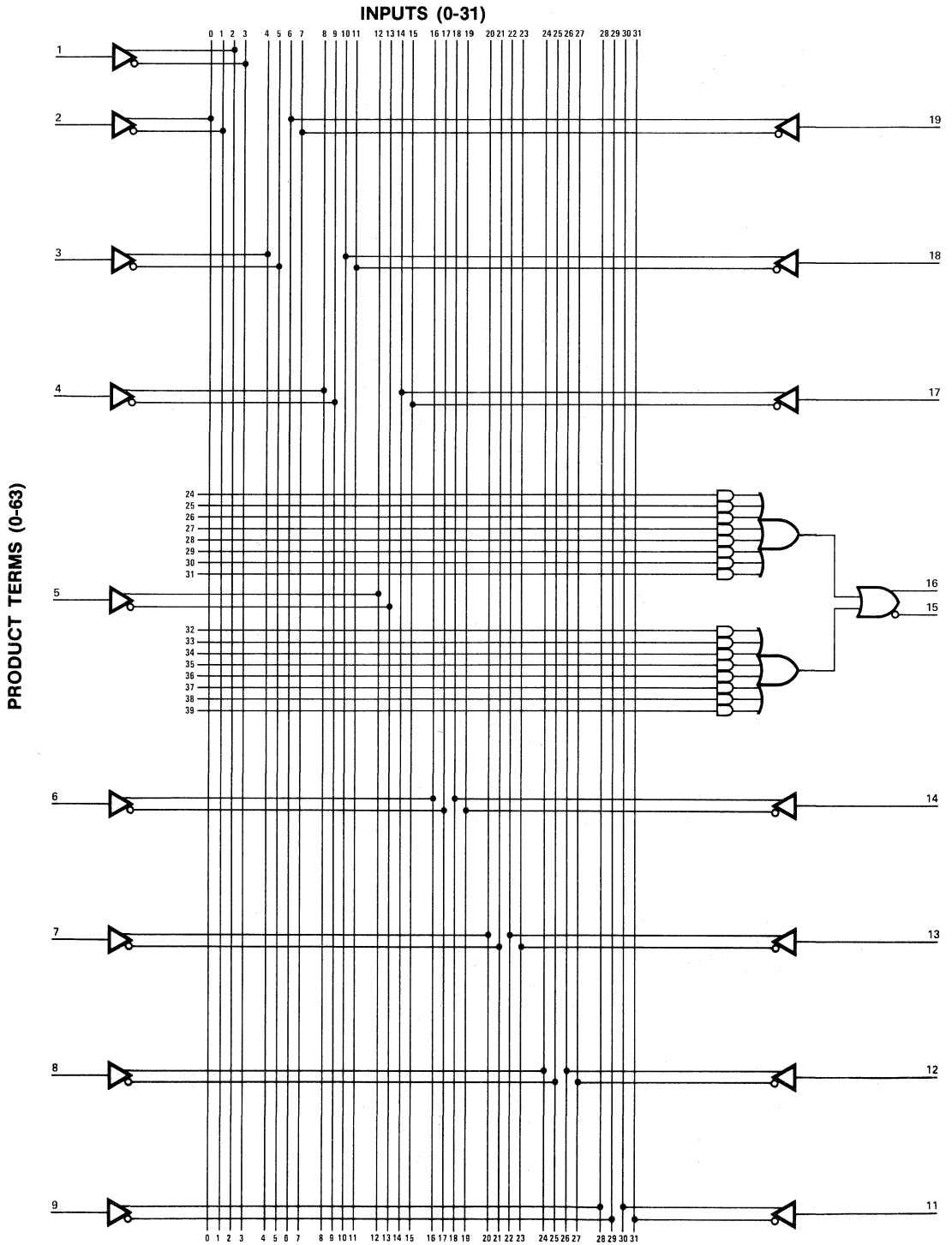
Logic Diagram PAL10H8

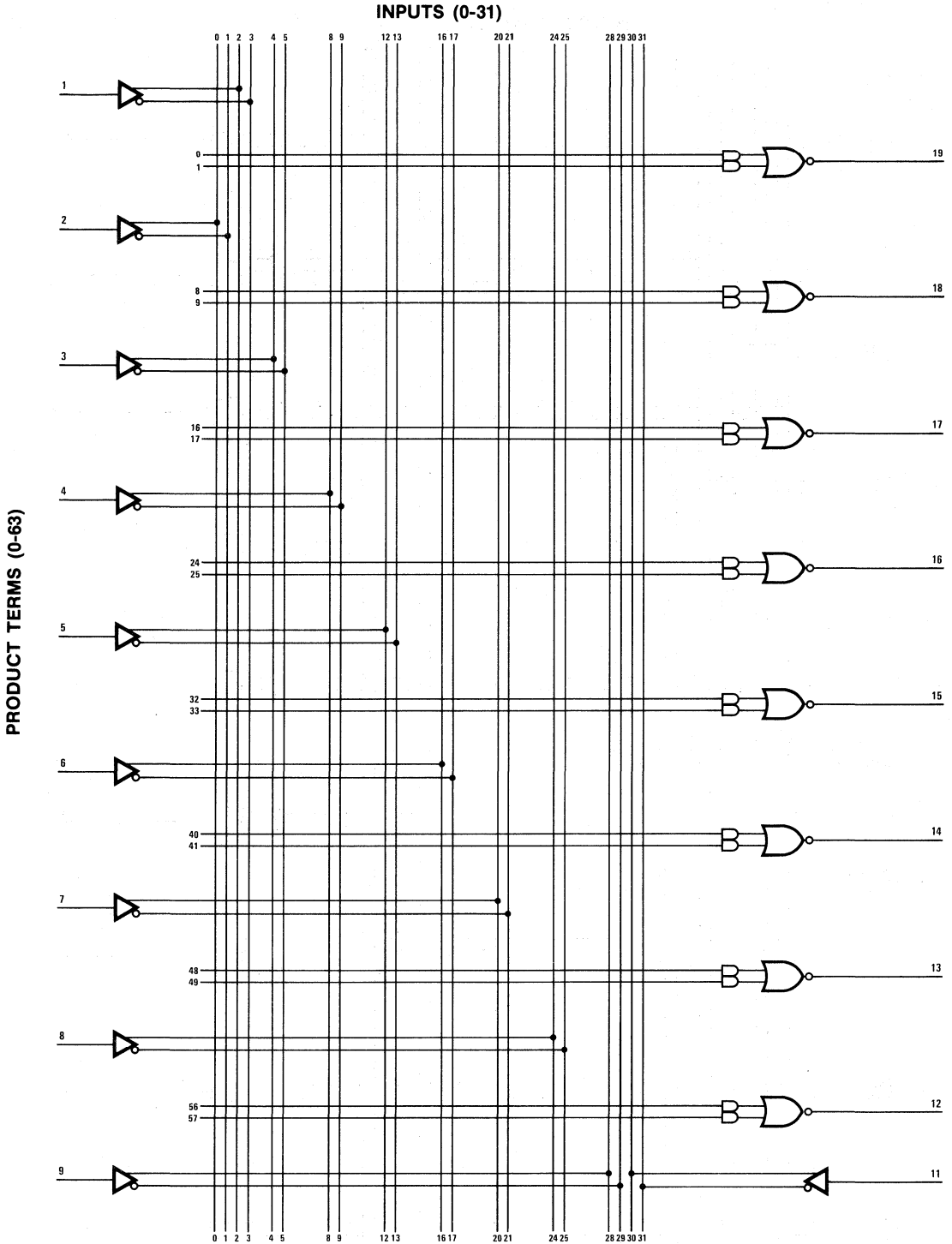


Logic Diagram PAL14H4

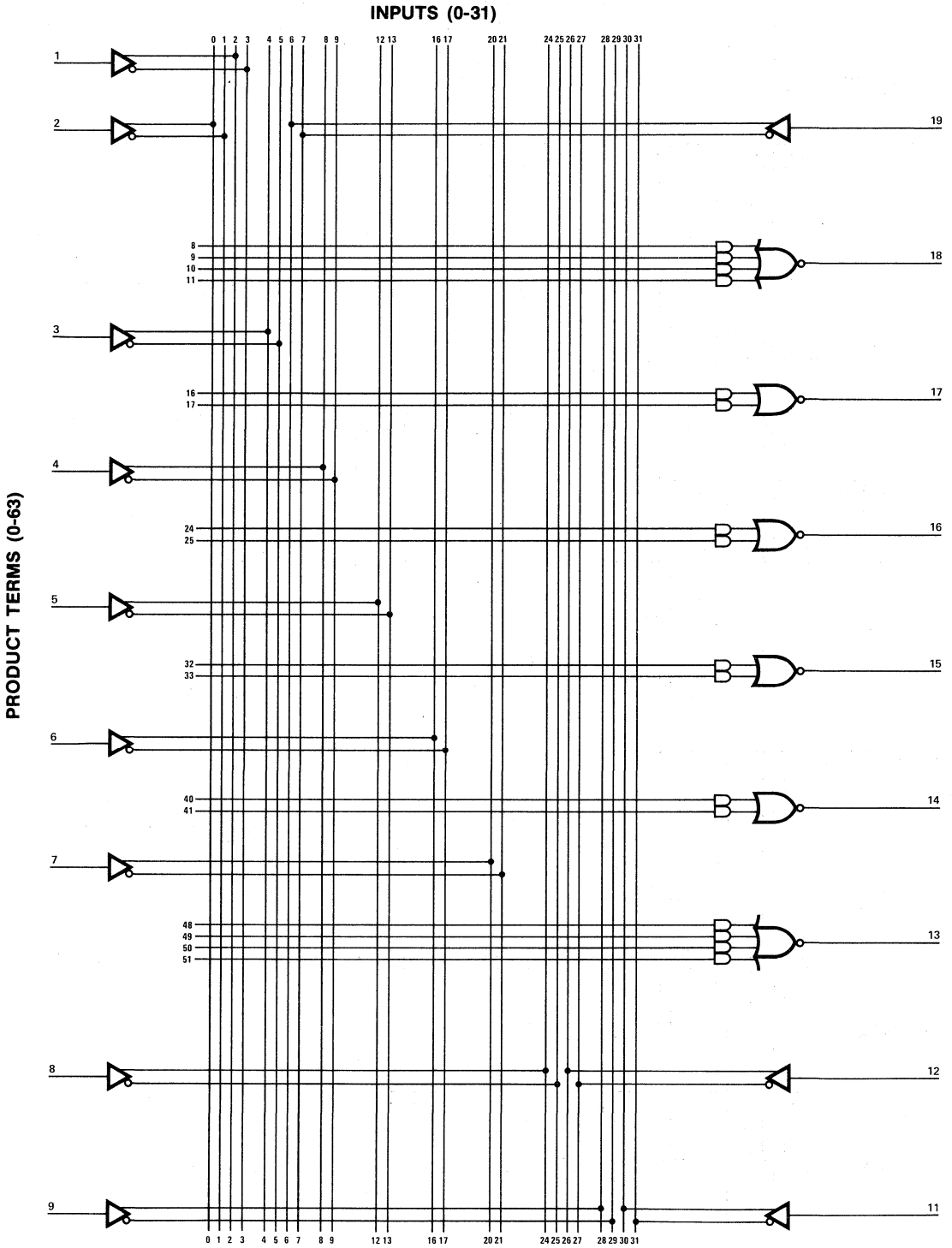


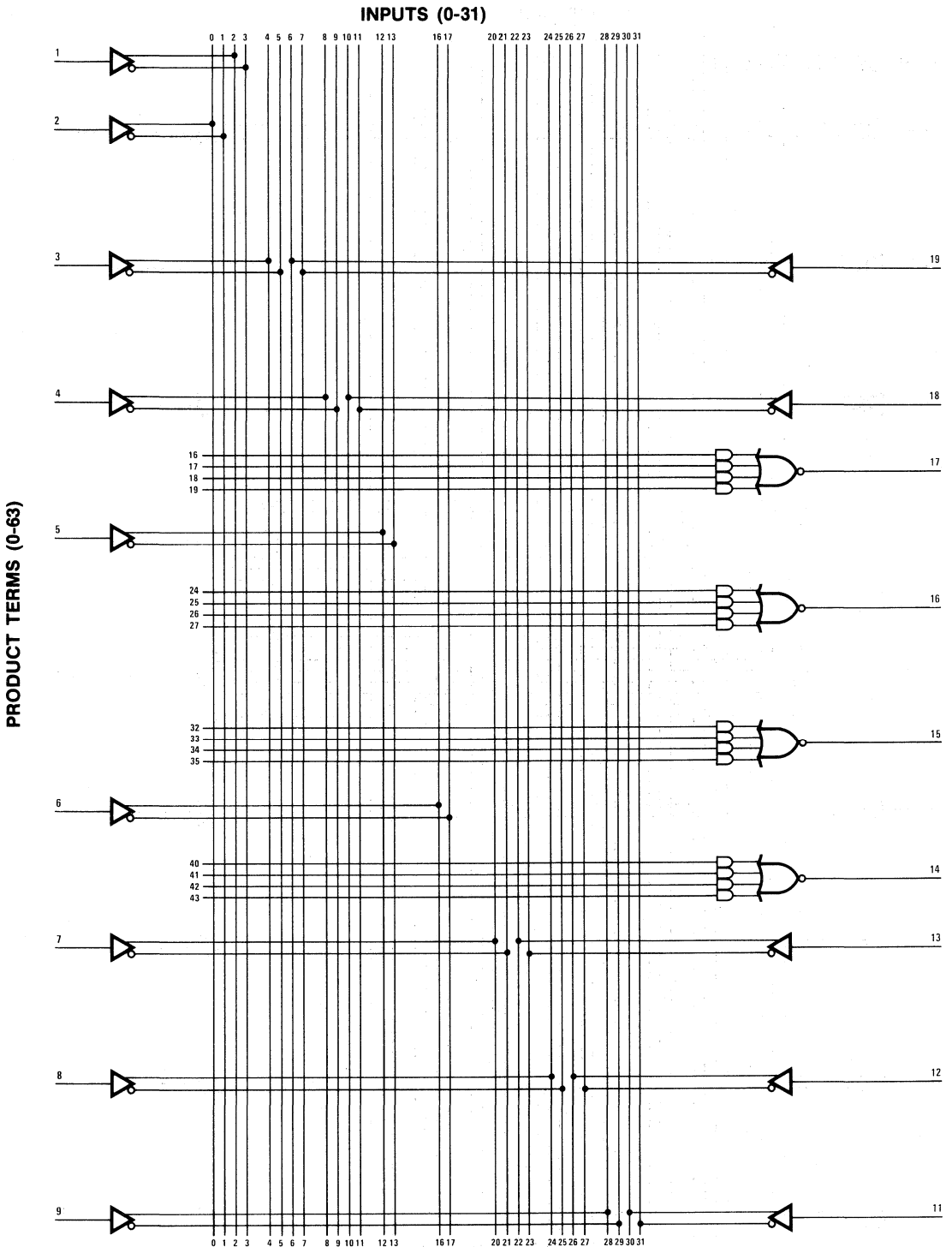


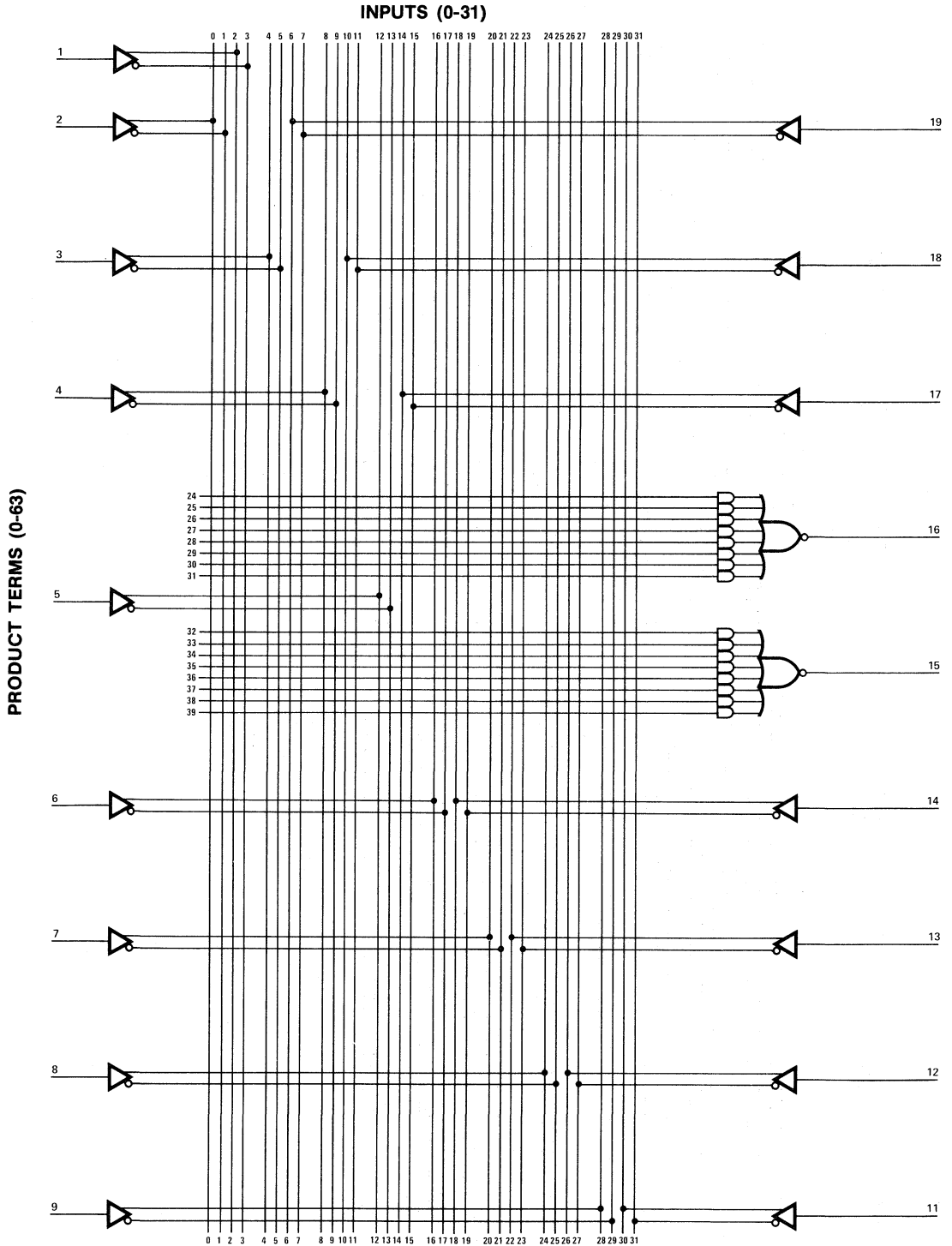




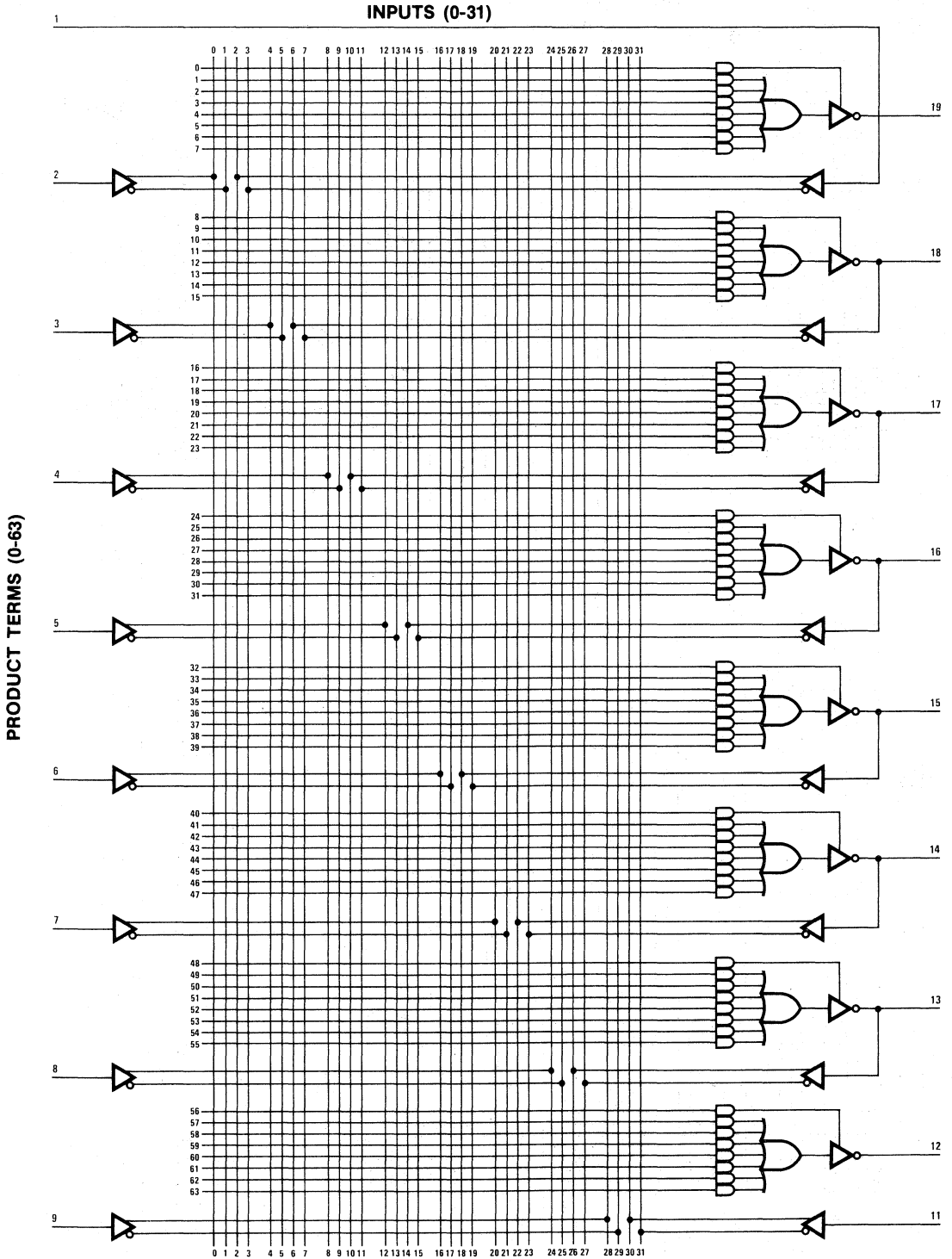
Logic Diagram PAL12L6





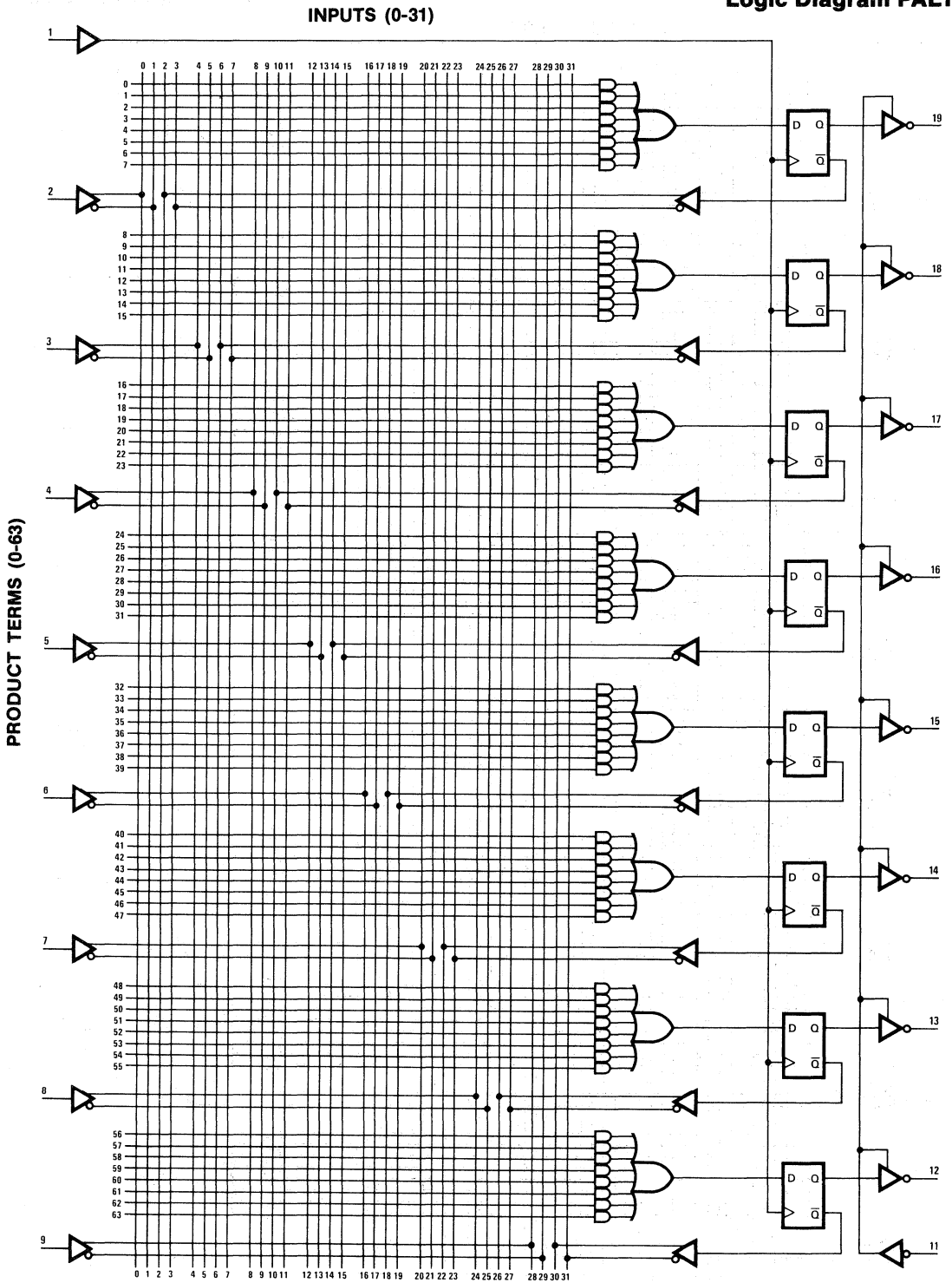


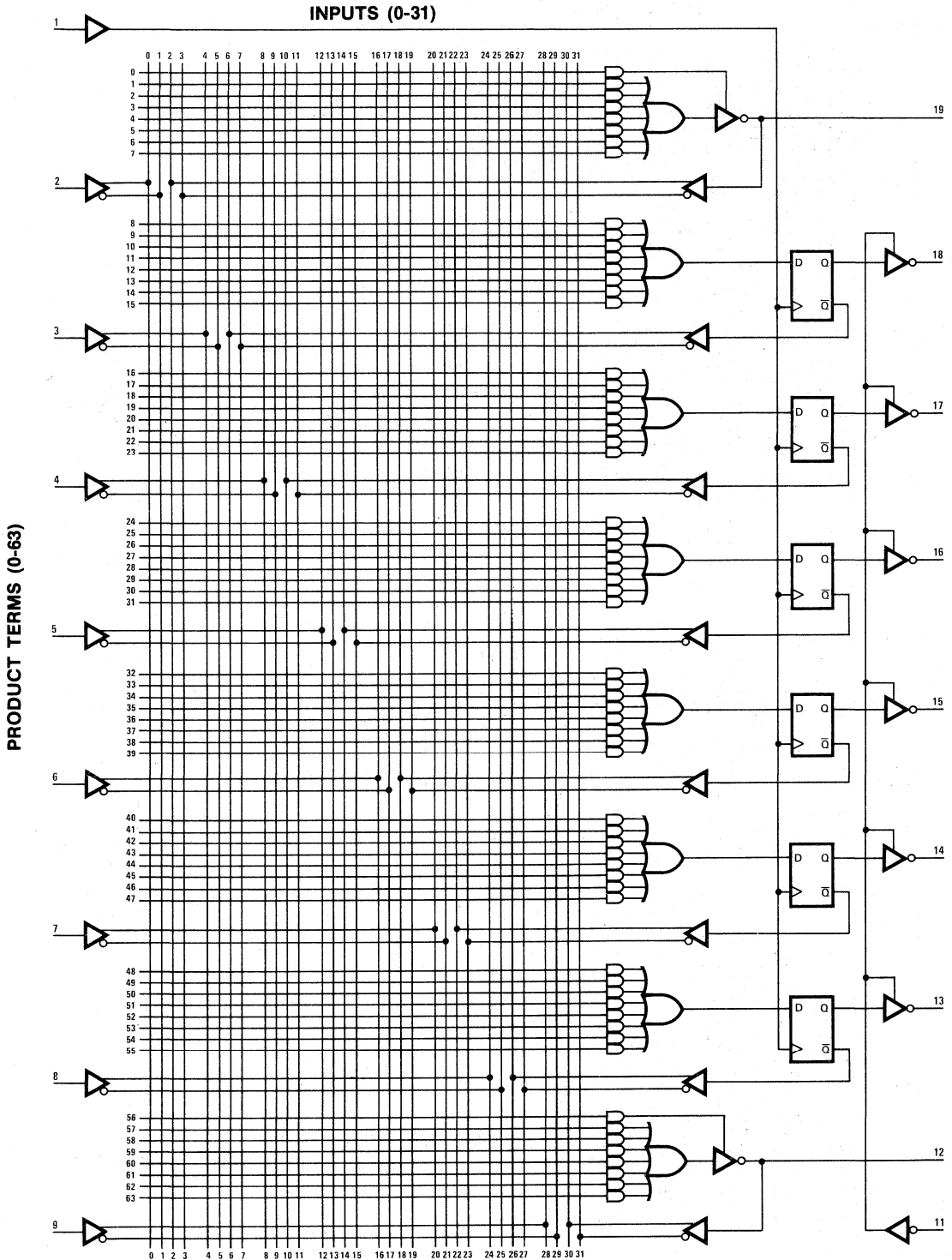
Logic Diagram PAL16L8

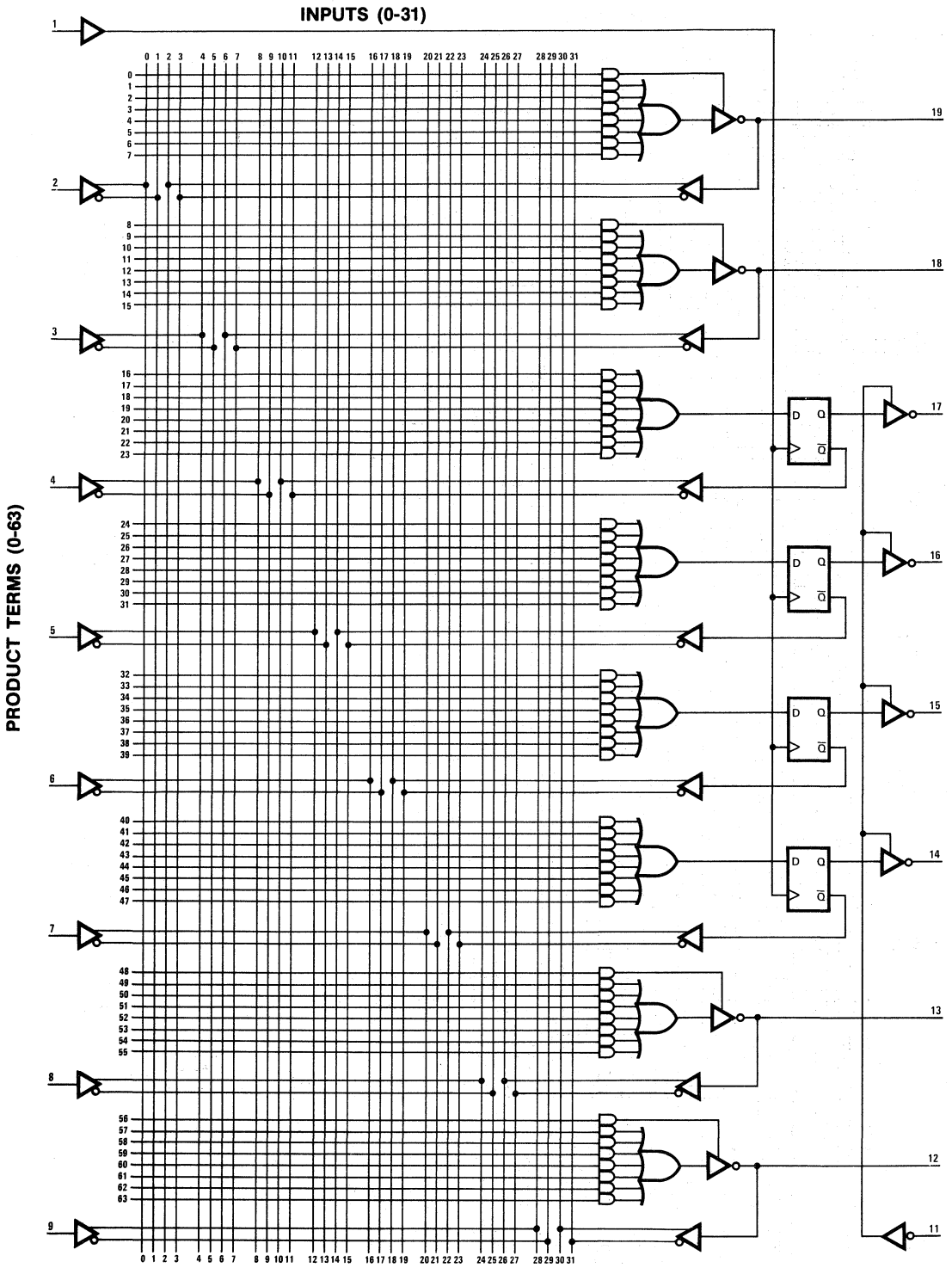


6

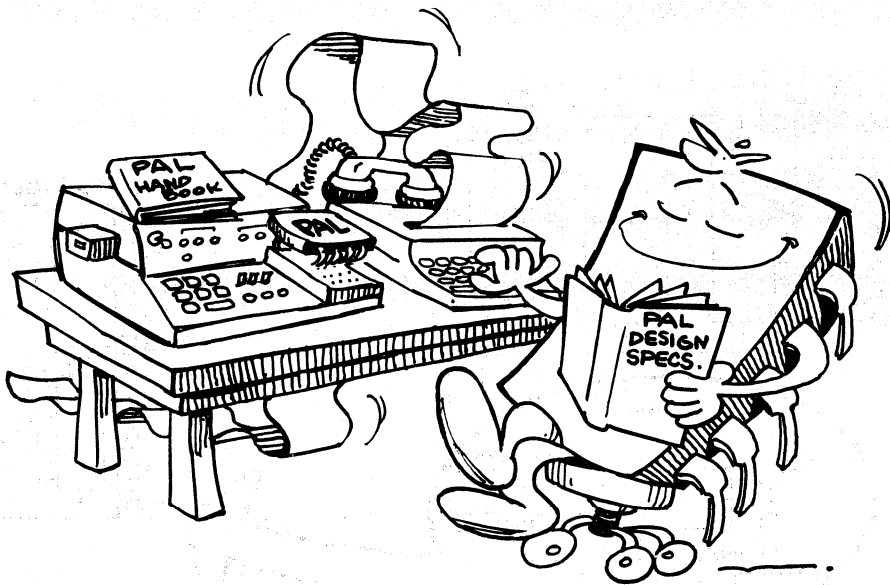
Logic Diagram PAL16R8







PAL Programming



Selecting the Right PAL

The 15 PAL part types offer a wide range of complexity to choose from. Starting with the PAL10H8 (10 inputs, 8 active high outputs), the first 9 PAL types can replace random SSI gate functions at about a 4 to 1 chip count reduction. With a variety of input/output pin ratios and Active High or Active Low outputs, this group, described as combinatorial, is designed to provide the Low Power Schottky (LS) fan-out and fan-in characteristics of 8 mA output sink (IOL) for totem-pole outputs and 250 μ A input loading (IIL).

The next 6 PALS provide the additional features of three-state outputs, state sequencing, arithmetic, and programmable input/output pin ratios. The three-state outputs drive the standard LS output sink of 24 mA (IOL), providing bus driving capability. These sequential PALS are ideal for replacing existing MSI and/or defining LSI functions not presently available.

Unused inputs should be tied to either VCC or GND. The series resistor required for unused inputs on standard TTL is NOT required for PALS, thus using less parts.

Defining the Pinout

The first step in designing a PAL is selecting the Pinout. The example shown below shows a method for circling a section of conventionally drawn logic to define a boundary for a PAL

function. This boundary will dictate a specific number of input pins and output pins. For the following example, 8 inputs and 6 outputs are required, well within the capability of the PAL10L8. Assignment of inputs and outputs to specific pins can be done using the PAL Logic Symbol as shown below.

Specifying the Design

The next step is to generate a fuse pattern in order to program a PAL. The following two methods are commonly used for generating a fuse pattern.

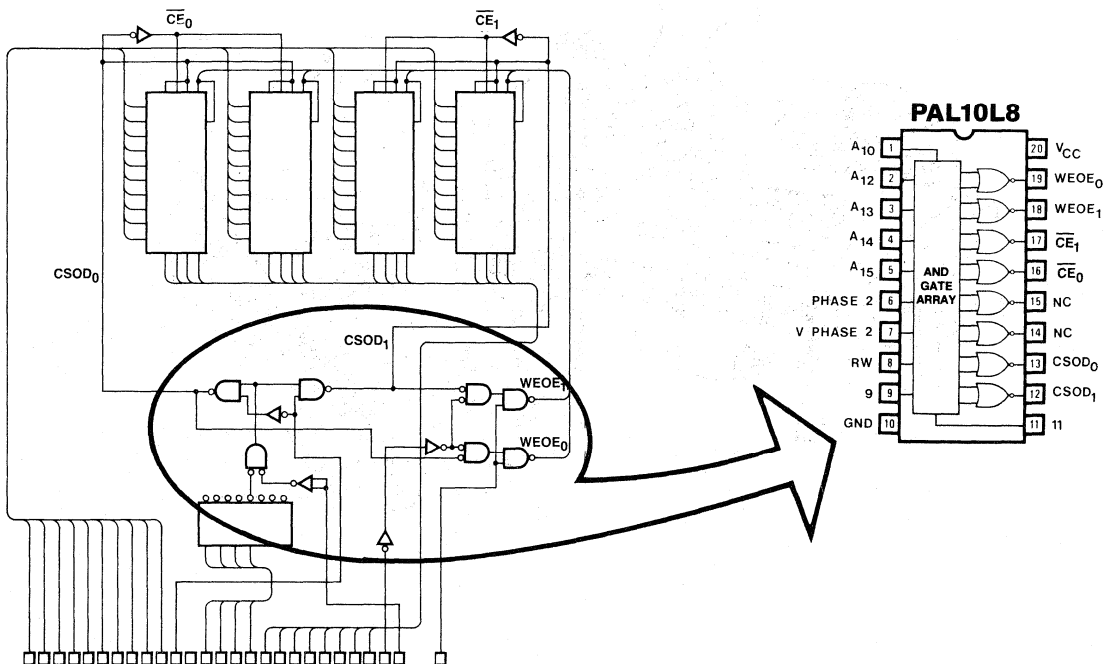
PALASM:

Logic equations are entered as specified on page 6-31 and the fuse pattern is generated.

MANUAL CODING:

In this case logic equations or conventional logic diagram is translated into PAL logic diagram. This is accomplished by marking PAL logic diagrams with appropriate fuse interconnections for the desired logic transfer function. The PAL logic diagram is then transformed into PAL programming format. The programming format can be used to either enter data into the PAL Programmer manually, or to generate a tape using BHLF, BPNP or HEX format.

The two methods described above are explained in detail on the following pages. Page 6-29 gives the necessary information required to convert the conventional logic into PAL logic.



PAL Programming

PAL Legend

Constants

LOW (L)	NEGATIVE (N)	ZERO (0)	GND	FALSE	×		FUSE NOT BLOWN
HIGH (H)	POSITIVE (P)	ONE (1)	V _{CC}	TRUE	-		FUSE BLOWN

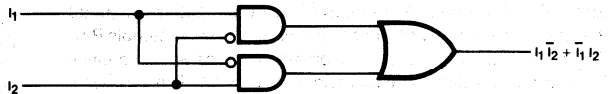
Operators

- = EQUAL
- := REPLACED BY FOLLOWING CLOCK
- / COMPLEMENT
- * AND, PRODUCT
- + OR, SUM
- :+ XOR
- :* XNOR
- () CONDITIONAL THREE STATE, IF STATEMENT, ARITHMETIC

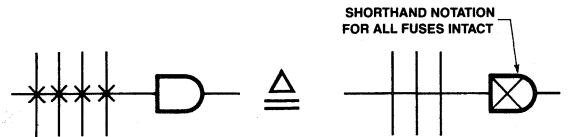
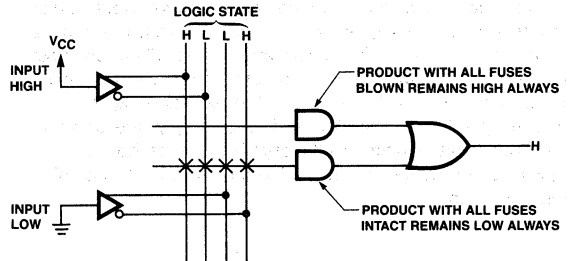
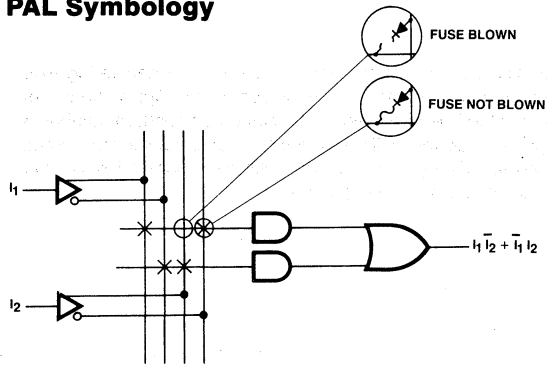
Equations

Standard	$Q_1 = I_1 \bar{I}_2 + \bar{I}_1 I_2$
PALASM	$O1 = I1*/I2 + /I1*I2$

Conventional Symbology

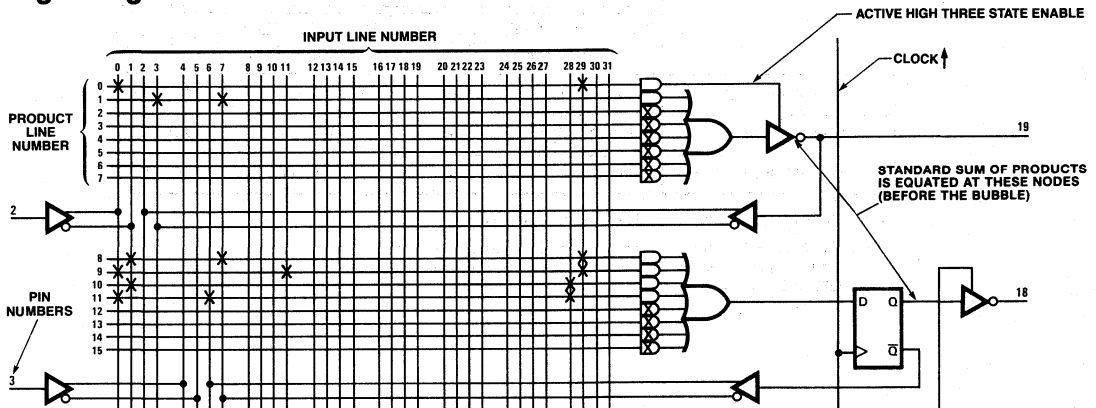


PAL Symbology



6

PAL Logic Diagram



Phantom Fuse

Phantom fuse locations are those locations where a fuse does not exist. These are shown by the missing outputs, product terms or input lines in the Logic Diagrams on pages 6-14 thru 6-22. The PALs with phantom fuse locations appear to the PROM programmer as a partially programmed 512x4 PROM. As the programmer will expect to verify all 2048 locations, the PAL programming format must provide the expected pattern for verifying non-existent fuse nodes. When filling out the programming format, Table 1 should be used for phantom fuse locations. The following PALs have phantom fuses:

PAL10H8	PAL10L8
PAL12H6	PAL12L6
PAL14H4	PAL14L4
PAL16H2	PAL16L2
PAL16C1	

Documenting the PAL Design Specification

The PAL Design Specification is a recommended *data sheet* format for describing the function of a PAL once it has acquired the unique personality of a particular fuse pattern. A sample PAL Design Specification is shown on the next page. It contains the essential features of a data sheet including 1) Device Name, 2) Pin List, 3) Description, 4) Function Table and 5) Logic Diagram (on additional page). Two additional features not found in conventional data sheets are also included. First, is the author's name and the date. This information is standard on most engineering documents. Second, are the equations which define the PAL transfer function. The equations specify the precise operation of the PAL and, accordingly, are useful in understanding the function. Of higher importance, however, the equations are the key to automating the process of "designing your own chip."

PALASM

The equations in the PAL Design Specification, along with the PIN List and part number, contain the exact information necessary to generate PAL fuse patterns. Any computer can transform the spec into programming instructions in the form of paper tape or, preferably, RS232C voltage waveforms for direct input to PROM programmers. With a little help from your computer, your PALs can be designed, documented and programmed within minutes.

PALASM, for PAL Assembler, is a Fortran IV program which translates a PAL Design Specification into a PAL Fuse Pattern and PAL Programming Format (BHLF, BPNP or HEX). The flow chart on page 6-32 outlines the PALASM operation. PALASM source code is available to users on the following pages. Other source code media is available on request.

PROM programmer fuse patterns for VIRGIN PALs, using PALASM, are shown on pages 6-44 thru 6-46. Note that the unprogrammed locations are shown by an 'X' and phantom fuse locations are shown by '□' or '○', representing 'H' or 'L', respectively.

Monolithic Memories will assist customers in generating PAL programming formats. Equations sent to the Applications Department will be assembled and assigned a bit pattern number. A copy of the pattern will be returned for customer verification and approval. A programming order will be processed only after customer approval. (See page 6-80)

Table 1

	ACTIVE HIGH LOGIC		ACTIVE LOW LOGIC	
	(PAL 10H8, 12H6, 14H4, 16H2)	LEGEND	(PAL 10L8, 12L6, 14L4, 16L2)	LEGEND
1) Missing output	H (P,1)	⊕	L (N, O)	⊖
2) Missing product	L (N, O)	⊖	L (N, O)	⊖
3) Missing input lines	H (P, 1)	⊕	H (P, 1)	⊕

Note 1: Missing product term overrides missing input line.

Note 2: For PAL16C1, first half of the array (product terms 0-31) acts as active high logic and the second half of the array (product terms 32-63) acts as active low logic device.

Sample PAL Design Specification

```

PALXXXX ← PAL PART NO. (MUST START AT LINE 1, COLUMN 1)
PATXXXX ← PATTERN NO.
NAME OF DEVICE (EG. CLOCK GENERATOR, PORT ADDRESS DECODER, ETC) ← NAME OF DEVICE (MUST START ON LINE 3)
PAL DESIGN SPECIFICATION
AUTHOR'S NAME, DATE

```

```

PIN1 PIN2 3 /4 5 6 7 8 9 GND 11 12 13 /14 15 16 /17
18 19 VCC

```

PIN LIST (MUST START ON LINE 5)
 CONSISTS OF 20 SYMBOLIC NAMES WHICH
 ARE CONSECUTIVELY ASSIGNED TO
 PINS 1 THRU 20.

```

19 = PIN1*4 + /PIN2
18 = 5 + 6 + 7 + /8 + 9*11
/17 := 8*9
16 = 9*8
IF (PIN1*PIN2) 15 = 3 + 6
/14 = 3 + 6
IF (VCC) 13 = 8*7 + PIN2

```

} EQUATIONS

← CONDITIONAL THREE STATE

← PALASM STOPS COMPILING AT FIRST UNDEFINED SYMBOL

DESCRIPTION:

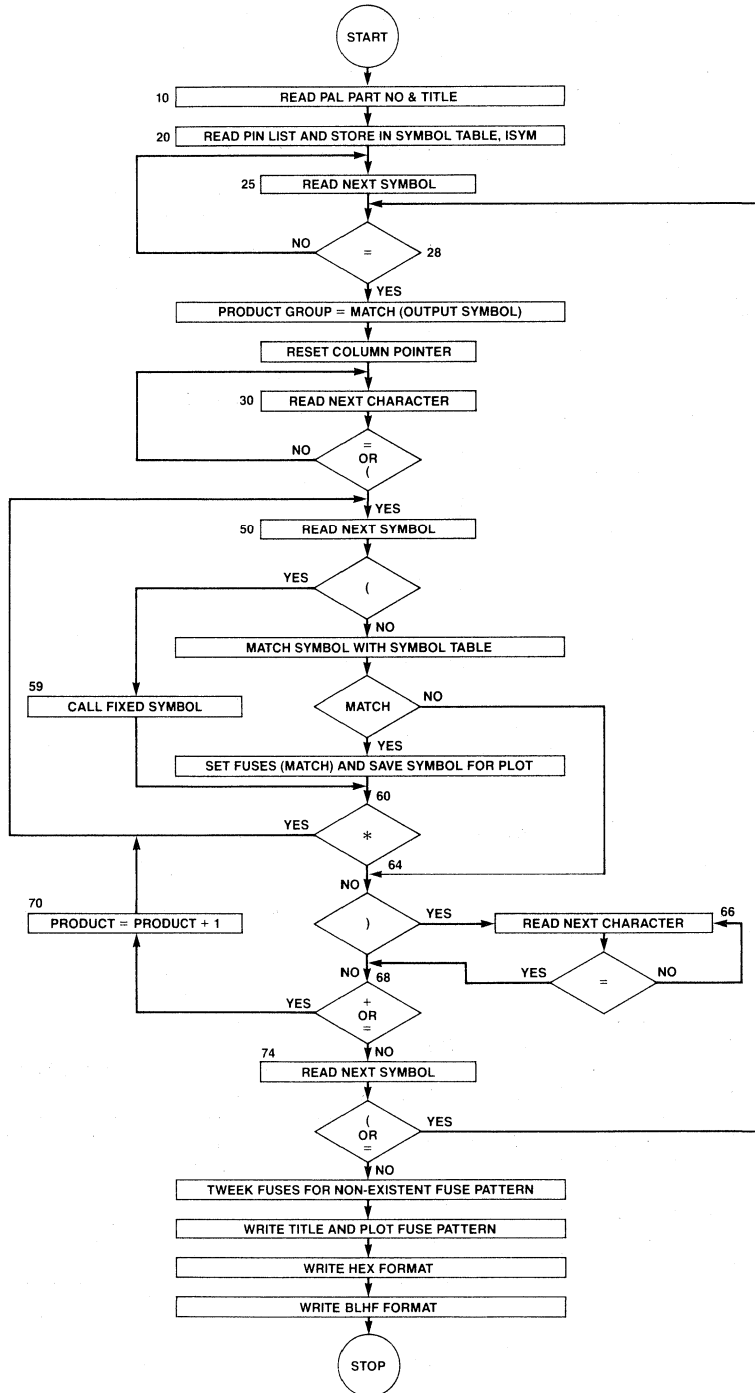
THIS PROGRAM DESCRIBES THE OPERATION OF THE DEVICE. APPLICATIONS INFORMATION MAY ALSO BE PROVIDED.

INPUTS		OUTPUTS										OPERATION	
PIN1	PIN2	7	8	9	12	13	14	15	16	17	18	19	
H	L	X	L	L	H	H	L	H	L	H	H	L	CLEAR
.
.
.
.

← SEE DEFINITION OF TERMS FOR FUNCTION TABLE DEFINITIONS

PAL Programming

PALASM Flow Chart



PAL Programming

PALASM Source Code

```
C
C
C   P A L A S M   -   TRANSLATES SYMBOLIC EQUATIONS INTO PAL OBJECT
C                     CODE . FORMATTED FOR DIRECT INPUT TO STANDARD
C                     PROM PROGRAMMERS.
C
C   INPUT:           PAL DESIGN SPECIFICATION ASSIGNED
C                     TO DATA SET REFERENCE NUMBER 1
C
C   OUTPUT:          FUSE PATTERN, HEX FORMAT, AND BHLF
C                     FORMAT ON DATA SET REFERENCE
C                     NUMBER 6.  COMMENTS ON DSRN 7 & 8
C
C   PART NUMBER:    THE PAL PART NUMBER MUST
C                     APPEAR IN COLUMN ONE OF LINE ONE
C
C   PIN LIST:       20 SYMBOLIC PIN NAMES MUST APPEAR
C                     STARTING ON LINE 5
C
C   EQUATIONS:      STARTING FIRST LINE AFTER THE
C                     PIN LIST IN THE FOLLOWING FORMS:
C
C                     A = B*C + D
C
C                     A := B*C + D
C
C                     IF( A*B ) C = D + E
C
C                     A2 := (A1:*:B1) + /C
C
C                     BLANKS ARE IGNORED
C
C   OPERATORS:      =      EQUALITY
C                     :=    REPLACED BY (AFTER CLOCK)
C                     /      COMPLEMENT
C                     *      AND, PRODUCT
C                     +      OR, SUM
C                     :+    EXCLUSIVE OR
C                     :*    EXCLUSIVE NOR
C                     ( )    CONDITIONAL THREE-STATE
C                             OR FIXED SYMBOL
C
C   FIXED SYMBOLS
C   FOR PAL16X4
C   AND PAL16A4
C   ONLY:           (AN+/BN)      WHERE N = 0,1,2,3
C                   (AN+BN)      FOR OUTPUT PINS
C                   (AN)         17,16,15,14, RESP
C                   (/AN+/BN)    A IS OUTPUT
C                   (/BN)       B IS INPUT
C                   (AN+:BN)
C                   (AN*/BN)
C                   (/AN+BN)
C                   (AN*:BN)
C                   (BN)
C                   (AN*BN)
C                   (/AN)
C                   (/AN*/BN)
C                   (/AN*BN)
C
C   SUBROUTINES:    INITLZ,GETSYM,INCR,MATCH,FIXSYM,
C                   TWEAK,PLOT,HEX,BHLF,MAP,SLIP
C
C   FUNCTIONS:      IXLATE
C
C   REV LEVEL:      J 1/16/80  JB,SK
C
C   FINE PRINT:     MONOLITHIC MEMORIES TAKES NO
C                   RESPONSIBILITY FOR THE OPERATION
C                   OR MAINTENANCE OF THIS PROGRAM.
C                   THE SOURCE CODE AS PRINTED HERE
C                   PRODUCED THE OBJECT CODE OF THE
C                   EXAMPLES IN THE APPLICATIONS
C                   SECTION ON A NATIONAL CSS IBM
C                   SYSTEM/370 FORTRAN IV(G).
C
C*****
```

PALASM Source Code

```

C     MAIN PROGRAM
C
COMMON  LBLANK, LLEFT, LAND, LOR, LSLASH, LEQUAL, LRIGHT
LOGICAL LBLANK, LLEFT, LAND, LOR, LSLASH, LEQUAL, LRIGHT, LFIRST, LFIX
LOGICAL LFUSES(32,64), LPHASE(20), LBUF(20), LMATCH
INTEGER  TITLE(80), ILINE(80), ICOLUM, ISYM(8,20), IBUF(8,20), C,H,R,P,
C       S,M,Q,IBLOW
C     DATA LFUSES/2048*.FALSE./, ICOLUM/0/, L/'L'/, H/'H'/, N/'N'/, P/'P'/,
C       C/'C'/, R/'R'/, M/'M'/, Q/'Q'/, IBLOW/0/, S/'S'/
C
READ(1,10) INOAI, IOT, INOO, TITLE, ILINE
10  FORMAT(3X, I2, A1, I1, //, 80A1, //, 80A1)
CALL INITLZ(INOAI, IOT, INOO, ITYPE, LFUSES, ILINE, ICOLUM)
DO 20 J=1,20
20  CALL GETSYM(LPHASE, ISYM, J, ILINE, ICOLUM, LFIX)
     IF(.NOT.(LEQUAL.OR.LLEFT.OR.LAND.OR.LOR.OR.LRIGHT)) GO TO 25
     WRITE(7,23)
23  FORMAT(' PIN LIST ERROR, LESS THAN 20 SYMBOLS')
25  CALL GETSYM(LBUF, IBUF, 1, ILINE, ICOLUM, LFIX)
28  IF(.NOT.LEQUAL) GO TO 25
     CALL MATCH(IMATCH, IBUF, ISYM)
     IF( (IMATCH.LT.12) .OR. (IMATCH.GT.19) ) GO TO 100
     I88PRO=(19-IMATCH)*8 + 1
     IF( IOT.EQ.C ) I88PRO=25
     ICOLUM=0
30  CALL INCR(ILINE, ICOLUM, LFIX)
     IF(.NOT.( LEQUAL.OR.LLEFT )) GO TO 30
     IF(.NOT.LLEFT) CALL SLIP(LFUSES, I88PRO, INOAI, IOT, INOO, IBLOW)
     DO 70 I8PRO=1,16
     IPROD = I88PRO + I8PRO - 1
     LFIRST=.TRUE.
50  CALL GETSYM(LBUF, IBUF, 1, ILINE, ICOLUM, LFIX)
     IF(LFIX) GO TO 59
     CALL MATCH(IMATCH, IBUF, ISYM)
     IF(IMATCH.EQ.0) GO TO 100
     IF(IMATCH.EQ.99) GO TO 64
     IF(.NOT.LFIRST) GO TO 58
     LFIRST=.FALSE.
     DO 56 I=1,32
     IBLOW = IBLOW + 1
     LFUSES(I, IPROD)=.TRUE.
56  IBUBL=0
58  IF((( LPHASE(IMATCH)).AND.(.NOT.LBUF(1))) .OR.
C     ((.NOT.LPHASE(IMATCH)).AND.( LBUF(1)))) IBUBL=1
     IINPUT=IXLATE(IMATCH, ITYPE)+IBUBL
     IF(IINPUT.LE.0) GO TO 60
     IBLOW = IBLOW - 1
     LFUSES(IINPUT, IPROD)=.FALSE.
     CALL PLOT(LBUF, IBUF, LFUSES, IPROD, TITLE, .FALSE., ITYPE)
     GO TO 60
59  CALL FIXSYM(LBUF, IBUF, ILINE, ICOLUM, LFIRST, LFUSES, IPROD,
C     LFIX)
60  IF(LAND) GO TO 50
64  IF(.NOT.LRIGHT) GO TO 68
66  CALL INCR(ILINE, ICOLUM, LFIX)
     IF(.NOT.LEQUAL) GO TO 66
68  IF(.NOT.(LOR.OR.LEQUAL)) GO TO 74
70  CONTINUE
74  CALL GETSYM(LBUF, IBUF, 1, ILINE, ICOLUM, LFIX)
     IF(LLEFT.OR.LEQUAL) GO TO 28

```


PALASM Source Code

```

100 IF((IBUF(1,1).EQ.C).AND.(IBUF(2,1).EQ.R).AND.(IBUF(4,1).EQ.P)
    C .AND.(IBUF(8,1).EQ.N)) GO TO 102
    WRITE(7,101) (IBUF(I,1),I=1,8),ILINE
101 FORMAT(' ERROR SYMBOL = ',8A1,/,80A1,/)
102 IF(ITYPE.LE.4) CALL TWEAK(ITYPE,IOT,LFUSES)
    WRITE(7,104) IBLW
104 FORMAT(' NUMBER OF FUSES BLOWN = ',I4)
    WRITE(8,106)
106 FORMAT(' OPERATION CODES: ',
    C 'P=PLOT H=HEX S=SHORT L=BHLF N=BPNF M=MAP Q=QUIT')
108 WRITE(8,110)
110 FORMAT(' ENTER OPERATION CODE')
    READ(5,120) IOP
120 FORMAT(1A1)
    CALL IODC2
    IF(IOP.EQ.P) CALL PLOT(LRUF,IBUF,LFUSES,IPROD,TITLE,.TRUE.,ITYPE)
    IF(IOP.EQ.H) CALL HEX(LFUSES,H)
    IF(IOP.EQ.S) CALL HEX(LFUSES,S)
    IF(IOP.EQ.L) CALL BHLF(LFUSES,H,L)
    IF(IOP.EQ.N) CALL BHLF(LFUSES,P,N)
    IF(IOP.EQ.M) CALL MAP(LFUSES)
    CALL IODC4
    IF(IOP.NE.Q) GO TO 108
    STOP
    END
C
C*****
C
SUBROUTINE INITLZ(INOAI,IOT,INOO,ITYPE,LFUSES,ILINE,ICOLUM,LFIX)
INTEGER L,R,X,A
LOGICAL LFIX
DATA L/'L'/,R/'R'/,X/'X'/,A/'A'/
    IF( INOAI .LT. 16 )           ITYPE = (INOAI/2) - 4
    IF( (INOAI .EQ. 16) )        ITYPE = 4
    IF( (INOAI .EQ. 16) .AND. (INOO .EQ. 8) ) ITYPE = 5
    IF( (IOT .EQ. R) .OR. (IOT .EQ. A) .OR. (IOT .EQ. X) ) ITYPE =6
    CALL INCR(ILINE,ICOLUM,LFIX)
    RETURN
    END
C
C*****
C
SUBROUTINE GETSYM(LPHASE,ISYM,J,ILINE,ICOLUM,LFIX)
COMMON LBLANK,LLEFT,LAND,LOR,LSLASH,LEQUAL,LRIGHT
LOGICAL LBLANK,LLEFT,LAND,LOR,LSLASH,LEQUAL,LRIGHT,LPHASE(20),LFIX
INTEGER ILINE(80),ISYM(8,20),IBLANK
DATA IBLANK/' '/
LFIX=.FALSE.
IF( .NOT. (LLEFT.OR.LAND.OR.LOR.OR.LEQUAL.OR.LRIGHT) ) GO TO 10
CALL INCR( ILINE,ICOLUM,LFIX)
IF(LLEFT) GO TO 60
10 LPHASE(J)=(.NOT. LSLASH )
IF(LPHASE(J)) GO TO 15
CALL INCR( ILINE,ICOLUM,LFIX)
15 DO 20 I=1,8
20 ISYM(I,J)=IBLANK
25 DO 30 I=1,7
30 ISYM(I,J)=ISYM(I+1,J)
ISYM(8,J)=ILINE(ICOLUM)
CALL INCR( ILINE,ICOLUM,LFIX)
IF( LLEFT.OR.LBLANK.OR.LAND.OR.LOR.OR.LRIGHT.OR.LEQUAL ) GO TO 40
GO TO 25
40 CONTINUE
C
WRITE(7,50) (ISYM(I,J), I=1,8)
C 50 FORMAT(' ',8A1)
RETURN
60 LFIX=.TRUE.
RETURN
END
C
C*****
C

```

PALASM Source Code

```

SUBROUTINE INCR(ILINE,ICOLUM,LFIX)
COMMON LBLANK,LLEFT,LAND,LOR,LSLASH,LEQUAL,LRIGHT
LOGICAL LBLANK,LLEFT,LAND,LOR,LSLASH,LEQUAL,LRIGHT,LFIX
INTEGER ILINE(80),IBLANK,ILEFT,IAND,IOR,ISLASH,IEQUAL,IRIGHT,
C      ICOLON
DATA IBLANK/' ',ILEFT/'(',IAND/'*',IOR/'+',
C      ISLASH/'/',IEQUAL/'=',IRIGHT/')',ICOLON/':'/
LBLANK=.FALSE.
10 ICOLUM=ICOLUM+1
IF(ICOLUM.LE.79) GO TO 30
READ(1,20,ERR=70,END=70) ILINE
ICOLUM=1
20 FORMAT(80A1)
30 IF( ILINE(ICOLUM) .EQ. IBLANK ) LBLANK=.TRUE.
C WRITE(7,50) ILINE(ICOLUM)
C 50 FORMAT(' ',1A1)
IF( ( ILINE(ICOLUM) .EQ. IBLANK ) .OR.
C { ( ILINE(ICOLUM) .EQ. ICOLON) .AND. (.NOT. LFIX) ) ) GO TO 10
LLEFT =( ILINE(ICOLUM) .EQ. ILEFT )
LAND =( ILINE(ICOLUM) .EQ. IAND )
LOR =( ILINE(ICOLUM) .EQ. IOR )
LSLASH=( ILINE(ICOLUM) .EQ. ISLASH )
LEQUAL=( ILINE(ICOLUM) .EQ. IEQUAL )
LRIGHT=( ILINE(ICOLUM) .EQ. IRIGHT )
60 RETURN
70 LBLANK=.TRUE.
RETURN
END

C
C*****
C
SUBROUTINE MATCH(IMATCH,IBUF,ISYM)
INTEGER IBUF(8,20),ISYM(8,20),C,A,R,Y
LOGICAL LMATCH
DATA C/'C'/,A/'A'/,R/'R'/,Y/'Y'/
IMATCH=0
DO 20 J=1,20
LMATCH=.TRUE.
DO 10 I=1,8
10 LMATCH=LMATCH.AND.(IBUF(I,1).EQ.ISYM(I,J))
IF(LMATCH) IMATCH=J
20 CONTINUE
IF((IBUF(3,1).EQ.C).AND.
C (IBUF(4,1).EQ.A).AND.
C (IBUF(5,1).EQ.R).AND.
C (IBUF(6,1).EQ.Y).AND.
C (IBUF(7,1).EQ.Y)) IMATCH=99
RETURN
END

C
C*****
C
FUNCTION IXLATE(IMATCH,ITYPE)
INTEGER ITABLE(20,6)
DATA ITABLE/
C 3, 1, 5, 9,13,17,21,25,29,-1,31,-1,-1,-1,-1,-1,-1,-1,-1,-1,
C 3, 1, 5, 9,13,17,21,25,29,-1,31,27,-1,-1,-1,-1,-1,-1, 7,-1,
C 3, 1, 5, 9,13,17,21,25,29,-1,31,27,23,-1,-1,-1,-1,11, 7,-1,
C 3, 1, 5, 9,13,17,21,25,29,-1,31,27,23,19,-1,-1,15,11, 7,-1,
C 3, 1, 5, 9,13,17,21,25,29,-1,31,-1,27,23,19,15,11, 7,-1,-1,
C -1, 1, 5, 9,13,17,21,25,29,-1,-1,31,27,23,19,15,11, 7, 3,-1/
IXLATE=ITABLE(IMATCH,ITYPE)
RETURN
END

C
C*****
C

```

PALASM Source Code

```

SUBROUTINE FIXSYM(LBUF,IBUF,ILINE,ICOLUM,LFIRST,LFUSES,IPROD,LFIX)
LOGICAL LBUF(20),LFUSES(32,64),LFIRST,LMATCH,LFIX
INTEGER IBUF(8,20),ILINE(80),FIXBUF(8),A,B,ISLASH,IOR,IAND,N,Q,
C   NO,N1,N2,N3,IBLANK,IRIGHT,TABLE(5,14)
DATA A/'A'/,B/'B'/,ISLASH/'/'/,IOR/'+'/,IBLANK/' '/,IRIGHT/'/'/,
C   IAND/'*'/,N/'N'/,Q/'Q'/,NO/'0'/,N1/'1'/,N2/'2'/,N3/'3'/,
C   ICOLON/'/'/,
C   TABLE
C   /,A',+'/,B',+'/,A',+'/,B',+'/,
C   /,A',+'/,A',+'/,B',+'/,B',+'/,
C   /,A',+'/,B',+'/,A',+'/,B',+'/,
C   /,A',+'/,B',+'/,B',+'/,A',+'/,B',+'/,
C   /,A',+'/,B',+'/,A',+'/,B',+'/,
C   /,A',+'/,A',+'/,B',+'/,B',+'/,
C   /,A',+'/,A',+'/,A',+'/,B',+'/,A',+'/,B',+'/
IINPUT=0
DO 20 I=1,8
    IBUF(I,1)=IBLANK
20    FIXBUF(I)=IBLANK
21    CALL INCR(I,ILINE,ICOLUM,LFIX)
        I=ILINE(ICOLUM)
        IF(I.EQ.IRIGHT) GO TO 40
        IF(I.EQ.NO) IINPUT=8
        IF(I.EQ.N1) IINPUT=12
        IF(I.EQ.N2) IINPUT=16
        IF(I.EQ.N3) IINPUT=20
DO 24 J=1,7
24    IBUF(J,1)=IBUF(J+1,1)
IBUF(8,1)=I
IF(.NOT. ( (I.EQ.A).OR.(I.EQ.B).OR.(I.EQ.ISLASH).OR.(I.EQ.IOR)
C   .OR.(I.EQ.IAND).OR.(I.EQ.ICOLON) ) ) GO TO 21
DO 30 I=1,4
30    FIXBUF(I)=FIXBUF(I+1)
FIXBUF(5)=ILINE(ICOLUM)
GO TO 21
40    IMATCH=0
DO 60 J=1,14
    LMATCH=.TRUE.
DO 50 I=1,5
50    LMATCH=LMATCH .AND. ( FIXBUF(I).EQ.TABLE(I,J) )
60    IF(LMATCH) IMATCH=J
IF(IMATCH.EQ.0) GO TO 100
IF(.NOT.LFIRST) GO TO 85
    LFIRST=.FALSE.
DO 80 I=1,32
80    LFUSES(I,IPROD)=.TRUE.
85    DO 90 I=1,4
    IF( (IMATCH-7).GT.0 ) LFUSES(IINPUT+I,IPROD)=.FALSE.
    IF( (IMATCH-7).GT.0 ) IMATCH=IMATCH-?
90    IMATCH=IMATCH+IMATCH
LBUF(1)=.TRUE.
CALL PLOT(LBUF,IBUF,LFUSES,IPROD,TITLE,.FALSE.,ITYPE)
100    LFIX=.FALSE.
CALL INCR(I,ILINE,ICOLUM,LFIX)
RETURN
END

C
C*****
C
SUBROUTINE IODC2
C*** THIS ROUTINE IS OPTIONAL. IT MAY BE USED TO TURN PERIPHERALS ON.
INTEGER DC2,BEL
DATA DC2/Z12000000/,BEL/Z2F000000/
WRITE(6,10) DC2,BEL
10 FORMAT(' ',2A1)
RETURN
END

C
C*****
C

```

PALASM Source Code

```

SUBROUTINE PLOT(LBUF,IBUF,LFUSES,IPROD,TITLE,LDUMP,ITYPE)
INTEGER IBUF(8,20),IOUT(64),IBLANK,IAND,IOR,ISLASH,IDASH,X,
C   ISAVE(64,32),TITLE(80)
DATA IBLANK/' '/,IAND/'*'/,ISAVE/2048*' '/,
C   IOR/'+'/,ISLASH/'/'/,X/'X'/,IDASH/'-'/'
LOGICAL LBUF(20),LFUSES(32,64),LDUMP
IF(LDUMP) GO TO 60
IF(ISAVE(IPROD,1).NE.IBLANK) RETURN
IF( LBUF(1) ) GO TO 5
DO 30 J=1,31
30   ISAVE(IPROD,J)=ISAVE(IPROD,J+1)
   ISAVE(IPROD,32)=ISLASH
5 DO 20 I=1,8
   IF( ISAVE(IPROD,1).NE.IBLANK ) RETURN
   IF( IBUF(I,1) .EQ. IBLANK ) GO TO 20
   DO 10 J=1,31
10   ISAVE(IPROD,J)=ISAVE(IPROD,J+1)
   ISAVE(IPROD,32)=IBUF(I,1)
20   CONTINUE
   IF(ISAVE(IPROD,1).NE.IBLANK) RETURN
40 DO 50 J=1,31
50   ISAVE(IPROD,J)=ISAVE(IPROD,J+1)
   ISAVE(IPROD,32)=IAND
RETURN
60 WRITE(6,62) TITLE
62 FORMAT(////,' ',80A1,/,/,
C '      11 1111 1111 2222 2222 2233',/,/,
C ' 0123 4567 8901 2345 6789 0123 4567 8901',/,/)
DO 100 I88PRO=1,57,8
DO 94 I8PRO=1,8
   IPROD=I88PRO+I8PRO-1
   ISAVE(IPROD,32)=IBLANK
DO 70 I=1,32
   IF( ISAVE(IPROD,1) .NE. IBLANK ) GO TO 70
DO 65 J=1,31
65   ISAVE(IPROD,J)=ISAVE(IPROD,J+1)
   ISAVE(IPROD,32)=IBLANK
70   CONTINUE
DO 80 I=1,32
   IOUT(I)=X
   IF( LFUSES(I,IPROD) ) IOUT(I)=IDASH
   IOUT(I+32)=ISAVE(IPROD,I)
80   CONTINUE
   IF( ITYPE .LE. 4 ) CALL FANTOM(ITYPE,IOUT,IPROD,I8PRO)
   IPROD=IPROD-1
   WRITE(6,90) IPROD,IOUT
90   FORMAT(' ',I2,8(' ',4A1),' ',32A1)
94   CONTINUE
   WRITE(6,96)
96   FORMAT(1X)
100  CONTINUE
   WRITE(6,110)
110  FORMAT(/,
C ' LEGEND: X : FUSE NOT BLOWN (L,N,0) - : FUSE BLOWN (H,P,1)')
   IF (ITYPE.LE.4) WRITE(6,111)
111  FORMAT(
C '      0 : PHANTOM FUSE (L,N,0) O : PHANTOM FUSE (H,P,1)')
   WRITE(6,112)
112  FORMAT(////)
RETURN
END
C
C*****
C

```

PAL Programming

PALASM Source Code

```

SUBROUTINE HEX(LFUSES,IOP)
LOGICAL LFUSES(32,64)
INTEGER ITEMP(64),S,H,IOP
DATA STX/Z02000000/,BEL/Z2F000000/,SOH/Z01000000/,
C H/'H'/,S/'S'/
IF(IOP.EQ.H) WRITE(6,10)
10 FORMAT(//,'
C***** NOTE: SOME PROM PROGRAMMERS NEED A START CHARACTER.
C***** THIS PROGRAM OUTPUTS AN STX FOR THE DATA I/O MODEL 9
C***** (USE SOH FOR MODEL 5)
WRITE(6,5) BEL,BEL,BEL,BEL,BEL,BEL,STX,SOH
5 FORMAT(9A1)
DO 40 I=1,33,32
INC=I-1
DO 40 IPROD=1,7,2
DO 20 J=1,2
DO 20 IINPUT=1,32
IHEX=0
IF(LFUSES(IINPUT,IPROD + J-1 + 0+INC)) IHEX=IHEX+1
IF(LFUSES(IINPUT,IPROD + J-1 + 8+INC)) IHEX=IHEX+2
IF(LFUSES(IINPUT,IPROD + J-1 +16+INC)) IHEX=IHEX+4
IF(LFUSES(IINPUT,IPROD + J-1 +24+INC)) IHEX=IHEX+8
20 ITEMP(IINPUT + 32*(J-1) )=IHEX
IF(IOP.EQ.H) WRITE(6,60) ITEMP
40 IF(IOP.EQ.S) WRITE(6,61) ITEMP
60 FORMAT(' ',32(Z1,' '),'.',/,',',32(Z1,' '),'.')
61 FORMAT(' ',64Z1)
IF(IOP.EQ.H) WRITE(6,70)
70 FORMAT(' ',//,'
RETURN
END
C
C*****
C
SUBROUTINE BHLF(LFUSES,H,L)
LOGICAL LFUSES(32,64)
INTEGER ITEMP(4,8),L,H
WRITE(6,10)
10 FORMAT(//,'
DO 20 I=1,33,32
INC=I-1
DO 20 IPROD=1,8
DO 20 J=1,25,8
DO 15 K=1,8
IINPUT=J+K-1
ITEMP(1,K)=L
ITEMP(2,K)=L
ITEMP(3,K)=L
ITEMP(4,K)=L
IF(LFUSES(IINPUT,IPROD+ 0+INC)) ITEMP(4,K)=H
IF(LFUSES(IINPUT,IPROD+ 8+INC)) ITEMP(3,K)=H
IF(LFUSES(IINPUT,IPROD+16+INC)) ITEMP(2,K)=H
IF(LFUSES(IINPUT,IPROD+24+INC)) ITEMP(1,K)=H
15 CONTINUE
20 WRITE(6,30) ITEMP
30 FORMAT(' ',8('B',4A1,'F '))
WRITE(6,10)
RETURN
END
C
C*****
C
SUBROUTINE IODC4
C*** THIS ROUTINE IS OPTIONAL. IT MAY BE USED TO TURN PERIPHERALS OFF.
INTEGER DC3,DC4,BEL
DATA DC3/Z37000000/,DC4/Z3C000000/,BEL/Z2F000000/
WRITE(6,10) BEL,DC3,DC4
10 FORMAT(' ',3A1)
RETURN
END
C
C*****
C
```

PALASM Source Code

```

SUBROUTINE TWEAK(ITYPE,IOT,LFUSES)
INTEGER L,C
LOGICAL LFUSES(32,64)
DATA L/'L'/,C/'C'/
IF(ITYPE.GE.4) GO TO 20
DO 10 IPROD=1,64
    LFUSES(15,IPROD)=.TRUE.
    LFUSES(16,IPROD)=.TRUE.
    LFUSES(19,IPROD)=.TRUE.
    LFUSES(20,IPROD)=.TRUE.
    IF(ITYPE.GE.3) GO TO 10
    LFUSES(11,IPROD)=.TRUE.
    LFUSES(12,IPROD)=.TRUE.
    LFUSES(23,IPROD)=.TRUE.
    LFUSES(24,IPROD)=.TRUE.
    IF(ITYPE.GE.2) GO TO 10
    LFUSES( 7,IPROD)=.TRUE.
    LFUSES( 8,IPROD)=.TRUE.
    LFUSES(27,IPROD)=.TRUE.
    LFUSES(28,IPROD)=.TRUE.
10 CONTINUE
DO 18 IINPUT=7,28
    DO 12 IPROD=1,57,8
        LFUSES(IINPUT,IPROD+4)=.FALSE.
        LFUSES(IINPUT,IPROD+5)=.FALSE.
        LFUSES(IINPUT,IPROD+6)=.FALSE.
12     LFUSES(IINPUT,IPROD+7)=.FALSE.
        IF(ITYPE.GE.3) GO TO 18
        DO 14 IPROD=17,41,8
            LFUSES(IINPUT,IPROD+2)=.FALSE.
            LFUSES(IINPUT,IPROD+3)=.FALSE.
14     IF(ITYPE.GE.2) GO TO 18
        DO 16 IPROD=1,57,8
            LFUSES(IINPUT,IPROD+2)=.FALSE.
            LFUSES(IINPUT,IPROD+3)=.FALSE.
16     CONTINUE
18 CONTINUE
20 IF( (ITYPE.EQ.1) .OR. ((ITYPE.EQ.4).AND.(IOT.EQ.L)) ) GO TO 100
DO 99 IINPUT=1,32
    DO 30 IPROD=1,8
        LFUSES(IINPUT,IPROD+ 0)= (IOT.NE.L)
        IF(IOT.NE.C) LFUSES(IINPUT,IPROD+56)= (IOT.NE.L)
30     IF(ITYPE.LE.2) GO TO 99
        DO 40 IPROD=1,8
            LFUSES(IINPUT,IPROD+ 8)= (IOT.NE.L)
            IF(IOT.NE.C) LFUSES(IINPUT,IPROD+48)= (IOT.NE.L)
40     IF(ITYPE.LE.3) GO TO 99
        DO 50 IPROD=1,8
            LFUSES(IINPUT,IPROD+16)= (IOT.NE.L)
            IF(IOT.NE.C) LFUSES(IINPUT,IPROD+40)= (IOT.NE.L)
50     CONTINUE
99     CONTINUE
100 RETURN
END

C
C*****
C
SUBROUTINE SLIP(LFUSES,I88PRO,INOAI,IOT,INOO,IBLOW)
LOGICAL LFUSES(32,64)
INTEGER R
DATA R/'R'/
IF( (INOAI.LT.16) .OR. (INOO.LT.4) .OR.
C   ( (IOT.EQ.R).AND.(INOO.EQ.8) ) .OR.
C   ( (I88PRO.GE. 9).AND.(I88PRO.LE.49).AND.(INOO.EQ.6) ) .OR.
C   ( (I88PRO.GE.17).AND.(I88PRO.LE.41).AND.(INOO.EQ.4) ) ) RETURN
DO 10 I=1,32
    IBLOW = IBLOW + 1
10 LFUSES(I,I88PRO) = .TRUE.
    I88PRO = I88PRO + 1
RETURN
END

C
C*****
C

```

PALASM Source Code

```

SUBROUTINE MAP(LFUSES)
LOGICAL LFUSES(32,64)
INTEGER X,D,ILINE(16),ITABLE(32)
DATA X/'X'/,D/'-'/,
C ITABLE/17,16,19,18,21,20,23,22,25,24,27,26,29,28,31,30,
C 13,12,15,14, 9, 8,11,10, 5, 4, 7, 6, 1, 0, 3, 2/
WRITE(6,10)
10 FORMAT( ' INPUT',/,/,
C ' 11 11 22 22 22 22 33',/,/,
C ' 76 98 10 32 54 76 98 10',/,/,
C ' 11 11 11 ',/,/,
C ' PRODUCT 32 54 98 10 54 76 10 32',/,/)
IPROD=7
IDELTA = -1
DO 50 I=1,2
DO 40 J=1,4
DO 30 K=1,4
DO 20 L=1,16
ILINE(L)=X
IF( LFUSES(ITABLE(L)+1 ,IPROD+1 ) ) ILINE(L)=D
20 WRITE(6,21) IPROD,ILINE
21 FORMAT(' ',I2,' ',8(2A1,' ' ) )
DO 22 L=1,16
ILINE(L)=X
22 IF( LFUSES(ITABLE(L)+16+1 ,IPROD+1 ) ) ILINE(L)=D
WRITE(6,21) IPROD,ILINE
IPROD = IPROD + IDELTA
DO 23 L=1,16
ILINE(L)=X
23 IF( LFUSES(ITABLE(L)+16+1 ,IPROD+1 ) ) ILINE(L)=D
WRITE(6,21) IPROD,ILINE
DO 24 L=1,16
ILINE(L)=X
24 IF( LFUSES(ITABLE(L)+1 ,IPROD+1 ) ) ILINE(L)=D
WRITE(6,21) IPROD,ILINE
IPROD = IPROD + IDELTA
30 WRITE(6,29)
29 FORMAT(' ')
40 IPROD = IPROD + 8*(1-IDELTA)
IPROD = 32
50 IDELTA = +1
WRITE(6,29)
WRITE(6,29)
RETURN
END
C
C*****
C
SUBROUTINE FANTOM(ITYPE,IOUT,IPROD,I8PRO)
INTEGER ITYPE,IOUT(64),IPROD,I8PRO,X,IDASH,FX,FIDASH
DATA X/'X'/,IDASH/'-'/,FX/'0'/,FIDASH/'O'/
DO 10 I=1,32
IF( IOUT(I).EQ.X ) IOUT(I)=FX
10 IF( IOUT(I).EQ.IDASH ) IOUT(I)=FIDASH
IF((ITYPE.EQ.4).AND.((IPROD.LE.24).OR.(IPROD.GE.41))) GO TO 100
IF((ITYPE.EQ.3).AND.((IPROD.LE.16).OR.(IPROD.GE.45))) GO TO 100
IF((ITYPE.EQ.2).AND.((IPROD.LE. 8).OR.(IPROD.GE.53))) GO TO 100
IF((ITYPE.LE.3).AND.(I8PRO.GE.5)) GO TO 100
IF((ITYPE.LE.2).AND.(IPROD.GE.19).AND.(IPROD.LE.48).AND.
C (I8PRO.GE.3)) GO TO 100
IF((ITYPE.EQ.1).AND.(I8PRO.GE.3)) GO TO 100
DO 50 I=1,32
IF(((I.EQ.15).OR.(I.EQ.16).OR.(I.EQ.19).OR.(I.EQ.20)).AND.
C (ITYPE.LE.3)) GO TO 50
IF(((I.EQ.11).OR.(I.EQ.12).OR.(I.EQ.23).OR.(I.EQ.24)).AND.
C (ITYPE.LE.2)) GO TO 50
IF(((I.EQ. 7).OR.(I.EQ. 8).OR.(I.EQ.27).OR.(I.EQ.28)).AND.
C (ITYPE.LE.1)) GO TO 50
IF(IOUT(I).EQ.FX ) IOUT(I)=X
IF(IOUT(I).EQ.FIDASH) IOUT(I)=IDASH
50 CONTINUE
100 RETURN
END
C
C*****
C

```


MANUAL CODING

Logic Diagrams

The phantom fuse locations are shown on pages 6-48 thru 6-65. Note that the input and product terms that were missing in the logic diagrams of previous section on pages 6-14 thru 6-22 are now being shown as phantom fuse locations. These locations are filled in according to the Table 1 on page 6-30.

The remaining locations are the nodes where fuses are intact. Fuses left intact are indicated by an "X" at the intersection of the input line and the product term. A blown fuse is not marked. The PAL logic diagrams are provided with no fuses marked, allowing a designer to put an "X" on the nodes where a fuse is to remain intact and leave the other nodes blank.

Once the logic diagram is completed, this information must be transferred to the programming format. Each fuse node is identified by a product line number and an input line number which are used to locate the corresponding square in the PAL programming format.

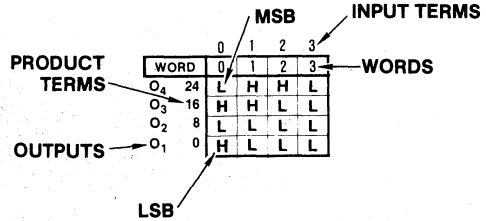
The following legend is being used:

Logic Diagram	Programming format
— ✱ —	L, N, O
— —	H, P, 1
— ⊕ —	Phantom Fuse Location (H, P, 1)
— ● —	Phantom Fuse Location (L, N, O)

Programming Format:

The programming format is designed such that it is compatible with standard PROM programmer format for 512x4 (2048-bit) PROM. Words addresses are in HEX since most of the PROM programmers use HEX addresses. A table which contains HEX to decimal conversion is also provided on page 6-75. Referring to page 6-49 note that the input lines go from left to right and are in sequence. The product terms go from top to bottom and are not in sequence and are scrambled. This is because, to form one 4-bit word, we need four different product terms on the same input line. A word is read from top to bottom and consists of four product terms on one input line. The top bit is most significant (MSB) and the bottom bit is least significant (LSB).

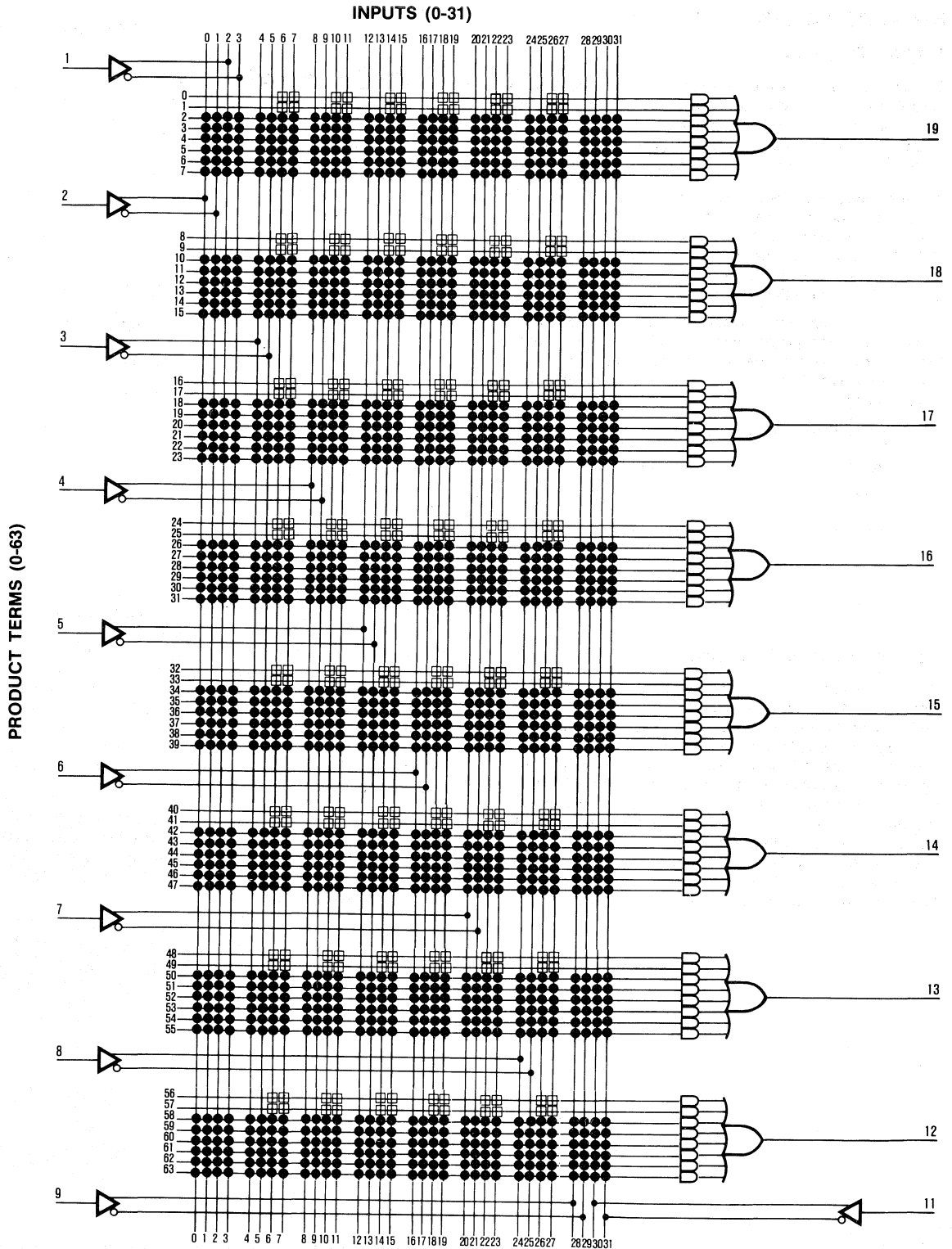
EXAMPLE



WORD	0	:	LHLH
WORD	1	:	HHLL
WORD	2	:	HLLL
WORD	3	:	LLLL

As in the case of logic diagrams, the programming format for the first nine PALs are filled with an 'H' or an 'L' representing the phantom fuse locations. The remaining blank squares are to be filled by the designer. If one decides to use a programming format other than BHLF, then 'H' and 'L' will have to be converted into the equivalent format. (e.g., if one decides to use BPNF format, then 'H' has to be replaced by 'P' and 'L' has to be replaced by 'N' on the programming format). Logic diagrams and the programming formats for all different options are shown on pages 6-48 thru 6-73.

The most common PROM programmer input medium is paper tape, with BHLF, BPNF or HEXADECIMAL format. Information regarding generation of paper tape and different formats are described on page 6-74.



PAL10H8

Programming Format

PATTERN:

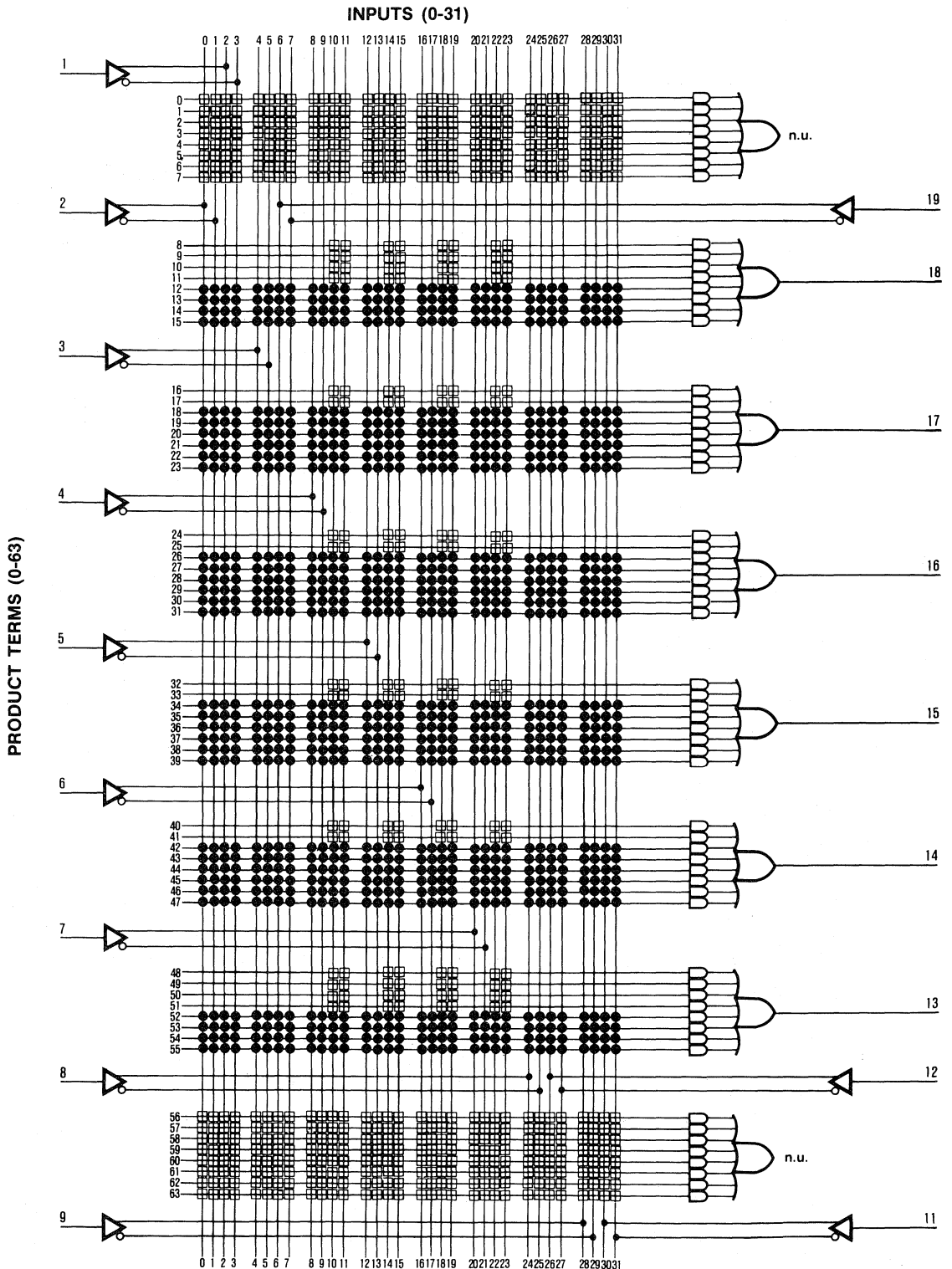
NAME:

PRODUCT TERMS (0-63)

DATE:

INPUTS (0-31)

		0 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24 25 26 27 28 29 30 31																															
WORD	20	20 21 22 23 24 25 26 27 28 29 2A 2B 2C 2D 2E 2F 30 31 32 33 34 35 36 37 38 39 3A 3B 3C 3D 3E 3F																															
O ₄	24	H H																															
O ₃	16	H H																															
O ₂	8	H H																															
O ₁	0	H H																															
WORD	25	25 26 27 28 29 2A 2B 2C 2D 2E 2F 30 31 32 33 34 35 36 37 38 39 3A 3B 3C 3D 3E 3F																															
O ₄	17	H H																															
O ₃	9	H H																															
O ₂	1	H H																															
O ₁	1	H H																															
WORD	40	40 41 42 43 44 45 46 47 48 49 4A 4B 4C 4D 4E 4F 50 51 52 53 54 55 56 57 58 59 5A 5B 5C 5D 5E 5F																															
O ₄	26	L L																															
O ₃	18	L L																															
O ₂	10	L L																															
O ₁	2	L L																															
WORD	60	60 61 62 63 64 65 66 67 68 69 6A 6B 6C 6D 6E 6F 70 71 72 73 74 75 76 77 78 79 7A 7B 7C 7D 7E 7F																															
O ₄	27	L L																															
O ₃	19	L L																															
O ₂	11	L L																															
O ₁	3	L L																															
WORD	80	80 81 82 83 84 85 86 87 88 89 8A 8B 8C 8D 8E 8F 90 91 92 93 94 95 96 97 98 99 9A 9B 9C 9D 9E 9F																															
O ₄	28	L L																															
O ₃	20	L L																															
O ₂	12	L L																															
O ₁	4	L L																															
WORD	A0	A0 A1 A2 A3 A4 A5 A6 A7 A8 A9 AA AB AC AD AE AF 80 B1 B2 B3 B4 B5 B6 B7 B8 B9 BA BB BC BD BE BF																															
O ₄	29	L L																															
O ₃	21	L L																															
O ₂	13	L L																															
O ₁	5	L L																															
WORD	C0	C0 C1 C2 C3 C4 C5 C6 C7 C8 C9 CA CB CC CD CE CF D0 D1 D2 D3 D4 D5 D6 D7 D8 D9 DA DB DC DD DE DF																															
O ₄	30	L L																															
O ₃	22	L L																															
O ₂	14	L L																															
O ₁	6	L L																															
WORD	E0	E0 E1 E2 E3 E4 E5 E6 E7 E8 E9 EA EB EC ED EE EF F0 F1 F2 F3 F4 F5 F6 F7 F8 F9 FA FB FC FD FE FF																															
O ₄	31	L L																															
O ₃	23	L L																															
O ₂	15	L L																															
O ₁	7	L L																															
WORD	100	100 101 102 103 104 105 106 107 108 109 10A 10B 10C 10D 10E 10F 110 111 112 113 114 115 116 117 118 119 11A 11B 11C 11D 11E 11F																															
O ₄	56	H H																															
O ₃	48	H H																															
O ₂	40	H H																															
O ₁	32	H H																															
WORD	120	120 121 122 123 124 125 126 127 128 129 12A 12B 12C 12D 12E 12F 130 131 132 133 134 135 136 137 138 139 13A 13B 13C 13D 13E 13F																															
O ₄	57	H H																															
O ₃	49	H H																															
O ₂	41	H H																															
O ₁	33	H H																															
WORD	140	140 141 142 143 144 145 146 147 148 149 14A 14B 14C 14D 14E 14F 150 151 152 153 154 155 156 157 158 159 15A 15B 15C 15D 15E 15F																															
O ₄	58	L L																															
O ₃	50	L L																															
O ₂	42	L L																															
O ₁	34	L L																															
WORD	160	160 161 162 163 164 165 166 167 168 169 16A 16B 16C 16D 16E 16F 170 171 172 173 174 175 176 177 178 179 17A 17B 17C 17D 17E 17F																															
O ₄	59	L L																															
O ₃	51	L L																															
O ₂	43	L L																															
O ₁	35	L L																															
WORD	180	180 181 182 183 184 185 186 187 188 189 18A 18B 18C 18D 18E 18F 190 191 192 193 194 195 196 197 198 199 19A 19B 19C 19D 19E 19F																															
O ₄	60	L L																															
O ₃	52	L L																															
O ₂	44	L L																															
O ₁	36	L L																															
WORD	1A0	1A0 1A1 1A2 1A3 1A4 1A5 1A6 1A7 1A8 1A9 1AA 1AB 1AC 1AD 1AE 1AF 1B0 1B1 1B2 1B3 1B4 1B5 1B6 1B7 1B8 1B9 1BA 1BB 1BC 1BD 1BE 1BF																															
O ₄	61	L L																															
O ₃	53	L L																															
O ₂	45	L L																															
O ₁	37	L L																															
WORD	1C0	1C0 1C1 1C2 1C3 1C4 1C5 1C6 1C7 1C8 1C9 1CA 1CB 1CC 1CD 1CE 1CF 1D0 1D1 1D2 1D3 1D4 1D5 1D6 1D7 1D8 1D9 1DA 1DB 1DC 1DD 1DE 1DF																															
O ₄	62	L L																															
O ₃	54	L L																															
O ₂	46	L L																															
O ₁	38	L L																															
WORD	1E0	1E0 1E1 1E2 1E3 1E4 1E5 1E6 1E7 1E8 1E9 1EA 1EB 1EC 1ED 1EE 1EF 1F0 1F1 1F2 1F3 1F4 1F5 1F6 1F7 1F8 1F9 1FA 1FB 1FC 1FD 1FE 1FF																															
O ₄	63	L L																															
O ₃	55	L L																															
O ₂	47	L L																															
O ₁	39	L L																															

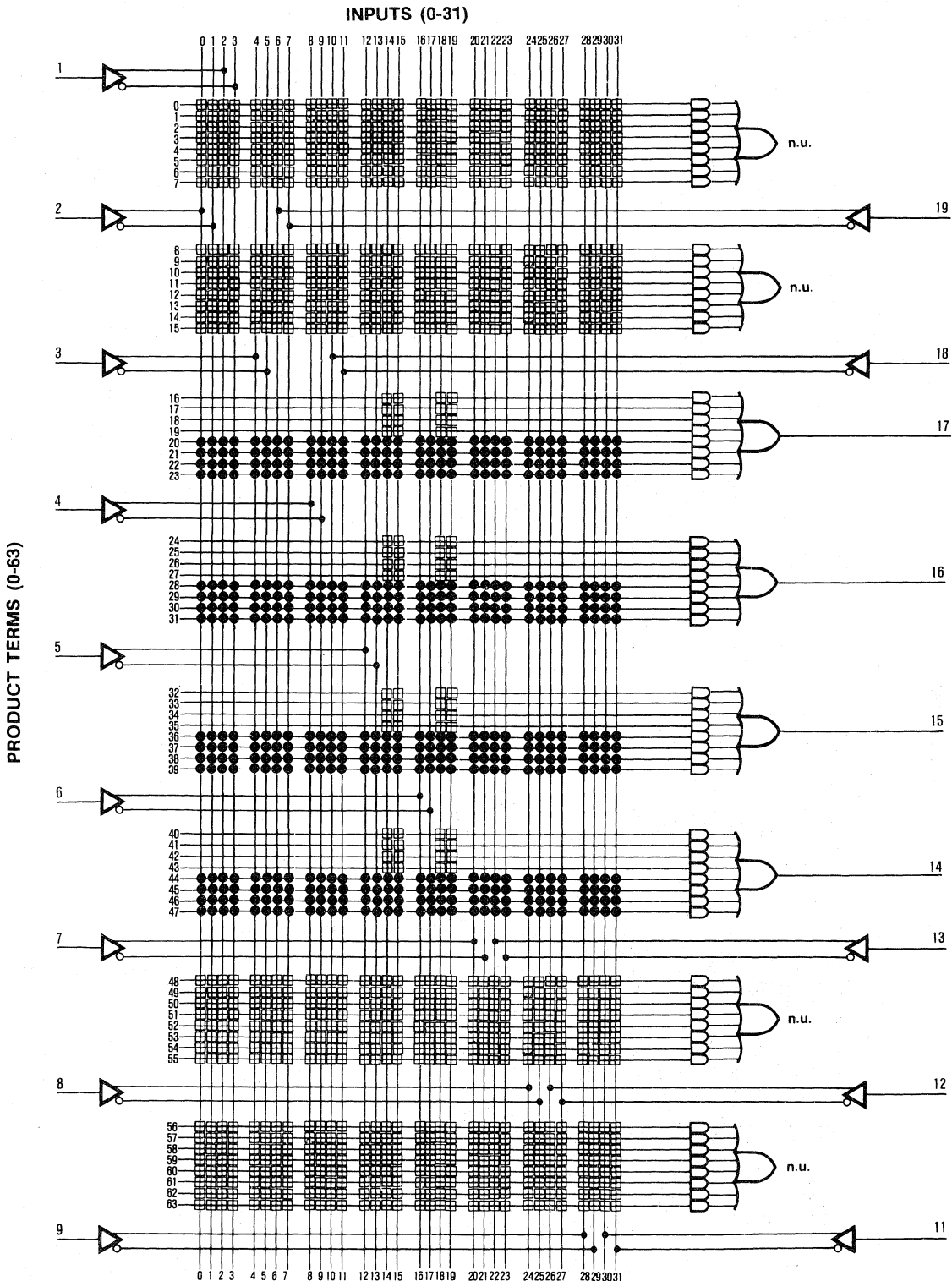


LEGEND:

● : Phantom Fuse (L, N, 0)

□ : Phantom Fuse (H, P, 1)

n.u. — not used



LEGEND:

● : Phantom Fuse (L, N, 0)

□ : Phantom Fuse (H, P, 1)

n.u. — not used

PAL14H4

Programming Format

PATTERN:

NAME:

PRODUCT TERMS (0-63)

DATE:

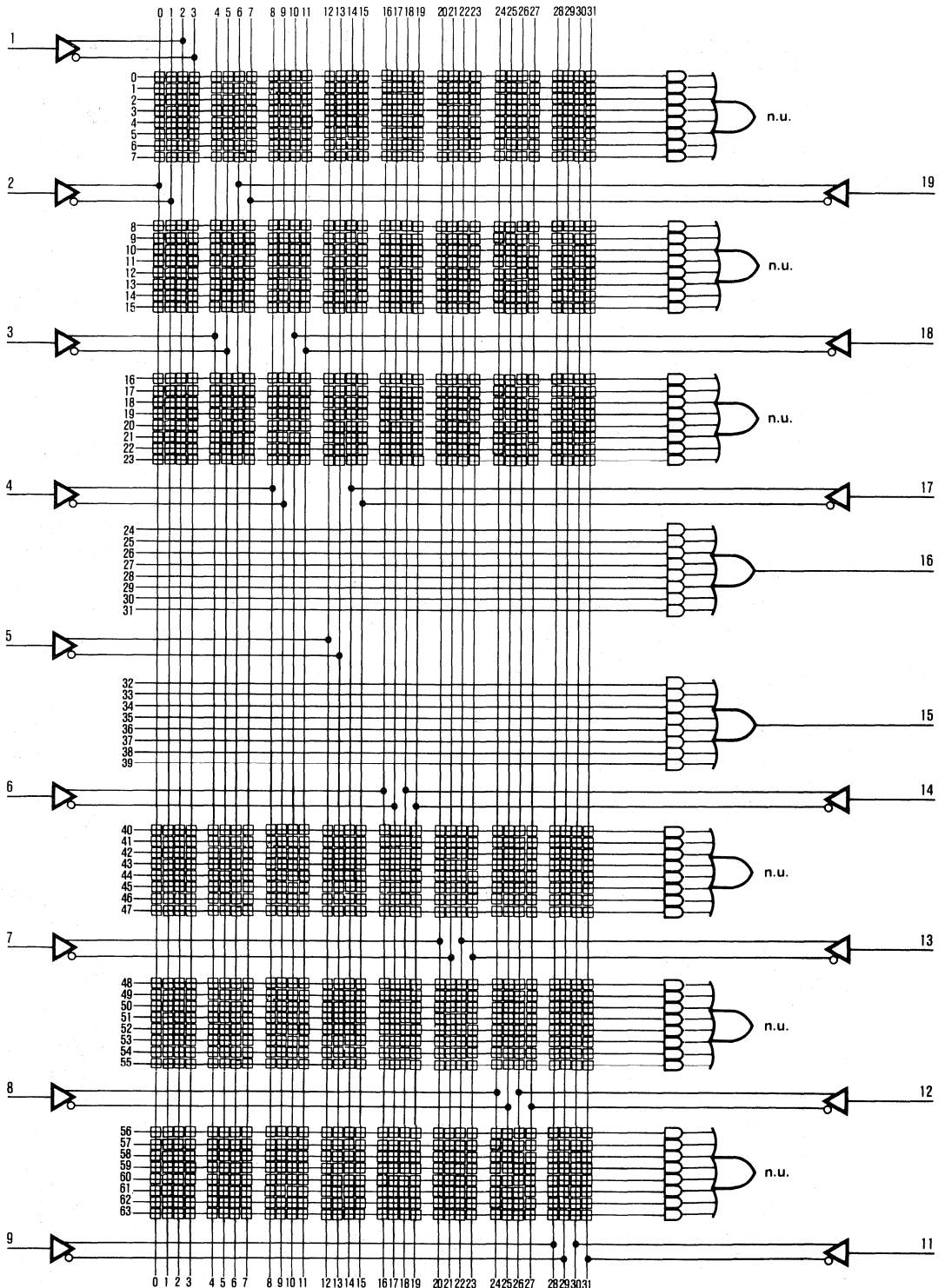
INPUTS (0-31)

Table with columns 0-31 and rows for words (0-39) and outputs (O4, O3, O2, O1). Each cell contains a character representing the value at that intersection.

6

INPUTS (0-31)

PRODUCT TERMS (0-63)

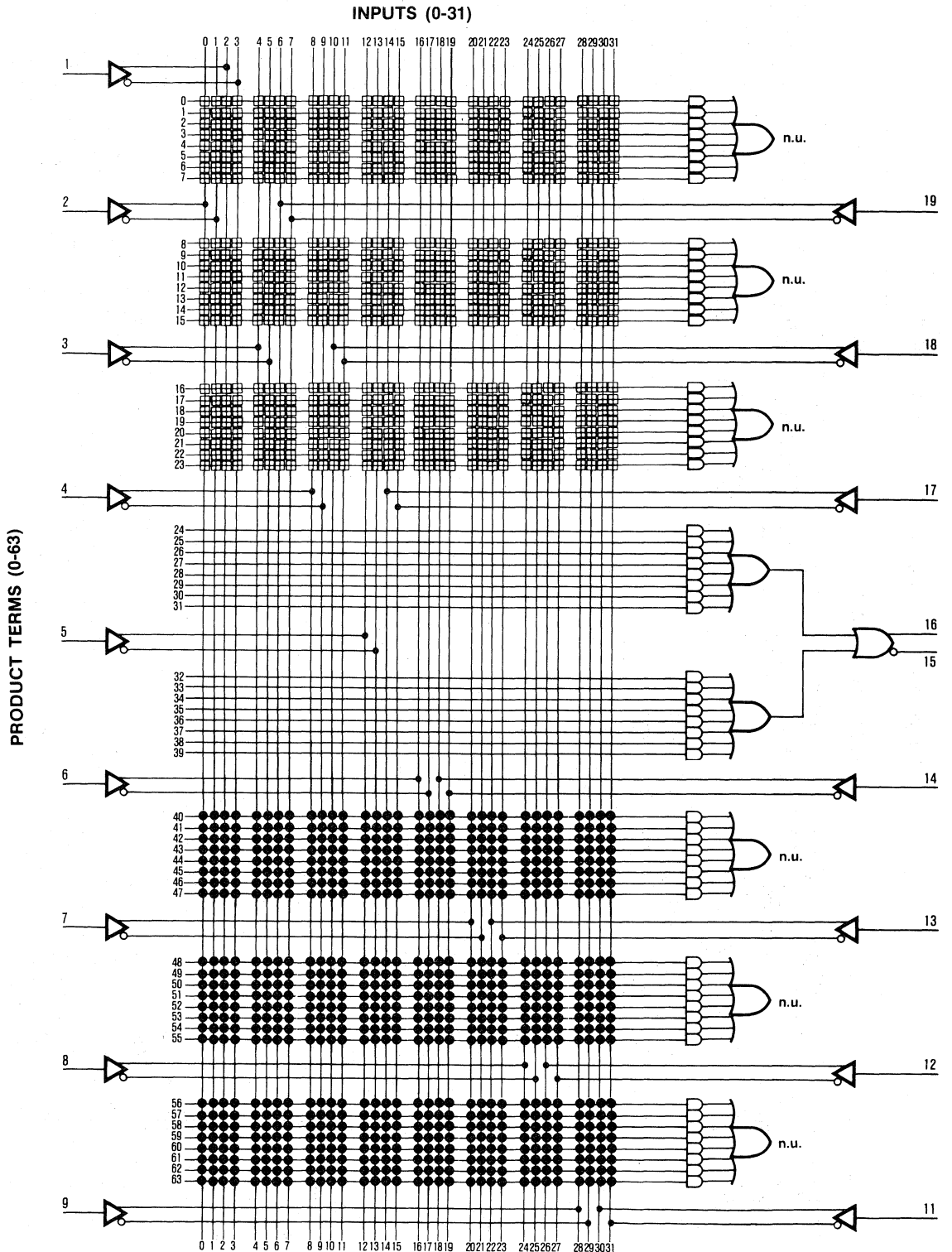


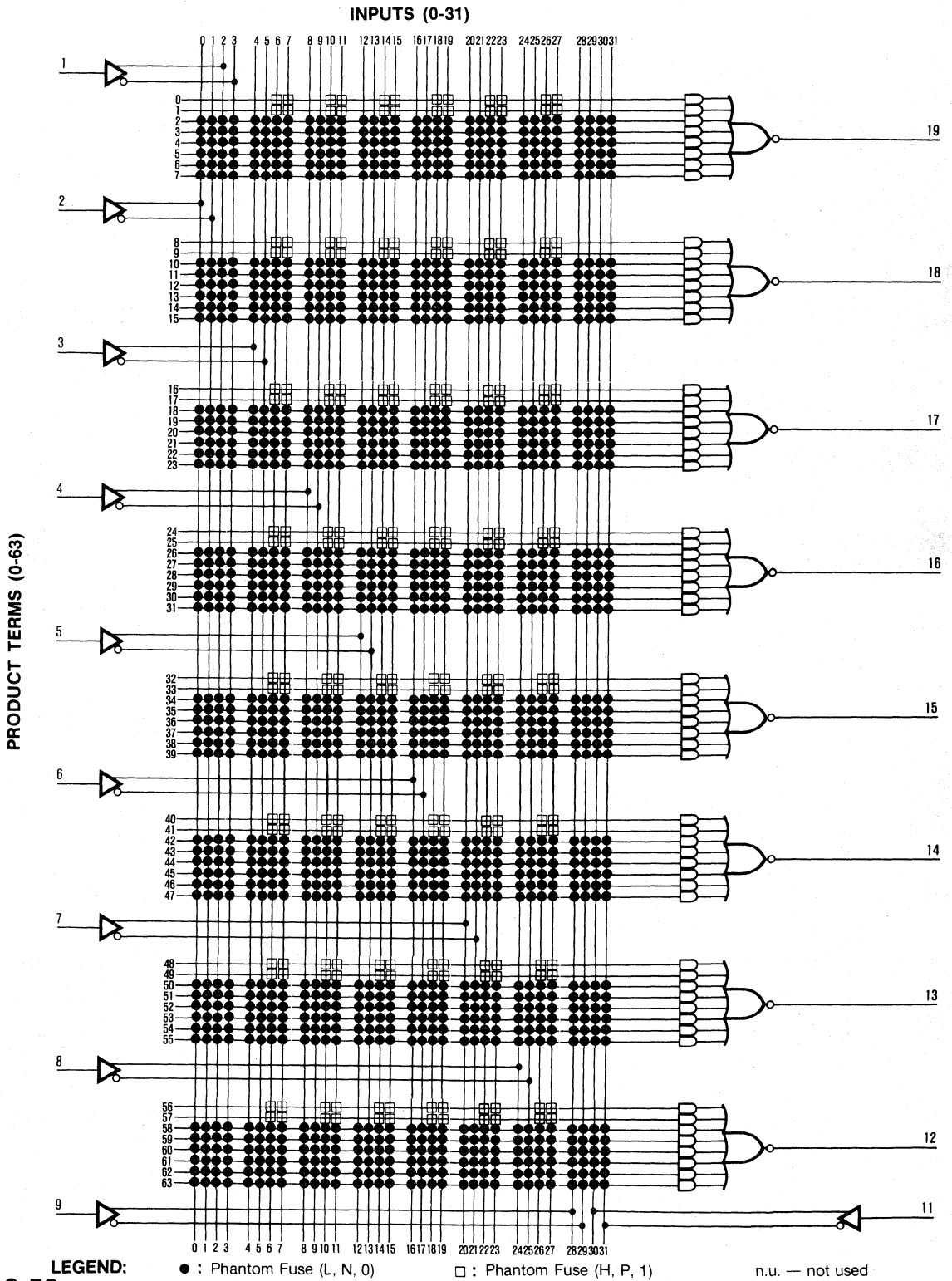
LEGEND:

● : Phantom Fuse (L, N, 0)

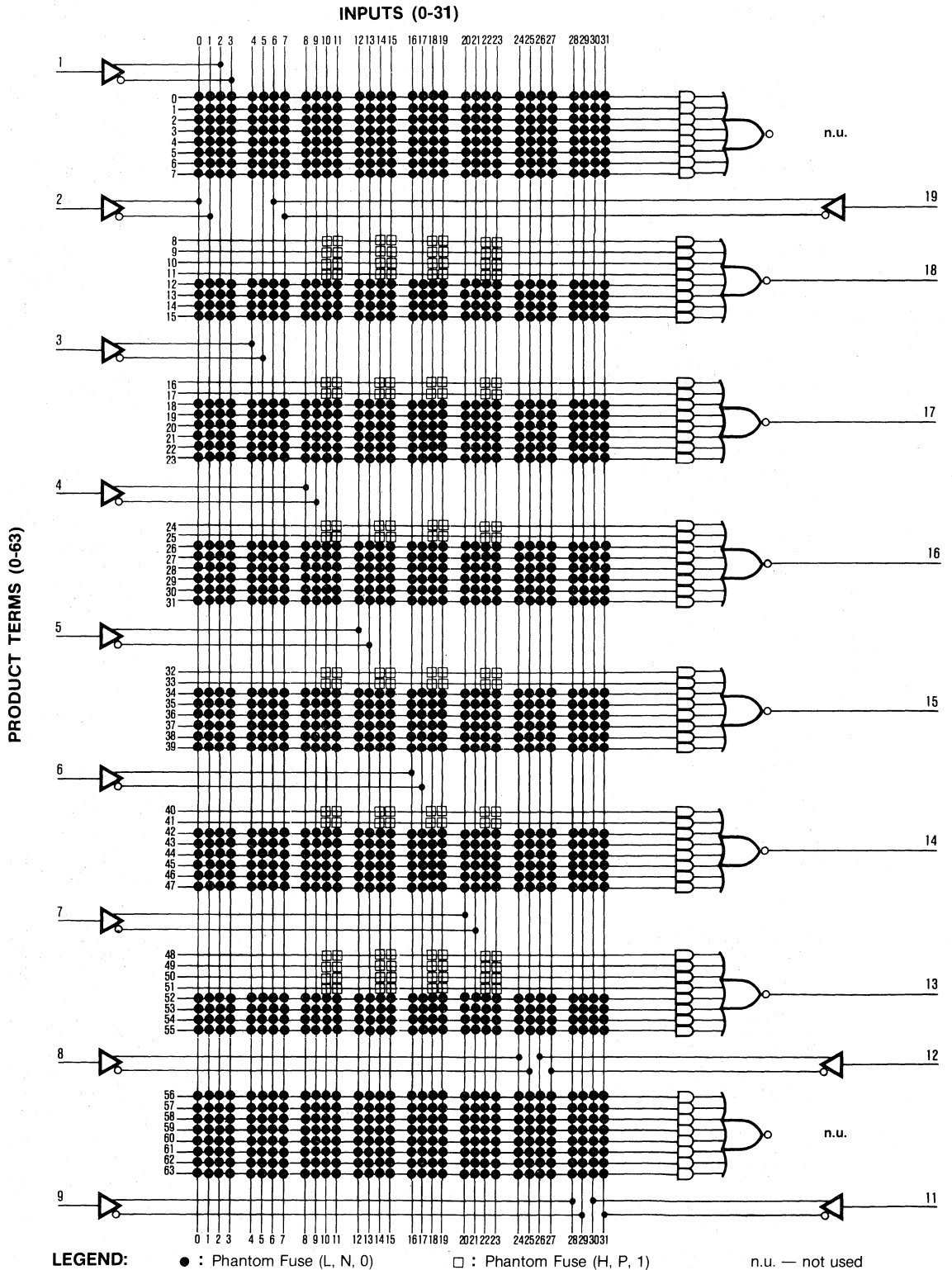
□ : Phantom Fuse (H, P, 1)

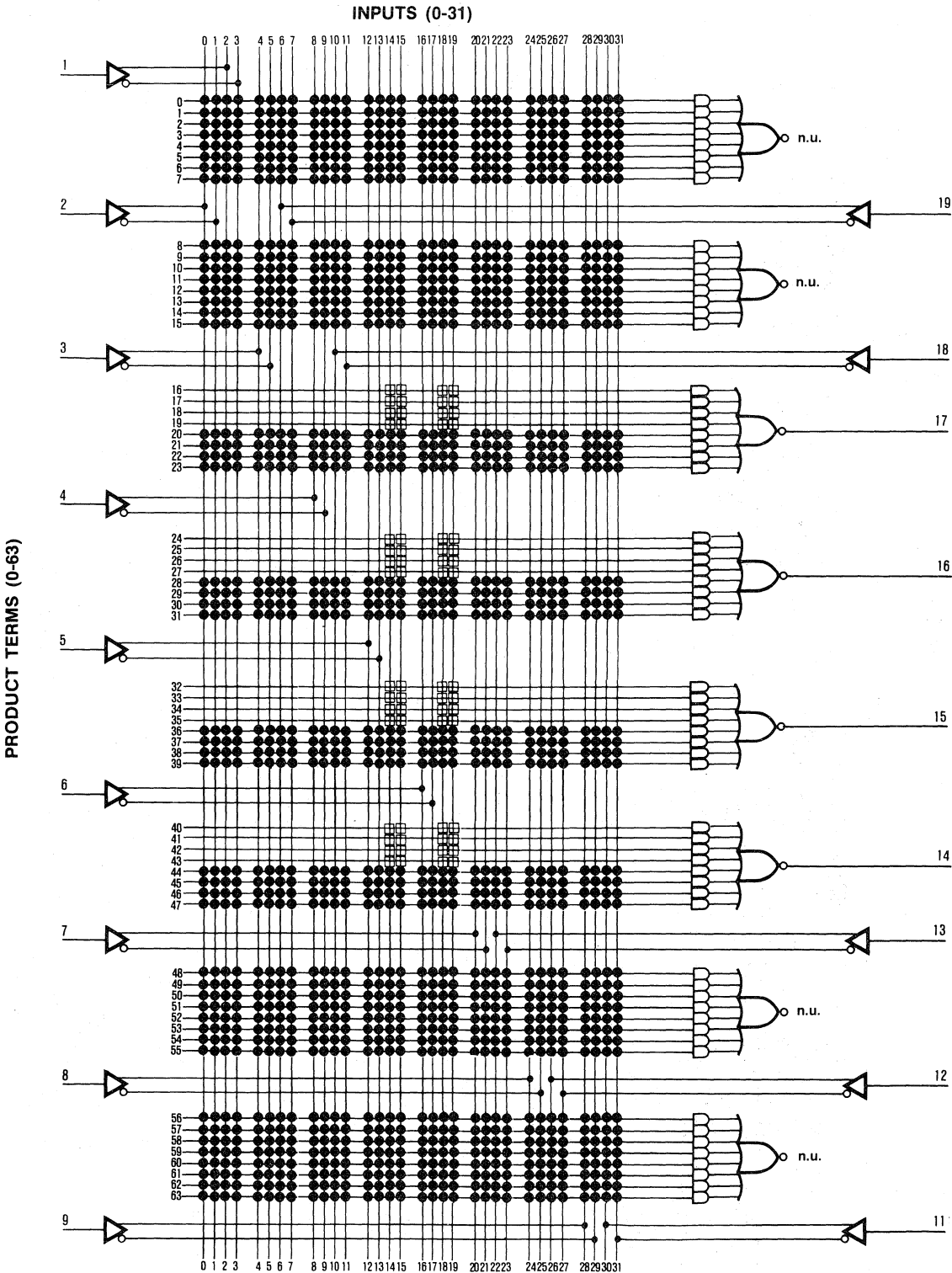
n.u. — not used

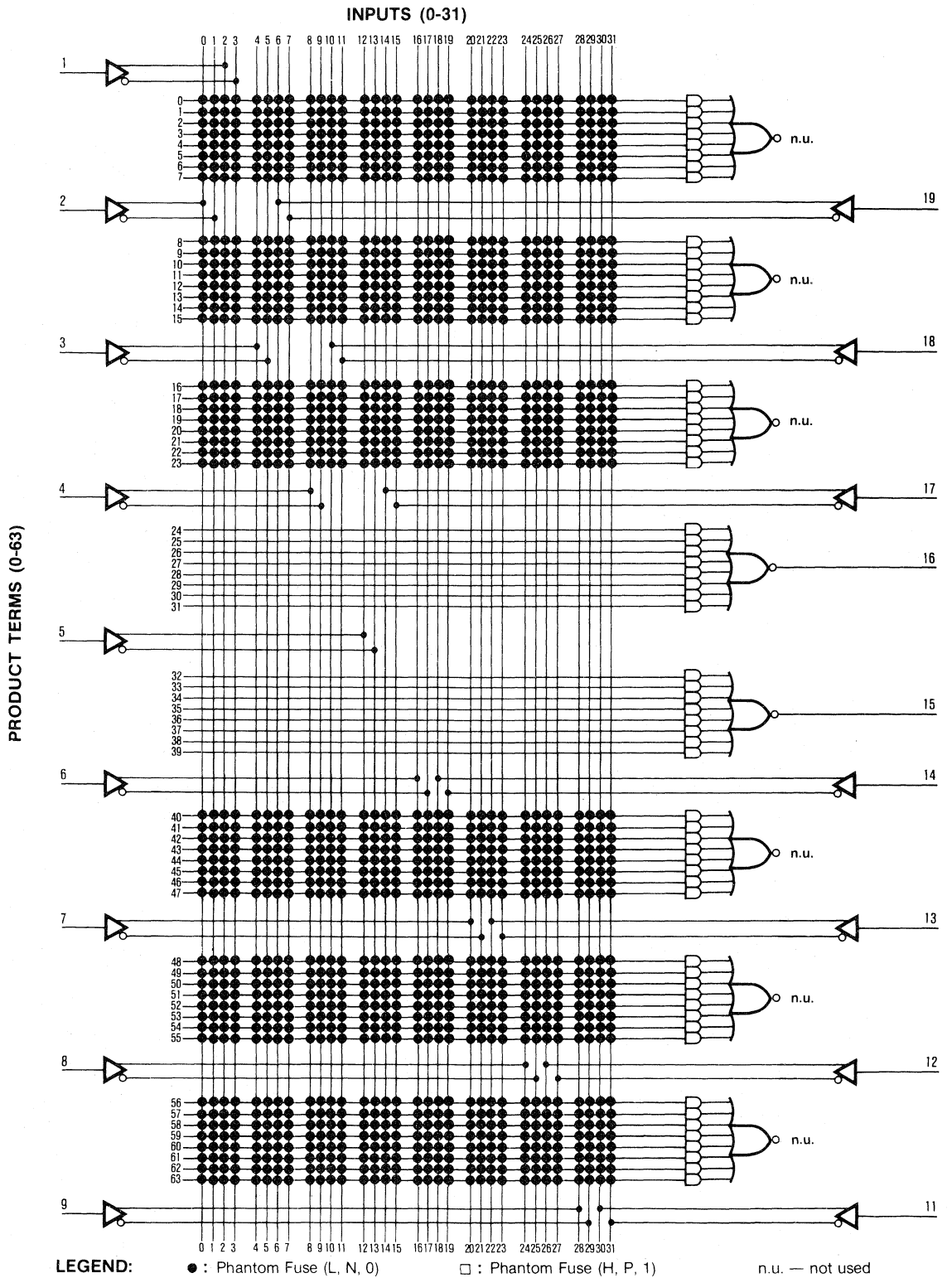




Logic Diagram PAL12L6







PAL16L2

Programming Format

PATTERN:

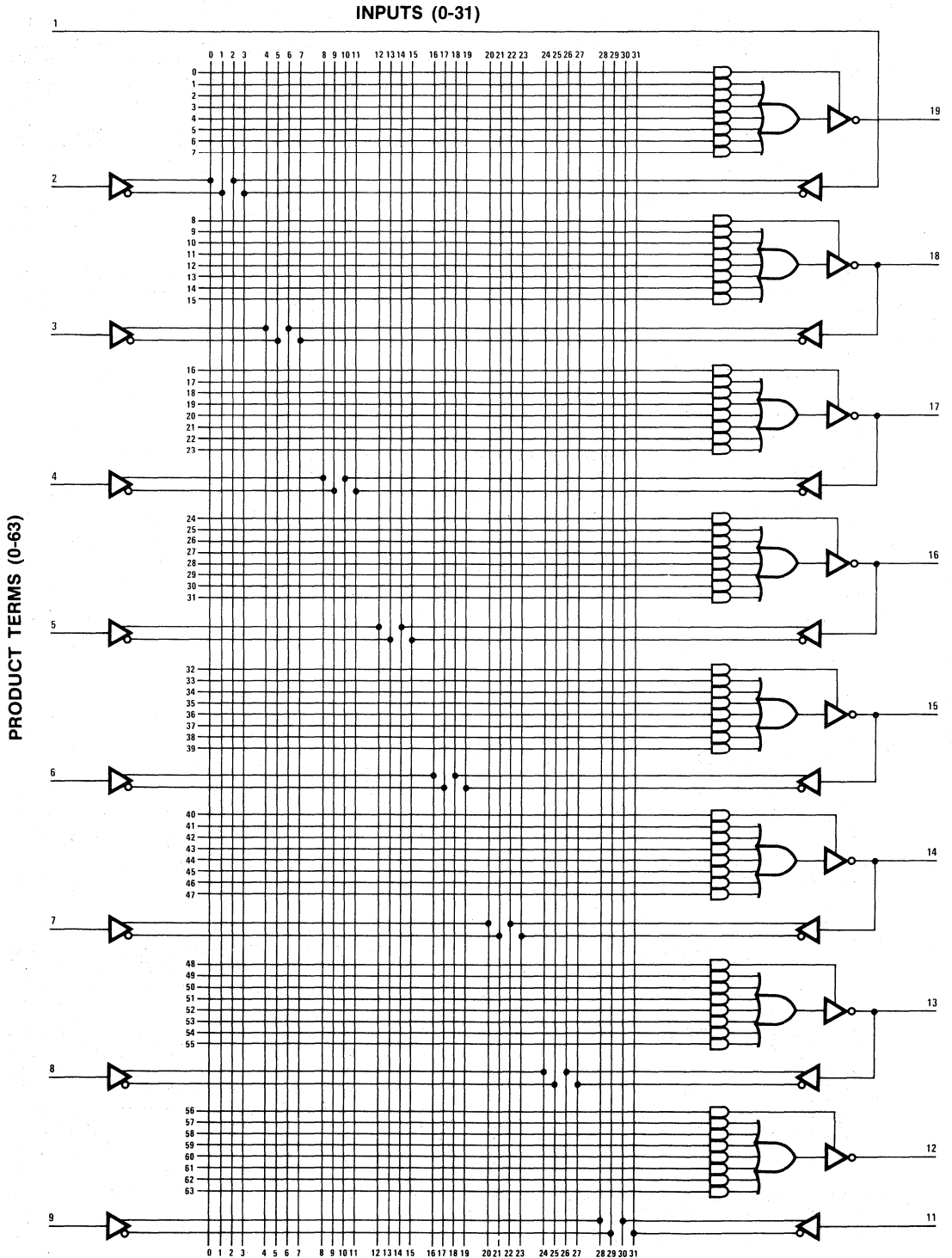
NAME:

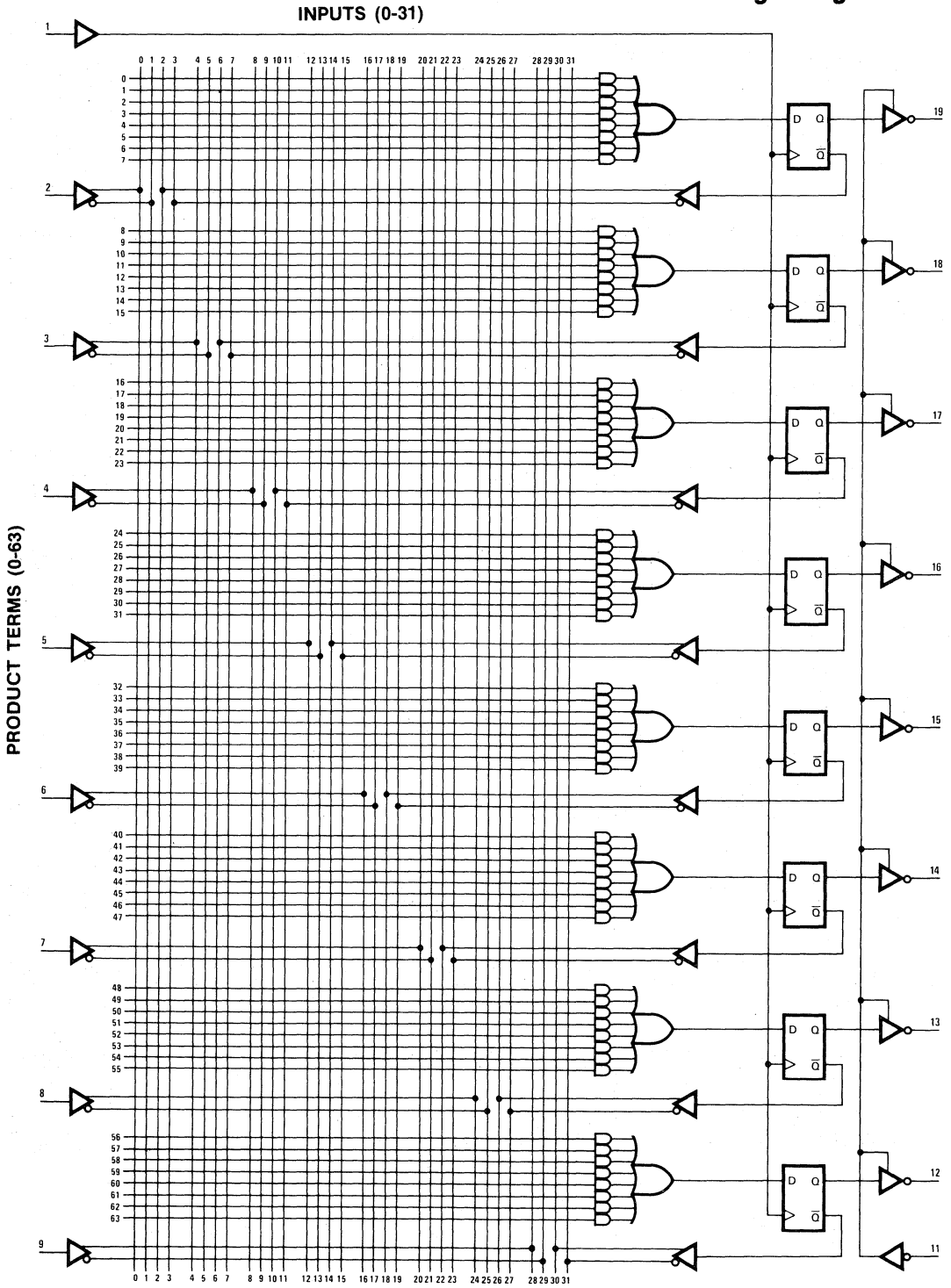
PRODUCT TERMS (0-63)

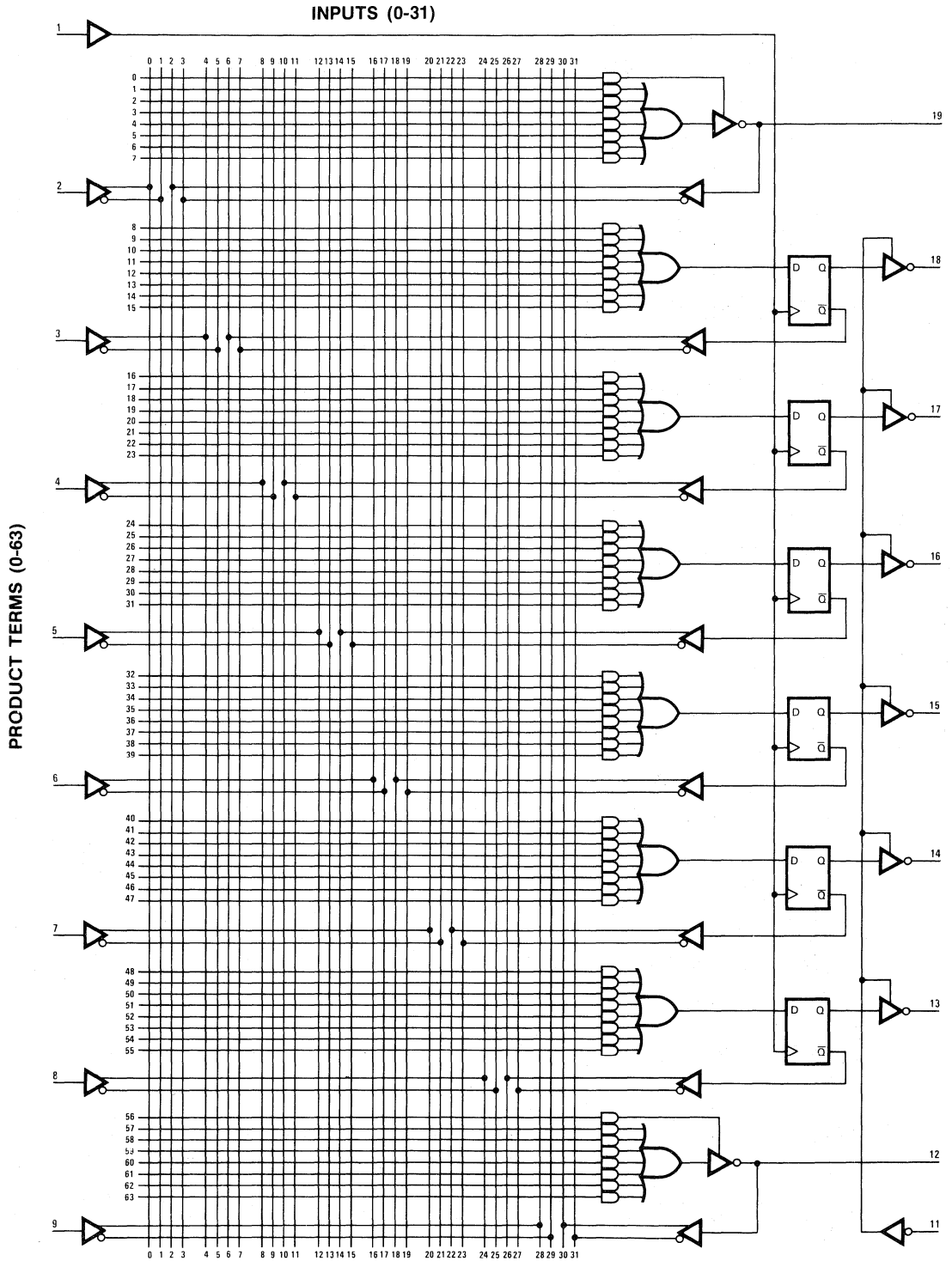
DATE:

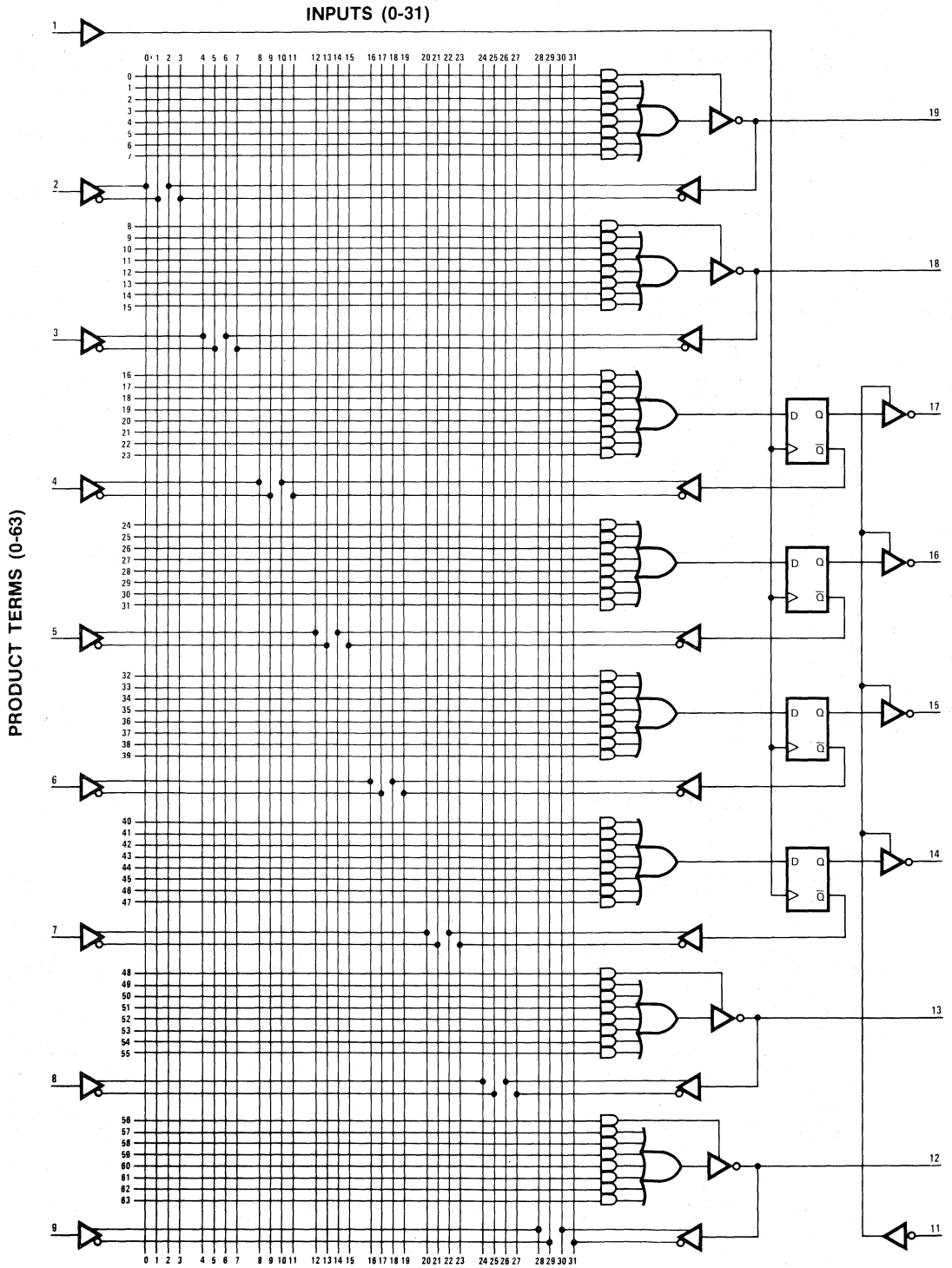
INPUTS (0-31)

	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25	26	27	28	29	30	31	
WORD	0	1	2	3	4	5	6	7	8	9	A	B	C	D	E	F	10	11	12	13	14	15	16	17	18	19	1A	1B	1C	1D	1E	1F	
O ₄	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	
O ₃	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	
O ₂	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	
O ₁	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	L	
WORD	20	21	22	23	24	25	26	27	28	29	2A	2B	2C	2D	2E	2F	30	31	32	33	34	35	36	37	38	39	3A	3B	3C	3D	3E	3F	
WORD	25	26	27	28	29	2A	2B	2C	2D	2E	2F	30	31	32	33	34	35	36	37	38	39	3A	3B	3C	3D	3E	3F						
WORD	40	41	42	43	44	45	46	47	48	49	4A	4B	4C	4D	4E	4F	50	51	52	53	54	55	56	57	58	59	5A	5B	5C	5D	5E	5F	
WORD	60	61	62	63	64	65	66	67	68	69	6A	6B	6C	6D	6E	6F	70	71	72	73	74	75	76	77	78	79	7A	7B	7C	7D	7E	7F	
WORD	80	81	82	83	84	85	86	87	88	89	8A	8B	8C	8D	8E	8F	90	91	92	93	94	95	96	97	98	99	9A	9B	9C	9D	9E	9F	
WORD	A0	A1	A2	A3	A4	A5	A6	A7	A8	A9	AA	AB	AC	AD	AE	AF	B0	B1	B2	B3	B4	B5	B6	B7	B8	B9	BA	BB	BC	BD	BE	BF	
WORD	C0	C1	C2	C3	C4	C5	C6	C7	C8	C9	CA	CB	CC	CD	CE	CF	D0	D1	D2	D3	D4	D5	D6	D7	D8	D9	DA	DB	DC	DD	DE	DF	
WORD	E0	E1	E2	E3	E4	E5	E6	E7	E8	E9	EA	EB	EC	ED	EE	EF	F0	F1	F2	F3	F4	F5	F6	F7	F8	F9	FA	FB	FC	FD	FE	FF	
WORD	100	101	102	103	104	105	106	107	108	109	10A	10B	10C	10D	10E	10F	110	111	112	113	114	115	116	117	118	119	11A	11B	11C	11D	11E	11F	
WORD	120	121	122	123	124	125	126	127	128	129	12A	12B	12C	12D	12E	12F	130	131	132	133	134	135	136	137	138	139	13A	13B	13C	13D	13E	13F	
WORD	140	141	142	143	144	145	146	147	148	149	14A	14B	14C	14D	14E	14F	150	151	152	153	154	155	156	157	158	159	15A	15B	15C	15D	15E	15F	
WORD	160	161	162	163	164	165	166	167	168	169	16A	16B	16C	16D	16E	16F	170	171	172	173	174	175	176	177	178	179	17A	17B	17C	17D	17E	17F	
WORD	180	181	182	183	184	185	186	187	188	189	18A	18B	18C	18D	18E	18F	190	191	192	193	194	195	196	197	198	199	19A	19B	19C	19D	19E	19F	
WORD	1A0	1A1	1A2	1A3	1A4	1A5	1A6	1A7	1A8	1A9	1AA	1AB	1AC	1AD	1AE	1AF	1B0	1B1	1B2	1B3	1B4	1B5	1B6	1B7	1B8	1B9	1BA	1BB	1BC	1BD	1BE	1BF	
WORD	1C0	1C1	1C2	1C3	1C4	1C5	1C6	1C7	1C8	1C9	1CA	1CB	1CC	1CD	1CE	1CF	1D0	1D1	1D2	1D3	1D4	1D5	1D6	1D7	1D8	1D9	1DA	1DB	1DC	1DD	1DE	1DF	
WORD	1E0	1E1	1E2	1E3	1E4	1E5	1E6	1E7	1E8	1E9	1EA	1EB	1EC	1ED	1EE	1EF	1F0	1F1	1F2	1F3	1F4	1F5	1F6	1F7	1F8	1F9	1FA	1FB	1FC	1FD	1FE	1FF	







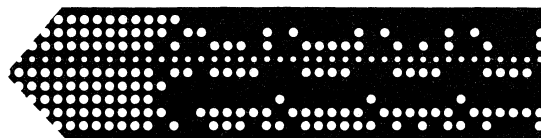


PAL Programming

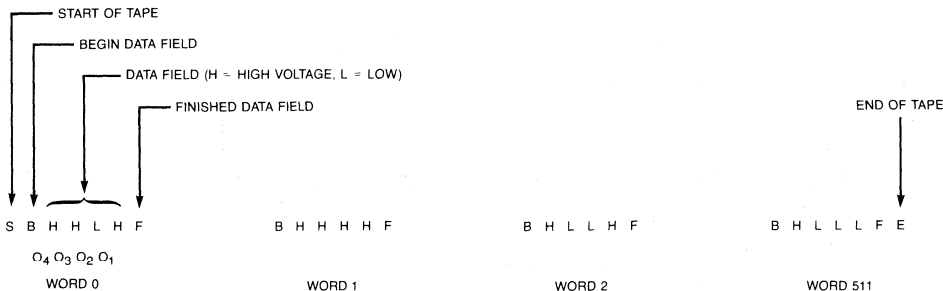
Paper Tape Inputs

Truth tables can be sent to MMI in an ASCII tape format. Information can be sent by mail or TWX. (MMI's TWX number is 910-339-9229.) Although MMI can program PALs with the tape in any format, the following formats have been the most popular.

8 Level TWX



BHLF Format



The required heading information at the beginning of the tape is as follows:

CUSTOMER'S NAME AND PHONE _____	CUSTOMER SYMBOLIZED PART NUMBER _____
CUSTOMER'S TWX NUMBER (IF ANY) _____	TRUTH TABLE NUMBER (IF ANY) _____
PURCHASE ORDER NUMBER _____	TYPE OF FORMAT (IF ASCII, HEX, BHLF, ETC.) _____
MMI PART NUMBER _____	25 BELL OR RUBOUT CHARACTERS _____

An example is shown below:

```
BLARNEY ELECTRONICS 408-735-8104  
TWX911-338-9225  
PO142  
PAL16R8  
0431  
PAT0001  
BHLF
```

(25 Bell or Rubout Characters)

```
S  
BLLLHF BLLLLF BLHLHF BLHHHF BLLHHF BHHHHF BLLLHF BLHLHF  
. . . . .  
. . . . .  
BLLLLF BLHLHF BLHHHF BLLHHF BHHHHF BLLLHF BLHLHF BLLLLF  
E
```

BPNF Format

This format is identical to the BHLF format with the exception that a "P" designates a positive bit, and hence a "high" level, and an "N" represents a negative bit, and hence a "low" level.

Hexadecimal Format

In this format the heading required is identical to the BHLF format but the data is different. Instead of an "S," the hexadecimal

data begins with the SOH or STX character (control A). The data is then represented by the hexadecimal character (0-9 and A-F) which represents the output data of address 0, followed by a space.

Next comes the output data of address 1 followed by a space, etc. The character ETX (control C) is used to end the data. Carriage return and line feed may be included to format the data when the tape is printed.

Applications



6

Example 1: Basic Gates

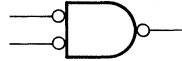
$$B = \neg A$$



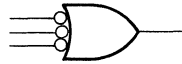
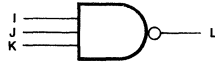
$$E = C \cdot D$$



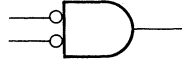
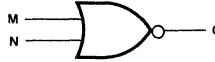
$$H = F + G$$



$$L = \neg I + \neg J + \neg K$$

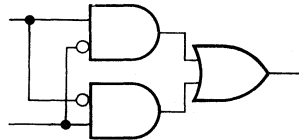


$$O = \neg M \cdot \neg N$$



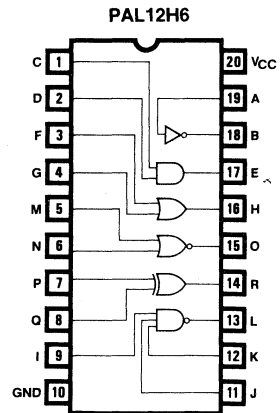
$$R = P \oplus Q$$

$$= P \cdot \neg Q + \neg P \cdot Q$$



This example demonstrates how fusible logic can implement the basic inverter, AND, OR, NAND, NOR, and exclusive-OR functions. Note the one to one correspondence between conventional logic symbology and PAL logic symbology. The PAL12H6 is selected because it has 12 inputs and 6 outputs. For this example, the fuse pattern is generated using

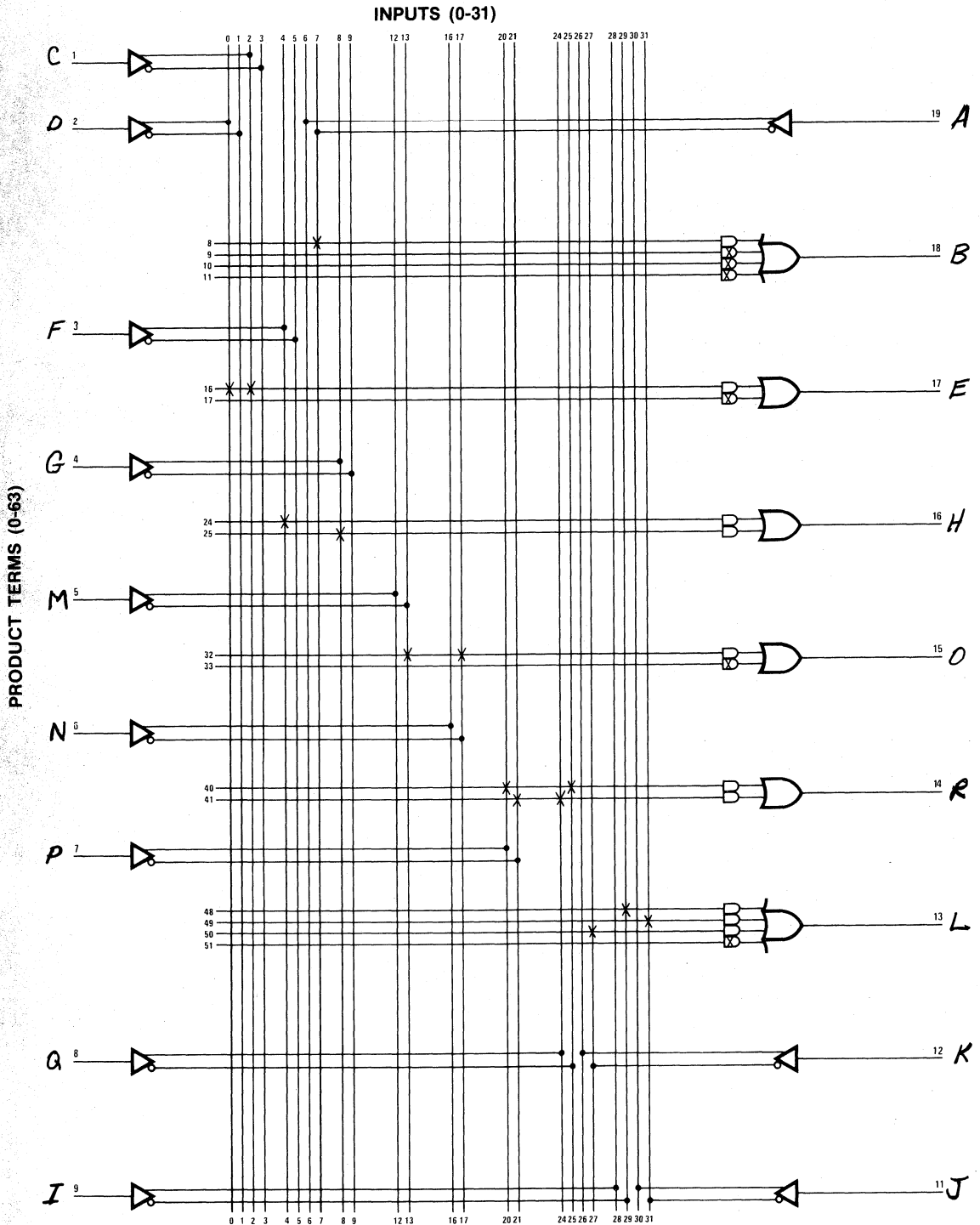
- a) PALASM
- b) Manual Programming Format (BHLF) Manual Coding



PAL Applications

Basic Gates

Logic Diagram PAL12H6



6

PAL Applications

PALASM Output: Basic Gates

Fuse Plot PAL12H6

```

          11 1111 1111 2222 2222 2233
0123 4567 8901 2345 6789 0123 4567 8901

0 0000 0000 0000 0000 0000 0000 0000 0000
1 0000 0000 0000 0000 0000 0000 0000 0000
2 0000 0000 0000 0000 0000 0000 0000 0000
3 0000 0000 0000 0000 0000 0000 0000 0000
4 0000 0000 0000 0000 0000 0000 0000 0000
5 0000 0000 0000 0000 0000 0000 0000 0000
6 0000 0000 0000 0000 0000 0000 0000 0000
7 0000 0000 0000 0000 0000 0000 0000 0000

8 ---- -X- --00 --00 --00 --00 ---- /A
9 XXXX XXXX XX00 XX00 XX00 XX00 XXXX XXXX
10 XXXX XXXX XX00 XX00 XX00 XX00 XXXX XXXX
11 XXXX XXXX XX00 XX00 XX00 XX00 XXXX XXXX
12 0000 0000 0000 0000 0000 0000 0000 0000
13 0000 0000 0000 0000 0000 0000 0000 0000
14 0000 0000 0000 0000 0000 0000 0000 0000
15 0000 0000 0000 0000 0000 0000 0000 0000

16 X-X- ---- --00 --00 --00 --00 ---- C*D
17 XXXX XXXX XX00 XX00 XX00 XX00 XXXX XXXX
18 0000 0000 0000 0000 0000 0000 0000 0000
19 0000 0000 0000 0000 0000 0000 0000 0000
20 0000 0000 0000 0000 0000 0000 0000 0000
21 0000 0000 0000 0000 0000 0000 0000 0000
22 0000 0000 0000 0000 0000 0000 0000 0000
23 0000 0000 0000 0000 0000 0000 0000 0000

24 ---- X--- --00 --00 --00 --00 ---- F
25 ---- ---- X-00 --00 --00 --00 ---- G
26 0000 0000 0000 0000 0000 0000 0000 0000
27 0000 0000 0000 0000 0000 0000 0000 0000
28 0000 0000 0000 0000 0000 0000 0000 0000
29 0000 0000 0000 0000 0000 0000 0000 0000
30 0000 0000 0000 0000 0000 0000 0000 0000
31 0000 0000 0000 0000 0000 0000 0000 0000

32 ---- ---- --00 -X00 -X00 --00 ---- /M*/N
33 XXXX XXXX XX00 XX00 XX00 XX00 XXXX XXXX
34 0000 0000 0000 0000 0000 0000 0000 0000
35 0000 0000 0000 0000 0000 0000 0000 0000
36 0000 0000 0000 0000 0000 0000 0000 0000
37 0000 0000 0000 0000 0000 0000 0000 0000
38 0000 0000 0000 0000 0000 0000 0000 0000
39 0000 0000 0000 0000 0000 0000 0000 0000

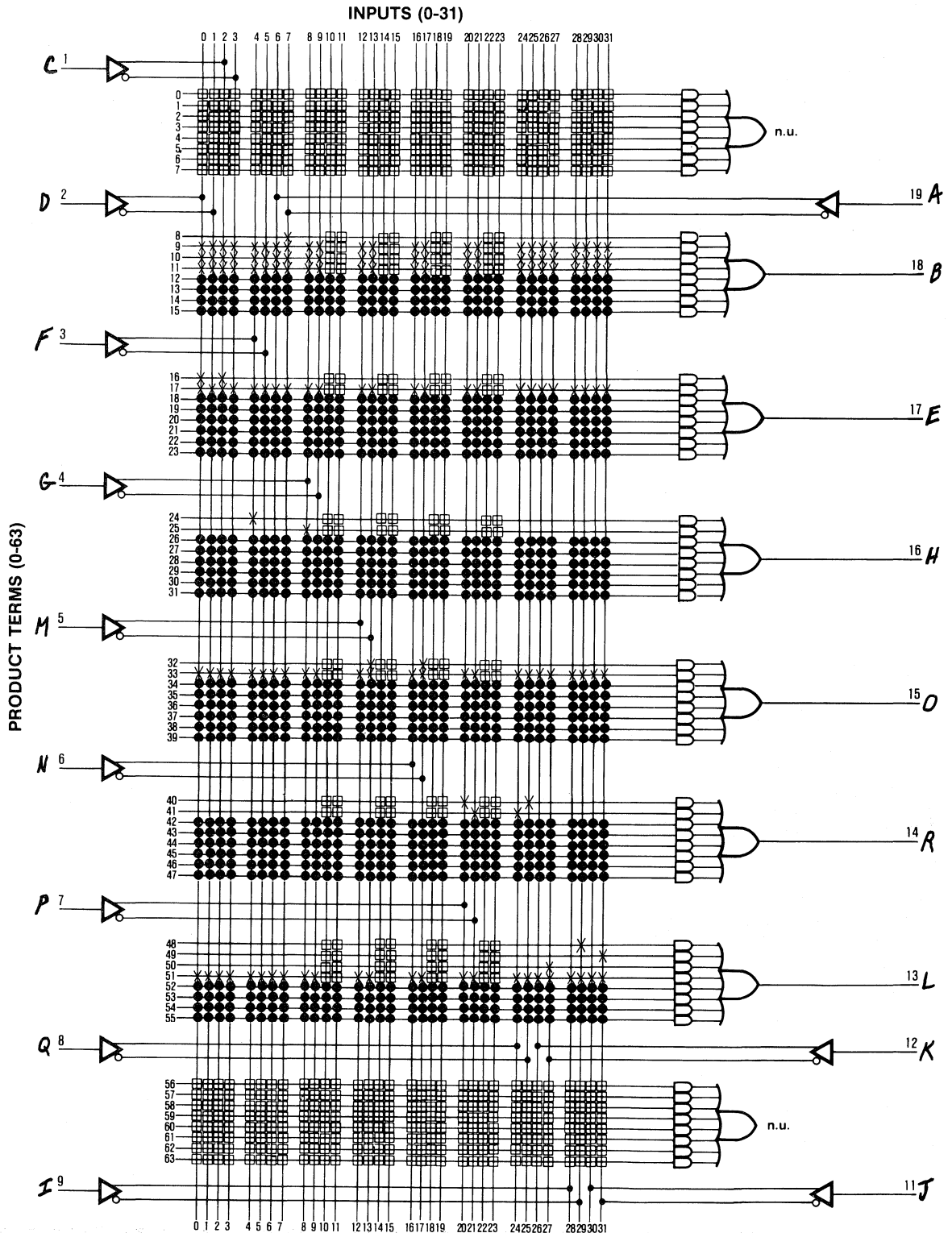
40 ---- ---- --00 --00 --00 X-00 -X-- ---- P*/Q
41 ---- ---- --00 --00 --00 -X00 X--- ---- /P*Q
42 0000 0000 0000 0000 0000 0000 0000 0000
43 0000 0000 0000 0000 0000 0000 0000 0000
44 0000 0000 0000 0000 0000 0000 0000 0000
45 0000 0000 0000 0000 0000 0000 0000 0000
46 0000 0000 0000 0000 0000 0000 0000 0000
47 0000 0000 0000 0000 0000 0000 0000 0000

48 ---- ---- --00 --00 --00 --00 ---- -X-- /I
49 ---- ---- --00 --00 --00 --00 ---- --X /J
50 ---- ---- --00 --00 --00 --00 ---- --X /K
51 XXXX XXXX XX00 XX00 XX00 XX00 XXXX XXXX
52 0000 0000 0000 0000 0000 0000 0000 0000
53 0000 0000 0000 0000 0000 0000 0000 0000
54 0000 0000 0000 0000 0000 0000 0000 0000
55 0000 0000 0000 0000 0000 0000 0000 0000

56 0000 0000 0000 0000 0000 0000 0000 0000
57 0000 0000 0000 0000 0000 0000 0000 0000
58 0000 0000 0000 0000 0000 0000 0000 0000
59 0000 0000 0000 0000 0000 0000 0000 0000
60 0000 0000 0000 0000 0000 0000 0000 0000
61 0000 0000 0000 0000 0000 0000 0000 0000
62 0000 0000 0000 0000 0000 0000 0000 0000
63 0000 0000 0000 0000 0000 0000 0000 0000

```

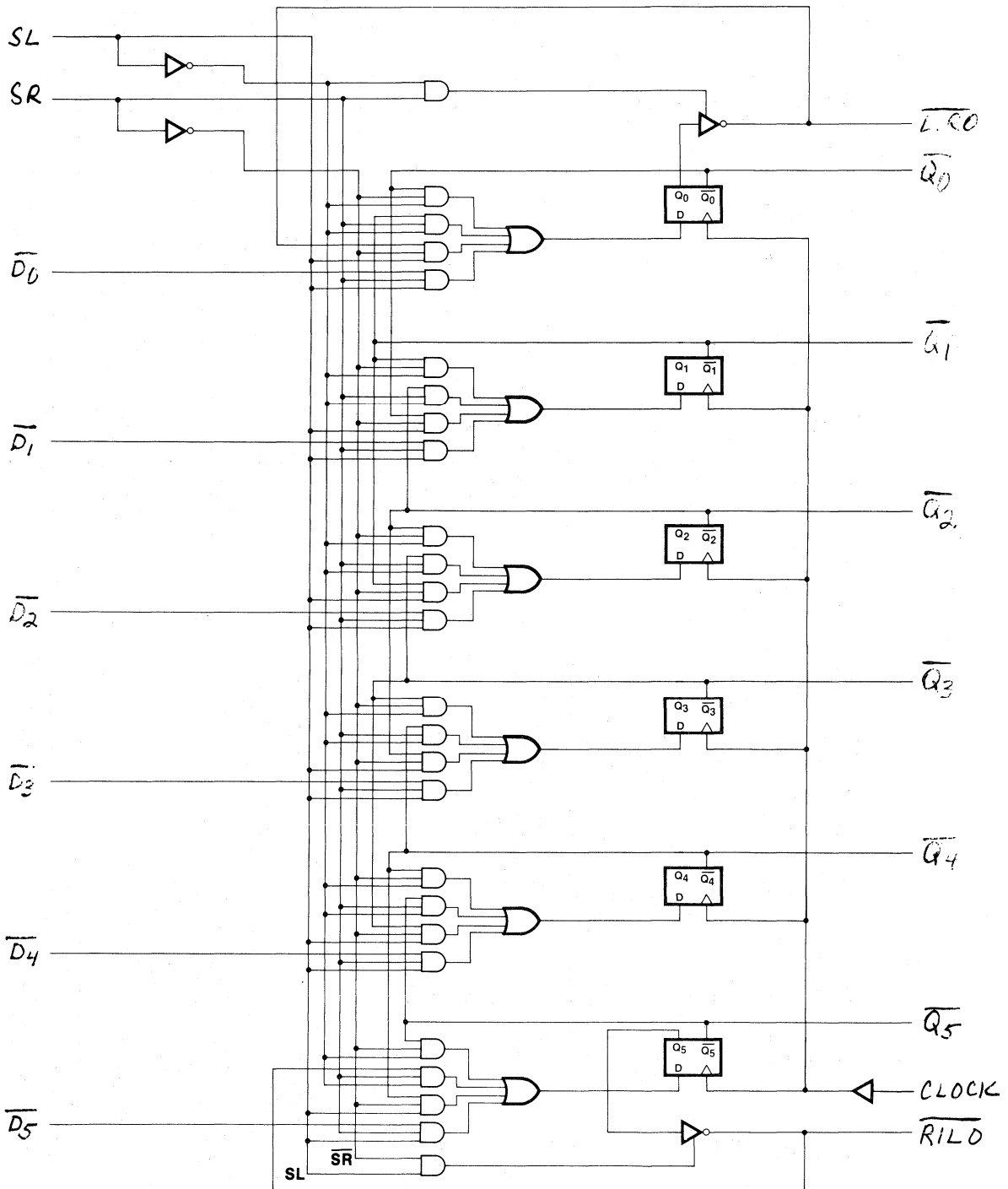
LEGEND: X : FUSE NOT BLOWN (L,N,0) - : FUSE BLOWN (H,P,1)
0 : PHANTOM FUSE (L,N,0) O : PHANTOM FUSE (H,P,1)



6-84 LEGEND:

- : Phantom Fuse (L, N, O)
- : Phantom Fuse (H, P, 1)
- n.u. — not used

**Example 2:
6-Bit Shift Register with Three-State Outputs**



PAL Applications

PALASM Output: 6-Bit Shift Register with Three-State Outputs

Design Specification PAL16R6

```
***** P00206 *****
YOUR PAL DESIGN SPEC IS ACCEPTED AS MONOLITHIC MEMORIES BIT
PATTERN NUMBER P00206 . YOUR PASSWORD IS PAT0005 .
PLEASE CONFIRM THAT THESE EQUATIONS ARE CORRECT. MONOLITHIC
MEMORIES WILL NOT PROCESS A PRODUCTION ORDER WITHOUT PROPER
APPROVAL. USE BP NO. P00206 WHEN PLACING A PROGRAMMING ORDER.
*****
```

CUSTOMER CONFIRMATION

I HAVE REVIEWED THIS PAL DESIGN SPECIFICATION AND UNDERSTAND THAT PALS ORDERED BY BIT PATTERN NUMBER P00206 WILL BE PROGRAMMED AS SPECIFIED BELOW.

CUSTOMER COMPANY NAME _____ CITY, STATE _____
 AUTHORISED SIGNATURE _____ DATE _____
 NAME (PRINT) _____ TITLE _____

RETURN TO MMI 1165 E. ARQUES SUNNYVALE, CA 94086 ATTN: _____

```
PAL16R6                PAL DESIGN SPECIFICATION
PAT0005                JOHN BIRKNER 11/20/77
6-BIT SHIFT REGISTER WITH THREE-STATE OUTPUTS
MMI,SV
CK SR D0 D1 D2 D3 D4 D5 SL GND /E RILO Q5 Q4 Q3 Q2 Q1 Q0 LIRO VCC
```

```
IF(SR*/SL) /LIRO=/Q0
/Q0 := /SR*/SL*/Q0 + SR*/SL*/Q1 + /SR*/SL*/LIRO + SR*/SL*/D0
/Q1 := /SR*/SL*/Q1 + SR*/SL*/Q2 + /SR*/SL*/Q0 + SR*/SL*/D1
/Q2 := /SR*/SL*/Q2 + SR*/SL*/Q3 + /SR*/SL*/Q1 + SR*/SL*/D2
/Q3 := /SR*/SL*/Q3 + SR*/SL*/Q4 + /SR*/SL*/Q2 + SR*/SL*/D3
/Q4 := /SR*/SL*/Q4 + SR*/SL*/Q5 + /SR*/SL*/Q3 + SR*/SL*/D4
/Q5 := /SR*/SL*/Q5 + SR*/SL*/RILO + /SR*/SL*/Q4 + SR*/SL*/D5
IF(/SR*/SL) /RILO=/Q5
```

DESCRIPTION:
 THE 6-BIT SHIFT REGISTER WILL HOLD , SHIFT RIGHT, SHIFT LEFT, OR LOAD ON THE RISING EDGE OF THE CLOCK (CK).
 THE THREE STATE OUTPUTS ARE HIGH-Z WHEN THE ENABLE LINE (/E) IS HIGH AND ENABLED WHEN ENABLE LINE (/E) IS LOW.

FUNCTION TABLE:

INPUTS					OUTPUTS									
! SL	SR	! RILO	! LIRO	! CLOCK	! RILO	Q5	Q4	Q3	Q2	Q1	Q0	! LIRO	! OPERATION	
! L	L	! X	! X	! L-H	! Z	! Q5	Q4	Q3	Q2	Q1	Q0	! Z	! HOLD	
! L	H	! RI	! X	! L-H	! Z	! R1	Q5	Q4	Q3	Q2	Q1	! Q1	! RIGHT SHFT!	
! H	L	! X	! LI	! L-H	! Q4	! Q4	Q3	Q2	Q1	Q0	LI	! Z	! LEFT SHFT!	
! H	H	! X	! X	! L-H	! Z	! D5	D4	D3	D2	D1	D0	! Z	! LOAD D	

NUMBER OF FUSES BLOWN = 818

PALASM Output

HEX FORMAT

```
E 1 F F F F F D F F F B F F F F 7 F F F F F F F F F F F F F F F F F F .
1 F F F F F F F E F F F D F F F F B F F F F 7 F F F F F F F F F F F 1 F F .
E 0 E C E E E A E E E E 6 E E E E E E E E E E E E E E E E E 0 E E E .
0 E E E E C E E E A E E E 6 E E E E E E E E E E E E E E E E E 0 E E E .
0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 .
0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 .
0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 .
F 0 F F F F F F F F F F F F F F F F F F F F F F F D F F F F B 7 8 F F .
8 F F F F F F F F F F F F F F F F F F F F F F F F F F F F F 5 F 8 F B .
7 0 7 7 7 7 7 7 7 7 7 7 7 7 7 7 7 6 7 7 7 5 7 7 7 3 7 7 7 7 7 7 7 7 .
0 7 7 7 7 7 7 7 7 7 7 7 7 7 7 7 7 6 7 7 7 5 7 7 7 3 7 7 7 7 7 7 7 7 .
0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 .
0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 .
0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 .
0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 .
```



PAL Applications

PALASM Output: 6-Bit Shift Register with Three-State Outputs

Fuse Plot PAL16R6

```

          11 1111 1111 2222 2222 2233
0123 4567 8901 2345 6789 0123 4567 8901

0 X--- ---- ---- ---- ---- ---- -X-- SR*/SL
1 ---- -X- ---- ---- ---- ---- ---- /Q0
2 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
3 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
4 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
5 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
6 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
7 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX

8 -X-- ---- -X- ---- ---- ---- ---- -X-- /SR*/SL*/Q0
9 X--- ---- -X- ---- ---- ---- ---- -X-- SR*/SL*/Q1
10 -X-X ---- ---- ---- ---- ---- -X-- /SR*SL*/LIRO
11 X--- -X- ---- ---- ---- ---- -X-- SR*SL*/D0
12 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
13 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
14 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
15 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX

16 -X-- ---- -X- ---- ---- ---- ---- -X-- /SR*/SL*/Q1
17 X--- ---- -X- ---- -X- ---- ---- -X-- SR*/SL*/Q2
18 -X-- ---- -X- ---- ---- ---- ---- -X-- /SR*SL*/Q0
19 X--- ---- -X- ---- ---- ---- ---- -X-- SR*SL*/D1
20 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
21 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
22 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
23 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX

24 -X-- ---- -X- ---- -X- ---- ---- -X-- /SR*/SL*/Q2
25 X--- ---- -X- ---- -X- ---- ---- -X-- SR*/SL*/Q3
26 -X-- ---- -X- ---- ---- ---- ---- -X-- /SR*SL*/Q1
27 X--- ---- -X- ---- ---- ---- ---- -X-- SR*SL*/D2
28 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
29 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
30 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
31 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX

32 -X-- ---- -X- ---- -X- ---- ---- -X-- /SR*/SL*/Q3
33 X--- ---- -X- ---- -X- ---- ---- -X-- SR*/SL*/Q4
34 -X-- ---- -X- ---- ---- ---- ---- -X-- /SR*SL*/Q2
35 X--- ---- -X- ---- -X- ---- ---- -X-- SR*SL*/D3
36 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
37 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
38 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
39 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX

40 -X-- ---- -X- ---- -X- ---- -X- ---- -X-- /SR*/SL*/Q4
41 X--- ---- -X- ---- -X- ---- -X- ---- -X-- SR*/SL*/R1LO
42 -X-- ---- -X- ---- -X- ---- -X- ---- -X-- /SR*SL*/Q3
43 X--- ---- -X- ---- -X- ---- -X- ---- -X-- SR*SL*/D4
44 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
45 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
46 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
47 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX

48 -X-- ---- -X- ---- -X- ---- -X- ---- -X-- /SR*/SL*/Q5
49 X--- ---- -X-X ---- -X-X ---- -X-X ---- -X-X SR*/SL*/R1LO
50 -X-- ---- -X- ---- -X- ---- -X- ---- -X-- /SR*SL*/Q4
51 X--- ---- -X- ---- -X- ---- -X- ---- -X-- SR*SL*/D5
52 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
53 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
54 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
55 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX

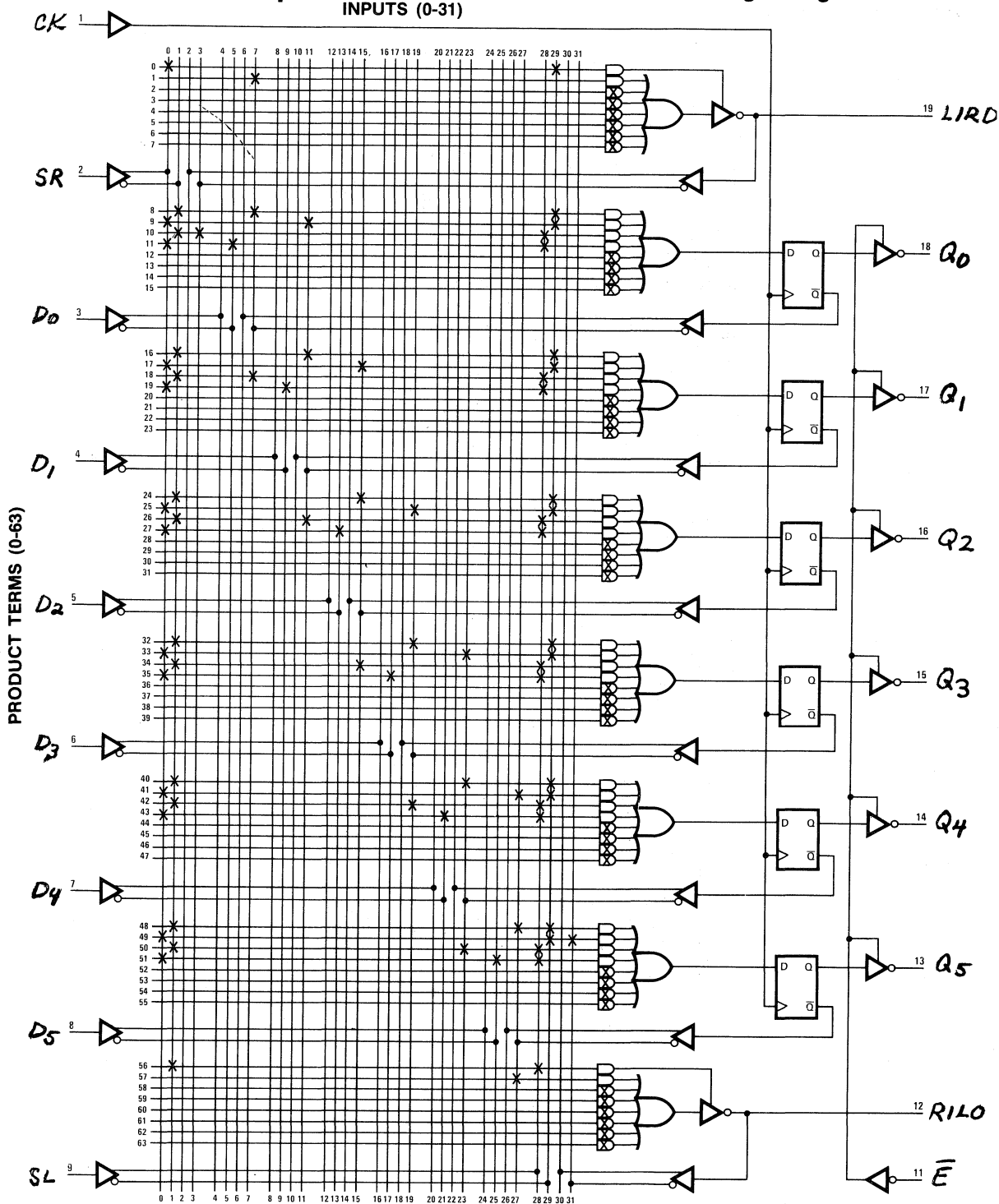
56 -X-- ---- -X- ---- -X- ---- -X- ---- -X-- /SR*SL
57 ---- ---- ---- ---- ---- ---- ---- /Q5
58 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
59 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
60 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
61 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
62 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX
63 XXXX XXXX XXXX XXXX XXXX XXXX XXXX XXXX

```

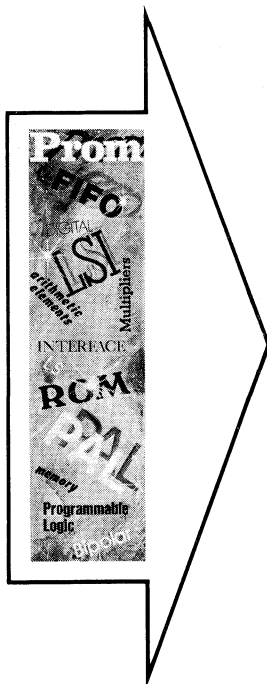
LEGEND: X : FUSE NOT BLOWN (L,N,0) - : FUSE BLOWN (H,P,1)

Manual Coding: 6-Bit Shift Register with Three-State Outputs

Logic Diagram PAL16R6







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First-In First-Out (FIFO) 64x4 Serial Memory

57/67401

U.S. Patent 4151609

Features/Benefits

- 10 MHz shift in, shift out guaranteed rates
- TTL inputs and outputs
- Readily expandable in word and bit dimensions
- Output pins directly opposite corresponding input pins
- Asynchronous or synchronous operation
- Pin compatible with Fairchild's F3341 MOS FIFO and ten times as fast

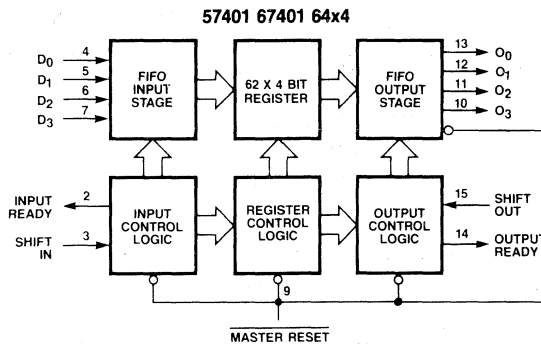
Ordering Information

PART NUMBER	PACKAGE	TEMPERATURE RANGE
57401	J16	Military
67401	J16	Commercial

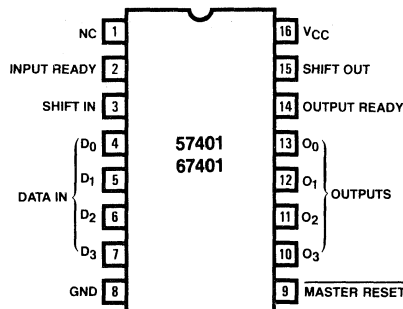
Description

The 67401 is an expandable "fall-through" high speed First-In First-Out (FIFO) memory organized 64 words by 4-bit. A 10 MHz data rate allows usage in high speed tape or disc controllers and communication buffer applications.

Block Diagram



Pin Configuration



Absolute Maximum Ratings

Supply Voltage, V_{CC}	7V
Input Voltage	7V
Off-state output voltage	5.5V
Storage temperature	-65° to +150°C

Operating Conditions

SYMBOL	PARAMETER	MILITARY			COMMERCIAL			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
T_A	Operating free-air temperature	-55		125	0		75	°C

Electrical Characteristics Over Operating Conditions

SYMBOL	PARAMETER		TEST CONDITIONS		MIN TYP MAX			UNIT
					MIN	TYP	MAX	
V_{IL}	Low-level input voltage				0.8			V
V_{IH}	High-level input voltage				2			V
V_{IC}	Input clamp voltage		$V_{CC} = \text{MIN}$	$I_I = -18\text{mA}$	-1.5			V
I_{IL1}	Low-level input current	D_0-D_3, MR	$V_{CC} = \text{MAX}$	$V_I = 0.45\text{V}$	-0.8			mA
I_{IL2}		SI, SO			-1.6			mA
I_{IH}	High-level input current		$V_{CC} = \text{MAX}$	$V_I = 2.4\text{V}$	50			μA
I_I	Maximum input current		$V_{CC} = \text{MAX}$	$V_I = 5.5\text{V}$	1			mA
V_{OL}	Low-level output voltage		$V_{CC} = \text{MIN}$ $V_{IL} = 0.8\text{V}$ $V_{IH} = 2\text{V}$	$I_{OL} = 8\text{mA}$	0.5			V
V_{OH}	High-level output voltage		$V_{CC} = \text{MIN}$ $V_{IL} = 0.8\text{V}$ $V_{IH} = 2\text{V}$	$I_{OH} = -0.9\text{mA}$	2.4			V
I_{OS}	Output short-circuit current *		$V_{CC} = 6\text{V}$	$V_O = 0.5\text{V}$	-20		-90	mA
I_{CC}	Supply current		$V_{CC} = \text{MAX}$	57401	150			mA
				67401	160			

* Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

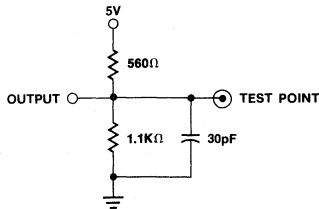
Switching Characteristics

Over Operating Conditions

SYMBOL	PARAMETER	FIGURE	MILITARY		COMMERCIAL		UNIT
			MIN	MAX	MIN	MAX	
f_{IN}	Shift In rate	1	7		10		MHz
t_{SIH}	Shift In HIGH time	1	45		35		ns
t_{SIL}	Shift In LOW time	1	45		35		ns
t_{IRL}	Shift In to input ready LOW	1		60		45	ns
t_{IRH}	Shift In to input ready HIGH	1		60		45	ns
t_{IDS}	Input data set up	1	10		5		ns
t_{IDH}	Input data hold time	1	55		45		ns
f_{OUT}	Shift Out rate	6	7		10		MHz
t_{SOH}	Shift Out HIGH time	6	45		35		ns
t_{SOL}	Shift Out LOW time	6	45		35		ns
t_{ORL}	Shift Out to Output Ready LOW	6		65		55	ns
t_{ORH}	Shift Out to Output Ready HIGH	6		65		55	ns
t_{OD}	Output data delay	6	10	65	10	55	ns
t_{PT}	Data throughput time	4, 9		4		3	μ s
t_{MRW}	Master Reset pulse*	11	30		35		ns
t_{MRORL}	Master Reset to OR LOW	11		65		60	ns
t_{MRIRH}	Master Reset to IR HIGH	11		65		60	ns
t_{MRS}	Master Reset to SI	11	45		35		ns
t_{IPH}	Input Ready pulse HIGH	4	20		20		ns
t_{OPH}	Output Ready pulse HIGH	9	20		20		ns

*Master reset clears all the cells to the empty state, and the data-outputs to a LOW-state.

Standard Test Load



Functional Description

Data Input

Data is entered into the FIFO on D0-D3 inputs. To enter data the Input Ready (IR) should be HIGH, indicating that the first location is ready to accept data. Data then present at the four data inputs is entered into the first location when the Shift In (SI) is brought HIGH. A SI HIGH signal causes the IR to go LOW. Data remains at the first location until SI is brought LOW. When SI is brought LOW and the FIFO is not full, IR will go HIGH, indicating that more room is available. Simultaneously, data will propagate to the second location and continue shifting until it reaches the output stage or a full location. If the memory is full, IR will remain LOW.

Data Transfer

Once data is entered into the second cell, the transfer of any full cell to the adjacent (downstream) empty cell is automatic, activated by an on-chip control. Thus data will stack up at the end of the device while empty locations will "bubble" to the front. t_{PT} defines the time required for the first data to travel from input to the output of a previously empty device.

Data Output

Data is read from the O0-O3 outputs. When data is shifted to the output stage, Output Ready (OR) goes HIGH, indicating the presence of valid data. When the OR is HIGH, data may be shifted out by bringing the Shift Out (SO) HIGH. A HIGH signal at SO causes the OR to go LOW. Valid data is maintained while the SO is HIGH. When SO is brought LOW the upstream data, provided that stage has valid data, is shifted to the output stage. When new valid data is shifted to the output stage, OR goes HIGH. If the FIFO is emptied, OR stays LOW, and O0-3 remains as before, (i.e. data does not change if FIFO is empty).

Input Ready and Output Ready may also be used as status signals indicating that the FIFO is completely full (Input Ready stays LOW for at least t_{PT}) or completely empty (Output Ready stays LOW for at least t_{PT}).

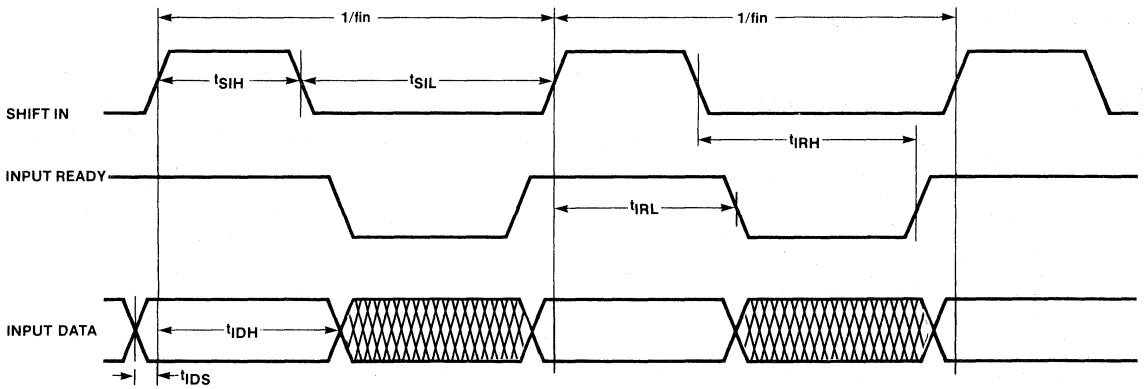


Figure 1. Input Timing

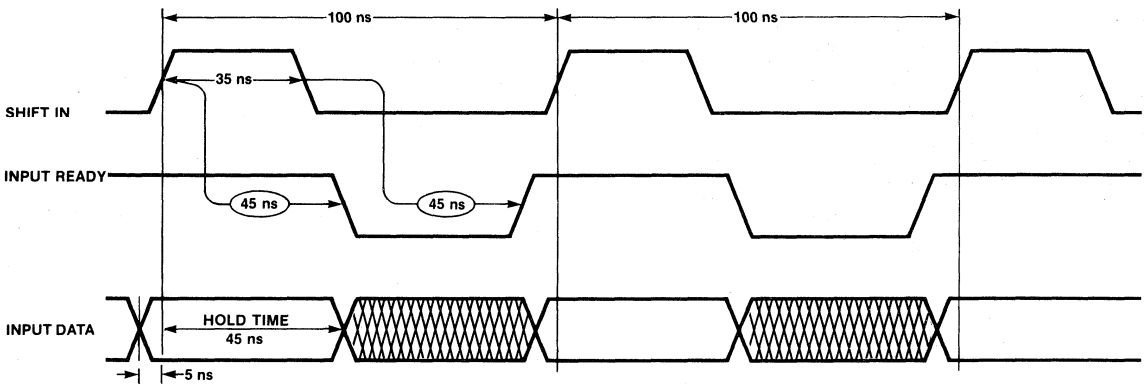


Figure 2. Typical Waveforms for 10 MHz Shift In Data Rate

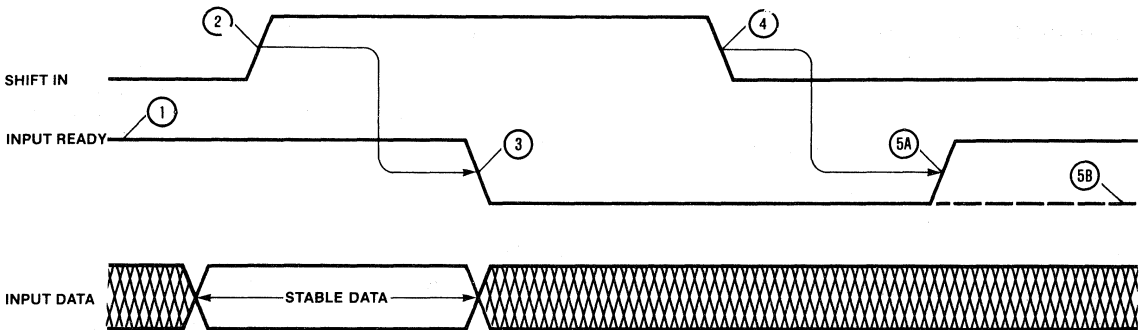


Figure 3. The Mechanism of Shifting Data into the FIFO

- ① Input Ready HIGH indicates space is available and a Shift In pulse may be applied.
- ② Input Data is loaded into the first word.
- ③ Input Ready goes LOW indicating the first word is full.
- ④ The Data from the first word is released for "fall-through" to second word.
- ⑤A The Data from the first word is transferred to second word. The first word is now empty as indicated by Input Ready HIGH.
- ⑤B If the second word is already full then the data remains at the first word. Since the FIFO is now full Input Ready remains low.

NOTE: Shift In pulses applied while Input Ready is LOW will be ignored (See Figure 5).

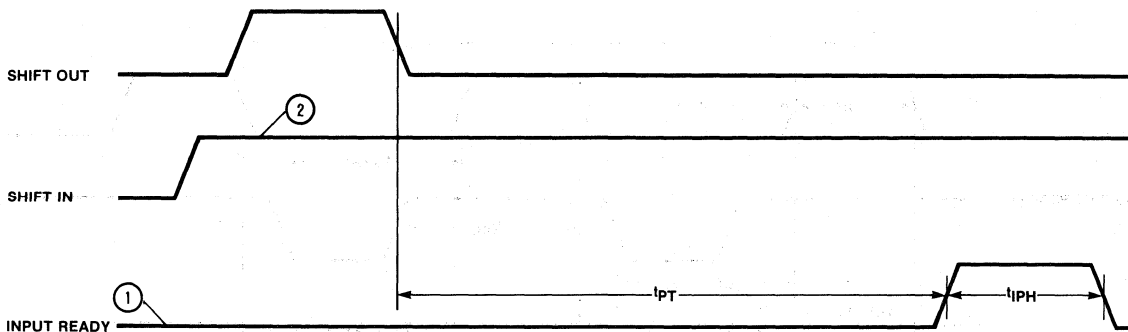
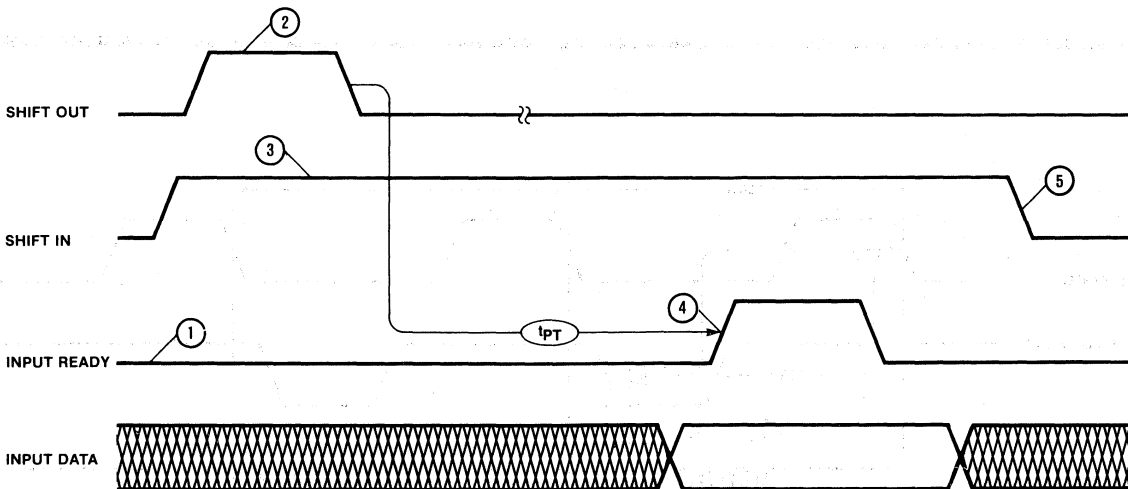


Figure 4. t_{IPH} Specification

- ① FIFO is initially full.
- ② Shift In held HIGH.



7

Figure 5. Data is Shifted In Whenever Shift In and Input Ready are Both HIGH

- ① FIFO is initially full.
- ② Shift Out pulse is applied. An empty location start "bubbling" to the front.
- ③ Shift In is held HIGH.
- ④ As soon as Input Ready becomes HIGH the Input Data is loaded into the first word.
- ⑤ The Data from the first word is released for "fall through" to second word.

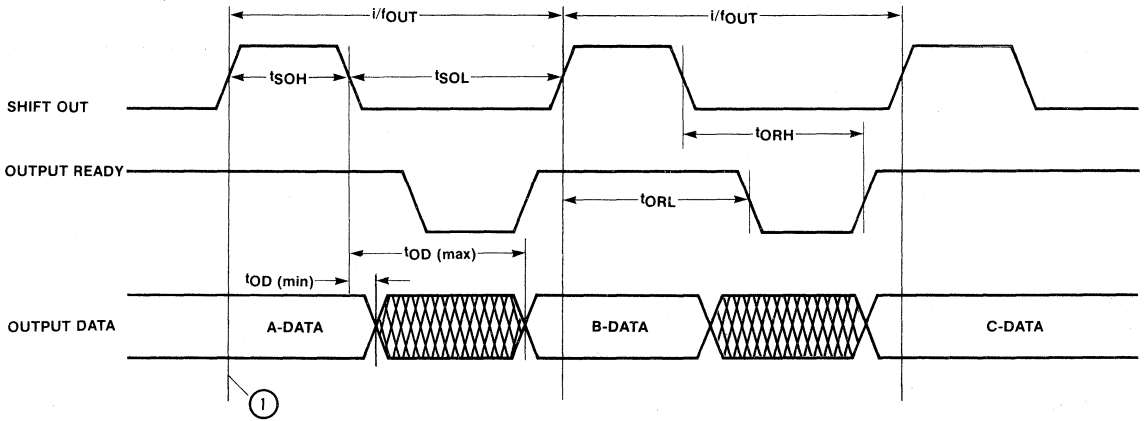


Figure 6. Output Timing

① The diagram assumes, that at this time, words 63, 62, 61 are loaded with A, B, C Data, respectively.

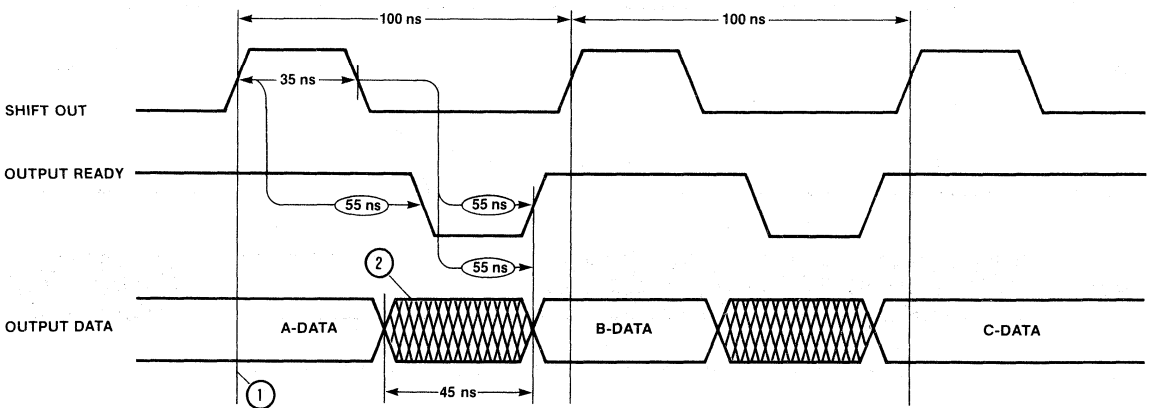


Figure 7. Typical Waveforms for 10 MHz Shift Out Data Rate

① The diagram assumes, that at this time, words 63, 62, 61 are loaded with A, B, C Data, respectively.

② Data in the crosshatched region may be A or B Data.

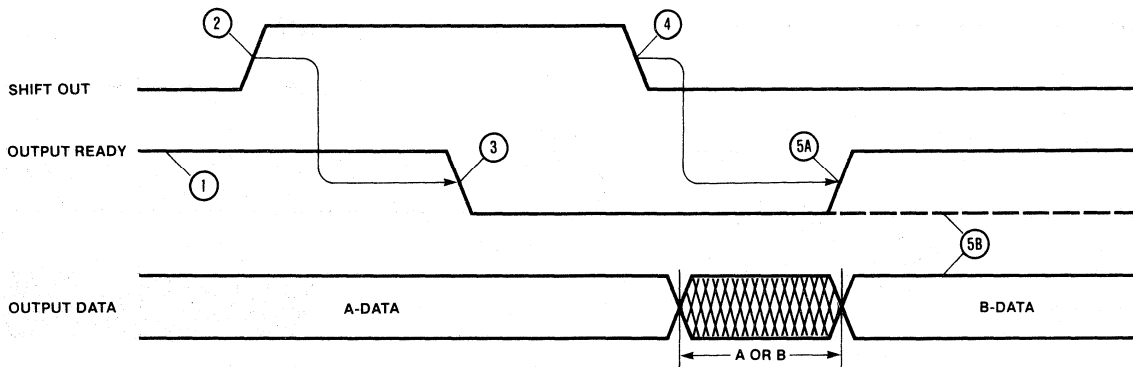


Figure 8. The Mechanism of Shifting Data Out of the FIFO.

- ① Output Ready HIGH indicates that data is available and a Shift Out pulse may be applied.
- ② Shift Out goes HIGH causing the next step.
- ③ Output Ready goes LOW.
- ④ Contents of word 62 (B-DATA) is released for "fall through" to word 63.
- 5A Output Ready goes HIGH indicating that new data (B) is now available at the FIFO outputs.
- 5B If the FIFO has only one word loaded (A-DATA) then Input Ready stays LOW and the A-DATA remains unchanged at the outputs.

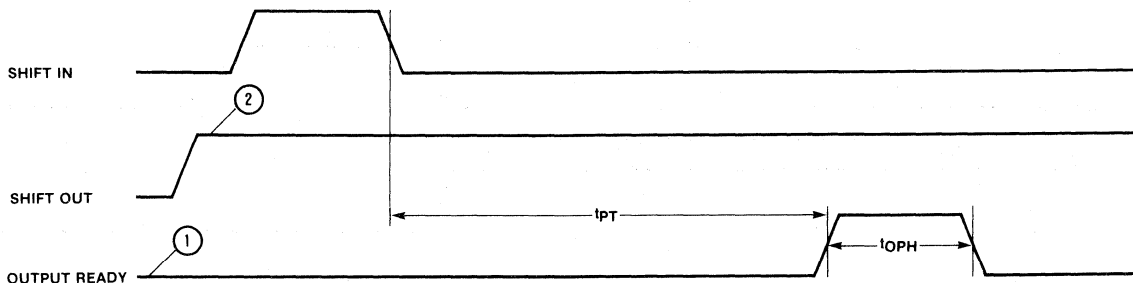


Figure 9. t_{PT} and t_{OPH} Specification

- ① FIFO initially empty.
- ② Shift Out held HIGH.

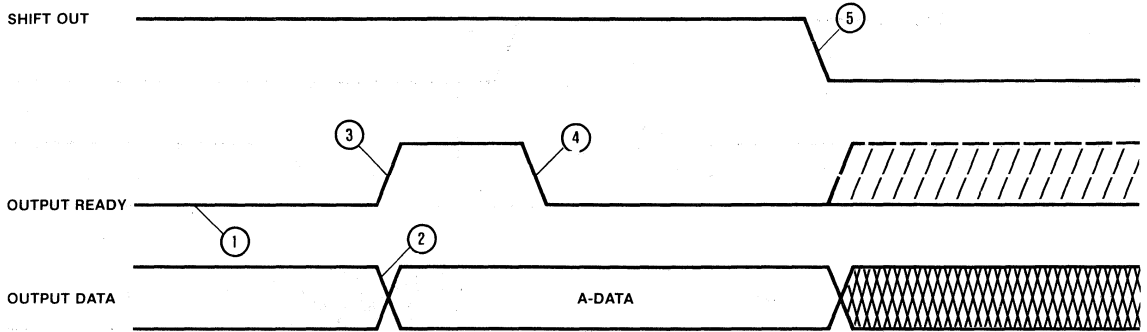


Figure 10. Data is Shifted Out Whenever Shift Out and Output Ready are Both HIGH.

- ① Word 63 is empty.
- ② New data (A) arrives at the outputs (word 63).
- ③ Output Ready goes HIGH indicating the arrival of the new data.
- ④ Since Shift Out is held HIGH, Output Ready goes immediately LOW.
- ⑤ As soon as Shift Out goes LOW the Output Data is subject to change as shown by the dashed line on Output Ready.

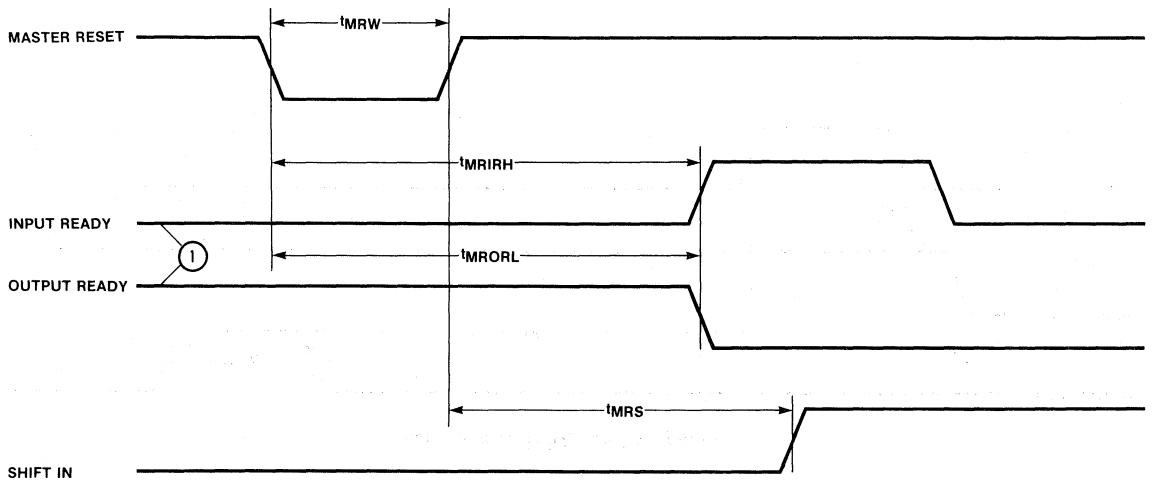


Figure 11. Master Reset Timing

- ① FIFO initially full.

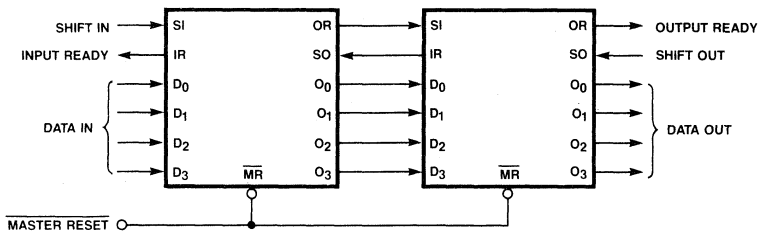


Figure 12. Cascading FIFOs to Form 128x4 FIFO.

FIFOs can be easily cascaded to any desired depth. The handshaking and associated timing between the FIFOs are handled by the FIFOs themselves.

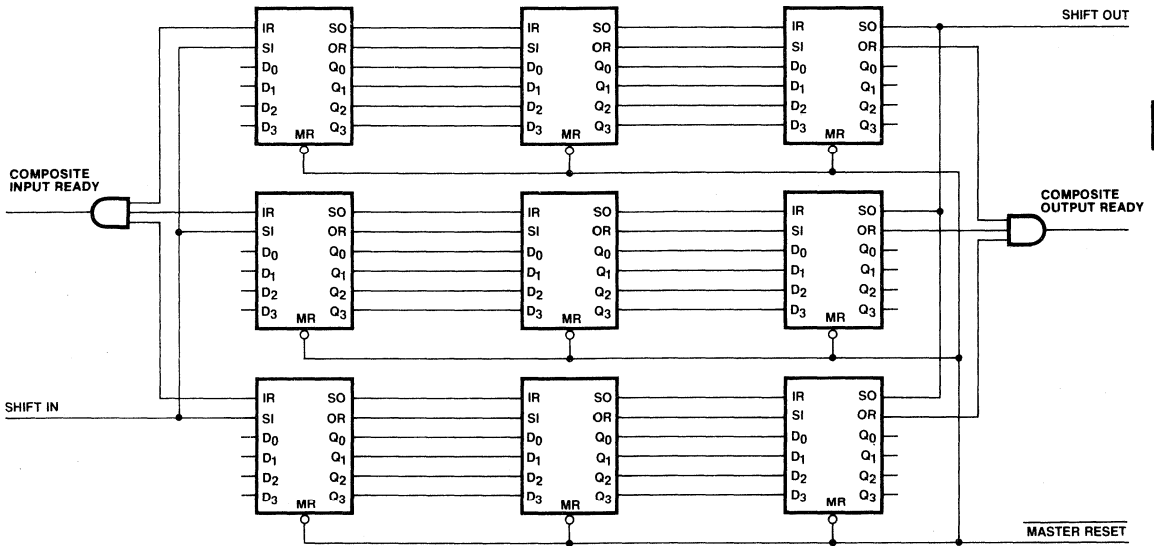
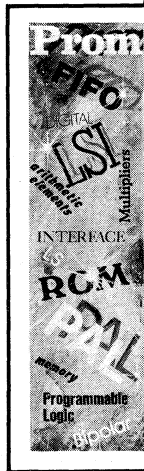


Figure 13. 192x12 FIFO.

FIFOs are expandable in depth and width. However, in forming wider words two external gates are required to generate composite Input and Output Ready flags. This need is due to the different fall through times of the FIFOs.





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Arithmetic Elements Selection Guide

The following selection guides are designed to simplify the choice of the particular function to fit the specific application.

High Speed Parallel Multipliers

DESCRIPTION	PART NO.	MAX DELAY	PINS	PAGE
8x8 Multiplier	67558-1	125 ns	40	8-3
	57558-1	135 ns	40	
	67558	150 ns	40	
	57558	155 ns	40	
8x8 Pipelined multiplier	67559 †	65 ns	40	†
	57559 †			
16x16 Pipelined multiplier	MPY-16 †	140 ns	64	†

Sequential Multipliers/Accumulators/Dividers

DESCRIPTION	PART NO.	MULTIPLICATION TIME	PINS	PAGE
8 Bits	67508 †	400 ns	24	†
	57508 †			
16 Bits	67516 †	800 ns	24	†
	57516 †			

Look-Up Tables

DESCRIPTION	PART NO.	MAX ACCESS TIME	PINS	PAGE
Sine (0°-90°) Look-Up Table	6086/7	100 ns	24	8-9
	5086/7	150 ns	24	8-9

MSI Arithmetic Elements

DESCRIPTION	PART NO.	MAX. ADD TIME	MAX. CARRY (OR GENERATE) TIME	PINS	PAGE
4 Bit ALU	5/74S381	27 ns	20 ns	20	8-11
4 Bit fast ALU (pin compatible to 74S381)	5/67S581/2†	17 ns	15 ns	20	†
4 Group carry-look-ahead generator	5/74S182		7 ns	16	8-15

† Data Sheet will appear in a future edition of the LSI Data Book. The performance shown is a design goal. Contact Application Department for additional information.

8 x 8 Multiplier

57/67558 57/67558-1

U.S. Patent 4153938

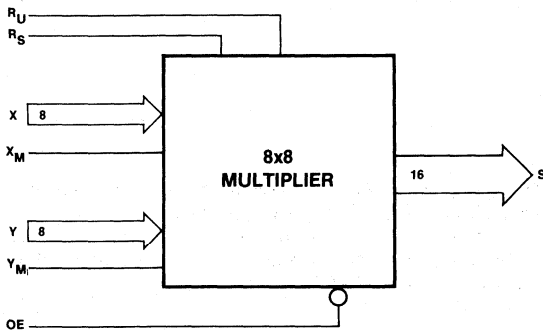
Features/Benefits

- Industry Standard
- Easy to Use; Combinatorial
- Unsigned, Signed, or Mixed Multiplication
- Rounding Inputs for Signed or Unsigned Operation
- Three-State Outputs for Bus Operation
- High Speed — 125 ns Max

Description

The 57558/67558 is a high speed 8 x 8 combinatorial Multiplier which can multiply two eight-bit unsigned or signed 2s complement numbers and generate the sixteen-bit unsigned or signed product. Each input operand X and Y has an associated Mode control line, X_M and Y_M respectively. When a Mode control line is at a Low logic level the operand is treated as an unsigned eight-bit number while if the Mode control is at a High logic level the operand is treated as an eight-bit signed 2s complement number. Two additional inputs R_S and R_U allow the addition of a bit in the multiplier array at the appropriate bit positions for rounding signed or unsigned fractional numbers. The most significant product bit is available in both True and Complement form to assist in expansion to larger signed multipliers. The product outputs are three-state, controlled by an active Low Output Enable which allows several Multipliers to be connected to a parallel bus or be used in a pipelined system. The device uses a single +5V power supply and is packaged in a standard 40-pin DIP.

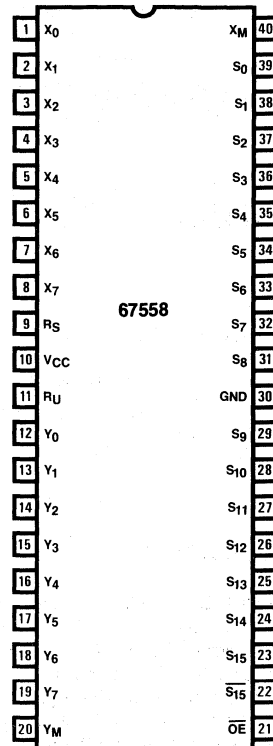
Logic Symbol



Ordering Information

PART NUMBER	PACKAGE	TEMPERATURE
57558, 57558-1	J40	Military
67558, 67558-1	J40	Commercial

Pin Configuration



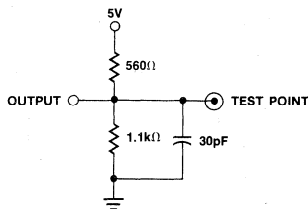
8

Switching Characteristics

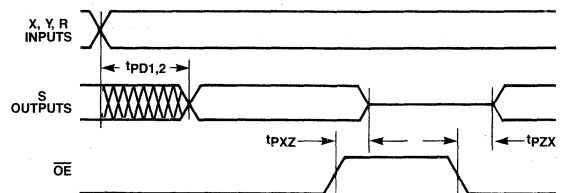
Over operating conditions

SYMBOL	PARAMETER	DEVICE	TYP	MAX	UNIT
t_{PXZ}	Delay from OE to S High Impedance State	67558	30	40	ns
		57558	30	50	
		67558-1	30	40	
		57558-1	30	50	
t_{PZX}	Delay from OE to S Active State	67558	30	40	ns
		57558	30	50	
		67558-1	30	40	
		57558-1	30	50	
t_{PD1}	Delay from Y, X to S_{0-4}	67558	80	135	ns
		57558	80	140	
		67558-1	80	115	
		57558-1	80	125	
t_{PD2}	Delay from Y, X to S_{5-15} , S_{15}	67558	100	150	ns
		57558	100	155	
		67558-1	100	125	
		57558-1	100	135	

Standard Test Load



Timing Waveform



Functional Description

The 57558/67558 Multiplier is an 8 x 8 combinatorial logic array capable of multiplying numbers in unsigned, signed 2s complement, or mixed notation. Each eight-bit input operand X and Y has associated with it a mode control which determines whether the array treats the number as signed or unsigned. If the mode control is at a High Logic level then the operand is treated as a 2s complement number with the most significant bit having a negative weight, while if the mode control is at a Low Logic level then the operand is treated as an unsigned number.

The multiplier provides all 16 product bits generated by the multiplication. For expansion during signed or mixed multiplication the most significant product bit has both true and complement available. This allows an adder to be used as a

subtractor in many applications and eliminates the need for SSI circuits.

Two inputs, R_S and R_U , are additional inputs to the array which allow the addition of a bit at the appropriate positions in the array so as to provide rounding to the best signed or unsigned fractional eight-bit result. These inputs can also be used for rounding in larger multipliers.

The product outputs of the multiplier are controlled by an active Low Output Enable control. When this control is at a Low Logic level the multiplier outputs are active, while if the control is at a High Logic level then the outputs are placed in a high-impedance state. This three-state capability allows multipliers to be placed on a common bus and also allows pipelining of multiplications for higher speed systems.

Absolute Maximum Ratings

Supply Voltage, V_{CC}	7V
Input Voltage	7V
Off-state output voltage	5.5V
Storage temperature	-65° to +150°C

Operating Conditions

SYMBOL	PARAMETER	MILITARY			COMMERCIAL			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
T_A	Operating free-air temperature				0		75	°C
T_C	Operating case temperature	-55		125				°C

Electrical Characteristics Over Operating Conditions

SYMBOL	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_{IL}	Low-level input voltage					0.8	V
V_{IH}	High-level input voltage			2			V
V_{IC}	Input clamp voltage	$V_{CC} = \text{MIN}$	$I_I = -18\text{mA}$			-1.5	V
I_{IL}	Low-level input current	$V_{CC} = \text{MAX}$	$V_I = 0.5\text{V}$			-1	mA
I_{IH}	High-level input current	$V_{CC} = \text{MAX}$	$V_I = 2.4\text{V}$			100	μA
I_I	Maximum input current	$V_{CC} = \text{MAX}$	$V_I = 5.5\text{V}$			1	mA
V_{OL}	Low-level output voltage	$V_{CC} = \text{MIN}$	$I_{OL} = 8\text{mA}$			0.5	V
V_{OH}	High-level output voltage	$V_{CC} = \text{MIN}$	$I_{OH} = -2\text{mA}$	2.4			V
I_{OZL}	Off-state output current	$V_{CC} = \text{MAX}$	$V_O = 0.5\text{V}$			-100	μA
I_{OZH}			$V_O = 2.4\text{V}$			100	μA
I_{OS}	Output short-circuit current*	$V_{CC} = \text{MAX}$	$V_O = 0\text{V}$	-10		-90	mA
I_{CC}	Supply current	$V_{CC} = \text{MAX}$			180	280	mA

* Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.



Rounding

Multiplication of two n-bit operands results in 2n-bit product[†]. Therefore, in n-bit system it is necessary to convert the double-length product into a single-length product. This can be accomplished by truncating or rounding. The following examples, illustrate the difference between the two conversion techniques in decimal arithmetic.

$$\begin{array}{l} 39.2 \rightarrow 39 \\ 39.6 \rightarrow 39 \end{array} \left. \vphantom{\begin{array}{l} 39.2 \\ 39.6 \end{array}} \right\} \text{Truncating}$$

$$\begin{array}{l} 39.2 + 0.5 = 39.7 \rightarrow 39 \\ 39.6 + 0.5 = 40.1 \rightarrow 40 \end{array} \left. \vphantom{\begin{array}{l} 39.2 \\ 39.6 \end{array}} \right\} \text{Rounding}$$

Obviously, rounding maintains more precision than truncating, but it may take one more step to implement. The additional step involves adding one-half of the weight of the single length LSB to the MSB of the discarded part e.g. in decimal arithmetic round-

ing 39.28 to one decimal point is accomplished by adding 0.05 to the number and truncating the LSB.

$$39.28 + 0.05 = 39.33 \rightarrow 39.3$$

The situation in binary arithmetic is quite similar, but two cases need to be considered; signed and unsigned data representation. In signed multiplication, the two MSBs are identical (except when both operands are -1) therefore, the best single length product is shifted one position to the right with respect to the unsigned multiplications. Figure 1 illustrates these two cases for the 8x8 multiplier. In the signed case, adding one-half of the S₇ weight is accomplished by adding 1 in bit position 6, and in the unsigned case 1 is added to bit position 7. Therefore, the 67558 multiplier has two rounding inputs, R_S and R_U. Thus, to get a rounded single length result the appropriate R input is tied to V_{CC} (logic one) and the other R input is grounded. If double length result is desired both R inputs are grounded.

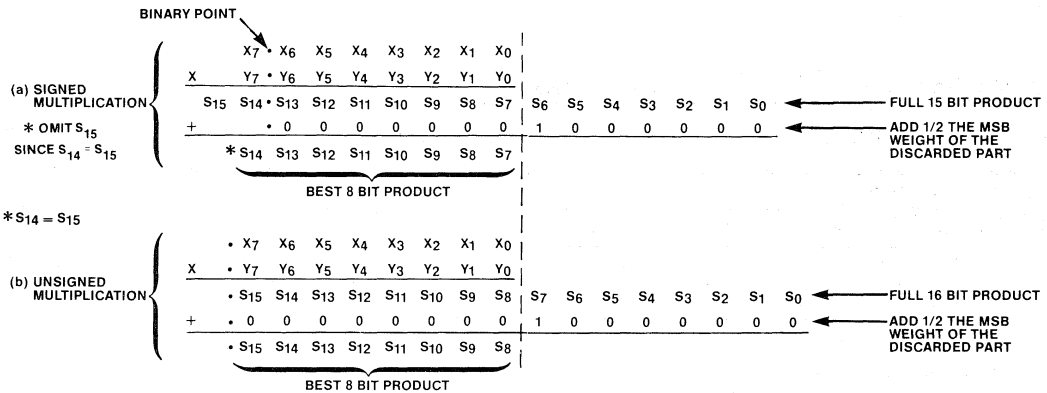


Figure 1. Rounding the Result of Binary Fractional Multiplication.

- (a) In signed (2's complement) notation, the MSB of each operand is the sign bit, and the binary point is to the right of the MSB. The resulting product has a redundant sign bit and the binary point is to the right of the second MSB of the product. The best eight-bit product is from S₁₄ through S₇, and rounding is performed by adding "1" to bit position S₆.
- (b) In unsigned notation the best 8-bit product, is the most significant half of the product, corrected by adding "1" to bit position S₇.

[†] In general: multiplication of M-bit operand by N-bit operand results in M + N bit product.

Signed Expansion

The most significant product bit has both true and complement outputs available. When building larger signed multipliers the partial products except at the lower stages are signed numbers. These unsigned and signed partial products must be added together to give the correct signed product. Having both the true and complement of the most significant product bit available assists in this addition. For example, say that two signed partial products must be added and MSI adders are used; we then have the situation of adding together the Carry from the previous adder stage plus the addition of the two negative most significant partial product bits. The result of adding these variables must be a positive sum and a negative carry (borrow). The equations for this are:

$$S = A \oplus B \oplus C$$

$$C_0 = AB + BC + CA$$

where C is the Carry In and A and B the sign bits of the two partial products.

Now an adder produces the equations:

$$S = A \oplus B \oplus C$$

$$C_0 = AB + BC + CA$$

Examining these equations it can be seen that if the inversion of A and B are used then the adder produces the inversion of the negative carry since

$$AB + B\bar{C} + \bar{C}A = \overline{AB + BC + C\bar{A}}$$

and the sum remains the same.

16 x 16 Two's Complement Multiplication

The 16-bit X operand is broken into two 8-bit operands (X₀-X₇ and X₈-X₁₅), and so is the Y operand. Since the situation is that of a cross product, four partial products are generated as follows:

$$A = X_L * Y_L$$

$$B = X_L * Y_H$$

$$C = X_H * Y_L$$

$$D = X_H * Y_H$$

where the subscript L stands for bits 0-7, and the subscript H stands for bits 8-15.

Expanding in two's complement multiplication requires a sign extension of the B and C partial products. Thus, B₁₅ and C₁₅ need to be extended eight positions to the left (to align with D₁₅). In this approach two more adders are required. But the complement of the MSB (S₁₅) on the 67558 can be used to save these two adders. The Figure shows the implementation of such a 16x16 signed two's complement multiplication.

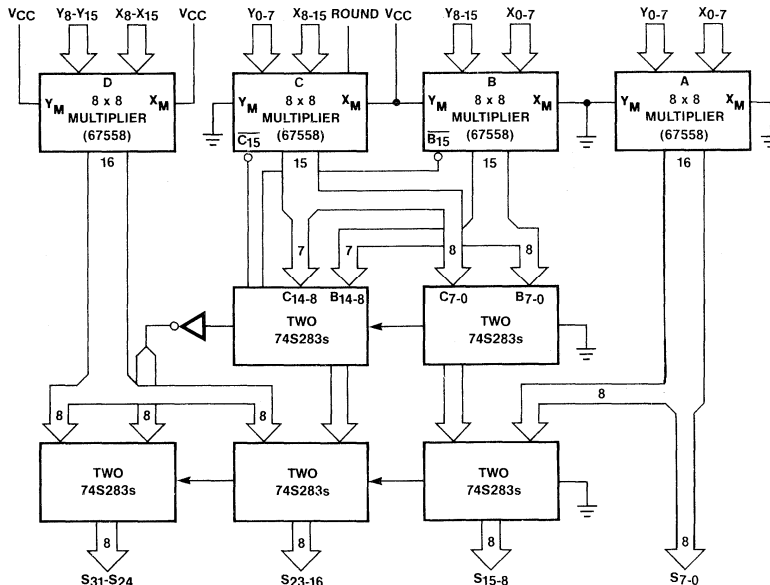


Figure 2. 16 x16 Two's Complement Signed Multiplication.

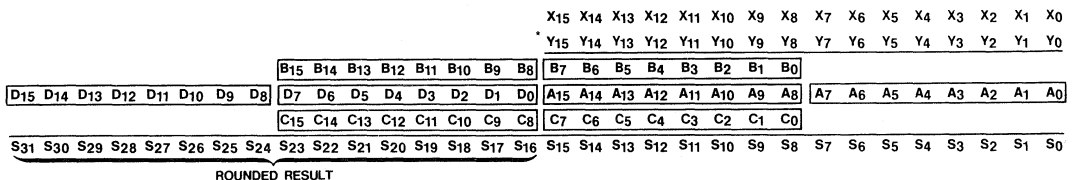


Figure 3. Unsigned Expansions of the 8x8 Multiplier to 16x16 Multiplication.

Sine (0° to 90°) Look Up Table Using a 1024 X 10 ROM (5/6255 5/6256) 5/6086 5/6087

Features/Benefits

- Input angle increments of $90^\circ/1024 = .0879^\circ$
- 10 bit binary outputs
- Low power dissipation. Typically 500 mw
- Fast access time 100 ns max.
- TTL compatible

Description

The 5255/6255, 1024 words by 10 bits Read Only Memory has been customized to make a sine θ look up table (5086/6086) for $0^\circ \leq \theta < 90^\circ$. The address inputs are used to divide the first 90° quadrant into angles increments of $90^\circ/1024$ words or $.0879^\circ$ /word. The memory outputs should be interpreted as binary weighted fractions where output 1 has a weight of $1/2$ or $.500$,

Ordering Information

PART NUMBER	PACKAGE	TEMPERATURE
5086/87	J24	Military
6086/87	J24	Commercial

output 2 has a weight of $1/4$ or $.250$, and so on until output 10 which has a weight of $1/1024$ or $.000976$. The 10 bit output code has not been rounded off so that output error will always be positive and less than $1/1024$ or $.0009765$. Round off error, in approximating the ROM input word, must be added or subtracted to the output error. For electrical characteristics and pin out refer to 6255 specifications (pages 4-3 through 4-5).

Example 1:

Find the sine 45°

Let X = the ROM word where sine 45° is stored

$$\frac{X}{1024 \text{ words}} = \frac{45^\circ}{90^\circ}$$

X = word 512

Word 511 has the following stored data and interpretation:

Output #	0 ₁	0 ₂	0 ₃	0 ₄	0 ₅	0 ₆	0 ₇	0 ₈	0 ₉	0 ₁₀	
Stored Data	H	L	H	H	L	H	L	H	L	L	(H = TTL HIGH)
Binary Weight	$\frac{1}{2}$	$\frac{1}{4}$	$\frac{1}{8}$	$\frac{1}{16}$	$\frac{1}{32}$	$\frac{1}{64}$	$\frac{1}{128}$	$\frac{1}{256}$	$\frac{1}{512}$	$\frac{1}{1024}$	

Adding the fractions wherever an "H" appears given.

$$\frac{1}{2} + \frac{1}{8} + \frac{1}{16} + \frac{1}{64} + \frac{1}{256} = .50000 + .12500 + .06250 + .01562 + .00391 = .70507$$

Handbook Value = .70711

Our Error = $.70711 - .70703 = .00008$

Example 2:

Find the sine 210°

This value is in quadrant three, therefore, $\theta' = 210^\circ - 180^\circ$ or 30°

$$\text{Let X = the ROM word where sine } 30^\circ \text{ is stored } \frac{X}{1024 \text{ words}} = \frac{30^\circ}{90^\circ}$$

X = word 341.33 (round off to word 341)

Word 341 has the following stored data and interpretation:

Output #	0 ₁	0 ₂	0 ₃	0 ₄	0 ₅	0 ₆	0 ₇	0 ₈	0 ₉	0 ₁₀
Stored Data	L	H	H	H	H	H	H	H	H	H
Binary Weight	$\frac{1}{2}$	$\frac{1}{4}$	$\frac{1}{8}$	$\frac{1}{16}$	$\frac{1}{32}$	$\frac{1}{64}$	$\frac{1}{128}$	$\frac{1}{256}$	$\frac{1}{512}$	$\frac{1}{1024}$

Adding the fractions wherever an "H" appears gives 0.49902

The sine 210° , therefore, = $-.49902$ with the sign generated by external logic. Note that the address 341 to which we rounded off is actually the sine 29.97° .

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Arithmetic Logic Unit/ Function Generator

SN54S381 SN74S381

Features/Benefits

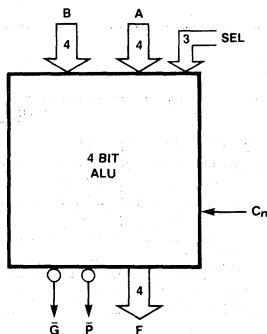
- A Fully Parallel 4-Bit ALU in 20-Pin Package for 0.300-inch Row Spacing
- Ideally Suited for High-Density Economical Processors
- Parallel Inputs and Outputs and Full Look-Ahead Provide System Flexibility
- Arithmetic and Logic Operations Selected Specifically to Simplify System Implementation:

A Minus B
B Minus A
A Plus B
and Five Other Functions

Description

The 'S381 is a Schottky TTL arithmetic logic unit (ALU)/function generator that performs eight binary arithmetic/logic operations on two 4-bit words as shown in the function table. These operations are selected by the three function-select lines (S0, S1, S2). A fully carry look-ahead circuit is provided for fast, simultaneous carry generation by means of two cascade outputs (\bar{P} and \bar{G}) for the four bits in the package.

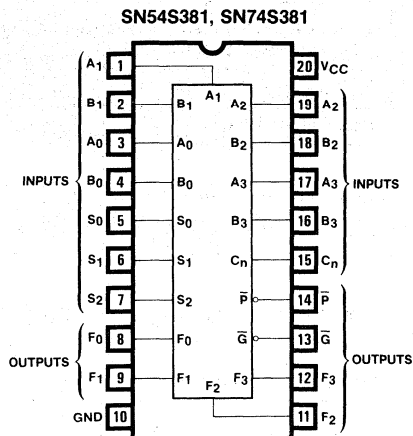
Logic Symbol



Ordering Information

PART NUMBER	PACKAGE	TEMPERATURE
SN54S381	J20	Military
SN74S381	J20	Commercial

Pin Configuration



Function Table

SELECTION			ARITHMETIC/LOGIC OPERATION
S2	S1	S0	
L	L	L	Clear †
L	L	H	B minus A
L	H	L	A minus B
L	H	H	A plus B
H	L	L	A ⊕ B
H	L	H	A + B
H	H	L	AB
H	H	H	Preset ††

† Force all F outputs to be Lows.
†† Force all F outputs to be Highs.

Absolute Maximum Ratings

Supply Voltage, V_{CC}	7V
Input Voltage	5.5V
Storage Temperature Range	-65°C to +150°C

Operating Conditions

SYMBOL	PARAMETER	MILITARY			COMMERCIAL			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
T_A	Operating free-air temperature	-55		125	0		70	°C

Electrical Characteristics Over operating conditions

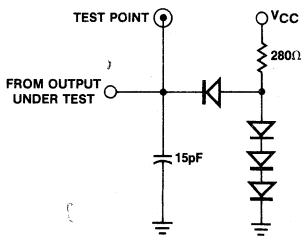
SYMBOL	PARAMETER	TEST CONDITIONS	MIN TYP MAX		UNIT
V_{IL}	Low-level input voltage			0.8	V
V_{IH}	High-level input voltage		2		V
V_{IC}	Input clamp voltage	$V_{CC} = \text{MIN}$ $I_I = -18\text{mA}$		-1.2	V
I_{IL}	Low-level input current	$V_{CC} = \text{MAX}$ $V_I = 0.5\text{V}$	Any S input	-2	mA
			Cn	-8	
			All others	-6	
I_{IH}	High-level input current	$V_{CC} = \text{MAX}$ $V_I = 2.7\text{V}$	Any S input	50	μA
			Cn	250	
			All others	200	
I_I	Maximum input current	$V_{CC} = \text{MAX}$ $V_I = 5.5\text{V}$		1	mA
V_{OL}	Low-level output voltage	$V_{CC} = \text{MIN}$ $V_{IH} = 2\text{V}$ $V_{IL} = 0.8\text{V}$ $I_{OL} = 20\text{mA}$		0.5	V
V_{OH}	High-level output voltage	$V_{CC} = \text{MIN}$ $V_{IH} = 2\text{V}$ $V_{IL} = 0.8\text{V}$ $I_{OH} = -1\text{mA}$	SN54S381	2.4 3.4	V
			SN74S381	2.7 3.4	
I_{OS}	Output short-circuit current*	$V_{CC} = \text{MAX}$	-40	-100	mA
I_{CC}	Supply current	$V_{CC} = \text{MAX}$		105 160	mA

* Not more than one output should be shorted at a time.

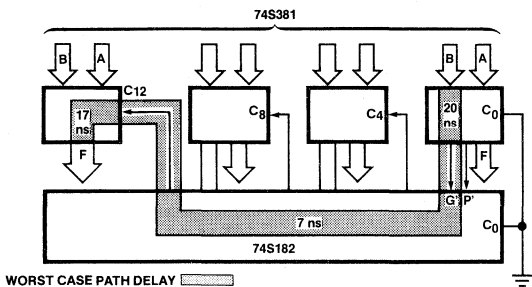
Switching Characteristics $V_{CC} = 5\text{V}$, $T_A = 25^\circ\text{C}$

SYMBOL	PARAMETER	FROM (INPUT)	TO (OUTPUT)	5/74S381		UNIT
				TYP	MAX	
t_P	Propagation delay time	C_n	Any F	10	17	ns
t_P	Propagation delay time	Any A or B	\bar{G}	12	20	ns
t_P	Propagation delay time	Any A or B	\bar{P}	11	18	ns
t_{PLH}	Propagation delay, low-to-high	Ai or Bi	Fi	18	27	ns
t_{PHL}	Propagation delay, high-to-low			16	25	ns
t_P	Propagation delay time	Any S	Fi, \bar{G} , \bar{P}	18	30	ns

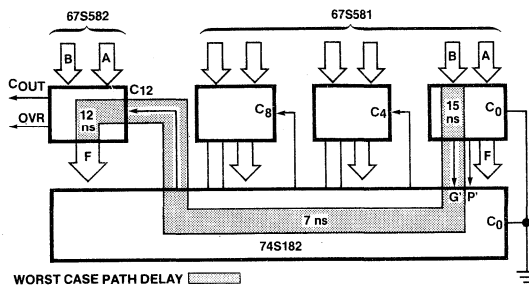
Standard Test Load



16-BIT ALU (USING 74S381)



16-BIT ALU (USING 67S581/2)



MAXIMUM DELAY OF ADDITION/SUBTRACTION.

	74S381	67S581
1-4 bits	27ns	22ns
5-16 bits	44ns	34ns
17-64 bits	64ns	54ns

Look-Ahead Carry Generators

SN54S182 SN74S182

Description

The SN54S182, and SN74S182 are high-speed, look-ahead carry generators capable of anticipating a carry across four binary adders or group of adders. They are cascadable to perform full look-ahead across n-bit adders. Carry, generate-carry, and propagate-carry functions are provided as enumerated in the pin designation table below.

When used in conjunction with 74S381, 67S581, 74S181, 2901, 6701 arithmetic logic units (ALU), these generators provide high-speed carry lookahead capability for any word length. Each 'S182 generates the look-ahead (anticipated carry) across a group of four ALU's and, in addition, other carry look-ahead circuits may be employed to anticipate carry across sections of four look-ahead packages up to n-bits.

The carry functions (inputs, outputs, generate, and propagate) of the look-ahead generators are implemented in the compatible forms for direct connection to the ALU. Logic equations for the 'S182 are:

$$C_{n+x} = G_0 + P_0 C_n$$

$$C_{n+y} = G_1 + P_1 G_0 + P_1 P_0 C_n$$

$$C_{n+z} = G_2 + P_2 G_1 + P_2 P_1 G_0 + P_2 P_1 P_0 C_n$$

$$\bar{G} = \bar{G}_3 + P_3 \bar{G}_2 + P_3 P_2 \bar{G}_1 + P_3 P_2 P_1 \bar{G}_0$$

$$\bar{P} = \bar{P}_3 P_2 P_1 P_0$$

or

$$\bar{C}_{n+x} = \bar{Y}_0 (X_0 + C_n)$$

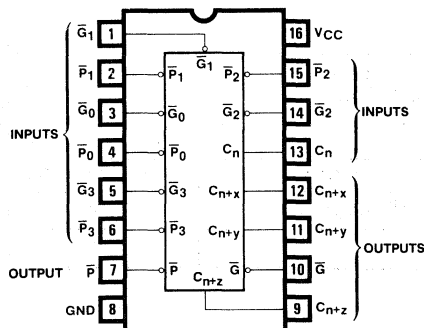
$$\bar{C}_{n+y} = \bar{Y}_1 [X_1 + Y_0 (X_0 + C_n)]$$

$$\bar{C}_{n+z} = \bar{Y}_2 [X_2 + Y_1 [X_1 + Y_0 (X_0 + C_n)]]$$

$$Y = Y_3 (X_3 + Y_2) (X_3 + X_2 + Y_1) (X_3 + X_2 + X_1 + Y_0)$$

$$X = X_3 + X_2 + X_1 + X_0$$

Pin Configuration



Ordering Information

PART NUMBER	PACKAGE	TEMPERATURE
SN54S182	J16	Military
SN74S182	J16	Commercial

Summarizing Tables

FUNCTION TABLE FOR C_{n+y} OUTPUT

INPUTS	OUTPUT
$\bar{G}_1 \bar{G}_0 \bar{P}_1 \bar{P}_0 C_n$	C_{n+y}
L X X X X	H
X L L X X	H
X X L L H	H
All other combinations	L

FUNCTION TABLE FOR \bar{P} OUTPUT

INPUTS	OUTPUT
$\bar{P}_3 \bar{P}_2 \bar{P}_1 \bar{P}_0$	\bar{P}
L L L L	L
All other combinations	H

FUNCTION TABLE FOR C_{n+x} OUTPUT

INPUTS	OUTPUT
$\bar{G}_0 \bar{P}_0 C_n$	C_{n+x}
L X X	H
X L H	H
All other combinations	L

FUNCTION TABLE FOR \bar{G} OUTPUT

INPUTS	OUTPUT
$\bar{G}_3 \bar{G}_2 \bar{G}_1 \bar{G}_0 \bar{P}_3 \bar{P}_2 \bar{P}_1$	\bar{G}
L X X X X X X	L
X L X X L X X	L
X X L X L L X	L
X X X L L L L	L
All other combinations	H

FUNCTION TABLE FOR C_{n+z} OUTPUT

INPUTS	OUTPUT
$\bar{G}_2 \bar{G}_1 \bar{G}_0 \bar{P}_2 \bar{P}_1 \bar{P}_0 \bar{C}_n$	C_{n+z}
L X X X X X X	H
X L X L X X X	H
X X L L L X X	H
X X X L L L H	H
All other combinations	L

H = High Level, L = Low Level, X = Irrelevant. Any inputs not shown in a given table are irrelevant with respect to that output.

8

Absolute Maximum Ratings

Supply Voltage, V_{CC}	7V
Input Voltage	5.5V
Storage Temperature Range	-65°C to +150°C

Operating Conditions

SYMBOL	PARAMETER	MILITARY			COMMERCIAL			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
T_A	Operating free-air temperature	-55		125	0		70	°C

Electrical Characteristics Over operating conditions

SYMBOL	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_{IL}	Low-level input voltage					0.8	V
V_{IH}	High-level input voltage			2			V
V_{IC}	Input clamp voltage	$V_{CC} = \text{MIN}$	$I_I = -18\text{mA}$			-1.2	V
I_{IL}	Low-level input current	$V_{CC} = \text{MAX}$	$V_I = 0.5\text{V}$	C_n input		-2	mA
				\overline{P}_3 input		-4	
				\overline{P}_2 input		-6	
				$\overline{P}_0, \overline{P}_1, \text{ or } \overline{G}_3$ input		-8	
				\overline{G}_0 or \overline{G}_2		-14	
				\overline{G}_1 input		-16	
I_{IH}	High-level input current	$V_{CC} = \text{MAX}$	$V_I = 2.7\text{V}$	C_n input		50	μA
				\overline{P}_3 input		100	
				\overline{P}_2 input		150	
				$\overline{P}_0, \overline{P}_1, \text{ or } \overline{G}_3$ input		200	
				\overline{G}_0 or \overline{G}_2		350	
				\overline{G}_1 input		400	
I_I	Maximum input current	$V_{CC} = \text{MAX}$	$V_I = 5.5\text{V}$			1	mA
V_{OL}	Low-level output voltage	$V_{CC} = \text{MIN}$ $V_{IL} = 0.8\text{V}$	$V_{IH} = 2\text{V}$ $I_{OH} = -1\text{mA}$			0.5	V
V_{OH}	High-level output voltage	$V_{CC} = \text{MIN}$ $V_{IL} = 0.8\text{V}$	$V_{IH} = 2\text{V}$ $I_{OL} = 20\text{mA}$	SN74S182	2.7	3.4	V
				SN54S182	2.5	3.4	
I_{OS}	Output short-circuit current *	$V_{CC} = \text{MAX}$		-40		-100	mA
I_{CCL}	Supply current, all outputs low	$V_{CC} = \text{MAX}$	See Note 1	SN74S182	69	109	mA
				SN54S182	69	99	
I_{CCH}	Supply current, all outputs high	$V_{CC} = 5\text{V}$	See Note 2		35		mA

* Not more than one output should be shorted at a time and duration of the short-circuit test should not exceed one second.

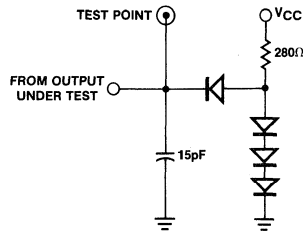
NOTES: 1. I_{CCL} is measured with all outputs open; inputs \overline{G}_0 , \overline{G}_1 , and \overline{G}_2 at 4.5 V; and all other inputs grounded.

2. I_{CCH} is measured with all outputs open, inputs \overline{P}_3 and \overline{G}_3 at 4.5 V, and all other inputs grounded.

Switching Characteristics $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

SYMBOL	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TYP	MAX	UNIT
t _{PLH}	Propagation delay, low-to-high	$\bar{G}0, \bar{G}1, \bar{G}2, \bar{G}3,$	$C_{n+x}, C_{n+y},$	4.5	7	ns
t _{PHL}	Propagation delay, high-to-low	$\bar{P}0, \bar{P}1, \bar{P}2, \text{ or } \bar{P}3$	or C_{n+z}	4.5	7	ns
t _{PLH}	Propagation delay, low-to-high	$\bar{G}0, \bar{G}1, \bar{G}2, \bar{G}3,$	\bar{G}	5	7.5	ns
t _{PHL}	Propagation delay, high-to-low	$\bar{P}1, \bar{P}2, \text{ or } \bar{P}3$		7	10.5	ns
t _{PLH}	Propagation delay, low-to-high	$\bar{P}0, \bar{P}1, \bar{P}2, \text{ or } \bar{P}3$	\bar{P}	4.5	6.5	ns
t _{PHL}	Propagation delay, high-to-low			6.5	10	ns
t _{PLH}	Propagation delay, low-to-high	C_n	$C_{n+x}, C_{n+y},$ or C_{n+z}	6.5	10	ns
t _{PHL}	Propagation delay, high-to-low			7	10.5	ns

Standard Test Load





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Octal Interface Selection Guide

FUNCTION	POWER	POLARITY	FEATURE	PART NUMBER		PAGE
				COMMERCIAL	MILITARY	
Buffer	LS	Non-invert	—	SN74LS244	SN54LS244	3
			—	SN74LS241	SN54LS241	3
		Schmitt Trigger	67LS304	57LS304	6	
			67LS301	57LS301	6	
	Invert	—	SN74LS240	SN54LS240	3	
		Schmitt Trigger	67LS300	57LS300	6	
	S	Non-invert	—	SN74S244	SN54S244	3
			—	SN74S241	SN54S241	3
Invert	—	SN74S240	SN54S240	3		
Transceiver	LS	Non-invert	—	SN74LS645	SN54LS645	8
Latch	LS	Non-invert	—	SN74LS373	SN54LS373	10
		Invert	—	67LS380	57LS380	13
	S	Non-invert	—	SN74S373	SN54S373	10
			32mA IOL	67S373	—	16
		Invert	—	67S380	57S380	13
			32mA IOL	67S382	—	18
Register	LS	Non-invert	—	SN74LS374	SN54LS374	10
		Invert	—	67LS376	57LS376	13
	S	Non-invert	—	SN74S374	SN54S374	10
			32mA IOL	67S374	—	16
		Invert	—	67S376	57S376	13
			32mA IOL	67S378	—	18

Package Types — All octal interface are in the 20 pin dual-in-line ceramic or plastic package.

Octal Buffers

SN54/74LS240 SN54/74S240
SN54/74LS241 SN54/74S241
SN54/74LS244 SN54/74S244

Features/Benefits

- Three-state outputs drive bus lines
- Low current PNP inputs reduce loading
- 20-pin Skinny DIP™ saves space
- 8-bits matches byte boundaries
- Ideal for microprocessor interface

Description

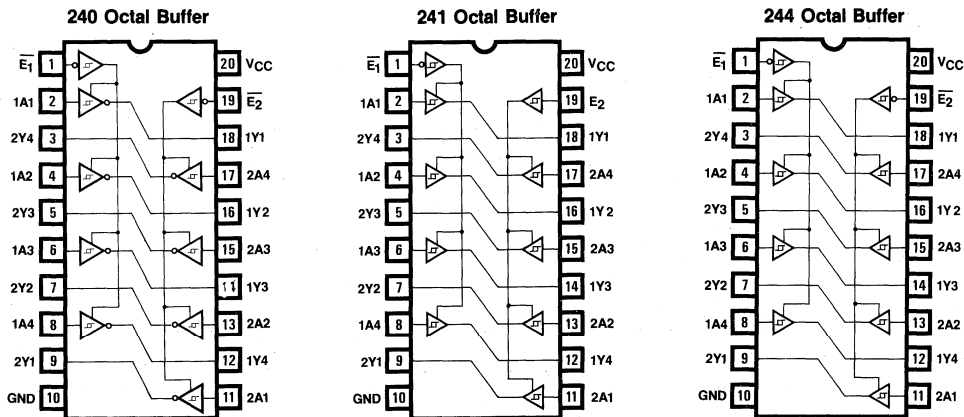
The Octal Buffers provide high speed and high current interface capability for bus organized Digital Systems. The three-state drivers will source a termination to ground (up to 133Ω) or sink a pull-up to VCC as in the popular 220Ω/330Ω computer peripheral termination. The PNP inputs provide improved fan-in with 0.2 mA I_{IL} on the Low Power Schottky buffers and 0.4mA I_{IL} on the Schottky buffers.

The 240 and 244 provide inverting and non-inverting outputs with active low enables. The 241 provides non-inverting outputs with both active low and active high enables allowing transceiver operation.

Ordering Information

PART NUMBER	PKG	TEMP.	ENABLE	POLARITY	POWER
SN54LS240 SN74LS240	J N,J	mil com	LOW	Invert	LS
SN54LS244 SN74LS244	J N,J	mil com	LOW	Non-invert	
SN54LS241 SN74LS241	J N,J	mil com	HIGH-LOW	Non-invert	
SN54S240 SN74S240	J N,J	mil com	LOW	Invert	S
SN54S244 SN74S244	J N,J	mil com	LOW	Non-Invert	
SN54S241 SN74S241	J N,J	mil com	HIGH-LOW	Non-Invert	

Logic Symbols



™Skinny DIP is a trademark of Monolithic Memories

Absolute Maximum Ratings

Supply Voltage V_{CC}	7V
Input Voltage	7V
Off-state output voltage	5.5V
Storage temperature	-65° to +150°C

Operating Conditions

SYMBOL	PARAMETER	MILITARY			COMMERCIAL			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
T_A	Operating free-air temperature	-55		125	0		75	°C

Electrical Characteristics Over Operating Conditions

SYMBOL	PARAMETER	TEST CONDITIONS	MILITARY			COMMERCIAL			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
V_{IL}	Low-level input voltage				0.7			0.8	V
V_{IH}	High-level input voltage		2			2			V
V_{IC}	Input clamp voltage	$V_{CC} = \text{MIN}, I_I = -18\text{mA}$			-1.5			-1.5	V
ΔV_T	Hysteresis ($V_{T+} - V_{T-}$)	$V_{CC} = \text{MIN}$	0.2	0.4		0.2	0.4		V
I_{IL}	Low-level input current	$V_{CC} = \text{MAX}, V_I = 0.4\text{V}$			-0.2			-0.2	mA
I_{IH}	High-level input current	$V_{CC} = \text{MAX}, V_I = 2.7\text{V}$			20			20	μA
I_I	Maximum input current	$V_{CC} = \text{MAX}, V_I = 7\text{V}$			0.1			0.1	mA
V_{OL}	Low-level output voltage	$V_{CC} = \text{MIN}, V_{IL} = \text{MAX}, V_{IH} = 2\text{V}$	$I_{OL} = 12\text{mA}$		0.4		0.4		V
			$I_{OL} = 24\text{mA}$				0.5		
V_{OH}	High-level output voltage	$V_{CC} = \text{MIN}, V_{IL} = 0.5\text{V}, V_{IH} = 2\text{V}$	$I_{OH} = -3\text{mA}$		2.4		3.4		V
			$I_{OH} = -12\text{mA}$		2				
			$I_{OH} = -15\text{mA}$				2		
I_{OZL}	Off-state output current	$V_{CC} = \text{MAX}, V_{IL} = \text{MAX}, V_{IH} = 2\text{V}$	$V_O = 0.4\text{V}$				-20		μA
I_{OZH}			$V_O = 2.7\text{V}$		20		20		
I_{OS}	Output short-circuit current *	$V_{CC} = \text{MAX}$	-40		-225	-40		-225	mA
I_{CC}	Supply Current	$V_{CC} = \text{MAX},$ Outputs open		LS240	17	27	17	27	mA
				LS241, LS244	17	27	17	27	
				LS240	26	44	26	44	
				LS241, LS244	27	46	27	46	
				LS240	29	50	29	50	
				LS241, LS244	32	54	32	54	

*Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

Switching Characteristics $V_{CC} = 5\text{V}, T_A = 25^\circ\text{C}$

SYMBOL	PARAMETER	TEST CONDITIONS (See Interface Test Load/Waveforms)	LS240			LS241, LS244			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
t_{PLH}	Data to Output delay	$C_L = 45\text{pF} \quad R_L = 667\Omega$	9	14		12	18	ns	
t_{PHL}			12	18		12	18	ns	
t_{PZL}	Output Enable delay		20	30		20	30	ns	
t_{PZH}			15	23		15	23	ns	
t_{PLZ}	Output Disable delay	$C_L = 5\text{pF} \quad R_L = 667\Omega$	15	25		15	25	ns	
t_{PHZ}			10	18		10	18	ns	

Absolute Maximum Ratings

Supply Voltage V _{CC}	7V
Input Voltage	5.5V
Off-state output voltage	5.5V
Storage temperature	-65° to +150°C

Operating Conditions

SYMBOL	PARAMETER	MILITARY			COMMERCIAL			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
T _A	Operating free-air temperature	-55		125*	0		75	°C

* The SN54S241/244J operating at free air temperature above 116°C requires a heat sink such that R_{θCA} is not more than 40°C/W.

Electrical Characteristics Over Operating Conditions

SYMBOL	PARAMETER	TEST CONDITIONS	MILITARY			COMMERCIAL			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
V _{IL}	Low-level input voltage				0.8		0.8	V	
V _{IH}	High-level input voltage		2			2		V	
V _{IC}	Input clamp voltage	V _{CC} = MIN I _I = -18mA			-1.2		-1.2	V	
ΔV _T	Hysteresis (V _{T+} - V _{T-})	V _{CC} = MIN	0.2	0.4		0.2	0.4	V	
I _{IL}	Low-level input current	V _{CC} = MAX V _I = 0.5V	Any A			-0.4			mA
			Any E			-2			
I _{IH}	High-level input current	V _{CC} = MAX V _I = 2.7V			50		50	μA	
I _I	Maximum input current	V _{CC} = MAX V _I = 5.5V			1		1	mA	
V _{OL}	Low-level output voltage	V _{CC} = MIN V _{IL} = 0.8V V _{IH} = 2V	I _{OL} = 48mA		0.55			V	
			I _{OL} = 64mA				0.55	V	
V _{OH}	High-level output voltage	V _{CC} = MIN V _{IL} = 0.8V V _{IH} = 2V	I _{OH} = -1mA			2.4	3.4	2.7	V
			I _{OH} = -3mA			2		2.4	
			I _{OH} = -12mA					2	
			I _{OH} = -15mA					2	
I _{OZL}	Off-state output current	V _{CC} = MAX V _{IL} = 0.8V V _{IH} = 2V	V _O = 0.5V		-50		-50	μA	
V _O = 2.4V				50		50	μA		
I _{OS}	Output short-circuit current †	V _{CC} = MAX	-50		-225	-50	-225	mA	
I _{CC}	Supply Current	V _{CC} = MAX Outputs open	Outputs High	S240	80	123	80	135	mA
				S241, S244	95	147	95	160	
				S240	100	145	100	150	
				S241, S244	120	170	120	180	
				S240	100	145	100	150	
Outputs Low	S240	100	145	100	150				
	S241, S244	120	170	120	180				
Outputs Disabled	S240	100	145	100	150				
	S241, S244	120	170	120	180				

† Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

Switching Characteristics V_{CC} = 5 V, T_A = 25° C

SYMBOL	PARAMETER	TEST CONDITIONS (See Interface Test Load/Waveforms)	S240			S241, S244			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
t _{PLH}	Data to Output delay	C _L = 50pF R _L = 90Ω	4.5	7		6	9	ns	
t _{PHL}			4.5	7		6	9	ns	
t _{PZL}	Output Enable delay		10	15		10	15	ns	
t _{PZH}			6.5	10		8	12	ns	
t _{PLZ}	Output Disable delay	C _L = 5pF R _L = 90Ω	10	15		10	15	ns	
t _{PHZ}			6	9		6	9	ns	



Octal Buffers with Schmitt Triggers

57/67LS300 57LS301 57/67LS304

Features/Benefits

- Schmitt trigger guarantees high noise margin
- Three-state outputs drive bus lines
- Low current PNP inputs reduce loading
- 20-pin Skinny DIP™ saves space
- 8-bits matches byte boundaries
- Ideal for microprocessor interface

Ordering Information

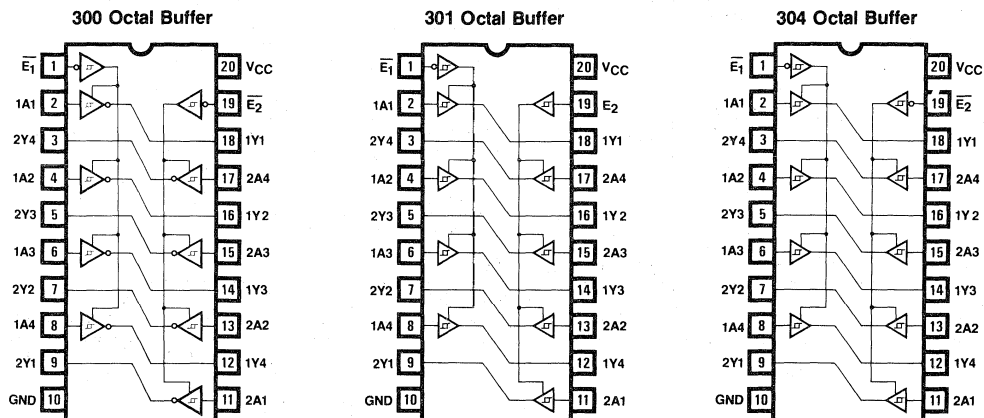
PART NUMBER	PKG	TEMP.	ENABLE	POLARITY	POWER
57LS300 67LS300	J N,J	mil com	LOW	Invert	LS
57LS304 67LS304	J N,J	mil com	LOW	Non-invert	
57LS301 67LS301	J N,J	mil com	HIGH- LOW		

Description

In addition to the standard Schottky and Low Power Schottky Octal Buffers, Monolithic Memories provides a full hysteresis with "a true" Schmitt trigger circuit. The improved performance characteristics are designed to be consistent with the SN54/74LS14 Hex Schmitt trigger and guarantee a full 400 mV noise immunity. The Schmitt trigger operation makes the LS buffers ideal for bus receivers in a noisy environment.

The Octal Buffers provide high speed and high current interface capability for bus organized Digital Systems. The PNP inputs provide improved fan-in with 0.2 mA I_L. The 300 and 304 provide inverting and non-inverting outputs with active low enables. The 301 provides non-inverting outputs with both active low and active high enables allowing transceiver operation.

Logic Symbols



Absolute Maximum Ratings

Supply Voltage VCC	7V
Input Voltage	7V
Off-state output voltage	5.5V
Storage temperature	-65° to +150°C

Operating Conditions

SYMBOL	PARAMETER	MILITARY			COMMERCIAL			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
T _A	Operating free-air temperature	-55		125	0		75	°C

Electrical Characteristics Over Operating Conditions

SYMBOL	PARAMETER	TEST CONDITIONS	MILITARY			COMMERCIAL			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
V _{T+}	Positive threshold voltage	V _{CC} = 5V	1.5	1.7	2.0	1.5	1.7	2.0	V
V _{T-}	Negative threshold voltage	V _{CC} = 5V	0.6	0.9	1.1	0.6	0.9	1.1	V
V _{IC}	Input clamp voltage	V _{CC} = MIN, I _I = -18mA			-1.5			-1.5	V
ΔV _T	Hysteresis (V _{T+} - V _{T-})	V _{CC} = 5V	0.4	0.8		0.4	0.8		V
I _{IL}	Low-level input current	V _{CC} = MAX, V _I = 0.4V			-0.2			-0.2	mA
I _{IH}	High-level input current	V _{CC} = MAX, V _I = 2.7V			20			20	μA
I _I	Maximum input current	V _{CC} = MAX, V _I = 7V			0.1			0.1	mA
V _{OL}	Low-level output voltage	V _{CC} = MIN, V _{T+} = 2V, V _{T-} = 0.6V, I _{OL} = 12mA			0.4			0.4	V
		I _{OL} = 24mA					0.5		
V _{OH}	High-level output voltage	V _{CC} = MIN, V _{T+} = 2V, V _{T-} = 0.6V, I _{OH} = -3mA	2.4	3.4		2.4	3.4		V
		I _{OH} = -12mA	2						
		I _{OH} = -15mA				2			
I _{OZL}	Off-state output current	V _{CC} = MAX, V _{T+} = 2V, V _{T-} = 0.6V, V _O = 0.4V			-20			-20	μA
I _{OZH}		V _O = 2.7V			20			20	
I _{OS}	Output short-circuit current *	V _{CC} = MAX	-40		-225	-40		-225	mA
I _{CC}	Supply Current	Outputs High Outputs Low Outputs Disabled V _{CC} = MAX, Outputs open	LS300	17	27	17	27	mA	
			LS301, LS304	18	31	18	31		
			LS300	26	44	26	44		
			LS301, LS304	32	46	32	46		
			LS300	29	50	29	50		
			LS301, LS304	34	54	34	54		

* Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

Switching Characteristics V_{CC} = 5 V, T_A = 25°C

SYMBOL	PARAMETER	TEST CONDITIONS (See Interface Test Load/Waveforms)	LS300			LS301, LS304			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
t _{PLH}	Data to Output delay	C _L = 45pF R _L = 667Ω		19		19		ns	
t _{PHL}				19		19		ns	
t _{PZL}	Output Enable delay			37		26		ns	
t _{PZH}				26		26		ns	
t _{PLZ}	Output Disable delay	C _L = 5pF R _L = 667Ω		19		22		ns	
t _{PHZ}				19		22		ns	



Octal Transceiver

SN54/74LS645

Features/Benefits

- 3-state outputs drive bus lines
- Low current PNP inputs reduce loading
- 20 pin Skinny DIP™ saves space
- 8-bits matches byte boundaries
- Ideal for microprocessor interface

Ordering Information

PART NUMBER	TYPE	TEMP	POLARITY	POWER
SN54LS645	J	mil	Non-	LS
SN74LS645	N,J	com	invert	

Description

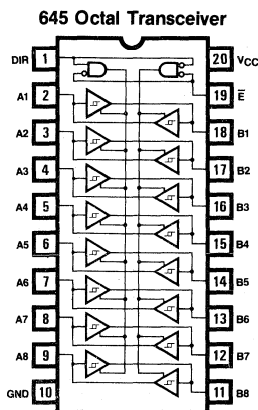
These Octal Bus transceivers are designed for asynchronous two-way communication between data buses. The control function implementation minimizes external timing requirements.

The device allows data transmission from the A bus to the B bus or from the B bus to the A bus depending upon the logic level at the direction control (DIR) input. The enable input (E) can be used to disable the device so that the buses are effectively isolated.

Function Table

ENABLE E	DIRECTION CONTROL DIR	OPERATION
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolated

Logic Symbol



SN54/74LS645

Absolute Maximum Ratings

Supply Voltage V_{CC}	7V
Input Voltage	7V
Off-state output voltage	5.5V
Storage temperature	-65° to +150°C

Operating Conditions

SYMBOL	PARAMETER	MILITARY			COMMERCIAL			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
T_A	Operating free-air temperature	-55		125	0		75	°C

Electrical Characteristics Over Operating Conditions

SYMBOL	PARAMETER	TEST CONDITIONS	MILITARY			COMMERCIAL			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
V_{IL}	Low-level input voltage				0.5			0.6	V
V_{IH}	High-level input voltage		2			2			V
V_{IC}	Input clamp voltage	$V_{CC} = \text{MIN}, I_I = -18\text{mA}$			-1.5			-1.5	V
ΔV_T	Hysteresis ($V_{T+} - V_{T-}$) A or B	$V_{CC} = \text{MIN}$	0.1	0.4		0.2	0.4		V
I_{IL}	Low-level input current	$V_{CC} = \text{MAX}, V_I = 0.4\text{V}$			-0.4			-0.4	mA
I_{IH}	High-level input current	$V_{CC} = \text{MAX}, V_I = 2.7\text{V}$			20			20	μA
I_I	Maximum input current	$V_{CC} = \text{MAX}, V_I = 5.5\text{V}$			0.1			0.1	mA
V_{OL}	Low-level output voltage	$V_{CC} = \text{MIN}, V_{IL} = \text{MAX}, V_{IH} = 2\text{V}$	$I_{OL} = 12\text{mA}$		0.25	0.4	0.25	0.4	V
			$I_{OL} = 24\text{mA}$				0.35	0.5	
V_{OH}	High-level output voltage	$V_{CC} = \text{MIN}, V_{IL} = \text{MAX}, V_{IH} = 2\text{V}$	$I_{OH} = -3\text{mA}$		2.4	3.4	2.4	3.4	V
			$I_{OH} = -12\text{mA}$		2				
			$I_{OH} = -15\text{mA}$				2		
I_{OZL}	Off-state output current	$V_{CC} = \text{MAX}, V_{IL} = \text{MAX}, V_{IH} = 2\text{V}$	$V_O = 0.4\text{V}$				-400	-400	μA
I_{OZH}			$V_O = 2.7\text{V}$				20	20	μA
I_{OS}	Output short-circuit current *	$V_{CC} = \text{MAX}$	-40		-225		-40	-225	mA
I_{CC}	Supply Current	Outputs High	$V_{CC} = \text{MAX}, \text{Outputs open}$		48	70	48	70	mA
		Outputs Low			62	90	62	90	
		Outputs Disabled			64	95	64	95	

* Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

Switching Characteristics $V_{CC} = 5\text{V}, T_A = 25^\circ\text{C}$

SYMBOL	PARAMETER	TEST CONDITIONS (See Interface Test Load/Waveforms)	A to B			B to A			UNIT	
			MIN	TYP	MAX	MIN	TYP	MAX		
t_{PLH}	Data to Output delay	$C_L = 45\text{pF}, R_L = 667\Omega$	8	15		8	15		ns	
t_{PHL}			11	15		11	15		ns	
t_{PZL}	Output Enable delay		31	40		31	40		ns	
t_{PZH}			26	40		26	40		ns	
t_{PLZ}	Output Disable delay		$C_L = 5\text{pF}, R_L = 667\Omega$	15	25		15	25		ns
t_{PHZ}			15	25		15	25		ns	

Octal Latches, Octal Registers

SN54/74LS373 SN54/74S373

SN54/74LS374 SN54/74S374

Features/Benefits

- 3-State Outputs Drive Bus Lines
- 20 Pin Skinny DIP™ Saves Space
- 8 Bits Matches Byte Boundaries
- Hysteresis Improves Noise Margin
- Low Current PNP Inputs Reduce Loading
- Ideal for Microprocessor Interface

Ordering Information

PART NUMBER	PKG	TEMP	POLARITY	TYPE	POWER
SN54LS373 SN74LS373	J N,J	mil com	Non-invert	Latch	LS
SN54LS374 SN74LS374	J N,J	mil com		Register	
SN54S373 SN74S373	J N,J	mil com		Latch	S
SN54S374 SN74S374	J N,J	mil com		Register	

Description

The latch passes eight (octal) bits of data from the inputs (D) to the outputs (Q) when the gate (G) is high. The data is "latched" when the gate (G) goes low. The register loads eight (octal) bits of input data and passes it to the output on the "rising edge" of the clock.

The three state outputs are active when \overline{OE} is low, and high

impedance when \overline{OE} is high. Schmitt-trigger buffers at the gate/clock inputs improve system noise margin by providing typically 400 mV of hysteresis.

All of the octal devices are packaged in the popular 20 Pin Skinny DIP™.

Function Tables

373 Octal Latch

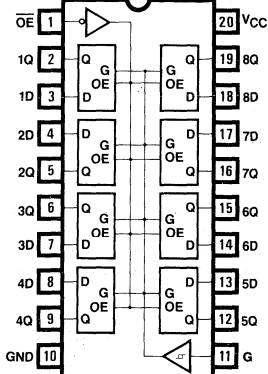
\overline{OE}	G	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q_0
H	X	X	Z

374 Octal Register

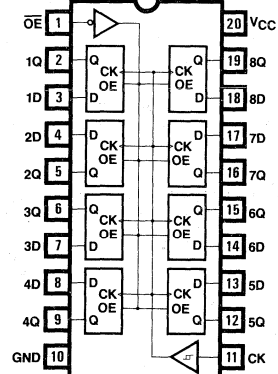
\overline{OE}	CK	D	Q
L	↑	H	H
L	↑	L	L
L	L	X	Q_0
H	X	X	Z

Logic Symbols

373 Octal Latch



374 Octal Register



Absolute Maximum Ratings

Supply Voltage, V _{CC}	7V
Input Voltage	7V
Off-state output voltage	5.5V
Storage temperature	-65° to +150°C

Operating Conditions

SYMBOL	PARAMETER	MILITARY			COMMERCIAL			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
T _A	Operating free air temperature	-55		125	0		75	°C

Electrical Characteristics Over Operating Conditions

SYMBOL	PARAMETER	TEST CONDITIONS	MILITARY			COMMERCIAL			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
V _{IL}	Low-level input voltage				0.7			0.8	V
V _{IH}	High-level input voltage		2			2			V
V _{IC}	Input clamp voltage	V _{CC} = MIN I _I = -18mA			-1.5			-1.5	V
I _{IL}	Low-level input current	V _{CC} = MAX V _I = 0.4V			-0.4			-0.4	mA
I _{IH}	High-level input current	V _{CC} = MAX V _I = 2.7V			20			20	μA
I _I	Maximum input current	V _{CC} = MAX V _I = 7V			0.1			0.1	mA
V _{OL}	Low-level output voltage	V _{CC} = MIN V _{IH} = MAX I _{OL} = 12mA		0.25	0.4		0.25	0.4	V
		V _{IH} = 2V I _{OL} = 24mA					0.35	0.5	
V _{OH}	High-level output voltage	V _{CC} = MIN V _{IL} = MAX V _{IH} = 2V		2.4	3.4				V
		I _{OH} = -1mA I _{OH} = -2.6mA					2.4	3.1	
I _{OZL}	Off-state output current	V _{CC} = MAX V _{IL} = MAX V _{IH} = 2V			-20			-20	μA
I _{OZH}		V _O = 0.4V V _O = 2.7V			20			20	
I _{OS}	Output short-circuit current *	V _{CC} = MAX		-30	-130		-30	-130	mA
I _{CC}	Supply current	V _{CC} = MAX Outputs open							mA
		LS373		24	40		24	40	
		LS374		27	40		27	40	

* Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

Switching Characteristics V_{CC} = 5 V, T_A = 25°C

SYMBOL	PARAMETER	TEST CONDITIONS (See Interface Test Load/Waveforms)	LS373			LS374			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
f _{MAX}	Maximum Clock frequency	C _L = 45pF R _L = 667Ω				35	50		MHz
t _{PLH}	Data to Output delay		12	18					ns
t _{PHL}			12	18					ns
t _{PLH}	Clock/Enable to output delay		20	30		15	28		ns
t _{PHL}			18	30		19	28		ns
t _{PZL}	Output Enable delay		25	36		21	28		ns
t _{PZH}		15	28		20	28		ns	
t _{PLZ}	Output Disable delay	C _L = 5pF R _L = 667Ω	15	25		14	25		ns
t _{PHZ}			12	20		12	20		ns
t _w	Width of Clock/Gate	High	15		15			ns	
		Low	15		15				
t _{su}	Setup time		0		20			ns	
t _h	Hold time		10		0				



Absolute Maximum Ratings

Supply Voltage, V _{CC}	7V
Input Voltage	5.5V
Off-state output voltage	5.5V
Storage temperature	-65° to +150°C

Operating Conditions

SYMBOL	PARAMETER	MILITARY			COMMERCIAL			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
T _A	Operating free air temperature	-55		125	0		75	°C

Electrical Characteristics Over Operating Conditions

SYMBOL	PARAMETER	TEST CONDITIONS	MILITARY			COMMERCIAL			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
V _{IL}	Low-level input voltage				0.8		0.8	V	
V _{IH}	High-level input voltage		2			2		V	
V _{IC}	Input clamp voltage	V _{CC} = MIN I _I = -18mA			-1.2		-1.2	V	
I _{IL}	Low-level input current	V _{CC} = MAX V _I = 0.5V			-0.25		-0.25	mA	
I _{IH}	High-level input current	V _{CC} = MAX V _I = 2.7V			50		50	μA	
I _I	Maximum input current	V _{CC} = MAX V _I = 5.5V			1		1	mA	
V _{OL}	Low-level output voltage	V _{CC} = MIN V _{IL} = 0.8V V _{IH} = 2V I _{OL} = 20mA			0.5		0.5	V	
V _{OH}	High-level output voltage	V _{CC} = MIN V _{IL} = 0.8V V _{IH} = 2V I _{OH} = -2mA	2.4	3.4				V	
						2.4	3.1		
I _{OZL}	Off-state output current	V _{CC} = MAX V _{IL} = 0.8V V _{IH} = 2V V _O = 0.5V			-50		-50	μA	
I _{OZH}		V _O = 2.4V			50		50	μA	
I _{OS}	Output short-circuit current*	V _{CC} = MAX	-40		-100	-40	-100	mA	
I _{CC}	Supply current	V _{CC} = MAX Outputs open			105	160	105	160	mA
		S373			90	140	90	140	

* Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

Switching Characteristics V_{CC} = 5 V, T_A = 25° C

SYMBOL	PARAMETER	TEST CONDITIONS (See Interface Test Load/Waveforms)	S373			S374			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
f _{MAX}	Maximum Clock frequency	C _L = 15pF R _L = 280Ω				75	100		MHz
t _{PLH}	Data to Output delay		5	9					ns
t _{PHL}			9	13					ns
t _{PLH}	Clock/Enable to output delay		7	14		8	15		ns
t _{PHL}			12	18		11	17		ns
t _{PZL}	Output Enable delay		11	18		11	18		ns
t _{PZH}			8	15		8	15		ns
t _{PLZ}	Output Disable delay		8	12		7	12		ns
t _{PHZ}		C _L = 5pF R _L = 280Ω	6	9		5	9		ns
t _w	Width of Clock/Gate	High	6		6			ns	
		Low	7.3		7.3				
t _{su}	Setup time		0		5			ns	
t _h	Hold time		10		2				

Octal Latches, Octal Registers With Inverting Outputs

57/67LS376 57/67S376
57/67LS380 57/67S380

Features/Benefits

- Inverting Outputs
- 3-State Outputs Drive Bus Lines
- 20 Pin Skinny DIP™ Saves Space
- 8 Bits Matches Byte Boundaries
- Hysteresis Improves Noise Margin
- Low Current PNP Inputs Reduce Loading
- Ideal for Microprocessor Interface

Description

In addition to the standard S and LS latches and Registers, Monolithic Memories provides inverting outputs instead of non-inverting outputs. The inverting outputs are intended for bus applications that require inversion as in interfacing the Am2901A 4-Bit Slice to an active low bus.

The latch passes eight (octal) bits of data from the inputs (D) to the outputs (Q) when the gate (G) is high. The data is "latched"

Function Tables

380 Octal Latch (Inverting)

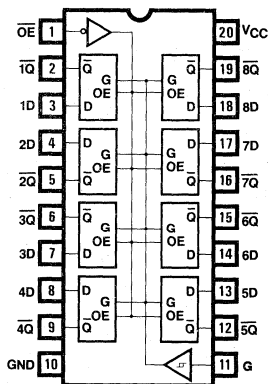
\overline{OE}	G	D	\overline{Q}
L	H	H	L
L	H	L	H
L	L	X	Q_0
H	X	X	Z

376 Octal Latch (Inverting)

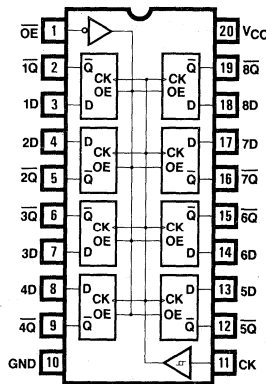
\overline{OE}	CK	D	\overline{Q}
L	↑	H	L
L	↑	L	H
L	L	X	Q_0
H	X	X	Z

Logic Symbols

380 Octal Latch (Inverting)



376 Octal Register (Inverting)



Ordering Information

PART NUMBER	PKG	TEMP	POLARITY	TYPE	POWER
57LS380 67LS380	J N,J	mil com	Invert	Latch	LS
57LS376 67LS376	J N,J	mil com		Register	
57S380 67S380	J N,J	mil com		Latch	S
57S376 67S376	J N,J	mil com		Register	

when the gate (G) goes low. The register loads eight (octal) bits of input data and passes it to the output on the "rising edge" of the clock.

The three state outputs are active when \overline{OE} is low, and high impedance when \overline{OE} is high. Schmitt-trigger buffers at the gate/clock inputs improve system noise margin by providing typically 400 mV of hysteresis.

All of the octal devices are packaged in the popular 20 Pin Skinny DIP™.

Absolute Maximum Ratings

Supply Voltage, V _{CC}	7V
Input Voltage	7V
Off-state output voltage	5.5V
Storage temperature	-65° to +150°C

Operating Conditions

SYMBOL	PARAMETER	MILITARY			COMMERCIAL			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
T _A	Operating free air temperature	-55		125	0		75	°C

Electrical Characteristics Over Operating Conditions

SYMBOL	PARAMETER	TEST CONDITIONS	MILITARY			COMMERCIAL			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
V _{IL}	Low-level input voltage				0.7		0.8	V	
V _{IH}	High-level input voltage		2			2		V	
V _{IC}	Input clamp voltage	V _{CC} = MIN I _I = -18mA			-1.5		-1.5	V	
I _{IL}	Low-level input current	V _{CC} = MAX V _I = 0.4V			-0.4		-0.4	mA	
I _{IH}	High-level input current	V _{CC} = MAX V _I = 2.7V			20		20	μA	
I _I	Maximum input current	V _{CC} = MAX V _I = 7V			0.1		0.1	mA	
V _{OL}	Low-level output voltage	V _{CC} = MIN V _{IL} = MAX V _{IH} = 2V	I _{OL} = 12mA	0.25	0.4	0.25	0.4	V	
			I _{OL} = 24mA	35	50	0.35	0.5		
V _{OH}	High-level output voltage	V _{CC} = MIN V _{IL} = MAX V _{IH} = 2V	I _{OH} = -1mA	2.4	3.4			V	
			I _{OH} = -2.6mA			2.4	3.1		
I _{OZL}	Off-state output current	V _{CC} = MAX V _{IL} = MAX V _{IH} = 2V	V _O = 0.4V				-20	μA	
I _{OZH}			V _O = 2.7V		20		20		
I _{OS}	Output short-circuit current *	V _{CC} = MAX	-30	-130	-30	-130	mA		
I _{CC}	Supply current	V _{CC} = MAX Outputs open	LS 380	36	48	36	48	mA	
			LS376	27	48	27	48		

* Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

Switching Characteristics V_{CC} = 5 V, T_A = 25°C

SYMBOL	PARAMETER	TEST CONDITIONS (See Interface Test Load/Waveforms)	LS380			LS376			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
f _{MAX}	Maximum Clock frequency	C _L = 45pF R _L = 667Ω						MHz	
t _{PLH}	Data to Output delay			17	25			ns	
t _{PHL}				12	25			ns	
t _{PLH}	Clock/Enable to output delay			20	35	19	30	ns	
t _{PHL}				18	35	15	30	ns	
t _{PZL}	Output Enable delay			25	36	21	30	ns	
t _{PZH}			17	30	20	30	ns		
t _{PLZ}	Output Disable delay	C _L = 5pF R _L = 667Ω		18	29	18	29	ns	
t _{PHZ}				16	24	16	24	ns	
t _w	Width of Clock/Gate	High	15		15		ns		
		Low	15						
t _{su}	Setup Time		0†		20†		ns		
t _h	Hold Time		10†		0†				

Absolute Maximum Ratings

Supply Voltage, VCC	7V
Input Voltage	5.5V
Off-state output voltage	5.5V
Storage temperature	-65° to +150°C

Operating Conditions

SYMBOL	PARAMETER	MILITARY			COMMERCIAL			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
T _A	Operating free air temperature	-55		125	0		75	°C

Electrical Characteristics Over Operating Conditions

SYMBOL	PARAMETER	TEST CONDITIONS	MILITARY			COMMERCIAL			UNIT	
			MIN	TYP	MAX	MIN	TYP	MAX		
V _{IL}	Low-level input voltage				0.8			0.8	V	
V _{IH}	High-level input voltage		2			2			V	
V _{IC}	Input clamp voltage	V _{CC} = MIN, I _I = -18mA			-1.2			-1.2	V	
I _{IL}	Low-level input current	V _{CC} = MAX, V _I = 0.5V			-0.25			-0.25	mA	
I _{IH}	High-level input current	V _{CC} = MAX, V _I = 2.7V			50			50	μA	
I _I	Maximum input current	V _{CC} = MAX, V _I = 5.5V			1			1	mA	
V _{OL}	Low-level output voltage	V _{CC} = MIN, V _{IL} = 0.8V, V _{IH} = 2V, I _{OL} = 20mA			0.5			0.5	V	
V _{OH}	High-level output voltage	V _{CC} = MIN, V _{IL} = 0.8V, V _{IH} = 2V, I _{OH} = -2mA	2.4	3.4					V	
							2.4	3.1		
I _{OZL}	Off-state output current	V _{CC} = MAX, V _{IL} = 0.8V, V _{IH} = 2V, V _O = 0.5V			-50			-50	μA	
I _{OZH}					50			50	μA	
I _{OS}	Output short-circuit current *	V _{CC} = MAX	-40		-100			-40	-100	mA
I _{CC}	Supply current	V _{CC} = MAX, Outputs open			105	160		105	160	mA
		S380			90	140		90	140	
		S376								

*Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

Switching Characteristics V_{CC} = 5 V, T_A = 25° C

SYMBOL	PARAMETER	TEST CONDITIONS (See Interface Test Load/Waveforms)	S380			S376			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
f _{MAX}	Maximum Clock frequency	C _L = 15pF R _L = 280Ω				75	100		MHz
t _{PLH}	Data to Output delay		9	18					ns
t _{PHL}			5	16					ns
t _{PLH}	Clock/Enable to output delay		12	22		11	20		ns
t _{PHL}			7	20		8	18		ns
t _{PZL}	Output Enable delay		11	20		11	20		ns
t _{PZH}		8	17		8	17		ns	
t _{PLZ}	Output Disable delay	C _L = 5pF R _L = 280Ω	8	16		7	16		ns
t _{PHZ}			6	13		5	13		ns
t _w	Width of Clock/Gate	High	6		6				ns
		Low	7.3		7.3				
t _{su}	Setup time		0		5				ns
t _h	Hold time		10		2				ns



Octal Latches, Octal Registers With 32mA Outputs

67S373 67S374

Features/Benefits

- 32mA I_{OL}
- 3-State Outputs Drive Bus Lines
- 20 Pin Skinny DIP™ Saves Space
- 8 Bits Matches Byte Boundaries
- Hysteresis Improves Noise Margin
- Low Current PNP Inputs Reduce Loading
- Ideal for Microprocessor Interface

Description

In addition to the standard S and LS latches and registers, Monolithic Memories provides increased output sink current (I_{OL}) from the standard Schottky I_{OL} of 20 mA to an improved 32 mA.

The higher I_{OL} is intended for upgrading systems which presently satisfy 32 mA requirements with SN54/74365, 366, 367, 368, Hex Buffers.

Function Tables

373 Octal Latch

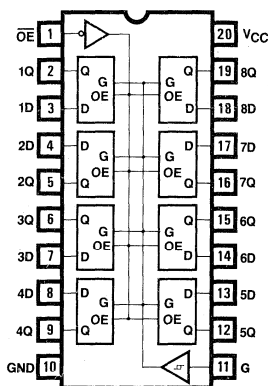
\overline{OE}	G	D	Q
L	H	H	H
L	H	L	L
L	L	X	Q ₀
H	X	X	Z

374 Octal Register

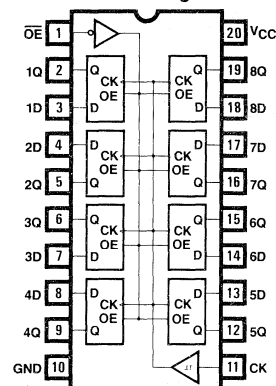
\overline{OE}	CK	D	Q
L	↑	H	H
L	↑	L	L
L	L	X	Q ₀
H	X	X	Z

Logic Symbols

373 Octal Latch



374 Octal Register



Ordering Information

PART NUMBER	PKG	TEMP	POLARITY	TYPE	POWER
67S373	N,J	com	Non-invert	Latch	S
67S374	N,J	com		Register	

The latch passes eight (octal) bits of data from the inputs (D) to the outputs (Q) when the gate (G) is high. The data is "latched" when the gate (G) goes low. The register loads eight (octal) bits of input data and passes it to the output on the "rising edge" of the clock.

The three state outputs are active when \overline{OE} is low, and high impedance when \overline{OE} is high. Schmitt-trigger buffers at the gate/clock inputs improve system noise margin by providing typically 400 mV of hysteresis.

All of the octal devices are packaged in the popular 20 Pin Skinny DIP™.

Absolute Maximum Ratings

Supply Voltage, V _{CC}	7V
Input Voltage	5.5V
Off-state output voltage	5.5V
Storage temperature	-65° to +150°C

Operating Conditions

SYMBOL	PARAMETER	COMMERCIAL			UNIT
		MIN	TYP	MAX	
V _{CC}	Supply voltage	4.75	5	5.25	V
T _A	Operating free air temperature	0		75	°C

Electrical Characteristics Over Operating Conditions

SYMBOL	PARAMETER	TEST CONDITIONS	COMMERCIAL			UNIT
			MIN	TYP	MAX	
V _{IL}	Low-level input voltage				0.8	V
V _{IH}	High-level input voltage		2			V
V _{IC}	Input clamp voltage	V _{CC} = MIN, I _I = -18mA			-1.2	V
I _{IL}	Low-level input current	V _{CC} = MAX, V _I = 0.5V			-0.25	mA
I _{IH}	High-level input current	V _{CC} = MAX, V _I = 2.7V			50	μA
I _I	Maximum input current	V _{CC} = MAX, V _I = 5.5V			1	mA
V _{OL}	Low-level output voltage	V _{CC} = MIN, V _{IL} = 0.8V, V _{IH} = 2V, I _{OL} = 32mA			0.5	V
V _{OH}	High-level output voltage	V _{CC} = MIN, V _{IL} = 0.8V, V _{IH} = 2V, I _{OH} = -6.5mA	2.4	3.1		V
I _{OZL}	Off-state output current	V _{CC} = MAX, V _{IL} = 0.8V, V _{IH} = 2V, V _O = 0.5V			-50	μA
I _{OZH}		V _O = 2.4V			50	μA
I _{OS}	Output short-circuit current *	V _{CC} = MAX,	-40		-100	mA
I _{CC}	Supply current	V _{CC} = MAX, S373		105	160	mA
		Outputs open, S374		90	140	

*Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

Switching Characteristics V_{CC} = 5 V, T_A = 25° C

SYMBOL	PARAMETER	TEST CONDITIONS (See Interface Test Load/Waveforms)	S373			S374			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
f _{MAX}	Maximum Clock frequency	C _L = 15pF R _L = 280Ω				75	100		MHz
t _{PLH}	Data to Output delay			5	9				ns
t _{PHL}				9	13				ns
t _{PLH}			Clock/Enable to output delay		7	14	8	15	
t _{PHL}				12	18	11	17		ns
t _{PZL}	Output Enable delay				11	18	11	18	
t _{PZH}				8	15	8	15		ns
t _{PLZ}	Output Disable delay	C _L = 5pF R _L = 280Ω		8	12	7	12		ns
t _{PHZ}				6	9	5	9		ns
t _w	Width of Clock/Enable	High	6		6			ns	
		Low	7.3		7.3				
t _{SU}	Setup Time		0		5			ns	
t _H	Hold Time		10		2			ns	



Octal Latches, Octal Registers With Inverting, 32 mA Outputs

67S378 67S382

Features/Benefits

- Inverting Outputs
- 32 mA IOL
- 3-State Outputs Drive Bus Lines
- 20 Pin Skinny DIP™ Saves Space
- 8 Bits Matches Byte Boundaries
- Hysteresis Improves Noise Margin
- Low Current PNP Inputs Reduce Loading
- Ideal for Microprocessor Interface

Description

In addition to the standard S and LS latches and registers, Monolithic Memories provides increased output sink current (IOL) from the standard Schottky IOL of 20 mA to an improved 32 mA, also inverting outputs instead of the standard non-inverting outputs.

The higher IOL is intended for upgrading systems which presently satisfy 32 mA requirements with SN54/74365, 366, 367, 368, Hex Buffers. The inverting outputs are intended for bus

Ordering Information

PART NUMBER	PKG	TEMP	POLARITY	TYPE	POWER
67S382	N,J	com	Invert	Latch	S
67S378	N,J	com		Register	

applications that require inversion as in interfacing the Am2901A 4-Bit Slice to an active low bus.

The latch passes eight (octal) bits of data from the inputs (D) to the outputs (Q) when the gate (G) is high. The data is "latched" when the gate (G) goes low. The register loads eight (octal) bits of input data and passes it to the output on the "rising edge" of the clock.

The three state outputs are active when \overline{OE} is low, and high impedance when \overline{OE} is high. Schmitt-trigger buffers at the gate/clock inputs improve system noise margin by providing typically 400 mV of hysteresis.

All of the octal devices are packaged in the popular 20 Pin Skinny DIP™.

Function Tables

382 Octal Latch (Inverting)

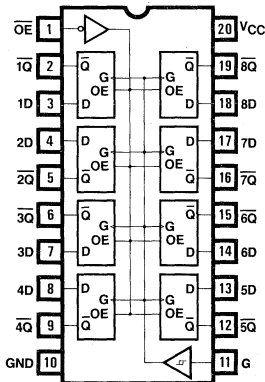
\overline{OE}	G	D	\overline{Q}
L	H	H	L
L	H	L	H
L	L	X	Q_0
H	X	X	Z

378 Octal Register (Inverting)

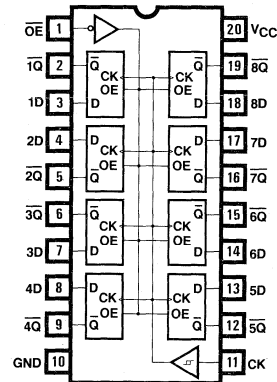
\overline{OE}	CK	D	\overline{Q}
L	↑	H	L
L	↑	L	H
L	L	X	Q_0
H	X	X	Z

Logic Symbols

382 Octal Latch (Inverting)



378 Octal Register (Inverting)



Monolithic Memories 

Absolute Maximum Ratings

Supply Voltage, V _{CC}	7V
Input Voltage	5.5V
Off-state output voltage	5.5V
Storage temperature	-65° to +150°C

Operating Conditions

SYMBOL	PARAMETER	COMMERCIAL			UNIT
		MIN	TYP	MAX	
V _{CC}	Supply voltage	4.75	5	5.25	V
T _A	Operating free air temperature	0		75	°C

Electrical Characteristics Over Operating Conditions

SYMBOL	PARAMETER	TEST CONDITIONS	COMMERCIAL			UNIT
			MIN	TYP	MAX	
V _{IL}	Low-level input voltage				0.8	V
V _{IH}	High-level input voltage		2			V
V _{IC}	Input clamp voltage	V _{CC} = MIN, I _I = -18mA			-1.2	V
I _{IL}	Low-level input current	V _{CC} = MAX, V _I = 0.5V			-0.25	mA
I _{IH}	High-level input current	V _{CC} = MAX, V _I = 2.7V			50	μA
I _I	Maximum input current	V _{CC} = MAX, V _I = 5.5V			1	mA
V _{OL}	Low-level output voltage	V _{CC} = MIN, V _{IL} = 0.8V, V _{IH} = 2V, I _{OL} = 32mA			0.5	V
V _{OH}	High-level output voltage	V _{CC} = MAX, V _{IL} = 0.8V, V _{IH} = 2V, I _{OH} = -6.5mA	2.4	3.1		V
I _{OZL}	Off-state output current	V _{CC} = MIN, V _{IL} = 0.8V, V _{IH} = 2V, V _O = 0.5V			-50	μA
I _{OZH}		V _O = 2.4V			50	μA
I _{OS}	Output short-circuit current *	V _{CC}	-40		-100	mA
I _{CC}	Supply current	V _{CC} = MAX, Outputs open		105	160	mA
		S382		90	140	

*Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second.

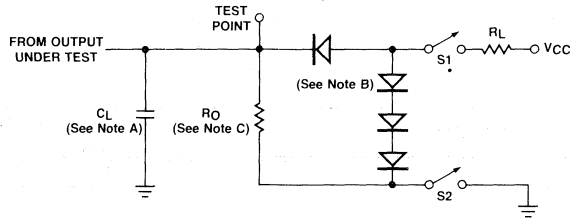
Switching Characteristics V_{CC} = 5 V, T_A = 25° C

SYMBOL	PARAMETER	TEST CONDITIONS (See Interface Test Load/Waveforms)	S382			S378			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
f _{MAX}	Maximum Clock frequency	C _L = 15pF R _L = 280Ω				75	100		MHz
t _{PLH}	Data to Output delay		9	18					ns
t _{PHL}			5	16					ns
t _{PLH}	Clock/Enable to output delay		12	22		11	20		ns
t _{PHL}			7	20		8	18		ns
t _{PZL}	Output Enable delay		11	20		11	20		ns
t _{PZH}		8	17		8	17		ns	
t _{PLZ}	Output Disable delay	C _L = 5pF R _L = 280Ω	8	16		7	16		ns
t _{PHZ}			6	13		5	13		ns
t _w	Width of Clock/Enable	High	6		6			ns	
		Low	7.3		7.3				
t _{su}	Setup Time		0		5		ns		
t _h	Hold Time		10		2				

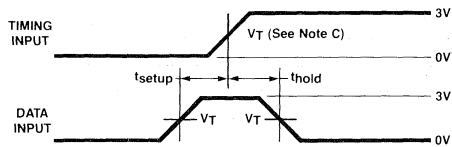


Interface Test Load/Waveforms

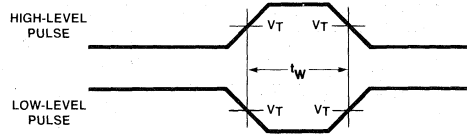
Test Load



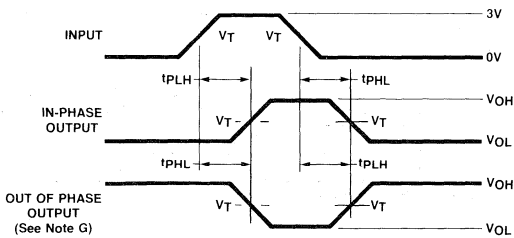
Test Waveforms



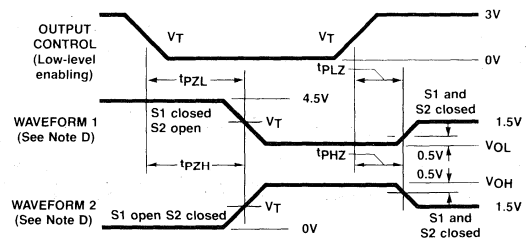
Setup and Hold



Pulse Width

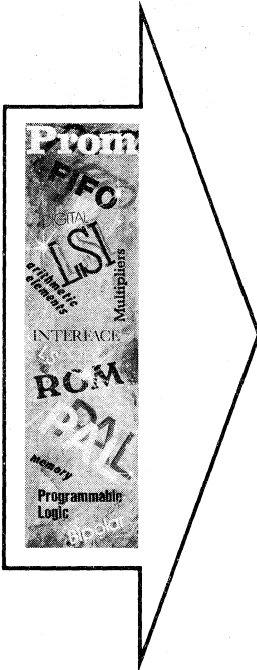


Propagation Delay



Enable and Disable

- NOTES: A. C_L includes probe and jig capacitance.
 B. All diodes are 1N916 or 1N3064.
 C. For Series 54/74S, 57/67S, $R_O = 1K$, $V_T = 1.5V$
 For Series 54/74LS and 57/67LS, $R_O = 5K$, $V_T = 1.2V$ excepting 57/67LS300, 301, 304
 For Series 54/74LS300, 301, 304 $R_O = 5K$, $V_T = V_{T+} = 1.7V$ for low to high input transition
 For Series 54/74LS300, 301, 304 $R_O = 5K$, $V_T = V_{T-} = 0.9V$ for high to low input transition
 D. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
 Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 E. In the examples above, the phase relationships between inputs and outputs have been chosen arbitrarily.
 F. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, $Z_{out} = 50\Omega$ and:
 For Series 54/74S and 57/67S, $t_R \leq 2.5$ ns $t_F \leq 2.5$ ns
 For Series 54/74LS and 57/67LS, and PALs, $t_R \leq 15$ ns $t_F \leq 6$ ns
 G. When measuring propagation delay times of 3-state outputs, switches S1 and S2 are closed.



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Setup Time

Setup time, t_{su}

The time interval between the application of a signal that is maintained at a specified input terminal and a consecutive active transition at another specified input terminal.

- NOTES: 1. The setup time is the actual time between two events and may be insufficient to accomplish the setup. A minimum value is specified that is the shortest interval for which correct operation of the logic element is guaranteed.
2. The setup time may have a negative value in which case the minimum limit defines the longest interval (between the active transition and the application of the other signal) for which correct operation of the logic element is guaranteed.

Voltage

High-level input voltage, V_{IH}

An input voltage within the more positive (less negative) of the two ranges of values used to represent the binary variables.

NOTE: A minimum is specified that is the least positive value of high-level voltage for which operation of the logic element within specification limits is guaranteed.

High-level output voltage, V_{OH}

The voltage at an output terminal with input conditions applied that according to the product specification will establish a high level at the output.

Input clamp voltage, V_{IC}

An input voltage in a region of relatively low differential resistance that serves to limit the input voltage swing.

Low-level input voltage, V_{IL}

An input voltage level within the less positive (more negative) of the two ranges of values used to represent the binary variables.

NOTE: A maximum is specified that is the most positive value of low-level input voltage for which operation of the logic element within specification limits is guaranteed.

Low-level output voltage, V_{OL}

The voltage at an output terminal with input conditions applied that according to the product specification will establish a low level at the output.

Negative-going threshold voltage, V_T-

The voltage level at a transition-operated input that causes operation of the logic element according to specification as the input voltage falls from a level above the positive-going threshold voltage, V_{T+} .

Positive-going threshold voltage, V_{T+}

The voltage level at a transition-operated input that causes operation of the logic element according to specification as the input voltage rises from a level below the negative-going threshold voltage, V_{T-} .

Truth Table Explanations

H	= high level (steady-state)
L	= low level (steady-state)
↑	= transition from low to high level
↓	= transition from high to low level
X	= irrelevant (any input, including transitions)
Z	= off (high-impedance) state of a 3-state output
a..h	= the level of steady-state inputs at inputs A through H respectively
Q_0	= level of Q before the indicated steady-state input conditions were established
\overline{Q}_0	= complement of Q_0 or level of \overline{Q} before the indicated steady-state input conditions were established
Q_n	= level of Q before the most recent active transition indicated by ↓ or ↑

If, in the input columns, a row contains only the symbols H, L, and/or X, this means the indicated output is valid whenever the input configuration is achieved and regardless of the sequence in which it is achieved. The output persists so long as the input configuration is maintained.

If, in the input columns, a row contains H, L, and/or X together with ↑ and/or ↓, this means the output is valid whenever the input configuration is achieved but the transition(s) must occur following the achievement of the steady-state levels. If the output is shown as a level (H, L, Q_0 , or \overline{Q}_0), it persists so long as the steady-state input levels and the levels that terminate indicated transitions are maintained. Unless otherwise indicated, input transitions in the opposite direction to those shown have no effect at the output.

Clock Frequency

Maximum clock frequency, f_{max}

The highest rate at which the clock input of a bistable circuit can be driven through its required sequence while maintaining stable transitions of logic level at the output with input conditions established that should cause changes of output logic level in accordance with the specification.

Current

High-level input current, I_{IH}

The current into * an input when a high-level voltage is applied to that input.

High-level output current, I_{OH}

The current into * an output with input conditions applied that according to the product specification will establish a high level at the output.

High-level output current, I_{CEX}

The high-level leakage current of an open collector output.

Low-level input current, I_{IL}

The current into * an input when a low-level voltage is applied to that input.

Low-level output current, I_{OL}

The current into * an output with input conditions applied that according to the product specification will establish a low level at the output.

Off-state (high-impedance-state) output current (of a three-state output), I_{OZ}

The current into * an output having three-state capability with input conditions applied that according to the product specification will establish the high-impedance state at the output.

Short-circuit output current, I_{OS}

The current into * an output when that output is short-circuited to ground (or other specified potential) with input conditions applied to establish the output logic level farthest from ground potential (or other specified potential).

Supply current, I_{CC}

The current into * the V_{CC} supply terminal of an integrated circuit.

*Current out of a terminal is given as a negative value.

Hold Time

Hold time, t_H

The interval during which a signal is retained at a specified input terminal after an active transition occurs at another specified input terminal.

NOTES: 1. The hold time is the actual time between two events and may be insufficient to accomplish the intended result. A minimum value is specified that is the shortest interval for which correct operation of the logic element is guaranteed.

2. The hold time may have a negative value in which case the minimum limit defines the longest interval (between the release of data and the active transition) for which correct operation of the logic element is guaranteed.

Output Enable and Disable Time

Output enable time (of a three-state output) to high level, t_{PZH} (or low level, t_{PZL})

The propagation delay time between the specified reference points on the input and output voltage waveforms with the three-state output changing from a high-impedance (off) state to the defined high (or low) level.

Output enable time (of a three-state output) to high or low level, t_{PZX}

The propagation delay time between the specified reference points on the input and output voltage waveforms with the three-state output changing from a high-impedance (off) state to either of the defined active levels (high or low).

Output disable time (of a three-state output) from high level, t_{PHZ} (or low level, t_{PLZ})

The propagation delay time between the specified reference points on the input and output voltage waveforms with the three-state output changing from the defined high (or low) level to a high-impedance (off) state.

Output disable time (of a three-state output) from high or low level, t_{PXZ}

The propagation delay time between the specified reference points on the input and output voltage waveforms with the three-state output changing from either of the defined active levels (high or low) to a high-impedance (off) state.

t_{EA} is the output enable access time of memory devices.
 t_{ER} is the output disable (enable recovery) time of memory devices.

Propagation Time

Propagation delay time, t_{PD}

The time between the specified reference points on the input and output voltage waveforms with the output changing from one defined level (high or low) to the other defined level.

Propagation delay time, low-to-high-level output, t_{PLH}

The time between the specified reference points on the input and output voltage waveforms with the output changing from the defined low level to the defined high level.

Propagation delay time, high-to-low-level output, t_{PHL}

The time between the specified reference points on the input and output voltage waveforms with the output changing from the defined high level to the defined low level.

t_{AA} is the address (to output) access time of memory devices.

Pulse Width

Pulse width, t_W

The time interval between specified reference points on the leading and trailing edges of the pulse waveform.

10

PROM/ROM Programming Input Format

Programming Input Formats

MMI can program your ROM or PROM from input data in any of several types: truth table, punched cards, paper tape or pre-programmed ROM or PROM. However, the preferred input data for PROMs is paper tape and for ROMs punched cards.

Truth Table Inputs

Devices are programmed at our facility from MMI truth table forms (available on request). For customers desiring to make their own forms, examples are shown below:

4-BIT OUTPUT	WORD NUMBER	PIN	OUTPUTS			
			10	11	12	13
	0		O ₄	O ₃	O ₂	O ₁
	1		H	H	H	L
	255		L	H	H	H

8-BIT OUTPUT	WORD NUMBER	PIN	OUTPUTS							
			17	16	15	14	13	11	10	9
	0		O ₈	O ₇	O ₆	O ₅	O ₄	O ₃	O ₂	O ₁
	1		H	H	H	L	H	L	H	H
	511		L	H	H	H	H	H	H	L

NOTE: A high voltage on the data out lines is signified by an "H." A low voltage on the data out lines is signified by an "L." The word number assumes positive logic on the address pins, so for example, word 1023 = HHHHHHHHHH.

Paper Tape Format Inputs

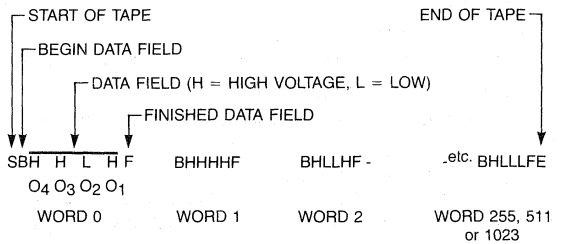
Truth tables can also be sent to MMI in an ASCII tape in either a 7 or 8 level format. Send information air mail or TWX 910-339-9224. The tape reading equipment at MMI only recognizes ASCII characters S, B, H, L, F and E and interprets them respectively

as Start, Begin a word, High data, Low data, Finish a word, and End of tape. All other characters such as carriage returns, line feeds, etc. are ignored so that comments and spaces may be sent in the data field to improve readability. Comments, however, should not use the characters S, B, H, L, F, E. Word addresses must begin with zero and count sequentially to word 31, 255, 511 or 1023 respectively.

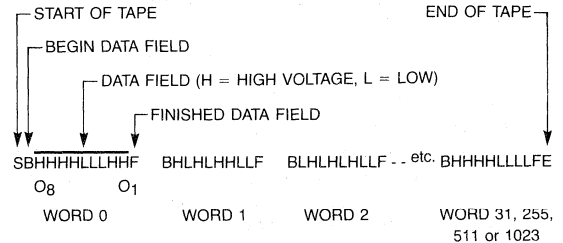
In order to assist the machine operator in determining where the heading information stops and the data field begins, 25 bell characters or rubout characters should precede the start of the truth table. Any type of 8 level paper tape (mylar, fanfold, etc.) is acceptable. Channel 1 is the most significant bit and channel 8 (parity) is ignored. Sprocket holes are located between channels 3 and 4. Note that the order of the outputs between characters B and F is O₄, O₃, O₂, O₁, not O₁, O₂, O₃, O₄.

A typical list of characters and their machine interpretations is shown below:

4-BIT OUTPUT



8-BIT OUTPUT



The required heading information at the beginning of the tape is as follows:

CUSTOMER'S NAME AND PHONE _____ TRUTH TABLE NUMBER _____
 CUSTOMER'S TWX NUMBER _____ NUMBER OF TRUTH TABLES _____
 PURCHASE ORDER NUMBER _____ TOTAL NUMBER OF PARTS _____
 MMI PART NUMBER _____ NUMBER OF PARTS OF EACH TRUTH TABLE _____
 CUSTOMER SYMBOLIZED PART NUMBER _____ 25 BELL OR RUBOUT CHARACTERS _____

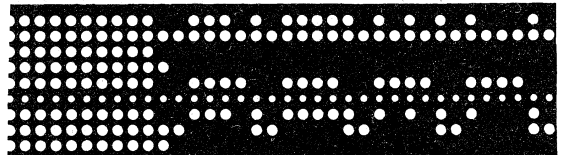
An example is shown below for a 256 x 4 PROM (6300)

SCOTT ELECTRONICS 408 426-6134
 TWX 911-338-9225

PO142
 6300
 0431
 12
 1
 3
 3

SBLLHF BLLLFF BLHLHF BLHHFF BLLHFF BHHHFF BLLLHF BLHLHF BLLLFF
 BLLLFF BLHLHF BLLHFF BHHHFF BHHLLF BLLHFF BHHLLF BLLLHF BLHLHF

8 level
 TWX



PROM/ROM Programming Input Format

ROM Programming Punched Card

ROMs can be programmed using several input methods. These are truth table, punched cards in the format shown below, paper tape in the same format as cards, and paper tape in the ASCII BHLF format of the equivalent PROM.

Punched Card or Tape Input

First card or line (80 columns max.): enter Company Name, Part Number, Data, Number of "L's" in Pattern.

(Free Form Entry: no commas; Paper Tape Format: terminate each line with carriage return and linefeed).

Hexadecimal Format

In this format the heading required is identical to the BHLF format but the data is different. Instead of an "S," the hexadecimal data begins with the SOH character (control A). The data is then represented by the hexadecimal character (0-9 and A-F) which represents the output data of address 0, followed by a space. Next comes the output data of address 1 followed by a space, etc. The character ETX (control C) is used to end the data. Carriage return and the line feed may be included to format the data when the tape is printed.

CARD 1

COMPANY NAME CX 1816—2052 7—12—70 L = 796

2nd Card Or Line thru Last (80 Columns Max.)

ENTER WORD ADDRESS OF FIRST DATA FIELD IN COLUMNS 1 THRU 5

Enter First Data Field (O₁₀—O₁) in Columns 8 thru 17

Enter Second Data Field (O₁₀—O₁) in Columns 19 thru 28

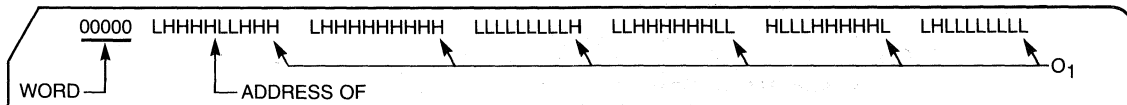
Enter Third Data Field (O₁₀—O₁) in Columns 30 thru 39

Enter Fourth Data Field (O₁₀—O₁) in Columns 41 thru 50

Enter Fifth Data Field (O₁₀—O₁) in Columns 52 thru 61

Enter Sixth Data Field (O₁₀—O₁) in Columns 63 thru 72

CARD 2



NOTE: Output 1 (O₁) is always in cols. 17,28,39,50,61,72

CARD 3

00006 LLLLLLLL HHHHHHHHH LHLHLLHHL HHHHHHLLL LLLHHHLHL HHHHHHLH

LAST CARD

01020 HLLLLLLL HHLHHHHHL LHLHLHLHL LLHLHLLHH

NOTES:

- Leading edge zeroes in the word number may be eliminated. Columns 73 thru 80 are for comments.
- Regardless of the number of outputs which a particular ROM has, the data for a specific output always goes in a specific column.

Output 1 (01)	Columns 17, 28, 39, 50, 61, 72
Output 2 (02)	Columns 16, 27, 38, 49, 60, 71
Output 3 (03)	Columns 15, 26, 37, 48, 59, 70
Output 4 (04)	Columns 14, 25, 36, 47, 58, 69

- | | |
|----------------|--------------------------------|
| Output 5 (05) | Columns 13, 24, 35, 46, 57, 68 |
| Output 6 (06) | Columns 12, 23, 34, 45, 56, 67 |
| Output 7 (07) | Columns 11, 22, 33, 44, 55, 66 |
| Output 8 (08) | Columns 10, 21, 32, 43, 54, 65 |
| Output 9 (09) | Columns 9, 20, 31, 42, 53, 64 |
| Output 10 (10) | Columns 8, 19, 30, 41, 52, 63 |

- 0 and 1 may replace L and H, but the customer must define for MMI whether 0 = L or 0 = H.

Application Notes

PROMS

- **PROM card simplifies computer diagnosis**
Shlomo Waser, Computer Design, January 1977
- **Registered PROMs Impact Computer Architecture**
John Birkner

PAL

- **Reduce random-logic complexity by using arrays of fuse-programmable circuits**
John Birkner, Electronic Design, August 16, 1978
- **High speed/low cost fuse link arrays compete with TTL 74S/LS**
John Birkner, WESCON '78
- **Synthesis of stable output state sequencers**
Bill Black, WESCON '78
- **PALs: Programmable logic functions help minimize hardware**
John Birkner, WESCON '79

FIFO

- **First-in First-out Memories**
Operations and Applications

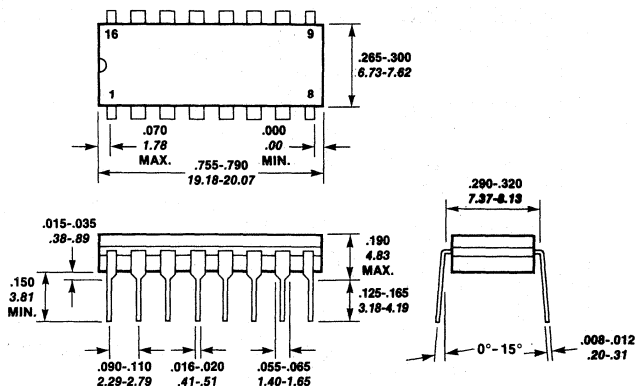
MULTIPLIERS

- **Real-time processing gains ground with fast digital multiplier**
Shlomo Waser and Allen Peterson, Electronics, September 29, 1977
- **State-of-the-art in high speed arithmetic integrated circuits**
Shlomo Waser, Computer Design, July 1978
- **Dedicated multiplier ICs speed up processing in fast computer systems**
Shlomo Waser, Electronic Design, September 1978
- **High-speed monolithic multipliers for real-time digital signal processing**
Shlomo Waser, Computer, October 1978
- **Medium-speed multipliers trim cost, shrink bandwidth in speed transmission**
Shlomo Waser and Dr. Allen Peterson, Electronic Design, February 1, 1979

J16 Ceramic DIP

$\theta_{JA} = 75^\circ \text{ C/W}$

$\theta_{JC} = 35^\circ \text{ C/W}$

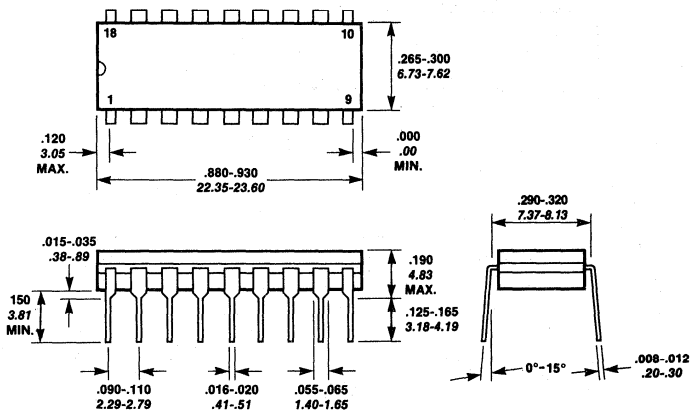


UNLESS OTHERWISE SPECIFIED:
ALL DIMENSIONS MIN.-MAX. IN INCHES.
ALL DIMENSIONS MIN.-MAX. IN MILLIMETERS.

J18 Ceramic DIP

$\theta_{JA} = 75^\circ \text{ C/W}$

$\theta_{JC} = 35^\circ \text{ C/W}$



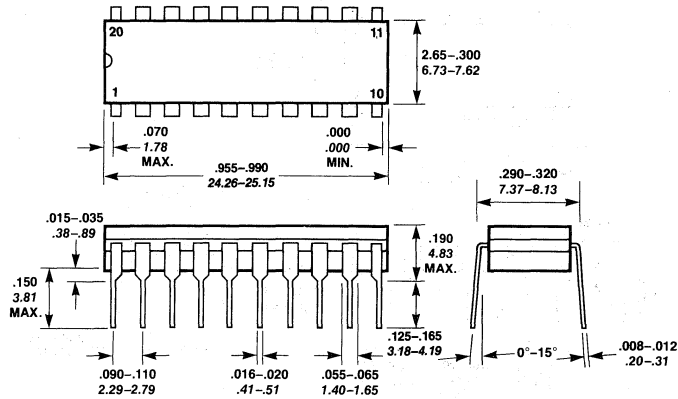
UNLESS OTHERWISE SPECIFIED:
ALL DIMENSIONS MIN.-MAX. IN INCHES.
ALL DIMENSIONS MIN.-MAX. IN MILLIMETERS.

10

J20 Ceramic DIP

$\theta_{JA} = 75^{\circ}C/W$

$\theta_{JC} = 35^{\circ}C/W$

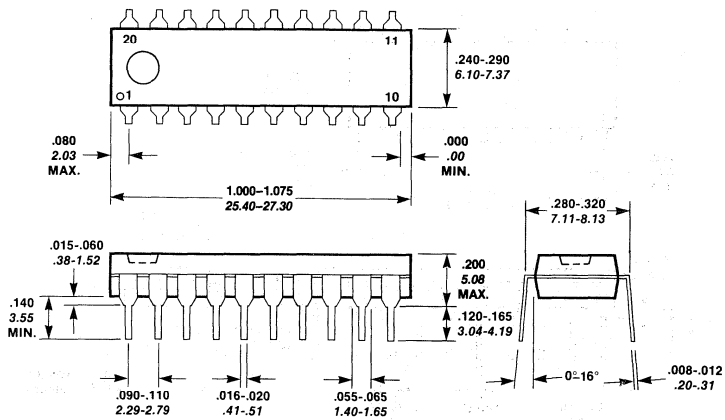


UNLESS OTHERWISE SPECIFIED:
ALL DIMENSIONS MIN.-MAX. IN INCHES.
ALL DIMENSIONS MIN.-MAX. IN MILLIMETERS.

N20 Plastic Kool DIP™

$\theta_{JA} = 75^{\circ}C/W$

$\theta_{JC} = 35^{\circ}C/W$

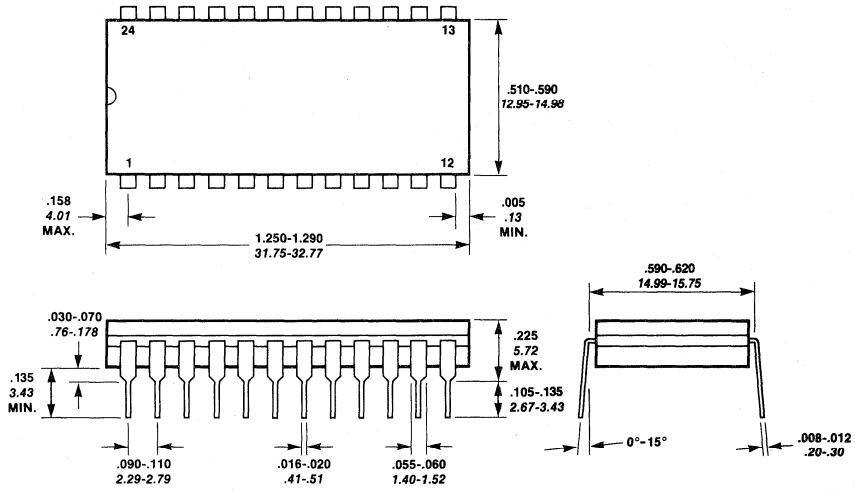


UNLESS OTHERWISE SPECIFIED:
ALL DIMENSIONS MIN.-MAX. IN INCHES.
ALL DIMENSIONS MIN.-MAX. IN MILLIMETERS.

J24 Ceramic DIP

$\theta_{JA} = 65^{\circ}\text{C/W}$

$\theta_{JC} = 30^{\circ}\text{C/W}$

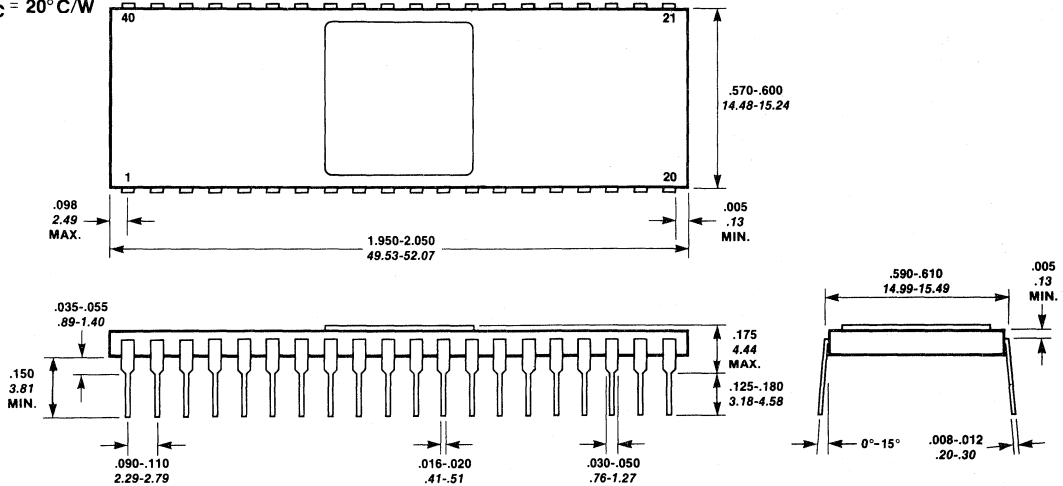


UNLESS OTHERWISE SPECIFIED:
ALL DIMENSIONS MIN.-MAX. IN INCHES.
ALL DIMENSIONS MIN.-MAX. IN MILLIMETERS

D40 Side Brazed Ceramic DIP

$\theta_{JA} = 55^{\circ}\text{C/W}$

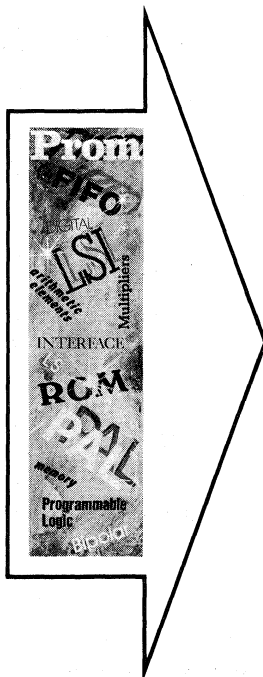
$\theta_{JC} = 20^{\circ}\text{C/W}$



UNLESS OTHERWISE SPECIFIED:
ALL DIMENSIONS MIN.-MAX. IN INCHES.
ALL DIMENSIONS MIN.-MAX. IN MILLIMETERS.



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Quality Components	(214) 387-4949
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Hall-Mark Electronics	(713) 781-6100
Quality Components	(713) 772-7100
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